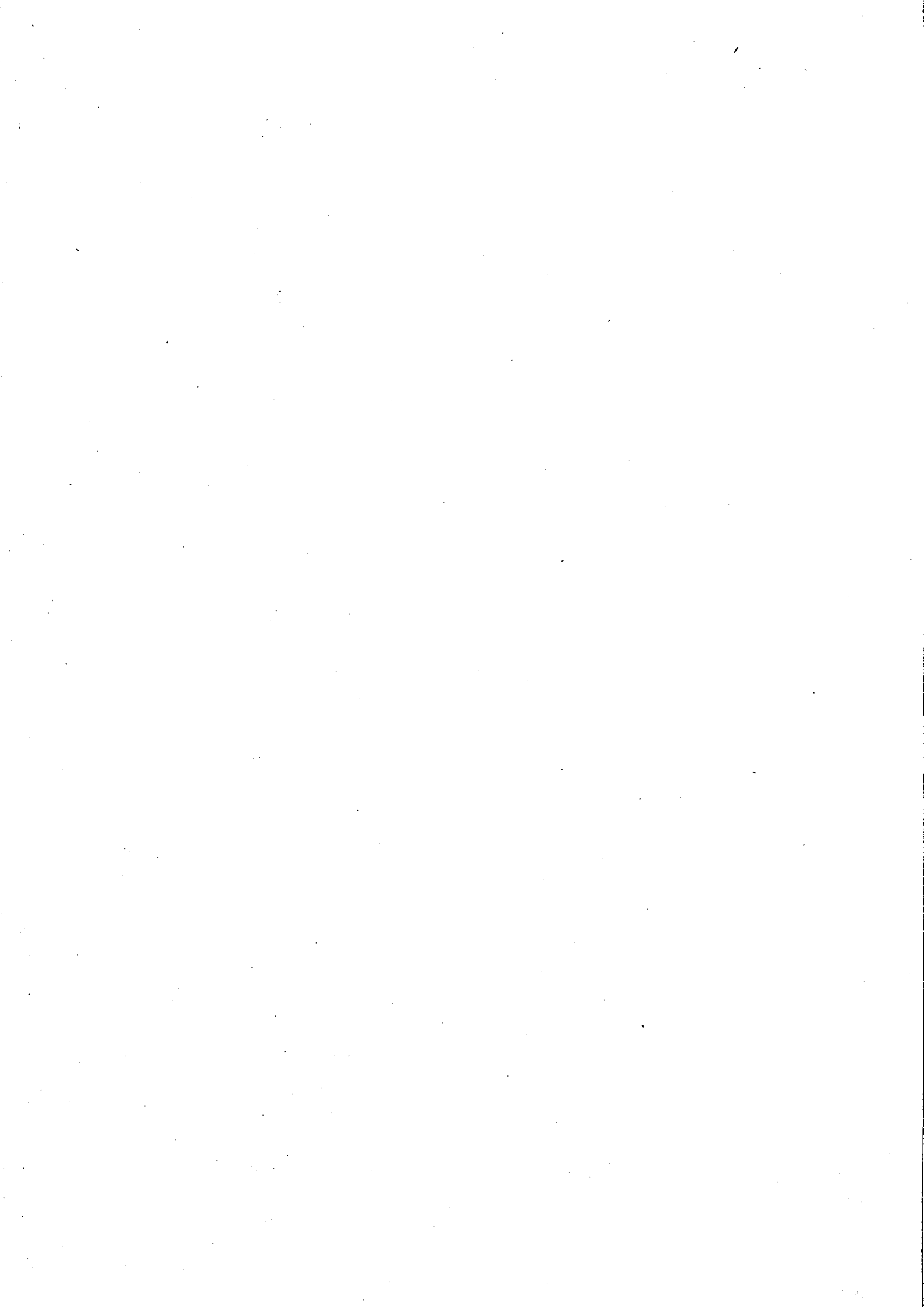




ESPRIT

**European strategic programme
for research and development
in information technology**

**Progress and results
1990/91**



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1990/91**

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Foreword

by Michel Carpentier, Director-General, DG XIII

□ At the end of June, the Community entered the last 18 months of the countdown to the completion of the internal market in the most sombre business climate since the single-market clock was set ticking in 1985. Competing against a falling dollar and yen, and with high interest rates in several Member States holding back investment, industry also faced stalled GATT talks, slumped share prices and a post-Gulf recession.

□ It would have been no surprise to find that the build-up of momentum towards the open market had abruptly slowed in the past few months, braked by defensive national reactions. Yet the drive to complete the groundwork for the European Community of the twenty-first century has, if anything, been stepped up. And with electronics underpinning so much of the modern economy, a successful European strategy in information technology and communications will be one of the mainstays of the whole '1992' edifice.

□ In 1960, more than half the workforce in the industrialized countries were employed in the direct manufacture of products. The figure now is less than one in five. The Community has been created during the transition from a basically manufacturing economy to an information-processing one. Information technology is itself a leading manufacturing sector, with world markets expected to be worth more than ECU 1 000 billion by the year 2000.

□ Yet the Community's trade deficit in electronics has doubled over the past four years to reach ECU 31 billion by the end of 1990, while the world market for electronics doubled in the same period. The traditional heavy dependence of European electronics companies on domestic markets has been a fundamental handicap. No European semiconductor manufacturer, for instance, has reached the 5% world market share reckoned to be the minimum necessary for industrial competitiveness, whereas 90% of the world market for 1 Mbit and above memory chips is controlled by Japanese companies.

□ The perception in Europe that there is no future in a national go-it-alone approach has, of course, driven the whole 1992 enterprise. I believe that the recent recessionary pressures have confirmed the validity of a pan-European approach to information and communications technologies by highlighting the structural weaknesses of the European market:

- the potential single market is still compartmentalized by restrictive public procurement rules and incompatible technical standards;
- it lacks dynamism: European industry's consumption of electronics is very much less per capita than in the USA or Japan;
- consumer preferences for established products and big-name suppliers lead to innovative new enterprises (especially the smaller ones) paying a high price as they strive to break into the market.

□ Nor is the competition for dominance on the global scale taking place on a level playing-field, what with significantly higher R&D financing costs in Europe than in Japan, defence and other government contracts succouring US high-tech companies, and the US-Japan chip pact obstructing free international trade negotiations.

□ These structural weaknesses in the European environment and distortions in international competition are now being addressed even more relentlessly by the Community after what I hope will be a short — but unfortunately sharp — recessionary shock. Late last year the Council of Ministers discussed a set of guidelines for a Community industrial policy, prepared by the Commission, which was followed this April by a paper (*The European electronics and information technology industry: state of play, issues at stake and proposals for action*) applying the principles formulated to the Community's information technology and electronics industry. The five main lines of action proposed involve the stimulation of demand, the refocusing of R&D, more and improved education and training, more even-handed international trading relations, and an improved environment for business.

□ I want to emphasize that the analyses and proposals build on the achievements of the 1980s and to stress that an open competitive environment will remain a central plank of Community policy in the 1990s. While the Community's role is to deliver the conditions in which European companies can achieve international competitiveness fairly and squarely by their own efforts, the main responsibility lies with the firms themselves. Given equitable conditions, the European information technology and electronics industry has the potential to be fully competitive on a world scale: for example, of 13 key emerging technologies identified in a US Department of Commerce report, 10 are related to electronics, and of these, Europe is ahead or level with the USA in seven and with Japan in six.

□ This technological potential is amply confirmed by the results of Community R&D initiatives, such as ESPRIT, which have made a substantial contribution to coordinating R&D in Europe and forging, through transnational partnerships, a new climate of confidence. ESPRIT itself has led, for instance, to a world-leading wafer-stepper using deep ultraviolet laser technology capable of defining the less than 0.35 micron geometries required for 64 Mbit memory chips and beyond, while more than 500 products world-wide have stemmed from ESPRIT work on the transputer, giving Europe a strong position in the fast-growing market for high-performance, low-cost parallel computers. Many other outstanding technology results, including standards, are evidenced in this report.

□ Europe has been in on the ground floor of the transition to open standards, which is effecting a profound change in the supplier-user relationship (open standards mean open markets). In the high-growth areas of software, services and systems design and integration, Europe maintains a strong capacity. In numerically controlled machine-tools, Europe was already responsible for over half the world's production in 1988 and has made tremendous progress since in computer-integrated manufacturing. In consumer electronics, Europe has taken the initiative in promoting the world-wide adoption of the most suitable HDTV standard, and with CD-I (Compact Disk Interactive) has launched a totally new product concept. And European companies have built solid positions in telecommunications, now entering a period of unprecedented international expansion as Community action creates a liberalized, harmonized single market for advanced equipment and services.

□ The information technology industry in Europe is far more than just a handful of long-established names: the Community has more than 13 000 IT companies. Completing the single market and furthering the necessary accompanying policies — in collaborative research, innovation and technology transfer, standardization, advanced trans-European communications, education and training — are priorities for the Commission as it works for an environment in which these companies can flourish.



Introduction

by J-M. Cadiou, Director, ESPRIT

Highlights

I am very pleased to report that over the past 18 months a significant number of major results from all work areas of the programme have been added to ESPRIT's already substantial slate of achievements. By mid-1991 a cumulative total of nearly **500 major results** had been reported by ESPRIT projects, either leading directly to commercial products or services, contributing to the establishment of international standards, or in the form of tools, methods and processes taken up by industry.

In the period under review, a further 107 **new projects** were launched (including three forming part of the start-up phase of JESSI, the industry-led Joint European submicron silicon initiative), and 43 **exploratory actions** initiated to further increase the already considerable involvement of SMEs in ESPRIT. An additional special action was started to promote SME usage of ASIC technology, and **special regional actions** were launched in Greece, Portugal and Spain, for example to accelerate the take-up of microelectronics technology. **ESPRIT clubs**, inaugurated in most Community Member States and some EFTA countries, have already started to increase awareness of the programme as a whole.

The **Basic research initiative**, launched in 1989, rapidly gained momentum in 1990/91; nearly all research actions have now completed their first 18 months of activity, several results have been produced with imminent industrial significance, and the proportion of actions with industrial participants has risen to over a quarter. The first three '**networks of excellence**' were set up early in 1991 to reinforce cooperation between research teams. Furthermore, joint NSF/DARPA/ESPRIT workshops were held to explore possible areas of

collaboration between the US and European fundamental research communities.

Also on the international front, substantial progress has been made in drawing up commonly acceptable terms of reference for a study covering the feasibility of cooperative research into advanced computer-integrated manufacturing systems. The discussions have involved Europe (the Community and EFTA), the USA, Japan, Canada and Australia.

This period also saw the thorough preparation of the **next phase of ESPRIT**, based on close consultation with representatives of all interested parties in the IT industry, a wide spectrum of user industries and the research community. The Council of Ministers gave its formal approval to the new phase on 8 July 1991, and the first general call for proposals was launched very shortly afterwards. Several **large-scale targeted projects** are currently under consideration: these will pull together technology advances to address the most critical issues of the 1990s. They include R&D projects and accompanying measures, as appropriate. The preparation of these projects is at different stages, with some ready for immediate implementation, and they are briefly described towards the end of this introduction.

The results achieved by ESPRIT on the technological side have had a major impact on the software, parallel processing, distributed computing and computer-integrated manufacturing fronts and in some critical areas of semiconductors. However, overall the IT and electronics industry is experiencing severe difficulties, and not just in Europe. Before analysing this and going on to outline the Community's response, I will first describe in more detail some of the technology results directly arising from ESPRIT projects.

ESPRIT technology results

Results from ESPRIT projects can be grouped into three broad categories. First are those consisting of advanced technology, ranging from improvements to breakthroughs, leading to products or services brought to the marketplace. Second, projects can produce tools, methods or processes which enhance the development or performance of industrial manufacturing processes, leading to shorter development times, higher quality, better yields and reduced costs. In the third category are results which make key contributions to the work of the various international standardization committees, and lead to the specification, drafting and ratification of IT standards.

The table shows an analysis of the 495 major results reported as of mid-1991.

Results arising from ESPRIT projects as of mid-1991	
Contributing directly to products or services	270
Tools and methods used outside ESPRIT	167
Contributions to international standards	58
Total results	495

Some illustrative examples of results from these categories are given below.

■ As a direct result of project 2048,¹ ASM-L (NL) has brought to the market a deep-UV stepper, a key piece of lithography equipment used in the manufacture of integrated circuits. Considered the most advanced R&D tool of its kind in the world, it can define structures as small as 0.18 microns, and is being used to develop the processes required for making chips at the 64 Mbit DRAM level and beyond. The advanced optics required for the production version of this deep-UV stepper are being developed in project 5002.

■ Anacad Computer Systems, a spin-off company from the CVS project consortium (project 802), recently signed an agreement with SGS-Thomson Microelectronics to supply more than 300 copies of ELDO, their high-precision, high-speed analogue simulator.

■ The transputer microprocessor from SGS-Thomson (F) is now the most widely sold 32-bit RISC processor in the world, with total sales already beyond the 450 000 unit mark. In April 1991 Inmos (a member of the SGS-Thomson group) announced the new-generation T9000. This is one of the world's most powerful RISC processors, with a peak performance of 200 Mips (or 25 Mflops). It was developed through work in SUPERNODE (projects 1085 and 2528), PUMA (project 2701) and GENESIS (projects 2447 and 2702). Today's transputer-based products provide supercomputing power at one-fifth of the cost of a conventional supercomputer. Through continuing development, the processing capabilities of the transputer have increased more than 10-fold in three years.

■ The portable common tool environment (PCTE) developed in PCTE (project 32) was confirmed in December 1990 as an international standard by ECMA, the European Computer Manufacturers Association. It is currently being validated by NATO. PCTE environments are now commercially available from Bull (F), DEC (USA), Hewlett-Packard (USA), IBM (USA) and SUN (USA). Software environments and PCTE-compliant tools are being offered by SFGL (F), Syseca (F), GIE Emeraude (F) and IPSYS (UK).

■ Redar Nah-Ortungstechnik (D) has sold several thousands of the transponder developed by Redar and Polydata (GR) in TRACIT (project 975) to Volkswagen. This device, which employs radio communication to receive and transmit information, is used by Volkswagen to identify automobile chassis as they pass through the factory and to record, and furnish on demand, relevant details of the manufacturing and assembly operations carried out on each. 'Reading' a chassis' status at various points along the

¹ Every ESPRIT project has a number and most have an acronym as well. For more information about a project, look it up in the Index (p. 147) or the Projects and participants list (p. 97).

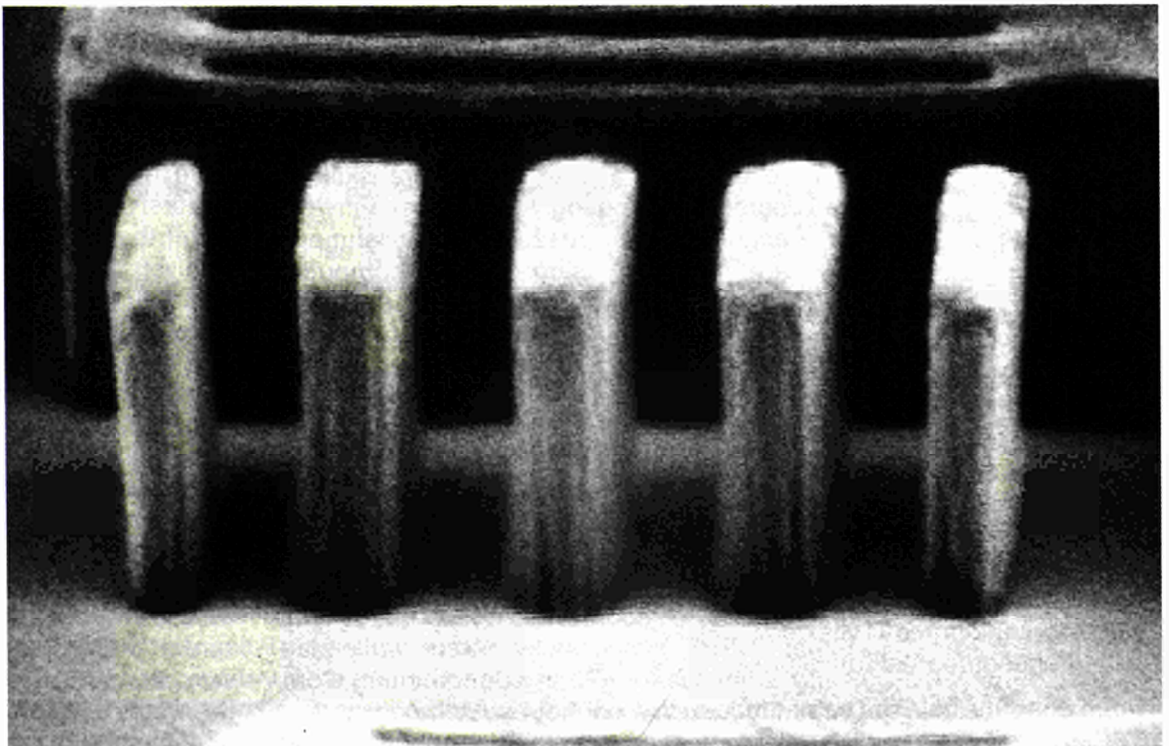
assembly line enables the right operations to be carried out on it at a particular station, as well as automatically routing it to the next appropriate one. This technique, enabling production planning to be decentralized and bringing greater flexibility to the manufacturing process, makes small-batch customized production runs more economic and so allows a greater choice to be offered to the customer. The system has also been sold to Hoesch, the German steel company, for identifying wagons in an in-plant railway system.

- CADEX (project 2195) has provided BMW with prototypes of the software required by the company for the exchange of data between 60 different types of CAD systems throughout its own organization and its 350 suppliers. Further demonstrations have been made at Fiat Aviazione, and the interface processors are scheduled for launch on the European market by the end of 1991.
- In March 1991 the Distributed Computing Model, Bull's major product in open systems, was announced at C-Bit '91. It incorporates key contributions from eight different ESPRIT projects, notably COMAN-DOS (projects 834 and 2071).
- Philips is launching Compact Disk Interactive (CD-I) in the USA and Japan in October 1991. CD-I, a consumer product integrating a microcomputer with a CD

drive in one unit, will enable hypermedia products to be accessed using a TV set as the monitor. The European launch is scheduled for 1992. The CD-I concept was developed in DOMESDAY (project 901). The full video image facility, an important marketing feature, was made possible through a coding algorithm (MPEG or ISO standard 11172) developed in COMIS (project 2012).

- Work in APACHIP (project 2075) has enabled MCTS (F) to bring to market tape for automated bonding (TAB) for IC packaging. TAB replaces the customary wires that connect a chip to its ceramic substrate and external pins, improving reliability and allowing higher packaging density. Vertical cooperation, notably between MCTS (TAB producer), Hoechst-Ceramtec (producer of ceramic packages) and Bull and Siemens-Nixdorf, enabled the achievement of this technical success, which is being further exploited in the production of flat screens, HDTVs and other consumer electronics applications.
- Thomson-LCD (F) has announced a 15 x 15 cm flat-panel liquid crystal display (LCD). This high-resolution colour display (1024 x 1024 pixels and 16 colours), already used for instrument readouts in a prototype aeroplane, is based on the outcome of MATRIX-LCD (project 2283).

0.25 micron structures printed using ASM Lithography's world-leading PAS 5000/70 deep-UV wafer-stepper (developed in project 2048) in combination with the photoresist technology of project 2265. The lithographic process determines the size of the smallest feature in an IC — the smaller the feature, the more densely packed the components, and the more powerful the chip. ASM-L's deep-UV stepper can define the features required for new-generation 64 Mbit memory chips and beyond.



- An advanced IC design software package marketed by Mentor Graphics (USA) was developed by IMEC (B) and Philips (NL) in CATHEDRAL (project 97).
- Apple Computers (USA) has set up a joint venture with Acorn (UK) to further develop and exploit the ARM, a RISC-type microprocessor. Its main feature is the amount of computing power obtained — 15 Mips — with an energy requirement of a mere 0.4 watts, which makes it a good candidate for portable workstations. The ARM-3 is a result of MULTIWORKS (project 2105).
- CHORUS, a distributed operating system extension to Unix, is being distributed by Unisys (USA). Chorus Systèmes (F) developed CHORUS by integrating results obtained through their participation in several ESPRIT projects: APHRODITE (project 1535), GENESIS (2447), PUMA (2701), MULTIWORKS (2105), COMAN-DOS (2071), ISA (2267) and EWS (2569).
- The VLSI design action (3700), set up to increase the number of students trained in VLSI design from 1 500 to 3 000 per year, has already exceeded this target: more than 5 000 students have been trained in the first year of operation, with 350 VLSI designs drawn up and 200 fabricated. The action now involves more than 200 academic institutions together with five major European foundries.
- The Parallel computing action (PCA), launched under the aegis of Information processing systems, has enabled over 300 researchers a year to acquire skills in parallel computing techniques. Fifty-five academic and research establishments are involved, using parallel computing systems based on the T800 transputer, and the action is helping to push forward development in this key area.

This selection of ESPRIT results demonstrates that despite its present difficulties, the European IT and electronics industry is able to develop and bring to market products and services with a winning edge, as well as playing an important role in the development of global standards. Of course, the collaborative R&D that ESPRIT successfully fosters, while playing a necessary role in strengthening Community industry, cannot by itself constitute a sufficient response to the current crisis.

In crisis: the IT and electronics industry

With an annual growth rate of around 15% throughout the 1980s, well in excess of the rise in GDP, the IT and electronics market has become one of the biggest sectors of the European economy, and is expected to become the largest by the end of the decade.

What makes the IT and electronics industry so strategic a sector for the Community is not only its size, but also its all-pervasive and catalytic nature. Its impact on employment is considerable: an estimated 60 to 65% of the working population is directly or indirectly dependent on these technologies and their applications. Its products and services provide a vital part of society's infrastructure, and its technologies are now used in virtually all economic and social activities. As a result, the IT and electronics industry has a major role to play in maintaining and strengthening the competitiveness of European industry as a whole. Yet the IT and electronics industry is now facing a serious crisis, which is affecting the USA and not just Europe alone.

The elements of the crisis

This crisis has both short-term and long-term, more structural, components. In the short term, the market is being affected by at least two factors. The first is the slow-down in demand precipitated by the Gulf crisis and other political uncertainties, which have pushed many users into delaying decisions on investing in new computer systems. At the time of writing, there are no signs yet of a recovery from this slow-down in demand: the results for the first quarter of 1991 still indicate a demand lower than for the same period last year, and analysts expect improvements only in the second half of 1991 at best. The second short-term cause is the depreciation of the dollar and the yen, which has made products from the USA and Japan more price-competitive than their European counterparts.

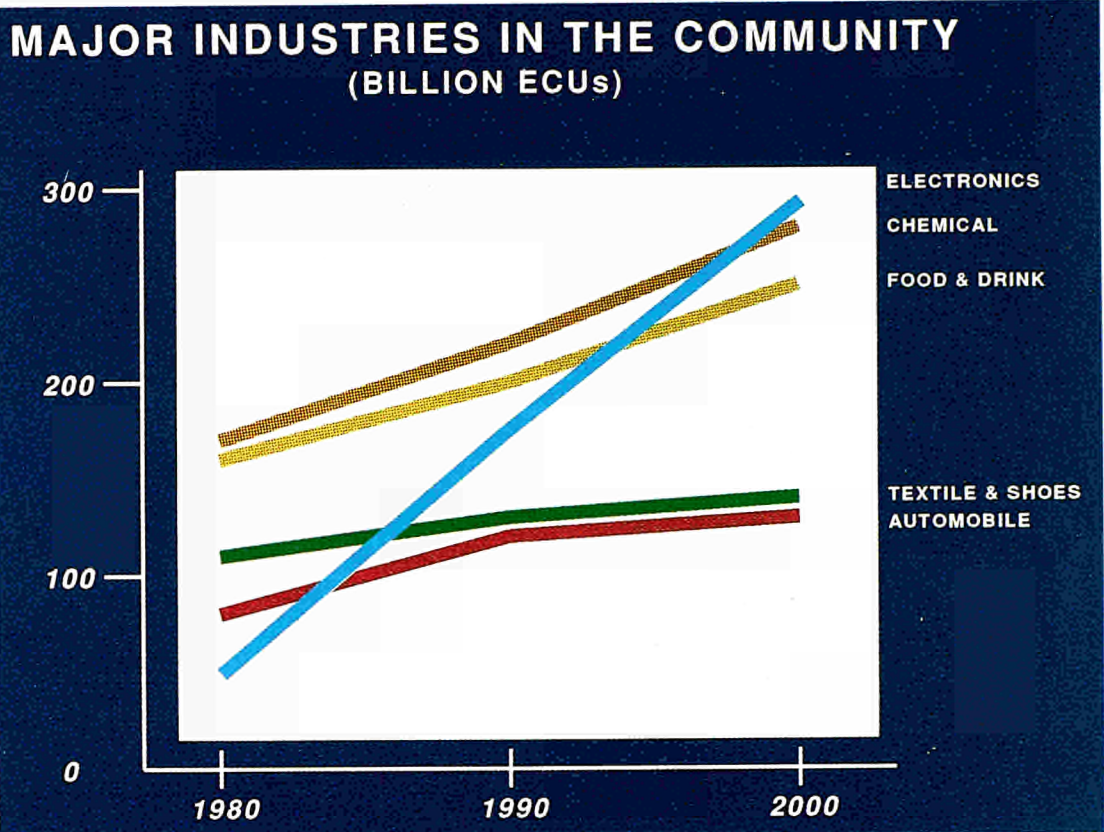
There are deep structural causes to the present crisis as well. The most important is the trend from proprietary to open systems, which is causing a complete reorientation of the IT industry and a drastic lowering of manufacturers' profit margins. At the same time, the rate of technology change is becoming faster than ever, with new generations of products now launched every three years on average.

This leads to escalating capital costs that have to be amortized over ever-shorter periods. Overall, the R&D investments of computer companies (in percentage of revenue terms) are more than twice the average of manufacturing industry as a whole, and those of semiconductor companies more than three times this figure.

This combination of increasing costs and reduced profit margins forces companies to increase volume, either through internal

the USA, public funding for R&D in IT is very high: at least USD 5 billion per year, of which about half comes from DARPA, NSF, DoE and other agencies, and the other half from the R&D part of the total USD 100 billion spent on defence procurement contracts. In Japan the mechanisms are different, but the scale of the financial savings in R&D costs enjoyed by the IT companies is similar. Recent major studies, including one by the Federal Reserve Bank of New York, have compared the full cost of capital for R&D, taking into account not only

The largest industry: the IT and electronics sector is likely to become the largest industry in the European Community, in terms of annual turnover, by the year 2000. These 'enabling' technologies are permeating the whole of our social and economic fabric and are now an integral part of the Community's development strategy. With their major impact on the competitiveness of the whole of the modern economy, on economic growth, and on the level of employment, IT and electronics are of crucial importance to the success of the unified internal market, and essential factors in Europe's control of its own destiny.



growth, which is difficult, by restructuring (via mergers and acquisitions), or by strategic alliances, all of which cause short-term difficulties before their advantages can take effect.

The high cost of capital

Considerable financial resources are necessary to cope with the increased investment required on the one hand by shorter product development cycles and by industrial restructuring on the other. European companies have severe difficulty in mustering these, given that capital markets in Europe are generally not properly geared to financing long-term or high-risk operations. Nor is public funding of sufficient scale available. In

interest rates but also factors such as the taxation system and requirements for equity in relation to debt. They show that Japanese companies have much lower long-term capital costs for R&D than their European counterparts. The difference — 10 percentage points during 1989 — effectively doubles the actual cost of R&D for European firms, and led to an estimated R&D cost saving of USD 6 billion for Japanese IT companies in 1989 alone (and note that previously the relative cost of capital in Japan was even lower). Under these circumstances, one needs to assess carefully whether or not European high technology companies, especially IT companies, are truly placed in a situation of fair competition.

European companies are also suffering more than their counterparts elsewhere in the

present difficult situation because they are in transition from a period when the Community market was highly fragmented to one when the single market will operate in a fully integrated way — but this will obviously take many years.

The efforts of the European IT industry

Despite these conditions, European companies have persevered. Facing up to their difficulties, they are engaged in restructuring operations, stepping up their efforts to reduce costs and increase productivity, and are striving to speed up their response to rapid changes in demand. The European IT industry, it should be stressed, is made up of over 13 000 companies of all shapes and sizes, and not just the few large ones in the public eye. Between 1984 and 1989 the whole IT industry managed to increase its market share in Europe from 47 to 55%, that is by eight percentage points, which is a very impressive accomplishment in such a competitive and fast-growing sector. Overall, total R&D investment more than doubled over that period, and the revenue of SMEs tripled. And the industry has demonstrated its ability to compete in global markets: even in the brutally competitive semiconductor area, for example, heavily dominated by Japanese companies, SGS-Thomson is now third in the world in non-volatile memories, which represents more than a quarter of the total semiconductor memory market, and first in Europe; while Siemens has gained an acknowledged presence in the DRAM market, the main area of strength of Japanese producers, where it now supplies 6% of the global demand for 1 Mbit chips, and is starting production of the 4 Mbit generation.

These are just a few examples, but they show that European IT companies can produce technologically competitive products and market them successfully. Yet it is an uphill struggle, as the current turmoil in the industry demonstrates, and the continuing survival of an independent European capability in this area is far from certain. Indeed, a careful analysis of the situation, and an examination of the factors putting European companies at a disadvantage relative to their competitors, leads to the conclusion that a comprehensive, structured policy is needed at Community level — one designed to create a more favourable climate for the industry to operate in.

A Community strategy

In April 1991 the Commission presented a communication to the Council of Ministers that addressed these issues, identified the key elements of an IT policy, and proposed a framework for mobilizing national resources throughout Europe in a series of strategic initiatives. This document — *The European electronics and IT industry: state of play, issues at stake and proposals for action* — is designed to open up a full debate on the issue at Community level, involving Member States, Community institutions, the industry, users and investors. Five general lines of action are proposed, and these are summarized below:

- **Demand** must be stimulated, in particular by promoting computerized links between companies and administrations and by launching projects designed to modernize IT and communications infrastructures in the education, transport, public health and environmental fields. The recently launched European nervous system (ENS) programme, aiming to develop links between the networks that already exist between national governments, industry and individual citizens, will play an important role.
- In the **training** area, the aim must be to provide scientists and engineers capable of developing and making maximum use of IT. The education system does not adapt as fast as it should to Europe's changing needs, and specific training initiatives should be addressed to both prepare the specialists required by the IT industry and train users to get the best profit from the use of IT. In particular, networks of excellence (as conceived by ESPRIT Basic research), composed of both academic and industrial teams geographically distributed throughout the Community, should continue to be set up in order to provide a critical mass of complementary knowledge and expertise, and help to share limited and expensive resources.
- In the **external relations** area, a trade policy is needed based on an open international trading system, access to the markets of the main trading partners, and the integration of European markets. A level playing-field has to be established together with fair 'rules of the game' in order to ensure equitable conditions of

competition and market access between the different regions of the world.

- It is also necessary to develop a **healthy business environment** by improving financing systems, supporting standardization, and developing the infrastructure needed for cooperation to develop and flourish. Current financing conditions in Europe militate against industries which need considerable investments in R&D and production capacity. The cost of such financing is much higher in Europe than in Japan: this severely distorts competition, and must be remedied.
- And in the area of **technology**, a 'second generation' of R&D is needed, ranging from fundamental research to industrial projects with a clear potential for commercialization. It is here that ESPRIT will play a major role.

The new phase of ESPRIT

ESPRIT's new phase is making a major contribution to implementing, in particular, the technology initiative identified in the Commission's paper. The programme continues to stimulate cooperative R&D projects and to focus on well-defined strategic objectives and technological priorities that take full account of the fast-changing industrial scene. Looking into the future, the overall industrial context and the necessity of higher investments in R&D make ESPRIT's cooperation mechanism, if anything, more necessary now than ever. The new phase of ESPRIT is part of the third framework programme for Community R&D activities, agreed for the period 1990-94, which foresees that out of ECU 5.7 billion earmarked for Community R&D, ECU 1.35 billion will be devoted to information technology. This new phase consists of four technological areas plus Basic research; a horizontal initiative in Open microprocessor systems; a set of supporting initiatives; and five large-scale 'second generation' targeted projects in line with the Commission's communication to the Council. These areas and initiatives are outlined below.

Microelectronics

The key objectives are to strengthen the Community's ability to design and manufacture leading-edge ICs and to ensure their ready

availability to a broad range of user companies. Particular attention will be paid to working in conjunction with JESSI, the Joint European submicron silicon initiative, and to creating favourable conditions for the use of application-specific integrated circuits (ASICs) by SMEs.

Software engineering and information processing systems

The objectives in this area are to apply software-intensive systems design and engineering techniques to user needs; to develop information servers and their interfaces that are appropriate to different users' tasks and levels of expertise; and to develop advanced architectures and their applications. The R&D tasks will take into account the major technology transfer and awareness initiative, ESSI, one of the 'second generation' large-scale targeted projects.

Advanced business and home systems — Peripherals

The work in this area aims to develop user-friendly support for cooperative working; promote the development and use of multimedia systems; demonstrate loosely coupled distributed systems; promote the introduction of information technology into the home; and develop selected peripheral technologies.

Computer-integrated manufacturing and engineering

The main aim is to demonstrate how the manufacturing and engineering industries can benefit from the application and integration of IT in products and processes. Taking an integrative approach, in which social, economic, organizational and environmental factors will play a decisive role, the work will centre around the following themes: promoting the use of open systems; promoting the development of modular and compatible system components that lend themselves to an incremental approach and which SMEs can afford; and developing new generations of handling systems.

Basic research

Basic research will continue to have four key aims: to enhance the potential for future

technological breakthroughs in IT; to benefit from the added value offered by cooperation at the European level; to contribute to the attainment of the programme's objectives from a position upstream of the market; and to reinforce interdisciplinary links. The results of any single Basic research project are expected to feed through into several projects and areas of technological R&D by providing the underlying knowledge and expertise needed to create future breakthroughs.

Open microprocessor systems initiative

The goal of the Open microprocessor systems initiative is to extend the concept of open systems and standards to the microprocessor systems environment, by providing an open framework based on the macrocell approach and software portability. It will interact with and build on the results of all the technological areas of ESPRIT, as well as on standards and other relevant developments world-wide.

Large-scale targeted projects

These will address the following domains:

- **Software**, to increase productivity by concentrating on production methods and tools and their early transfer to users. This is an area where R&D must be accompanied by broad dissemination of results and training activities, and the pilot phase of a major European system and software initiative (ESSI) will be launched early next year.
- **CIM**, to strengthen European manufacturing capabilities.
- **Microelectronics**, to develop IC design and manufacturing technologies for both

standard ICs and ASICs. ESPRIT will collaborate with the Eureka JESSI programme in the area of submicron silicon technology.

- **Peripherals**, developing, in particular, high-resolution flat-panel display technology.
- **High-performance computing**, notably to take advantage of the possibilities offered by progress in the field of parallel processing.

The new phase of ESPRIT represents an important element of the Community's new approach towards IT and electronics: more tightly focused and integrated; more concerned with feedback between users and suppliers, in order to link technology push with market pull; looking upstream to strengthen training in advanced topics and techniques; and directing more effort towards technology transfer. It will contribute to the Community objective of creating the conditions for the European IT industry to improve its competitiveness both on its home ground and in the wider international arena.

Yet, important as it is, this programme is not enough. The financial amounts currently involved are too small to compensate for the enormous advantages which IT companies enjoy in other regions of the world. Furthermore, an R&D programme can only be one part of an overall strategy. For the European IT companies' own efforts to bear fruit, the Community must show the political will and determination to provide them with the right environment: through technology, it may be the shape and future of our whole society which is now at stake.



Microelectronics

Overview

Objectives

The Microelectronics (MEL) activities of the ESPRIT programme concentrate on stimulating the creation of the design tools, process technologies, equipment and support industries required by European electronics goods manufacturing companies to create their own integrated circuits (ICs) tailored for specific uses — the so-called application-specific integrated circuits (ASICs). ASICs are a more efficient and cost-effective alternative to purchasing standard, non-optimized components.

Sales of electronic systems amounted to ECU 630 billion world-wide in 1990 and consumed ECU 77 billion-worth of microelectronic components, including ASICs, which currently make up about 30% of the world IC market. Microelectronics provides the technology foundation for information technology (IT) and telecommunications, and has extended its impact far beyond these sectors, representing a significant source of added value in a growing range of products, ranging from toys to telephones and word-processors to washing-machines. The competitiveness of Europe's IT industry depends on its early mastery of microelectronics, and this means gaining fast access to emerging technologies at the definition stage and being able to incorporate them into future generations of products.

Trends

The key to success in the IT market as a whole — and in the microelectronics sector in particular — is the rapid update of technologies, as the industry is marked by a high rate of product innovation, leading to ever-shorter life-cycles of increasingly 'intelligent' products. Microelectronics companies have to invest on average 16% of their sales in R&D compared to 10% in the IT industry overall and

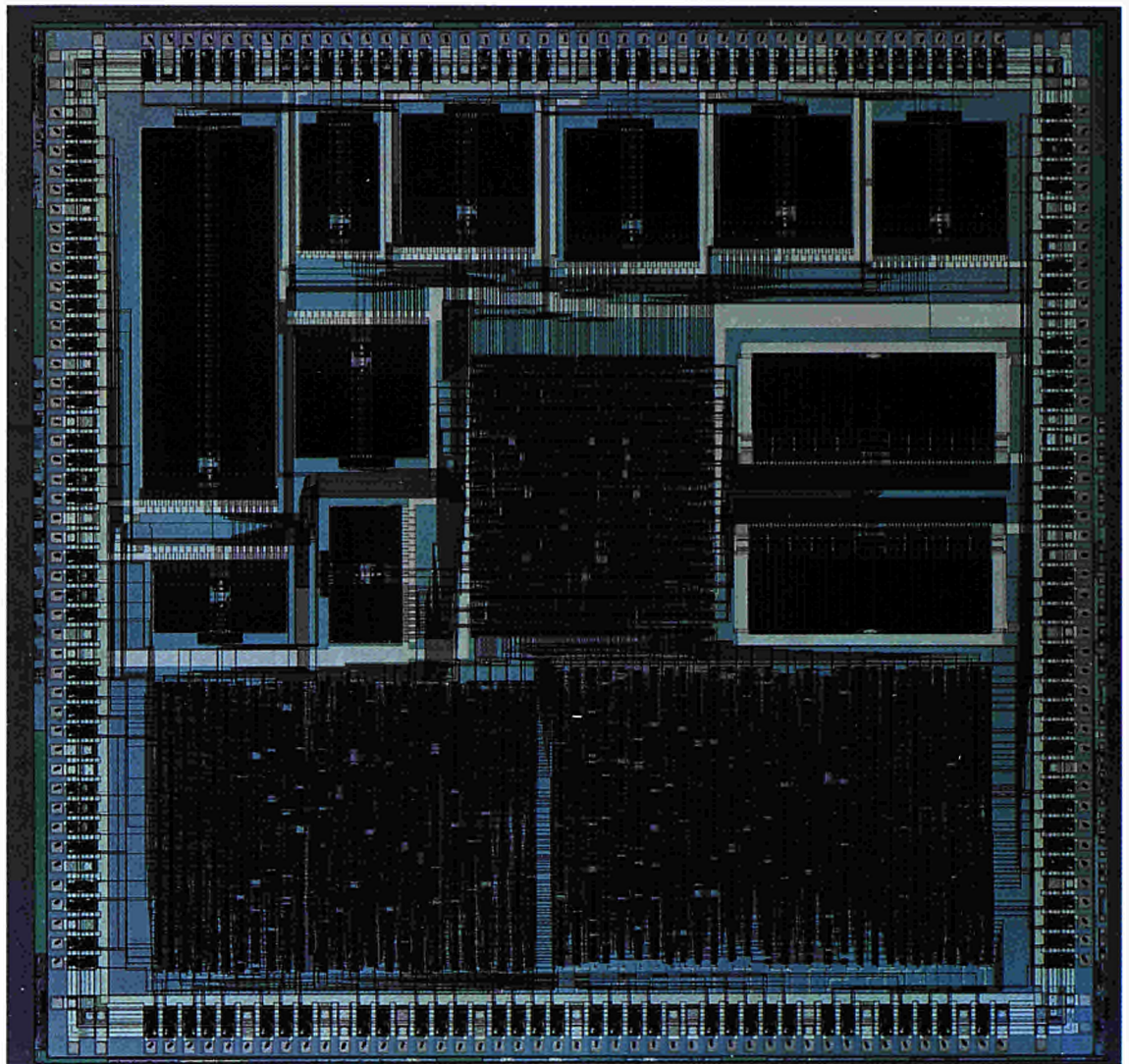
3 to 4% in the aerospace, automotive and chemical sectors. Furthermore, with capital investment running at around 20% of sales, the total investment in a new technology is comparable to the total revenue accrued from the previous generation. Hence both firms and governments invest substantially in R&D. Cooperation between competitors at the level of pre-competitive R&D allows the growing costs of research to be shared, spreads the risk of new ventures, and fosters the industrial restructuring required to give companies the chance of a significant presence in global markets.

During 1990 there were a total of 64 ongoing microelectronics projects. Seven projects were completed. The industrial character of the programme has been stressed through the launch of several demand-driven projects, with specific attention paid to the establishment of cooperation between manufacturers and users.

Community participation in JESSI

The background to the present participation of the Community in JESSI lies in the shared strategic purpose of the microelectronics actions within JESSI and ESPRIT. Both aim to consolidate the foundations of microelectronics in Europe to the benefit of systems houses of all sizes. The main difference between the two strategies is that ESPRIT, by its very nature, is precompetitive, addressing a broad range of technologies in order to cover the very varied spectrum of needs in the Community; while JESSI, in line with its inclusion in the Eureka programme, is more strongly market-oriented and has advanced CMOS technology as its focus. In the area of sub-micron CMOS technologies, there is thus a great potential for fruitful collaboration

Help for IC designers: using the macrocell design techniques and tools developed in AIDA (project 888), Siemens has produced a 32-bit coprocessor for automation systems, pictured here, that integrates more than 300 000 transistors. As VLSI circuits become more complex, CAD techniques, software tools and design methods must advance to match them. AIDA has extended the capabilities of a wide range of individual CAD tools so that tools for different tasks, developed in different companies, can be used in combination. A notable feature of the AIDA system is the incorporation in the IC designs of built-in test modules which make it possible to test the manufactured chip at a much lower cost than before.



between the ESPRIT and JESSI programmes. The participation of the Community in JESSI will be in those activities which, by virtue of their characteristics, expected benefits and particular participants, are best carried out at Community level.

Provision has been made for effective exchange of technology and results between ESPRIT and JESSI projects, which extends to organizations in countries currently outside the JESSI programme.

CAD and design methodology

Computer-aided design (CAD) is one of the key enabling technologies needed to support the electronics systems and components industries. It is also the basis of a self-supporting industry which, until now, has been dominated by a small number of US-based companies. However, the market in Europe is

currently expanding more rapidly than elsewhere, and there is evidence that the investment in CAD over recent years is starting to pay off. From a total of 28 CAD projects in ESPRIT, 68 firm commercial results have been reported. Of these, 62% contribute directly to products or services, 26% relate to tools and methods, and the rest have made contributions to international standards. Some of the more important results are detailed below.

SNI, Siemens-Nixdorf-Informationssysteme (D), which has emerged onto the world electronics CAD scene with the SIGGRAPH-EL product, is already selling the CALANY floor-planner tool resulting from AIDA (project 888). CALANY gives cost improvements resulting from a reduction of 50% in total block area and performance improvements of up to 35% in total wire length.

Anacad Computer Systems, a small German company arising from CVS (project 802), has

signed an agreement with SGS-Thomson Microelectronics (F) to supply more than 300 copies of ELDO, their high-precision, high-speed analogue simulator, for integration with SGS-Thomson's MOZART multi-level digital simulator, also partially developed in CVS.

The latest mainframe computer from Bull, the DPS 7000 series, is the most powerful in Europe, capable of more than 220 transactions per second and of handling up to 4 000 terminals. The 11 VLSI chips used (with up to 500 000 transistors per chip) were all tested using the CATI system which Bull developed in collaboration with other companies in EVEREST (project 2318) and IDPS (projects 2426 and 5075). The fault-diagnosis tools made it possible to design and test these complex chips without any increase in cost or time compared with the previous chip generation.

Cryptech, a small Belgian firm, has developed a single-chip hardware implementation of the DES encryption algorithm. It is being manufactured in Belgium by Mietec. This product gives cheap and easy access to all users of the standard DES algorithm and is

proving a major success, helped by its world-beating conversion speed (in excess of 18 Mbit/s). Cryptech used the CATHEDRAL design methodology, transferred with the help of IMEC (B) from the results of projects 97 and 1058.

SGS-Thomson Microelectronics (F) has demonstrated the capabilities of the CAD tools developed in CANDI (project 2268) by designing and fabricating a colour decoder chip that can decode digital luminance and chrominance to analogue RGB signals. The prototype will be used in the 1 000 HDTV sets supplied for the forthcoming Olympic Games in Barcelona.

CAD standards and infrastructure

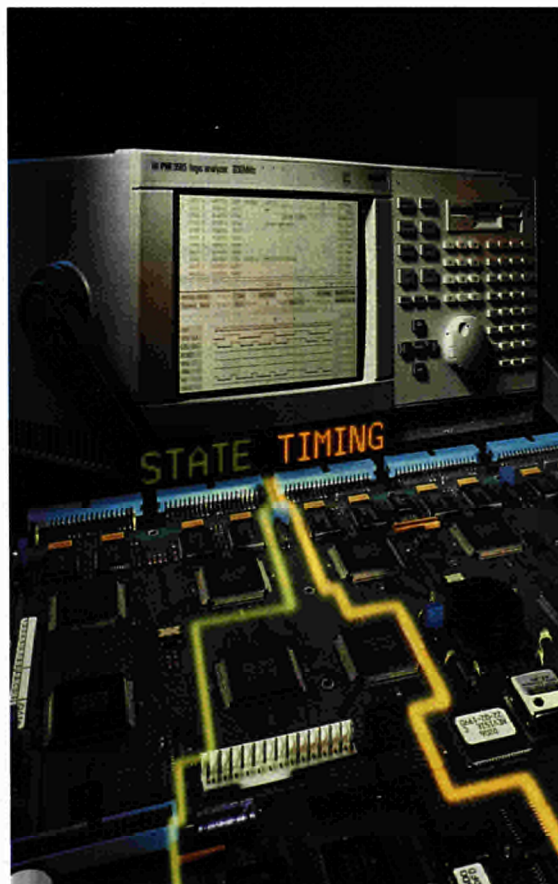
ECIP (project 2072) is paving the way for internationally accepted standards in CAD for VLSI in several domains. The longest established of these is in design data exchange. One of the organizations in the project, Manchester University (UK), in addition to representing Europe on the international EDIF (Electronic Data Interchange Format) Technical Committee, has established an EDIF validation service which satisfies a world-wide demand for checking conformity of data to the new standard.

A new development in CAD standards is the initiative to agree guidelines for standards in CAD frameworks. Through the initiative of organizations working in JESSI CAD-Frame (project 5082) and in ECIP, significant contributions are being made to this important area. Each technical subcommittee has either a chair or co-chair from Europe, and at least one of the four CFI meetings is held in Europe each year. A first prototype is being demonstrated at the Design Automation '91 conference in San Francisco, alongside other commercially developed prototypes. SNI (D) has announced a product, FrameWare, based on the early results of CAD-Frame.

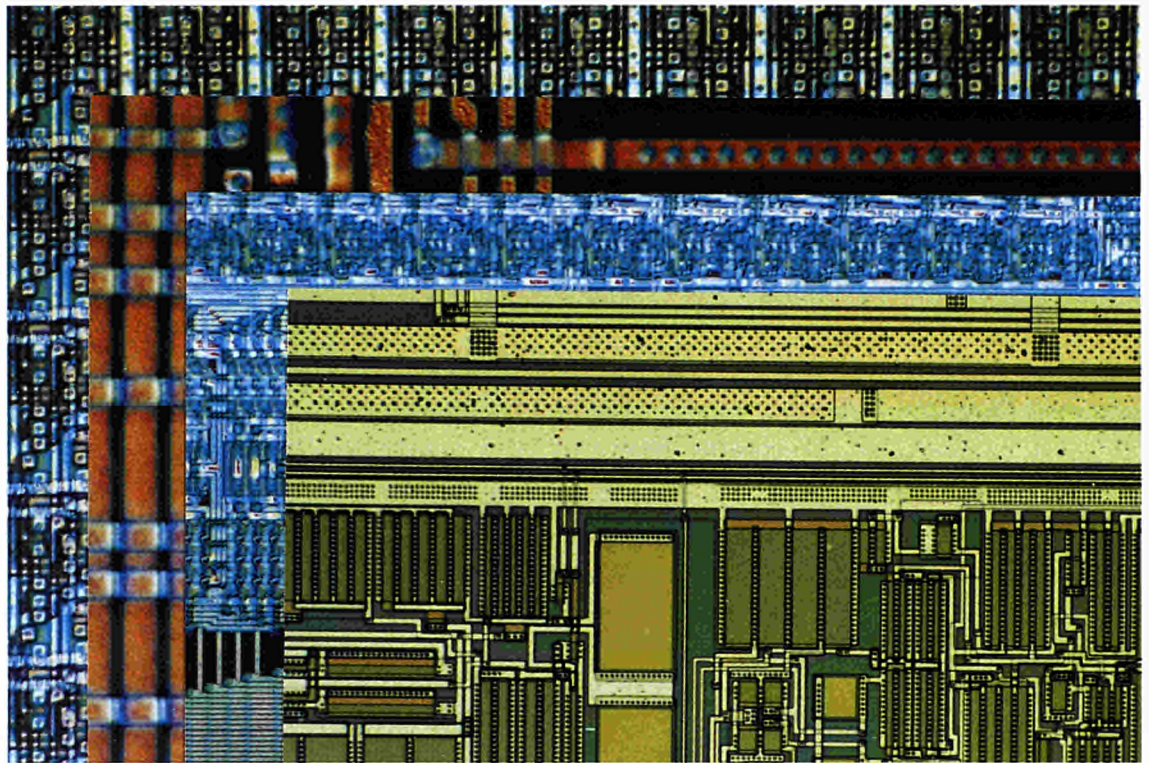
Validation and test

In the drive towards ever-increasing system complexity and with more and more demands on performance, one of the major bottlenecks is in verification and testing. Up to one-half of the final cost of a complex chip or printed-circuit board can be attributed either directly or indirectly to test problems. The strategy for answering this hitherto intractable question is through constraining design methodologies in order to ensure testability. Two projects are attacking this problem in different areas.

Testing PCBs: *the Philips Logic Analyser at the top of the picture has been designed to use boundary scan test (BST) practices, resulting from project 2478, to simplify test and fault diagnosis procedures. The BST technique allows the testing of complex digital printed circuit boards (PCBs), like the one shown, via serial access from the edge connector to the periphery of the integrated circuits on the PCB. This method is much cheaper than conventional electronic testing.*



Joint logic: a collage of detailed segments from a four-channel digital signal processor (produced by Alcatel-Mietec) destined for telecommunications applications. The combination of analogue and digital circuit elements on the same flexible CMOS chip stems from work in project 5080 (JOINT LOGIC), which brings together the major IC manufacturers in Europe to develop the basic fabrication concept for a competitive 0.5 micron CMOS technology suitable for a broad range of applications.



The first is 'Research into boundary scan test implementation' (project 2478). The effective and efficient testing of chips, boards and systems can be dramatically affected by incorporating the boundary scan philosophy into both standard ICs and ASICs. The project has had great influence on the specification and implementation of world test standards by creating a data model which has been incorporated into the electronic data interchange format (EDIF) as well as strongly influencing the work of the IEEE 1149 test standards committee. Philips (NL), a partner in the project, has decided to commercialize the results and to enter the tester market with a low-cost range of products specifically designed to test chips, boards and systems equipped with boundary scan.

EVEREST (project 2318), the second project in this area, has made a major contribution to the test view of the EDIF standard, where the definition has been led by an international team largely made up of EC members. An example of software which has already undergone successful exploitation is the SPHINX tool. This has already been used to produce several chips, including one containing 120 000 transistors that worked correctly in its first implementation.

Silicon technologies

Research activities in this area are mainly directed towards the development of technologies needed for the medium- to high-volume production of consumer, telecommunications and industrial ICs. The work encompasses a wide range of process technologies and is carried out under the headings of five IC process activities:

- core CMOS, for digital applications,
- flexible CMOS, for multifunctional applications,
- bipolar, for high-performance and high-speed digital, analogue and mixed analogue-digital circuits,
- BiCMOS, for fast digital and mixed analogue-digital circuits,
- high voltage.

Provisions are made in the projects to stimulate the take-up of results and to encourage the use of advanced technology by incorporating demonstrators applied to real applications, and by involving qualified users, including SMEs. Links have been established with other CAD, design and library projects in

all activities, and the methodologies used pave the way towards second-sourcing capabilities.

Flexible CMOS

Flexible CMOS technologies are created by the addition of process options to a core sub-micron CMOS process. The building of the core process is currently undertaken in two projects: JOINT LOGIC (project 5080) and ACCES (project 5048).

Three projects — JOINT LOGIC (project 5080), ADCIS (project 2193) and APBB (project 2039) — are building options to these cores to extend the process features to enable low voltage operation (down to 1.5 V), lower power consumption, optimization for embedded memories (DRAM and SRAM), and the inclusion of fundamental analogue components.

The JOINT LOGIC project is developing analogue and memory options to be added onto a 1 and 0.7 micron digital CMOS process developed in the same project, and a special low-voltage (1.5 V) CMOS process. Micro-controllers, digital signal processors, ICs for smart cards, battery-operated circuitry, composite arrays and applications in the audio, TV, telecommunications and automotive markets are under development.

In the ADCIS project, a 1 micron CMOS process is being adopted and characterized for mixed analogue/digital functions by Mietec (B), Matra-MHS (F) and CNET (E). At the same time, the development of design tools for building a system capable of producing silicon compilers, an analogue cell library and analogue basic converter functional blocks are being developed. The software related to the first version of this CAD tool (block placement, global router, simulation system), mixed layout generators, and specific compilers

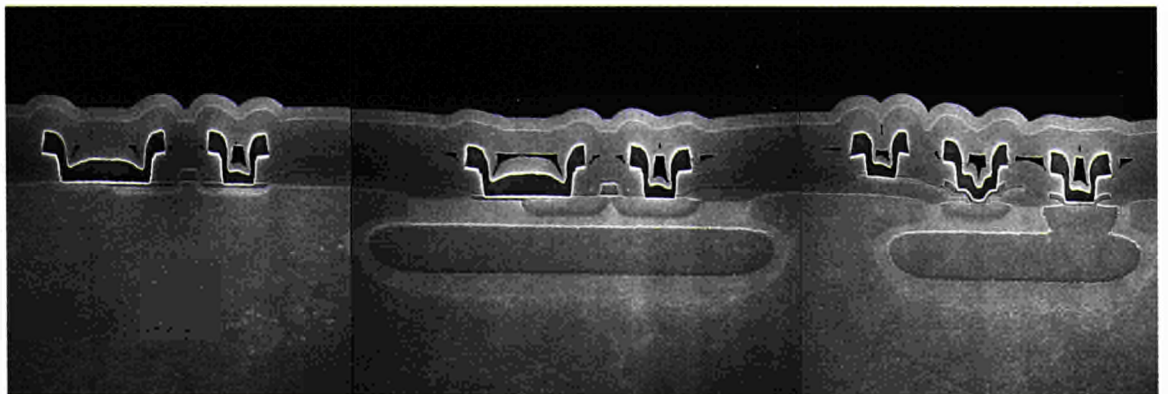
(analogue/digital/analogue converters) are being commercialized by Anacad Computer Systems (D). In addition, a complex video processor for telecommunication, multimedia terminal and videophone applications is being designed and fabricated.

The APBB (Advanced PROM building blocks) project has achieved the integration of EPROM and EEPROM memory devices into 1 and 1.2 micron CMOS processes (GEC-Plessey (UK) and SGS-Thomson (I)) and into a low-voltage (1.5 V, 2 micron design rule) CMOS process (Eurosil (D)). To exploit the key features of this technology, adequate CAD tools, building blocks for system designers and appropriate test methods have also been developed. Early access to the results has been provided to a number of SMEs to further increase the impact of the project: the resulting collaborations have led to the building of a number of demonstrators, including a gate array with embedded EEPROM, a microcontroller with on-board EPROM and EEPROM, low-voltage ICs for identification applications, an intelligent battery-charger for optimizing NiCd battery life, and ICs for electricity meters, smart cards and musical instrument applications.

BiCMOS

Although the performance of BiCMOS processes will always be a compromise between the best bipolar and best CMOS processes, the combination of bipolar features (analogue parameters, speed, driving capabilities) and CMOS properties (density, memory) creates a very challenging opportunity for many system designers. The BiCMOS market is expected to expand very quickly, with a cumulative annual growth rate of 60% from ECU 500 million in 1990 to ECU 5 billion in 1995 — an increase from 1 to 6% of the total IC market in only five years.

BiCMOS: a cross-section of the three basic transistors used in project 2430 on sub-micron BiCMOS (bipolar/CMOS). This project has developed a VLSI technology combining high-density CMOS with bipolar circuitry of similar density, but better suited to tasks such as analogue interfacing.



There are two projects in this field, BiCMOS and CANDI. In BiCMOS (project 2430), Philips (NL) has now completed the development of its 1 micron bipolar CMOS process with double poly, self-aligned n-p-n transistors and a silicide polysilicon emitter, while Siemens (D) has produced the first demonstrators in their 0.8 micron, digitally oriented process with very advanced trench isolation. An advanced demonstrator design, a one-chip video-bandwidth analogue/digital converter with an accuracy of more than 12 bits, has been realized. On the digital side, a 16 kbit ECL-driven SRAM has been made with an access time of only 3.5 ns, one of the best performances achieved world-wide to date.

In CANDI (project 2268), SGS-Thomson (F) and Telefunken (D) have demonstrated the compatibility of their 1.2 micron BiCMOS technology. The aim of this project is to transfer bipolar and CMOS processes originating from other ESPRIT projects. The main result lies in the sophisticated designs using BiCMOS technology for different application areas: an HDTV-RGB decoder, a mobile receiver for cellular networks, and shuffler/scramble circuits for asynchronous telephone networks. A library with more than 100 cells has been created in order to facilitate the use of the technology by systems users.

The next steps in these projects are to extend the processes to wider analogue use; for example, the implementation of vertical p-n-p with the addition of only one mask step. The evaluation and implementation of a RISC 3000 or 4000 processor is planned, as well as a self-calibrating 16-bit resolution analogue/digital converter and advanced FIR filter designs for HDTV.

BiPolar

BASE, the technology integration project (2016) aiming to develop bipolar technologies, builds on the results of the earlier ESPRIT projects 243 and 281. New transistor architectures have been developed and lateral and vertical device dimensions shrunk in order to meet the requirements for applications such as mobile telephones. The newly developed technology pushes the performance of silicon technology closer to that of III-V technology, but at lower production costs.

In particular, the designs achieved gate delays below 30 ps and significant reductions in power consumption, power delay product and noise. This performance is equivalent to the

best results reported in the literature, and is three times better than that achievable by the production technologies presently available.

In addition to the development of pre-production technology, very advanced device structures have been realized. These include a silicon device architecture (BASIC) with minimized parasitic structures, especially suitable for optimum analogue performance, and a device structure realized using selective deposition of silicon with a speed performance beyond the specifications for standard technology. Furthermore, bipolar transistors have been fabricated containing epitaxial strained layers of germanium-doped silicon (23 nm thick $\text{Si}_{0.75}\text{Ge}_{0.25}$ capped with silicon). Although the introduction of these layers in integrated circuits imposes new demands on device architectures and processing, they have the potential to improve speed and noise figures in bipolar circuits five-fold.

The BASE technology has been used by Plessey (UK) to design a 10 Gbit/s 64-1 multiplexer demonstrator for RACE project 1052, and SGS-Thomson (I) has established close collaboration with RACE project 1036 for the demonstration of a 2.5 Gbit/s fibre-optic system.

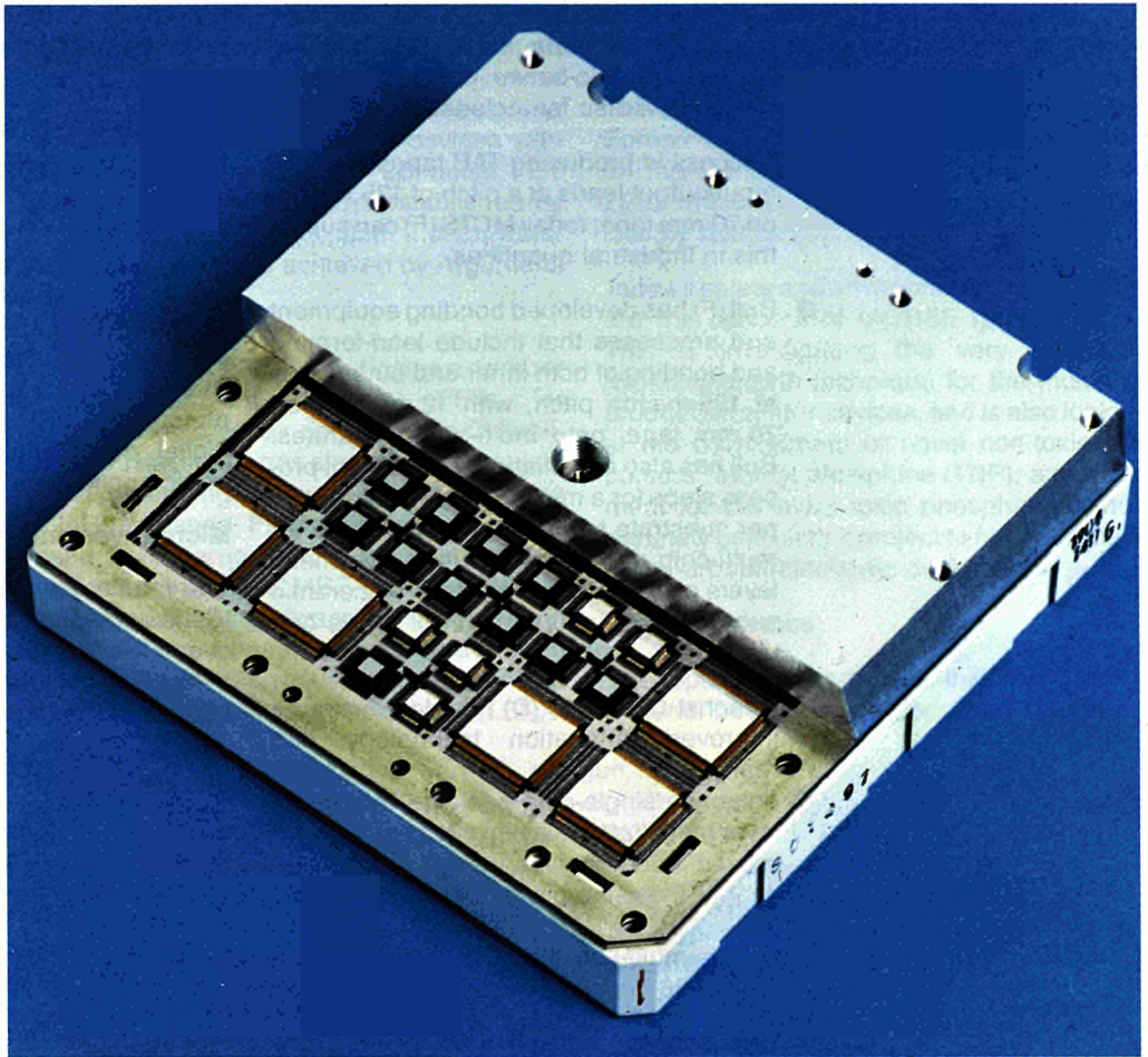
The project partners are the most competent manufacturers of bipolar circuits in Europe, with each partner concentrating on specific optimizations of the technology for speed, complexity, and analogue and digital functionality. These different technologies strengthen the European industrial position in application areas such as consumer electronics (Philips), telecommunications (Siemens), and radio and instrumentation (Telefunken, Plessey). The 1989 world bipolar market of ECU 13.6 billion is expected to increase to ECU 16.2 billion by 1994.

High voltage

In SMILE (project 2272), a high-voltage IC technology suitable for lamp ballast applications has been designed and demonstrated. The devices are combined with low-cost high-voltage packaging technology and are under evaluation to identify any critical behaviour in performance and reliability related to the high voltages involved.

Different types of high voltage devices such as IGBT (insulated gate bipolar transistors), LDMOS (lateral double diffused MOS), and

Packaging for high performance: a demonstrator from APACHIP (project 2075), showing a multichip mainframe computer module from Siemens-Nixdorf which uses a high-density organic substrate with 16 VLSI and 32 LSI devices mounted by tape automated bonding (TAB). The VLSI devices are 12 mm square and have 316 input/output connections. APACHIP aims to provide advanced packaging solutions for multichip modules and single-chip package applications. As well as packaging techniques, the project covers the development of high-density, high-performance substrates, a new connector concept, reliability aspects, and new inspection methods.



other n- and p-type BJT (bipolar junction transistors) up to 650 V have been integrated on the same silicon chip while remaining fully isolated from each other.

Supporting models for circuit simulation have been generated and parameters extracted. Macro cells comprising a high-voltage bridge driver, control circuits, low-voltage power-supply and start-up circuit, and a high-voltage full-bridge dedicated to lamp circuits have been designed and demonstrated under 250 V operating conditions, showing that a fully integrated solution is practical. A redesigned version is being developed using a 650 V technology which will extend bulb lifetime, save energy, and allow features such as dimming and flicker suppression to be added.

The global market for lamp-bulbs is expected to reach ECU 30 billion in 1995, of which ECU 3.6 billion will be for ballast applications and ECU 1.2 billion for electronic components such as those demonstrated in SMILE. In ad-

dition, the technology has application in a wide range of sectors such as domestic appliances, industrial controllers, intelligent power supplies and telephone exchange components.

VLSI packaging

In order to gain maximum advantage from ESPRIT's technology innovation projects, a complementary improvement is needed in the materials and structures of chip packaging. Two ESPRIT projects are creating compatible packaging and assembly schemes for high pin-count functions as well as accounting for high speed and high reliability needs.

APACHIP (project 2075) covers all areas of packaging, ranging from high density chip assembly and interconnection using very fine substrates, to packaging and testing for high-density, high pin-count applications for advanced VLSI circuits. These products cover both packaged electronic assemblies (multi-

chip modules) and packaging material supplies needed for tape automated bonding (TAB) and ceramic-based packages. Major results achieved so far include:

- Success in producing TAB tapes with 316 input/output leads at a pitch of 125 micron on 70 mm tape; today MCTS (F) can supply this in industrial quantities.
- Bull (F) has developed bonding equipment and processes that include lead-forming and bonding of both inner and outer leads at 125 micron pitch, with 12 mm ICs on 70 mm tape, onto multi-chip substrates. Bull has also established the different process steps for a multi-layer polyimide-copper substrate technology as the basis for multi-chip modules with up to five metal layers on a 10 cm square co-fired ceramic substrate (100 micron pitch of tracks and via holes).
- Hoechst Ceramtec (D) has demonstrated improved fabrication technology and realized a number of new packages, notably a single-chip package with multi-layer metallization, a pin grid array with improved heat transfer (using a tungsten-copper insert), a pin grid array with inner lead pitch of 200 micron, and a 10 cm square multi-chip package substrate containing 888 connector pads.
- High-density organic multi-chip substrates have achieved world-class specifications in terms of low resistance conductor tracks at pitches down to 80 micron, via holes as small as 30 micron in diameter, controlled impedance tracks, and up to 17 metal layers (signal and power/ground). The aim is to exploit this track definition capability to build complete mainframe central processor units on a single substrate requiring fewer layers.
- Extensive thermal modelling has led to the successful development of several water-cooled and air-cooled demonstrators. The multi-chip modules of Siemens, Bull and Hoechst Ceramtec, described above, have been used in evaluations of thermal and mechanical characteristics.

PLASIC (project 5033) is providing guidelines on how to build, model and evaluate plastic packages for VLSI devices in telecommunications, industrial control and automotive applications requiring high reliability. This project provides the major submicron integration

technology projects with a low-cost high-reliability packaging route.

Compound semiconductor technologies

III-V compound semiconducting materials offer a unique range of very attractive properties; low power consumption, high operating speed and the ability to process both optical and electrical signals. Materials such as gallium arsenide (GaAs) and indium phosphide (InP) are suitable for analogue, digital, mixed analogue-digital and optoelectronic applications.

Microwaves and millimetre waves

The market for GaAs microwave and digital ICs is expected to grow world-wide at a rate over 50% per year to reach over ECU 1.2 billion by 1994. This growth is mainly concentrated in the computer, automotive, communications and broadcasting sectors of the market.

Five ESPRIT projects were launched in 1990 to address applications in the automotive, mobile communications and direct broadcast by satellite (DBS) areas. The current total of six projects make up a comprehensive programme on compound semiconductors for microwave and millimetre applications in the 1-60 GHz range.

Among these, AIMS (project 5032) is focused on applications between 20-30 GHz for short-hop land links and very small aperture satellite terminals. A range of generic monolithic microwave ICs are being developed covering transmit/receive switches, low-noise amplifiers, non-linear circuits, voltage-controlled oscillators and solid-state power amplifiers. The project has already demonstrated heterojunction field-effect transistors (HFETs) with world-class noise figures and power capabilities.

COSMIC (project 5018) concentrates on components for applications between 1-20 GHz. On the L-band, the key demonstrators are trans-impedance amplifiers for optical receivers and RF amplifier/mixer monolithic microwave ICs (MMICs) for mobile communications, global positioning by satellite applications and broadband ISDN. On the X-band, MMICs are targeted at the highly competitive market of DBS receivers. On the K/Ku-band, ICs are being developed for point-

to-multipoint communications. State-of-the-art results have already been obtained, such as the novel self-aligned high electron mobility transistor (HEMT) process implemented by Siemens (D) for devices with submicron gate length, the 2D noise FET (field-effect transistor) model established by Politecnico di Torino (I), and the on-wafer noise measurements achieved by Argumens (D).

GIANTS (project 2035) investigates a number of advanced InGaAs-based FETs for microelectronic and optoelectronic applications. The project has already met its objective of generating a secure European source of InGaAs-based FETs. Picogiga, a Paris-based SME participant, is gaining a global presence in the field of MBE-grown epi-wafers through making significant improvements in its MBE material. Important results have been obtained in quasi-2D modelling for device and circuit design. A software package, HELENA,

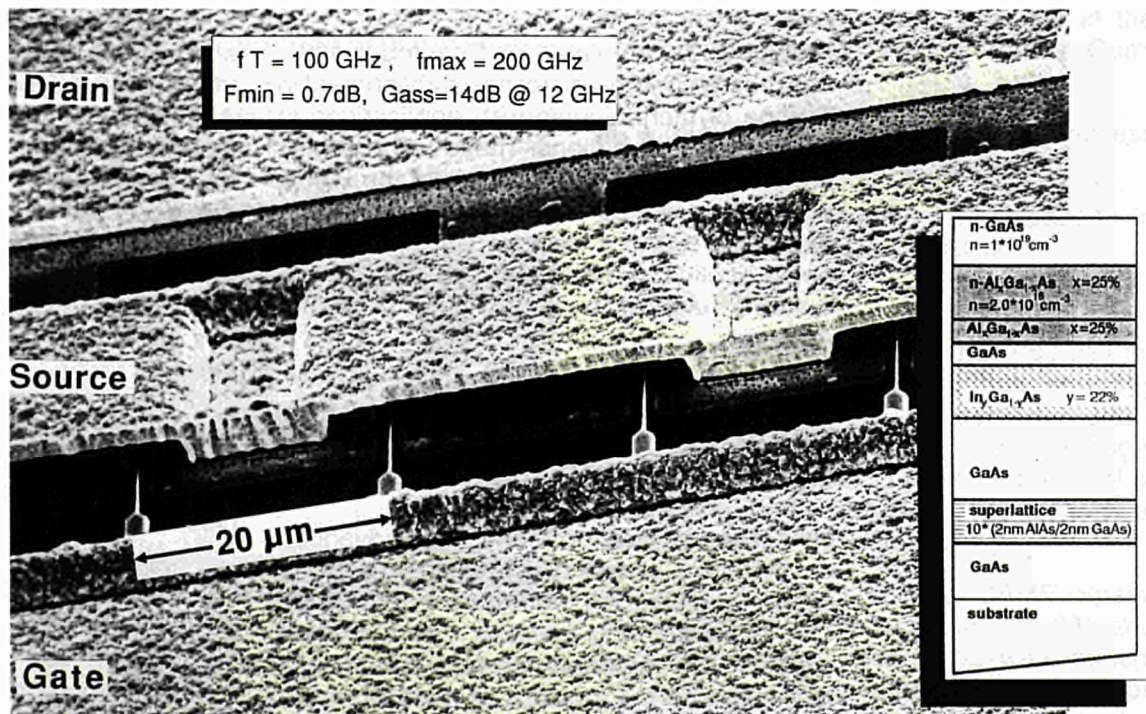
structures such as GaAs lasers and InP waveguides, and has already delivered a new 7" x 2" device to European user companies. This project is expected to further strengthen Europe's world-leading position by building on the results of ESPRIT projects 927 and 2518, which are currently being commercialized by Aixtron (D).

Today's safety and environment requirements are the concern of MORSE (project 5031). This is investigating the very promising MOMBE growth technique for the industrial production of III-V devices, and is also looking at the development of novel non-toxic precursors. Tributyl phosphine (TBP), a replacement for the more toxic phosphine, is now routinely used in this project to fabricate state-of-the-art optoelectronic devices.

Optoelectronics

The optical properties of InP make it the material best suited for long wavelength op-

III-V devices: a photomicrograph of a very advanced hetero-junction field-effect transistor (HFET) structure supplied by Daimler-Benz. The device, developed in AIMS (project 5032), has achieved world-class performance and is suited for applications involving very small aperture satellite terminals. AIMS is one of the core projects in ESPRIT's research into low-cost III-V based MMICs (monolithic micro/millimetre wave ICs) and appropriate CAD tools and manufacturing processes.



has been developed by universit  de Lille (F) and is being commercialized.

Besides this technology development work, two projects are focused on the development of very advanced III-V material deposition equipment. PLANET (project 5003) addresses high throughput, multi-wafer MOVPE reactors suitable for growing hetero-struct-

ural communications. The main application area is in the data-processing, communications, industrial and automotive sectors, where the market is forecast to double to ECU 5 billion by 1995.

Significant advances have been made under OLIVES (project 2289) in the technologies of holographic optical elements, low-loss waveguides, optical modulators, receiver arrays and component mounting for applica-

tions in optical interconnections for VLSI and electronic systems. A variety of demonstrators have shown first-class results:

- Using chip-level region-to-region optical clock distribution produces a six-fold increase in clock speed. A simulation of a 1 000-node neural network shows the technique can offer a performance gain of two orders of magnitude.
- Reduction in the volume occupied by the interconnection medium, increased flexibility in the interconnection topology, and, at high data rates, an increase in the density of interconnections.
- Hybrid integration of optoelectronic components and silicon circuits, as demonstrated on a 64 MQW modulator array. Assessment of the performance of individual hybridized elements on the same design has shown the best reported results for long wavelength refractive devices.

Project 263, completed in December 1989, has greatly contributed to the establishment in Europe of technologies with applications in optical communications. These technologies are already being exploited under the RACE programme, where high-quality lasers, optoelectronic ICs and low-loss waveguides are being applied in a range of communications systems and also in optically switched networks.

Manufacturing, process equipment and materials

New technologies, no matter how advanced or innovative, cannot be exploited unless efficient manufacturing methods are employed. The manufacturing process has two main aspects: the materials support (machinery, facilities) and the logistics of their organization (automation, CAM, etc). The optimization of the overall production process in order to maximize yields and reduce unit costs is the subject of manufacturing science. In recognition of its vital importance, an ambitious project, 'Manufacturing science and technology' (project 5081), grouping together all the major European IC manufacturers, was launched in 1990. Europe has a strong position, worldwide, in materials for semiconductor manufacturing (process gases and chemicals, resists, wafers, etc.), while it is

relatively weak in the domain of equipment, with only a 10% world market share in the area of wafer processing.

Lithography equipment

ESPRIT provides comprehensive coverage of all the main aspects of advanced lithography. This includes equipment, materials and the related processes for deep-UV steppers, E-beam lithography, and reticle processing and handling.

A wafer-stepper is one of the most strategically important pieces of equipment for IC manufacturers. At present, minimal feature sizes in production are in the 0.7 micron region, and are expected to reach 0.35 micron by 1995 in state-of-the-art memories, with ASIC applications following close behind. New techniques will have to be developed for lower ranges. The most promising is the use of deep ultra-violet (DUV) light, but this poses formidable problems, principally in the areas of lens optics, alignment precision, and resist materials. All these aspects are being very successfully tackled in DEEP-UV (project 2048). A prototype stepper was fabricated at ASM-L (NL), with a lens made by Carl Zeiss (D) incorporating some unique features, such as through-the-lens alignment. The system demonstrated record-beating performance in resolution, alignment accuracy and throughput, and is the most advanced stepper of its kind in the world. Several units based on this prototype have been sold to IC R&D facilities around the world.

Complementing this work, single and multi-layer DUV-specific resists have been developed by Hoechst and Siemens with the close cooperation of IC manufacturers. Evaluation of the results of these projects is being performed by IMEC (B) and LETI (F), who have both acquired DUV steppers. DRYDEL (project 2265) is extending DESIRE, a single-layer resist technique, to cover the deep-UV region, whilst in the reticle generation area FREE (project 5030) has been recently launched.

Multi-process/multi-chamber equipment

The increasingly stringent constraints on the quality of the thin films constituting ever more miniaturized ICs demands a new trend in wafer processing: the grouping together of related process steps and their sequential performance in several clustered vacuum-processing and transfer chambers. It is

estimated that with feature sizes of 0.5 micron and below, the use of multi-process/multi-chamber vacuum-sealed equipment will be a necessity for certain critical process steps. This approach requires new equipment designs and the development of modified or new processes.

During the first phase of MCBRIDE (project 2403), which includes ASM-I (NL), LETI (F) and SGS-Thomson (I), a prototype multi-chamber reactor has been developed which allows the deposition of inter-poly ONO (oxide-nitride-oxide) films in a single integrated wafer-processing system. This equipment is suitable for the most sophisticated EPROM and EEPROM devices. This first prototype (consisting of a high-frequency cleaning module, LPCVD and oxidation reactors plus wafer handler and elevator units) has been installed at LETI for further testing and evaluation. Complementary work on process characterization and preliminary engineering of the next version of the reactor are in progress at ASM-I.

In support of MCBRIDE, PROMIMPS (project 5041) was launched in 1990 involving equipment manufacturers, users, and three research institutes. The objective of the project is to realize the integration of different processes in multi-chamber 'cluster' tools. The

technology' (project 5081) using as a basis the know-how developed in AMS. The project participants, all of them IC manufacturers, are examining each step in the IC manufacturing process in order to increase the cost-effectiveness of their VLSI manufacturing operations. The project is producing common recommendations and standard guidelines for process equipment and materials manufacturers that will also enable the latter to improve their products.

Accompanying measures

Microelectronics activities in ESPRIT also aim to stimulate awareness through the dissemination of information and the encouragement of new users, in particular SMEs. This goal is being addressed in four ways:

- by increasing user participation in technology demonstrators (for example, SME participation in the APBB project);
- by three special actions targeted at the more peripheral regions of the Community;
- within the Concerted technology access for SMEs (CTA-SME) special action;
- through encouraging participation in Special interest groups (SIGs).

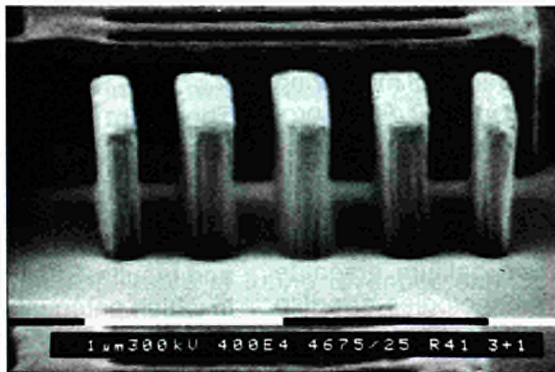
Special actions

Following the evaluation of the 1989 call for proposals, it was apparent that specially tailored actions were needed in certain peripheral regions, notably Spain, Portugal and Greece, in order to promote the level of awareness and industrial application of microelectronic technologies.

In 1990/91 the first phases of GAME (Spain, action 5083), AICI (Portugal, action 5691) and VLSI-DPE (Greece, action 5692) were launched. Each was set up after close consultation with the respective national administration and aims to:

- encourage links and the transfer of technology from other ESPRIT microelectronics actions or projects in order to bring the organizations concerned into closer involvement with the European microelectronics R&D community;
- build on and mobilize existing resources, both intellectual and material, in the countries involved;

0.25 micron structures printed using ASM-L's PAS 5000/70 deep-UV wafer-stepper (developed in project 2048) in combination with the photoresist technology of project 2265. 0.18 micron has been achieved using a special mask and resist.

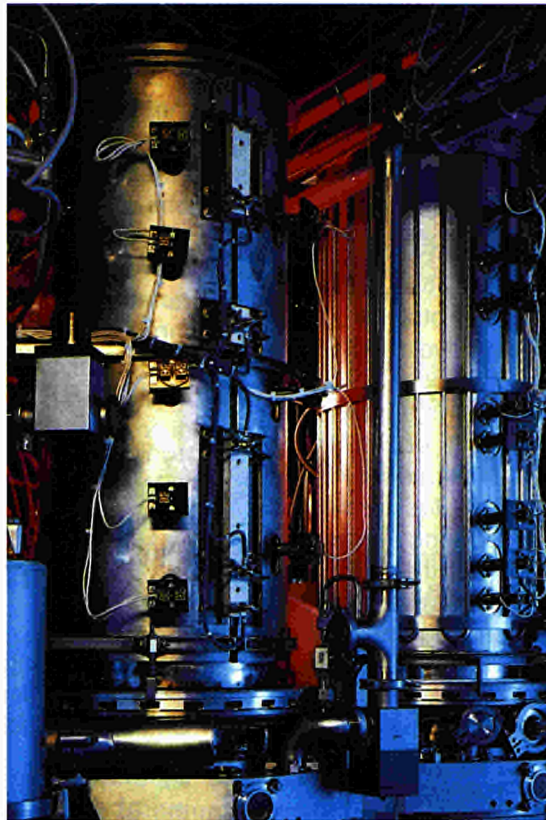


application areas chosen are silicide metallization, CVD blanket deposition of tungsten, and inter-metal dielectrics.

Manufacturing science

The completion of AMS (project 1551) in December 1990 has led to the participants obtaining attractive solutions to IC manufacturing problems, particularly with respect to contamination control and yield improvement as well as in interfaces and communication protocols for IC production equipment. Further collaborative work of a more advanced nature in process automation is now being undertaken within 'Manufacturing science and

Multi-chamber equipment: a view of the multi-chamber reactor developed for the deposition of ONO (oxide-silicon-oxide) layers in MCBRIDE (project 2403). The machine has been designed for use in the production of EPROM and EEPROM memories and non-volatile ASICs. With feature sizes of 0.5 micron and below, the use of multi-chamber/multi-process vacuum-sealed equipment will become a necessity for certain critical process steps.



- promote local cooperation between research institutes, academia and industry with the objective of enabling local industry to better benefit from existing local know-how.

In the first year of operation, considerable success has been achieved in terms of mobilizing existing resources, and some 50 ASIC projects, predominantly involving first-time users, have been initiated. The application of ASICs has become a common (but not the only) theme of these actions. Additional activities in high-voltage smart power, gallium arsenide and integrated sensor technologies are also under way.

Concerted technology access for SMEs (CTA-SME)

ASICs are considered to be key to the competitiveness of European companies, especially small and medium-sized industries. However, it has been estimated that only around 2 000 of the estimated 25 000 SMEs in the Community have incorporated ASICs into their products, mainly due to a lack of awareness and training.

Measures designed to encourage SMEs in the use of microelectronic technologies are taking place or being planned in several Member States. CTA-SME (action 5084) plans

to generate links between these initiatives (including the ESPRIT special actions described earlier) in order to bring about closer collaboration and the cross-fertilization of ideas.

In addition to convening workshops and setting up training activities, the pilot phase of CTA-SME is preparing (in collaboration with the relevant Member State programmes) technology transfer packages covering training aspects, documentation, design tools, component libraries, etc., and information on the market analysis, economic assessment, design and fabrication of ASICs. Initially drawing on the results of existing ESPRIT microelectronics projects, these packages will be made available to SMEs and national SME service centres throughout the European Community.

If the pilot phase, after independent evaluation, is found to have been successful, the Commission will propose the launch of a five-year action with the aim of making available a wide portfolio of emerging technologies (such as BiCMOS, non-volatile CMOS ASICs, smart power and GaAs, etc.) to the large number of European SMEs that could, as recent surveys indicate, incorporate ASICs and other microelectronics components into their products and so gain a competitive advantage in the global information technology market.

Special interest groups (SIGs)

There are now six SIGs operating in the microelectronics area. These groups have generated many reports, guidelines and *ad hoc* inter-company standards in addition to acting as a forum for the exchange of ideas and results. SIGs create the fertile conditions in which potential future ESPRIT projects are conceived. In addition to the four groups that have been operational for several years, two new ones were launched in 1990, covering reliability and analogue design issues. The SIGs currently supported are:

- CAVE (CAD for VLSI in Europe),
- VLSI manufacturing automation and standards,
- Lithography,
- Analogue circuit design,
- Reliability,
- Electronic materials.

Further details are given in the chapter on awareness activities.



Information processing systems

Overview

The Information processing systems (IPS) area of ESPRIT aims to provide a selected range of generic technologies that are critical for the development of IT products likely to come onto the market in the 1990s. The generic nature of these technologies makes them applicable to a wide range of system products, offering a real advantage to vendors and providing high value to users.

The main objective of IPS is to produce more powerful and reliable systems at an affordable cost by supporting projects in four key sub-areas: Advanced system architectures, Information servers, Systems design and engineering, and Signal processing systems. Forty-one new projects and 17 exploratory actions were launched as a result of the general call for proposals that closed in January 1990. The competition for projects was particularly strong in IPS, which received 220 proposals, half of the total submitted. This clearly indicates that European enterprises, and in particular SMEs, continue to demonstrate an appetite and a drive to invest in the development of advanced technologies that are seen as a critical source of future revenues and competitiveness.

In the course of the past 18 months, four important trends have been apparent:

■ Continuing commercialization of earlier results

A market is now developing for the high-performance parallel computer systems explored and developed in a number of earlier ESPRIT projects, and this has been matched by the emergence of an increasing number of European suppliers, mostly small but all now experiencing a period of rapid growth. New software products are reaching the marketplace, such as

commercial implementations of the Portable Common Tool Environment (PCTE). In addition, European knowledge-based system products and companies show a sharp increase in their share of a world market estimated to exceed ECU 20 billion by the end of decade.

■ Intensified standards-related activities

In all sub-areas, major projects are tackling the issue of establishing standards in order to increase the range of choice available to end-users while lowering the risks and costs experienced by system developers and vendors.

■ Towards integrated systems and object orientation

Individual technologies and disciplines are being combined to address wider problems. For example, the drive towards a new generation of information servers relies extensively on the progressive fusion of work in advanced architectures, intelligent interfaces and deductive knowledge-based systems. Object orientation lends itself to conceptual modelling and software design methods. Similarly, object-oriented options are increasingly favoured in the development of new generations of information management systems.

■ Excellent progress in technology transfer

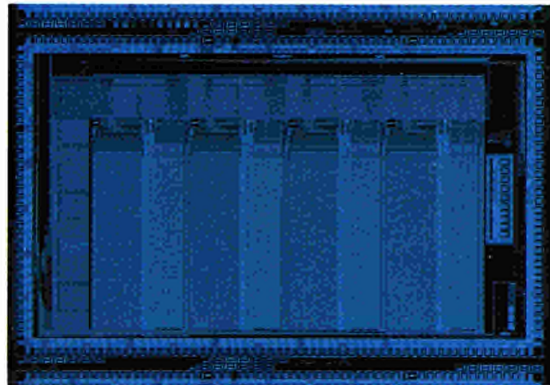
The Parallel computing action (PCA) has enabled 55 academic and research establishments to acquire parallel systems, and over 300 researchers a year

are now being trained in parallel computing techniques.

Advanced systems architectures

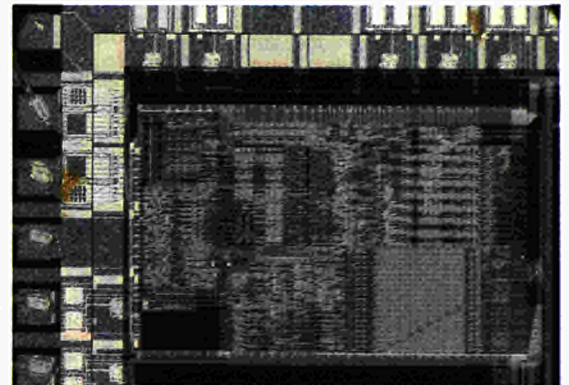
Since its inception, this area of IPS has been pursued with the view that future computing needs cannot be adequately met by implementing conventional processing systems using ever-more exotic technology to increase

The next generation: the T9000 transputer, launched in April this year, will accelerate the progress of parallel computing into the mainstream. Shown are test chips for the cache memory (left) and communication (right) subsystems, developed in PUMA (project 2701).



High-performance components show dramatic improvements

In April 1991, following the successful development of the T800 transputer in the SUPERNODE project, Inmos (UK) announced its successor, the T9000. This is one of the world's most powerful RISC processors, with a peak performance of 200 Mips or 25 Mflops, and with four 20 Mbyte/s communications channels per chip. The T9000 is aimed at low-cost architectures and works with a 5 MHz



basic clockrates and processing power. Work on highly parallel systems is now achieving dramatic reductions in cost/performance ratios, and the potential redundancy offered by multiprocessor systems is leading to ever higher levels of overall system dependability. The new generation of parallel processing systems are now offering supercomputer levels of performance at minicomputer costs, and, importantly, they are scalable, with low levels of incremental cost.

To date, IPS projects in this area have resulted in the construction of several prototype systems. An increasingly used standard component, the T800 transputer, has been developed and is now employed as the basis for a variety of commercial products. The T800 transputer, developed within SUPERNODE (project 1085), is the key component in a range of parallel systems offered by a group of rapidly growing SMEs that includes Telmat (F), Parsytec (D), and Meiko and Parsys (UK). By 1990, 240 000 T800 transputer chips had been sold, bringing sales to 400 000 units, the highest achieved for any RISC microprocessor. By 1995, the overall transputer market is expected to reach ECU 1 billion. Further improvement of the basic architecture for large-scale parallel systems and their fundamental components is now being addressed by PUMA (project 2701) and GP-MIMD (project 5404).

clock (compared with 33 MHz for current scalar products). Today's transputer-based products range from 25 to 600 Mflops, providing supercomputing power at one-fifth of the cost. Through continuing development, the processing capabilities of the transputer have increased more than ten-fold in three years.

Complementing the processing performance of the T9000 is a new communication chip, the C104, developed in PUMA (project 2701). A joint patent has been applied for by two of the partners, Inmos (UK) and Siemens (D). The improved communication mechanism is critical to improving the ability to scale up transputer-based parallel-processing systems, raising the number of nodes from, say, 1 000 to 10 000 in a single system. A combination of an order of magnitude improvement in basic node performance together with a further order of magnitude improvement in the number of nodes that can be deployed now offers a potential 100-fold boost to current Supernode-type systems.

PADMAVATI (project 967) explored the architecture and environment appropriate for real-time artificial intelligence (AI) applications, for example in speech and image understanding. Such applications often require a dynamic routing capability in communication and an associative capability in

SUPERNODE: *the Mousetrap is a prototype handheld computer, ruggedized for field use, based on a miniaturized Supernode processor module delivering 200 Mips. Developed by DRA (formerly RSRE), the Mousetrap system incorporates a 5" colour liquid-crystal display. In the picture, this is showing a false-colour contour map of the Isle of Wight, generated from software that simulates what a hypothetical observer could see from a particular viewpoint (black is below the horizon). An application being explored is the siting of transmitters in accordance with both technical (line-of-sight) and environmental considerations.*



data access. To meet these specific needs, a dynamic routing chip (DYNET) produced by Thomson-CSF (F) and a state-of-the-art CAM (content-addressable memory) from GEC (UK) are now commercially available. These results represent a major step forward in the development of architectures suitable for AI applications where real-time requirements must be met.

Architectures: further exploration and the need for standards

GP-MIMD (project 5404) brings together a substantial group of European organizations concerned with the development and exploitation of transputer-based systems. In addition to work designed to point the way forward to a new generation of message-passing computers, there is a strong emphasis on the development of a standard machine architecture and standard applications support interfaces. Operating systems providers Chorus Systèmes (F) and Perihelion (UK) are collaborating to provide an improved operating system environment that builds on their current products (the Chorus micro-kernel and

the Helios tools and environment, providing X-Windows and Unix capabilities).

Communications are important for parallel processors and have received significant attention within IPS, with new computational models and architectures being developed. The parallel random access machine (PRAM) model is a topic of research in PUMA (project 2701) and GP-MIMD (project 5404). GENESIS (project 1041) examines the issues to be addressed for ultra-fast distributed-memory architectures, and the current phase of the project concentrates on the challenging software issues. AMUS (project 2716) is exploring the development of ultra-fast, multi-processor, scalar-processing nodes.

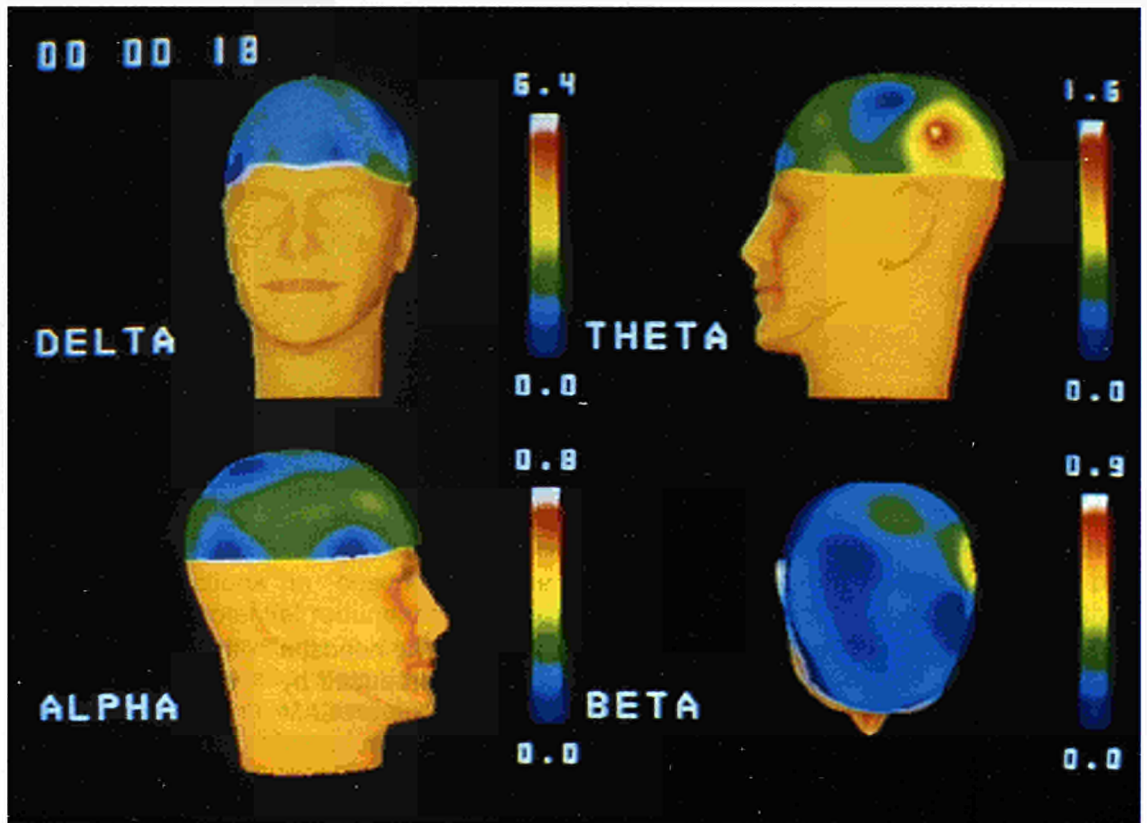
The growth of distributed-processor architectures offers both a challenge and an opportunity with respect to systems reliability and dependability. Both of these related issues have been addressed by DELTA-4 (project 818), where the main industrial partners Bull (F), Ferranti (UK) and SEMA (F) have an open-architecture, fault-tolerant demonstration distributed banking system for Crédit agricole and a further manufacturing demonstrator with Renault.

Software: making systems more accessible

The 1990 Call strengthened the software component in the domain of high-performance architectures with the addition of COMPARE (project 5399), which is examining basic compilation technology and aims to extend, where appropriate, the technology in tools for com-

neural computing, have been the subject of intensive R&D activities and growing industrial interest. The neural computing approach, inherently parallel and capable of dealing with incomplete information, is expected to lead to more powerful and flexible information processing systems through the fuller exploitation of the possibilities offered by massively parallel architectures.

Brain waves: *Telmat's T. Node supercomputer, derived from SUPER-NODE (projects 1085 and 2528), takes just one second to analyse and display electrical signals from the brain monitored by electroencephalography. The key to unlocking the processing power of parallel computers is to provide software tools that make program-writing easier, and the SUPERNODE II project is producing a range of software to meet this need.*



piler generation for parallel machines. It joins SUPERNODE II (project 2528) as the second major software project (software issues will be the main focus for future actions in the area). SUPERNODE II has already ported a version of the Portable Common Tool Environment (PCTE) onto a Supernode system together with the world-leading standard numerical libraries from Numerical Algorithms Group (UK) and state-of-the-art simulation algorithms.

New approaches: neurocomputing and optical processing

To complement the tools and methods developed in knowledge engineering, which are largely based on logical representation and deduction models, new kinds of information processing, generally referred to as

The approach taken in ESPRIT has been to evaluate the new technology of neural networks over a range of industrial applications, development tools and environments. These activities have been mainly carried out in ANNIE (project 2092), whose results are being delivered through a set of awareness and technology transfer actions. Another area of work aims to provide application developers with a complete software and hardware environment. PYGMALION (project 2059) delivered the MIMENICE software environment now commercially available from the Thomson-CSF (F) spin-off company Mimetics. The hardware environment is now under development in GALATEA (project 5293), where a silicon compiler for neural network ASICs is being produced.

Optical computing has the potential to play an important role in future information process-

Supercomputers: the TNode range sold by Telmat, spanning 30 Mflops to 4.4 Gflops.



ing systems. The development of basic optical interconnection technologies is taking place in the Microelectronics area of ESPRIT, while the more speculative area of 'computing using light' has been investigated in COOP (project 1035) and is currently under examination in NAOPIA (project 2288). In conjunction with research on the basic technologies required to provide the appropriate range of components, the task of placing prototypes in industrial environments is under way. A hybrid acousto-optical image-processing system for parts recognition has shown promising results in COUSTO (project 866), and has been further improved in NAOPIA (project 2288) to a point far beyond the current video processing rate of 50 images/s — NAOPIA has demonstrated 1 000 images/s, adequate for HDTV-quality applications.

Information servers

Work on Information servers is aimed at overcoming the constraints placed on users by the current speed of access to computer-based information and the data manipulation and presentation facilities presently available. R&D activities in this area address the representation, distribution, availability and integrity of large volumes of complex, diverse information. The challenge is to achieve this in a way appropriate to the task to hand and the user's level of expertise. The projects concerned draw extensively on previous work on advanced architectures and knowledge engineering.

Current information management systems have difficulty in meeting the growing requirement for handling mixed-media information comprising images, graphics, speech and

text. Dealing with an ever-growing volume and complexity of data is another challenge, equalled by pressure from users for more convivial ways of interacting with systems. Overall, it is estimated that traditional database systems are at present able to cope with only 5% of the total information available to the average organization. A new generation of information management technologies is needed.

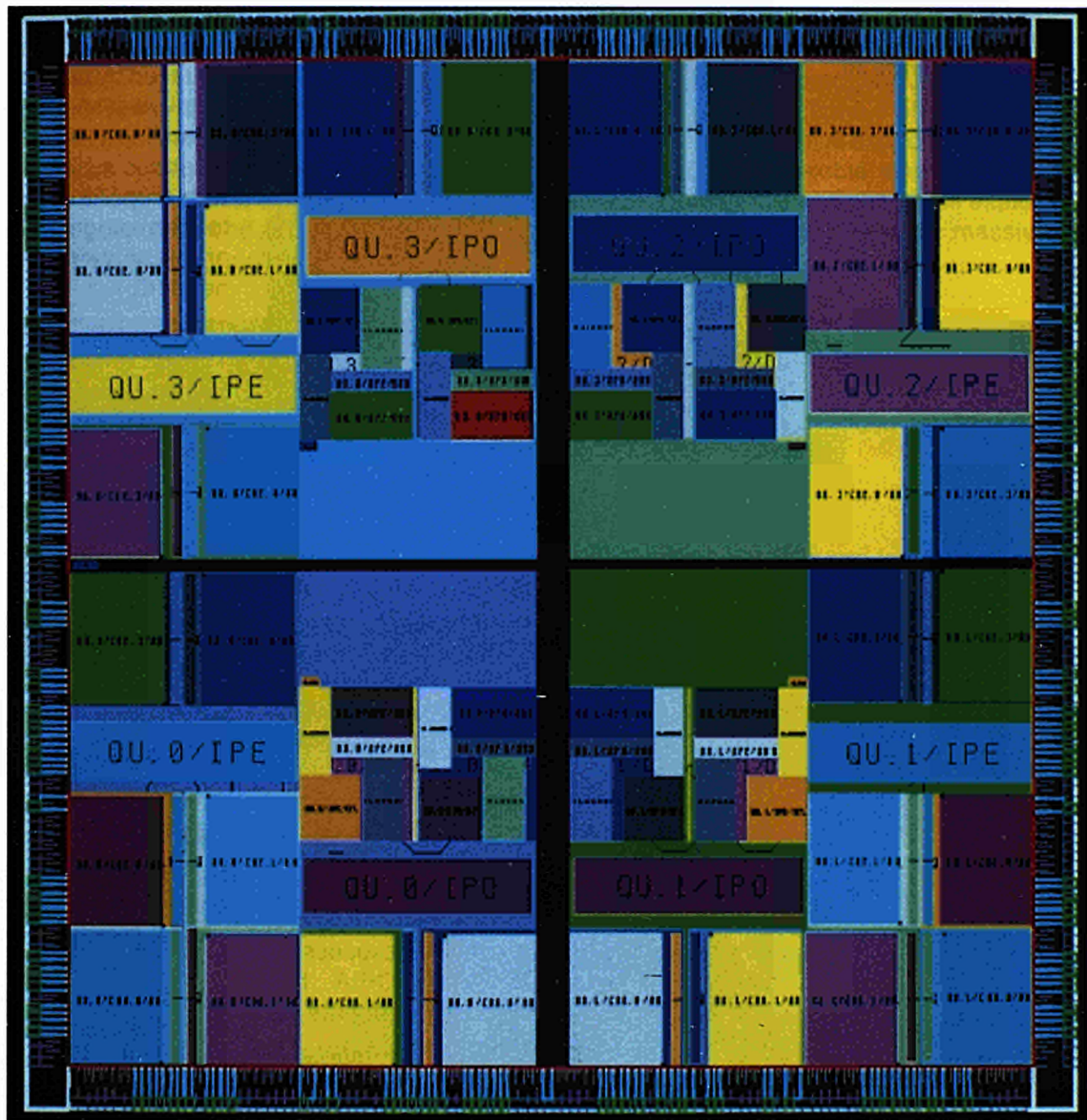
These considerations have been the driving force behind this new focus of interest. It draws on work undertaken in the Advanced architectures sub-area, where highly parallel systems offer a clear potential for meeting the system performance figures required and where object management issues have been extensively explored. It also incorporates activities initiated in the Knowledge engineering sub-area, where knowledge-based approaches have been used to improve the quality of human/computer interaction and have addressed the question of increasing 'intelligence' within the information store itself.

Higher performance — the continuing challenge

Good progress towards a parallel engine front-ending a database with deductive capabilities has been made by the major project in this field, EDS (project 2025). EDS is evaluating the capabilities of the system in a selected range of commercial applications. The project has already established leading-edge results both in parallel computing, with the development of a distributed shared-store system, and in the relational database domain, with extensions to SQL. The three main commercial partners, ICL (UK), Bull (F) and Siemens (D), intend to exploit the EDS results in their future product lines.

In a complementary line of research, significant improvements in memory management have been achieved by STRETCH (project 2443). This project is concerned with systems supporting the representation and manipulation of large knowledge-bases, and the project team, coordinated by Alcatel Alsthom Recherche (F), has developed a very fast main-memory object manager and is progressing towards a full-scale demonstrator.

Information server: the EDS (project 2025) delta network, optimized for high-performance parallel processing, is based on a 400 000 transistor ASIC designed by Siemens. Shown is the block layout for the ASIC displayed on a workstation during the chip design process. The EDS project is developing an information server to meet the challenges of handling ever-growing volumes of information and more and more complex application systems.



Making information more available: database distribution and integration

Integration of new systems with existing databases is a key factor in encouraging IT uptake, and good progress has been made towards solving one aspect of this problem in EPSILON (project 530). The project has successfully developed an environment which facilitates the building of a distributed knowledge-based management system layer on top of existing database management systems. The system is being used for a banking application and as part of a treasury management support system, and its implementation on parallel architectures is being further explored in the EDS project.

Heterogeneity in database systems is another factor which has to be addressed, and this is being tackled by KIWIS (project 2424) and

AIMS (project 5210). KIWIS has implemented a 'federation' of KIWIS nodes and is investigating interfaces to SQL. AIMS places considerable emphasis on extending traditional database functionalities in addition to incorporating knowledge components as well as methods of reusing existing information sources. Both KIWIS and AIMS draw on results from previous ESPRIT projects.

Making information more accessible: improving the utility and knowledge components

All of the above projects address, in a variety of complementary ways, the addition of 'intelligence' to the information stored within the system and advances in the manner of the interaction with the user. Further recent additions to the IPS portfolio in this general do-

main are PLUS (project 5254) and EMIR (project 5312), examining the use of linguistics to support information retrieval.

Systems design and engineering

Software and related services are already the second largest component of the IT industry and are forecast to become the dominant source of business in the course of the decade. Europe accounted for 23% of the ECU 63 billion world market for software and services in 1984, and this share is estimated to grow to 33% of an ECU 353 billion world market by 1993. Furthermore, this leading position does not take into account the activities in software development undertaken in user organizations, estimated to be an order of magnitude larger than that accounted for by the traded software sector.

Software is now clearly positioned as the major added-value component in most IT systems. Moreover, given the critical contribution of these systems to the efficiency and responsiveness of the organizations in which they are deployed, a capability to design and realize such systems in a cost-effective, predictable manner and to appropriate quality standards is vital to the future success of both the European vendor and user industries.

IPS activities in systems design and engineering have contributed substantially to methods, tools and standards that are laying a basis for a strong European capability in this domain. Work to date has demonstrated the increasing convergence of traditional software design and engineering with the newer field of knowledge-based systems engineering.

Work on systems design has focused on developing improved methods for the design of software applications, providing new tools to support these methods and establishing a standard framework within which the tools can be deployed to support project teams.

Systems design standards

The IPS-led work on a Portable Common Tool Environment (PCTE) has led to the definition of a standard which was recently (December 1990) confirmed by the European Computer Manufacturers Association (ECMA) as ECMA Standard 149. The work leading to the stand-

ard originated in a cluster of ESPRIT projects centred around the original PCTE research (project 32), and was subsequently pursued, with ESPRIT's support, through the standardization procedures of ECMA and the technical committee responsible for its definition.

The standardization work attracted wide international support and encouragement, not only from the major European vendors but also from major US players and Japanese companies. Important technical input has also been provided by the Independent European Programme Group, a nine-nation consortium within NATO, which has mounted a programme to validate the PCTE standard in terms of its suitability for defence needs. The Group will use the results of the validation activity to help with the further evolution of the standard.

An additional important contribution of this work has been a reference model for CASE (computer-aided software engineering) tools, which was also adopted by ECMA. The quality of this work has been confirmed by requests from the US National Institute of Standards and Technology to collaborate on the development of the ECMA model as the basis for their own work on reference models in this area.

The emergence of a standard and the progressive agreements on a CASE reference model are important steps in improving the market for CASE tools and environments. They provide the user with wider freedom to mix and match individual tools to suit particular requirements, and offer vendors the possibility of lower development costs as they can increasingly work to accepted interface standards. PCTE environments are now commercially available on workstations from Bull, DEC, HP, IBM and Sun. Software environments and PCTE-compliant tools are now being offered by a range of software suppliers such as SFGL, Syseca, GIE Emeraude and IPSYS.

Systems design: key contributions to software assessment

Given the significant role that software now plays, the development of objective methods of assessment is increasingly seen as an important further step in developing the market for software products. Well-founded assessment processes are seen as contributing to a more open and better relationship between customer and supplier.

After only two years of work, SCOPE (project 2151) has already delivered a number of key recommendations to European standards bodies on this important issue. The tools and process being developed within SCOPE are continuing to be applied to a wide range of case studies to give further authority and confidence to the recommendations made and to extend the range of assessment approaches and the number of products that can be assessed.

Reliability issues and safety-critical systems are topics of special importance in the field of software assessment, and these have been addressed by REQUEST (project 300) and MUSE (project 1257), respectively.

REQUEST has provided improved and validated techniques for measuring and modelling software quality and reliability, and has exchanged tools with the Alvey software library, with further agreements under negotiation. REQUEST metrics are in use in ICL (UK) to define software quality environments, in Elektronik Centralen (DK) who provide services to other Danish companies, and in other ESPRIT projects.

MUSE has progressed the state of the art in the assessment of safety-critical systems. Partners are now providing expert services, incorporating results into their own internal procedures, organizing technology transfer to wider groups, and have produced technology prototypes aimed at supporting the assessment of important classes of system. SAMSON, a prototype expert system developed by the project to help assess the quality of safety-critical systems, has already been requested for use by companies outside the consortium. ATHENA, a tool for complexity measurement and maintenance assistance, and DEMETER and MODECON, for calculating design metrics based on two simple description languages, are other important outputs from the project.

Transferring results into the marketplace has been a focus of attention in IPS, and an early achievement in this field has come from METKIT (project 2384), which has already provided enhanced tools for teaching software metrics to managers, software engineers and students. The main features include a modular course structure, computer-aided-learning (CAL) techniques, and the use of video. Future developments of the work may include the use of CD-I.

Systems design: contributions to products

In addition to the extensive range of products stemming from the PCTE actions noted above, the work on system design, especially on object orientation and software reuse, has contributed to further product offerings which are now coming on to the market. ESI (F) have used results from KNOSOS (project 974) to further consolidate their world market lead in crash simulation software. The KNOSOS techniques for software reuse are now incorporated in CRASHSTATION, a support tool for the PAM-CRASH system, used by the great majority of car manufacturers world-wide.

GSI Teci (F) and TXT (I) are both exploiting results from DRAGON (project 1550). GSI Teci is marketing the job supervisor that was explored within the project and which supports the execution of multiple Ada programmes on target systems. The improved experience with multiprocessors has served as the basis for a new real-time craft multiprocessor product. TXT is pursuing the industrial exploitation of the object-oriented language and the preprocessor developed in the project. A number of companies and consortia have indicated interest in acting as beta test-sites, and evaluation copies of the preprocessor are currently in use both in Europe and the USA.

Knowledge engineering

Knowledge engineering has been of increasing importance in the field of advanced information processing systems and is making significant contributions to systems design and engineering.

Knowledge-based systems: developing the market

A significant set of projects were established in the earlier phase of the programme to demonstrate the practical application of knowledge-based systems (KBS) to problems on a scale found in real-world applications. The aim was to demonstrate that the technology was mature enough to begin to offer solutions to a broad class of systems problems. Successful applications of the technology have now been demonstrated in areas as diverse as process control, manufacturing, diagnosis, banking, intelligent interfaces, and medicine. Using the technology is

now almost routine in many computer-integrated manufacturing (CIM) and advanced business and home systems — Peripherals (ABHS-P) ESPRIT projects. Knowledge-based systems have gained widespread acceptance.

Application demonstrators within the Knowledge engineering area of IPS have made a major contribution to the development of this market, leading to products such as SPIRITS from Syseca (F), and ESB 96, an expert system shell developed by Plessey (UK) and sold by Siemens (D). These products support the development of intelligent interfaces and are derived from earlier work done in ESB (project 96). CARMEN, a user interface builder and rapid prototyping tool sold by BIM (B), is a result of LOKI (project 107). An expert system shell based on EMG (project 599) is commercially available from the start-up company Hugin, and SPIRAL, a Prolog program environment for safety-critical application areas based on work in ALPES (project 973), is available from CRIL (F).

The need for an engineering approach

With the rapid acceptance of knowledge-based systems (KBS) technology as a significant source of adding value to more traditional software systems, the development of methods and tools to support the building of well-founded knowledge-based systems has become an R&D priority. Several IPS projects have made important contributions to this end.

A methodology for the critical knowledge acquisition phase of knowledge engineering has been provided by KADS (project 1098). This methodology, now marketed by the commercial partners, has attracted the attention of other companies such as Arthur Anderson and IBM, both of which are adopting KADS as a standard methodology. Academic partners have established broad-based technology transfer actions and supporting tools, including the object-oriented graphical language, PCE, developed by Universiteit van Amsterdam (NL), and the Shelley workbench. These are now on the market both in Europe and the USA. The KADS results have also been used by two projects led by CAP Gemini (F). ACKNOWLEDGE (project 2576) is aimed at the construction of a knowledge engineering workbench to provide an integrated environment for knowledge elicitation and acquisition, and KADS II (project 5248) aims to

extend methods to support the full life-cycle of KBS projects and will examine the issues of integration with software engineering tools and techniques.

Engineering specific applications

Work has also been directed at the engineering of more specific KBS systems, such as those that are distributed or have to meet real-time constraints.

KBS-SHIP (project 1074) is concerned with engineering distributed, cooperating systems. Coordinated by the Danish Maritime Institute, it aims to help bridge and engine-room officers carry out duties ranging from voyage planning to alarm-handling by providing a decision-support system and a standard framework for integrating shipboard data communication and information systems.

The novel KBS-SHIP approach is to combine artificial intelligence techniques with operational analysis methods to help with drawing up plans for voyages, alarm diagnosis and handling, and in preparing maintenance schedules and loading plans. A computer-based systems manager supervises the communication and collaboration of the individual systems, drawing on the support of individual expert systems, which include one storing all the relevant regulations governing the operation of a complex ship. Other subsystems include the expert voyage pilot (EVP) and expert loading system (ELS). The voyage planner has been demonstrated, is currently on sea trials, and is being commercialized by Krupp (D). An expert system product for machinery operation, stemming from the same project, will be available from Søren (DK).

Real-time issues are being addressed in AITRAS (project 2167), which is building a system shell and design tools for the real-time analysis of instrumentation signals. Prototype system components have been completed and are being tested on a number of safety-critical applications, including the non-destructive diagnosis of faults in nuclear steam generator turbines. Project partners Laborec (B) and Tecnatom (E) have exploitation plans for both the industrial applications and the tools and techniques with which the applications can be built, while partners Cognitec (F) and AI Systems (B) are using the techniques in other products.

Developments in constraint logic programming (CLP)

In addition to the advanced engineering concerns discussed above, other R&D in IPS ensures continued support for the further development of technology in areas of broad potential and wide application. Constraint satisfaction is one example, where the close integration between numeric and symbolic processing has already provided manageable solutions to problems that have hitherto presented major combinatorial difficulties. Application domains as diverse as production planning, VLSI design, diagnosis, financial systems, logistics and network management have all been shown as areas where the application of CLP has the potential to offer significant benefits.

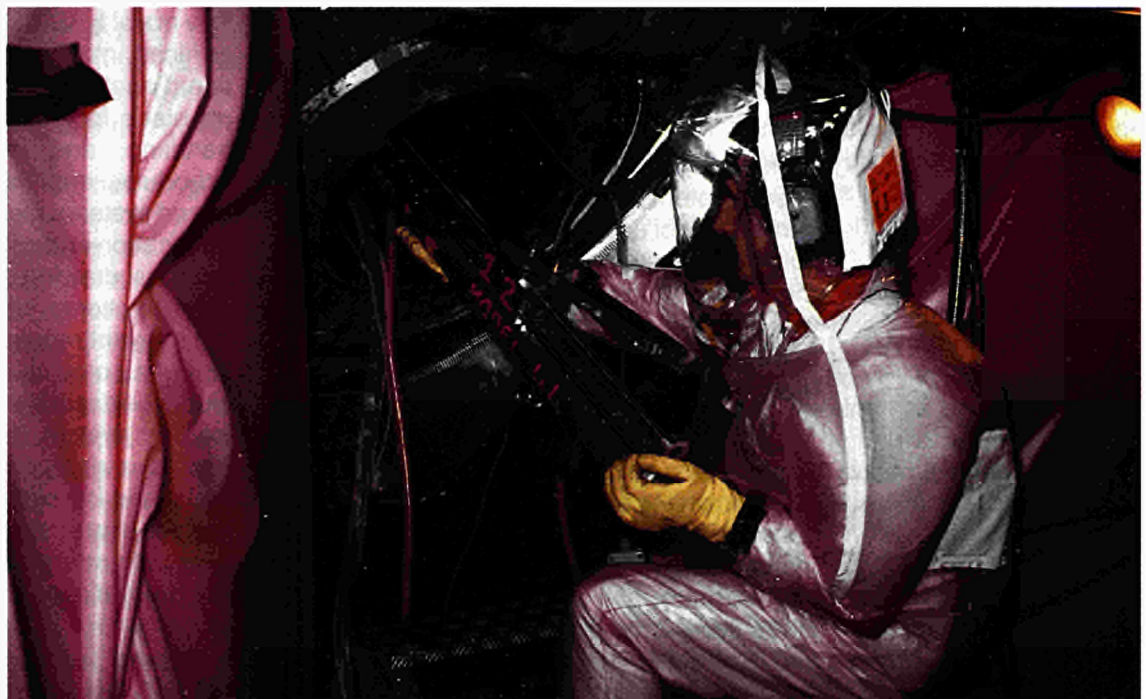
ESPRIT has contributed substantially to establishing Europe as a source of leading-

in CHIC (project 5291) and the supporting technology in PRINCE (project 5246).

Further moves towards systems engineering

A significant step towards defining a common systems engineering model suitable for a wide range of applications has been made with the completion of the definition stage of ATMOSPHERE (project 2565). This major project extends the concepts and approaches developed within software engineering to embrace the full set of systems engineering requirements. It aims to integrate key aspects of CAD, CAE and CASE support, using existing technologies (such as PCTE) where appropriate, and to establish an architectural framework and supporting integration technologies to ensure that the ATMOSPHERE tools and environments are open and well integrated. The project brings

Signal analysis: an operator installs a remote-controlled manipulator to inspect a steam generator tube in the DOEL-II nuclear reactor in Belgium. The signals delivered by the manipulator will be analysed by a system stemming from AITRAS (project 2167).



edge competence in the CLP domain. The Prolog III product from Prologia, derived from the work on PROLOG III (project 1106), incorporates strong constraint resolution capabilities. It is currently the most widely-used CLP tool available world-wide, with more than 300 licences already sold. Furthermore, the user partners in the project, Daimler-Benz (D) and Robert Bosch (D), now plan to continue to exploit CLP techniques internally for diagnosis and testing and for CAD. The application domains are being further developed

together many of Europe's leading CASE and system engineering players. 'Proof of concept' demonstrators have already been developed, and the major partners aim to build well-engineered environment demonstrators addressing four important application areas:

- aerospace systems and distributed systems, using a framework integration approach;

- digital computer network systems, again with a framework integration approach,
- communications systems, with a toolset-driven integration approach,
- process control systems, with a combination of toolset- and framework-driven integration.

The environments will all be piloted and evaluated through the involvement of systems engineers in selected partners' products divisions. Environments and toolsets resulting from the project are planned for subsequent commercialization by partners, as is a substantial programme of technology transfer.

The progressive intersection of system design with knowledge-based systems engineering has reached a point where it is beneficial to treat further developments as a joint set of actions. The focus in future will be on systems engineering techniques.

Signal processing systems

This sub-area of IPS R&D exemplifies, above all, the need for a true systems engineering approach. Signal processing projects draw extensively on the technologies of knowledge engineering and advanced architectures, build complex software and hardware components, and engineer their overall integration into major IT systems.

The work is concerned with systems where large quantities of complex, external-world data have to be recorded and handled in real-time, and focuses on the provision of 'automatic' interfaces that enable a computer system to respond promptly to external stimuli. Such systems are the critical components of applications involving speech recognition and vision applications, and they are finding their place not only in industrial applications, such as robotics and inspection, but also in medical imaging, environment monitoring, and systems to aid the handicapped.

Two major application areas are covered in IPS signal-processing work: vision and speech understanding.

Vision systems: 'open architecture' standards

Computer vision systems are increasingly becoming the high-value component in

systems that address applications such as surface inspection, parts recognition, quality control, testing and measurement, and tracking. As the more rapid deployment of such systems is greatly impeded by comparatively high system and development costs, it makes economic sense to aim for the establishment of more cost-efficient standard interfaces and components. ARVISA (project 5225), launched as a result of the last Call, brings together major European vision systems organizations committed to achieving practical standards for the interfaces, protocols and software components that will comprise the vision systems likely to be on the market over the latter part of the decade. ARVISA is seen as a project of strategic importance.

Scene understanding: technical challenge and major market opportunity

A current major weakness in systems designed to understand scenes is the comparative lack of machine-readable knowledge concerning the information needed to process images. MUSIP (project 2316) has built a prototype image database combined with a knowledge-based scene-understanding workstation and powerful data-handling facilities. The prototype is currently being validated on a medical imaging system and a remote sensing application concerned with flood and deforestation monitoring.

In this same area, SKIDS (project 1560) has demonstrated a system that can merge numeric and symbolic data and is able to reason about the scene under observation. SKIDS has developed the principles of a generic architecture for multisensor integration, with particular emphasis on two classes of application: mobile robots, where the sensors are grouped together but the environment is unknown, and wide-area surveillance systems, where the sensors are distributed but fixed. The latter can be used for monitoring offshore oil-fields, nuclear plants and airports.

The results of the work are now being integrated into a surveillance system in VIEWS (project 2152), which will extend the 'understanding' capability to encompass moving scenes, with applications at airports and in motorway traffic control.

Speech: excellent progress in setting quality assessment standards

Many of the key European speech organizations have come together in SAM (project 2589) to define standards for the assessment of speech synthesis and recognition systems. Until recently, access to a systematically recorded set of data has been highly restricted, and this has inhibited the development of quality speech system components. In 1991 SAM established the first multilingual database, consisting of a set of 16 CD-ROMs containing speech recordings in eight European languages, along with recognizer tests and scoring protocols. This database now represents a major European asset. Standardized hardware definitions and software support packages have been developed, providing uniform facilities for database acquisition, annotation and management. The SAM standards are already in use in Europe and North America, and the SESAM workstation has been accepted as a reference.

Future speech products

The provision of a common testbed for speech technology applications is a key component in the progress towards the achievement of an increased volume of speech applications. This is one of the aims of SUNSTAR (project 2094), which has developed an operational dialogue design tool. SUNSTAR focuses on the development of human/computer interfaces based on speech input and output, and is aimed at the professional office and public telephone network environments. The project concentrates on the integration of existing technologies, with the tools currently in use for developing three major application demonstrators combining both speech understanding and synthesis. SUNDIAL (project 2218) is also concerned with methods of using speech in the human/computer interface, and is developing the technologies of continuous speech recognition and understanding. The application prototypes planned are interactive information services, including a hotel vacancy database (Italian), and a flight enquiry and reservation system (English and French).

A multilingual dimension is contributed by POLYGLOT (project 2104) through the provision of a text-to-speech/speech-to-text system for six European languages. An automatic language identifier for five of these languages

has already been demonstrated, and two medical dictation systems developed, for radiology (in Italian) and pathology (English).

Awareness activities**Parallel computing action (PCA)**

IPS has made a considerable investment in technology transfer in the parallel computing area. Following a competitive call for proposals, the Parallel computing action (PCA) has now established systems in 55 academic and research establishments throughout the Community. An additional 20 institutions are invited to participate in twice-yearly information workshops. The Inmos (UK) T800 transputer is the basis of most of the research vehicles in the selected projects. As a result, some 300 researchers per year are now given exposure to, and training on, parallel systems. This is a considerable contribution to widening the European skill-base necessary to push forward development in this area.

ESSI: European systems and software initiative

Considerable attention has also been devoted to the planning of a major European systems and software initiative (ESSI) that aims to secure a sharp increase in the productivity and capabilities of system and software engineers by encouraging the take-up and use of modern system design and production techniques. SMEs will receive particular attention.

The background to ESSI lies in the continuing trend for European companies to become more and more dependent on information technology to achieve and maintain internal efficiency, quality of service and competitive edge. Information technology systems are extremely software-intensive, yet the complex software needed is difficult to specify and design, costly and time-consuming to develop, and are not easily tested before use nor subsequently maintained. Moreover, most system designers and programmers employ tools and methods developed some time ago, though more recently developed techniques can provide significant gains in productivity and quality. These factors have led to an acute crisis of supply, which ESSI will address in three main ways:

- *Application experiments*, by supporting the critical testing and evaluation of advanced methods and tools. The intention is to reach system and software project leaders, opinion-formers in a position to introduce and foster the use of new techniques.
- *Training*, with activities aimed at establishing the better understanding and acceptance of the best methods and tools available, underpinning this with provision for the upgrading of existing skills.
- *Dissemination*, with Community-wide awareness and dissemination activities to link communities of developers and assist the rapid transfer of new and proven tools, methods and services into the marketplace.

A pilot phase will be launched as part of the new phase of ESPRIT, beginning later in 1991 with the selection by open competitive tender

of an ESSI service organization responsible under contract to the Commission for the day-to-day administration of the initiative.

Special interest groups (SIGs)

IPS has encouraged the formation of a number of Special interest groups (SIGs) among partners of IPS projects. Current SIGs are active in:

- LISP,
- Vienna development method (VDM) and formal methods,
- Metrics,
- European Languages Standards Group for MIMD computers,
- Software maintenance.



Advanced business and home systems — Peripherals

Overview

Objectives

The products and services of the IT industry have become essential elements in improving productivity, flexibility and competitiveness throughout business and public administration. In industrial and commercial enterprises IT investments are instrumental in generating revenue. The IT user industries rely on advanced business systems to implement timely solutions and address the business opportunities in an ever more competitive marketplace. The Advanced business and home systems — Peripherals area (ABHS-P) of ESPRIT is developing key technologies, applications and services for this very broad market, which had a global turnover of ECU 700 billion in 1990, ECU 175 billion of which was within the European Community. By the year 2000 this is expected to reach 10% of Community GDP.

ABHS-P brings together the major IT companies, leading-edge users and small and medium-sized companies (SMEs) to create IT system solutions based on the concept of open systems. The aim is to enhance the competitive strength and efficiency of the European Community through the provision of easily implementable multivendor systems based on the ISO standard for Open distributed processing (ODP) and the support of multimedia (sound, text, graphics and images) through a European family of advanced workstations and peripherals. Work in ABHS-P has significantly influenced the relevant international standards and is helping to ensure reliable, affordable and customizable systems for all types of business users.

An additional and complementary area of work is that of open systems for homes and 'in-

telligent' buildings. In this area, too, a major impact has been made on standardization. Home automation lags behind business automation by several years, but it is expected to be a major market for IT companies in the future. ABHS-P aims to put European IT companies in a position to exploit this trend through the provision of systems and services that will bring an improved quality of life for Europeans both at work and at home.

The work carried out has received strong support from the major IT companies in Europe, and has also been successful in involving a wide range of other enterprises, including public administrations, private user organizations and academic research groups. Particular encouragement is being given to SMEs to participate in and benefit from the research. In connection with this, SMESPRIT (exploratory action 5639) was set up in 1990 to investigate the feasibility of an integrated computer-based system for supporting IT planning in SMEs.

133 projects and exploratory actions have been launched within ABHS-P to date, focused on three main themes providing:

- integrated systems for business,
- integrated systems for homes and intelligent buildings,
- advanced peripheral subsystems.

In addition to these, a major new initiative has been launched in open microprocessor systems.

Integrated systems for business

Integration with flexibility has become a key customer requirement in information

technology world-wide, particularly in Europe. User organizations are actively seeking solutions to the problems created in the past by building systems based on incompatible products supplied by different vendors. Users need to protect their existing investments while moving towards more advanced systems that better integrate the functions of different parts of the organization. R&D in ABHS-P is making significant contributions to affordable, reliable European solutions. Major European IT companies and user organizations are involved in projects which are exerting a strong influence on international standards and laying the basis for competitive European products.

During the past 18 months advances have been made in several key areas including distributed systems, the exploitation of ISDN, information management technologies, CD-ROM, and workstations. Significant results have been achieved in integrating the various technologies required in advanced business applications, and in developing the necessary environments and tools for building advanced applications including multimedia applications. Finally, several projects have made contributions towards facilitating the uptake of IT in organizations and to ensuring that the development and use of IT systems is consistent with improving the quality of life as well as the efficiency of business.

Integrated systems for homes and intelligent buildings

During the 1990s, the impact of IT will extend well beyond the boundaries of business applications. IT promises to revolutionize the home and public buildings. Home appliances, linked under the control of microprocessors and connected to the outside world, will be able to provide an entire range of new services and perform at levels never before possible. Buildings will incorporate sophisticated networks capable of providing a broad spectrum of services such as personal security, energy management, heating, lighting, control of appliances, health monitoring, entertainment systems, educational facilities and working from home. IT components will be incorporated into both brown and white goods (for example, music systems and dishwashers) so that these can become integrated into the home electronic system. Companies manufacturing such goods will need to adapt to these changes in order to remain com-

petitive. Until recently, the USA and Japan were leading this field, positioning their industries ready for the new markets that are already opening up. However, the R&D undertaken in ABHS-P has now put European industry firmly in the lead by fostering collaborative research amongst European companies to define, validate and promote European standards for the interoperability of home systems products.

Advanced peripheral subsystems

Peripheral subsystems are essential in a wide range of IT domains, including systems for businesses, homes and intelligent buildings. In order to concentrate funding on a closely coordinated set of key projects, peripherals R&D, previously divided between the areas of Microelectronics and Office and business systems, was consolidated in 1990 into ABHS-P.

The European IT industry faces very strong competition in regard to peripherals but has particular strengths on which it can build; R&D in ESPRIT needs to be highly focused on the key trends in this field. The past year and a half has seen the first consolidation of work on peripheral devices and the start of work on peripheral subsystems. Significant results have been achieved, including products based on the work done in the field of flat-panel displays. In addition, building on earlier results, several projects dealing mainly with materials for recording devices and liquid crystal displays (LCDs) have reached a stage of development where it is possible to build prototypes for demonstration in 1992. Exploratory actions have also been launched in memory and printer subsystems to define the profiles and characteristics of further key European initiatives in these fields.

Building strength in open microprocessor systems

Microprocessors have become very widely used in many areas, and in order to facilitate the building of competitive European IT systems around them, a new initiative has been launched, the Open microprocessor systems initiative (OMI).

Integrated business systems

The last year and a half has seen major product announcements from the European IT in-

dustry based on ESPRIT R&D results achieved in integrated business systems and their underlying technologies. A key element in this success has been the strong emphasis on open systems.

Leading the way in distributed systems

The value of ESPRIT's strategic orientation towards open systems was exemplified by Bull's major product announcement, in March 1991, of its Distributed Computing Model. This incorporates the commercial exploitation of results from eight different ESPRIT projects, six of which are in the ABHS-P area, including COMANDOS (projects 834 and 2071). In addition to its contributions to the Distributed Computing Model, COMANDOS has also enabled Bull to play an influential role in industry standardization bodies such as the Open Software Foundation and the Object Management Group.

ISA (project 2267) has also made significant contributions to standardization, having provided more than half of the text of the current ISO draft standard on Open distributed processing. It has also led to the development of the very successful ANSAware suite, giving Europe a world lead in the field of heterogeneous distributed systems. ANSAware is available on licence through APM (UK), and has been adopted by NASA to support its distributed astrophysics data system, the largest distributed system in the world, with around 600 nodes, 50 databases and 10 000 users. A demonstration at the 1990 ESPRIT Conference exhibition showed the system working with five different makes of

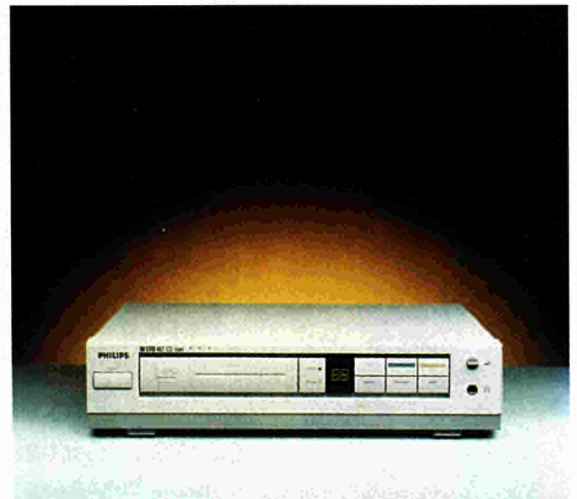
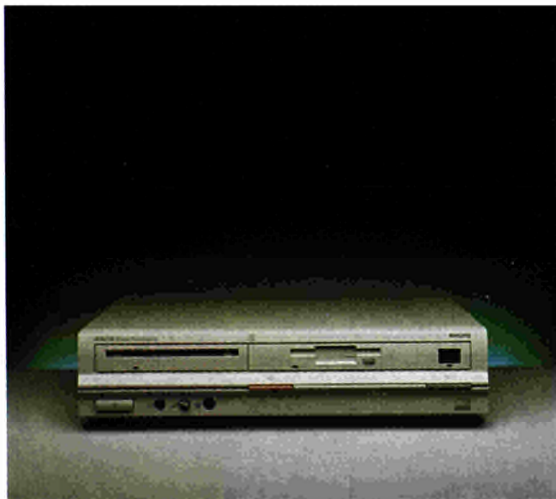
computers online in Brussels and via satellite links to the NASA system in the USA.

The market for distributed systems is forecast to grow tenfold to reach ECU 73 billion worldwide by 1995. The work done under ESPRIT has reinforced the excellent reputation which European companies and research institutes (such as Trinity College Dublin) have in this field, helping to ensure that European industry will be in a good position to compete for a significant share of this rapidly emerging market in Europe and world-wide.

Exploiting the communications infrastructure

Value-added services are an important IT market, and work in ABHS-P is helping to provide a competitive base for European companies. Results from MIAC and MIAS (projects 1057 and 2684) represent a European breakthrough in developing a framework of standards for controlling and using the Integrated Services Digital Network (ISDN). ISDN is one of the most important developments in telecommunications, enabling voice, data and video signals to be efficiently transmitted using the existing telephone cables, making high-quality communications widely available to business. The results of MIAC and MIAS will help European companies to exploit the potential of this new infrastructure to the full. A demonstration at the 1990 ESPRIT Conference exhibition showed people in different offices working cooperatively on a common task using moving video images to see one another on screen while exchanging fax messages, accessing databases and editing text.

'Interactive' CD:
Philips's single-unit CD-I system for professional applications; the CDI 602, is pictured left. A European launch for the mass market version, shown on the right, is scheduled for 1992, following its introduction in the USA and Japan this year. The CD-I concept was developed in DOMESDAY (project 901).



The workstation of the 1990s: producing multimedia products requires so-called 'authoring' workstations, such as the Olivetti CP 486, here pictured on the left, while users need a low-cost 'delivery' workstation, such as Acorn's R260, shown on the right. Both were developed in MULTIWORKS (project 2105). The CD-ROM, centre, is the publishing medium. The aim of MULTIWORKS is to develop an office workstation that allows the manipulation of video, graphics, voice, sound, and text, and their combination in one multimedia document with facilities comparable to those now available in desktop text-plus-graphics publishing systems.



In a complementary line of R&D, DAMS (projects 1059 and 2146) has made significant progress towards a prototype distributed PBX capable of integrating circuit-switched and packet-switched services within the business environment.

Multimedia concepts

New concepts which combine direct user interaction with multimedia storage, based on CD-ROM technologies, are finding their way to the consumer electronics area. CD-Interactive (CD-I), to be introduced by Philips in the USA at the end of 1991, offers people the possibility of hypermedia-type interaction through their television sets with text, graphics, audio and video information. Although the product looks quite different from the DOMESDAY prototype, the concepts (i.e. putting the multimedia data and the access program required on the same CD) were developed in DOMESDAY (project 901). CD-I uses ISO standard 11172 developed by the ISO MPEG group drawing on the work done in COMIS (project 2102).

CD-ROM looks set to become a widely used storage medium during the 1990s.

Work in project 2499, CDR, is developing an advanced, flexible workbench for fast and cost-effective development of multimedia CD-ROM applications. A first complete version of the workbench was demonstrated at the ESPRIT 1990 Conference exhibition, with the first commercial release scheduled for 1991.

Supporting document exchange

In the past, when a document created using one word-processor has been passed to another, its format was lost or disrupted. What is needed is a document standard to which different document creation packages all adhere, so that each package can recognize the structure of documents created by another. ESPRIT has helped to fund development of the Open document architecture (ODA), which is now a member of the OSI family of standards and has been adopted by leading European IT companies. ODA products are now available from many leading European companies including Bull, Siemens, ICL and British Telecommunications.

A number of these were shown during the 1990 ESPRIT exhibition and the first ODA

Symposium, which took place simultaneously in Paris. A joint demonstration showed the exchange of ODA multimedia documents (incorporating both graphics and text) among six different sites in four countries.

Providing powerful, user-friendly workstations

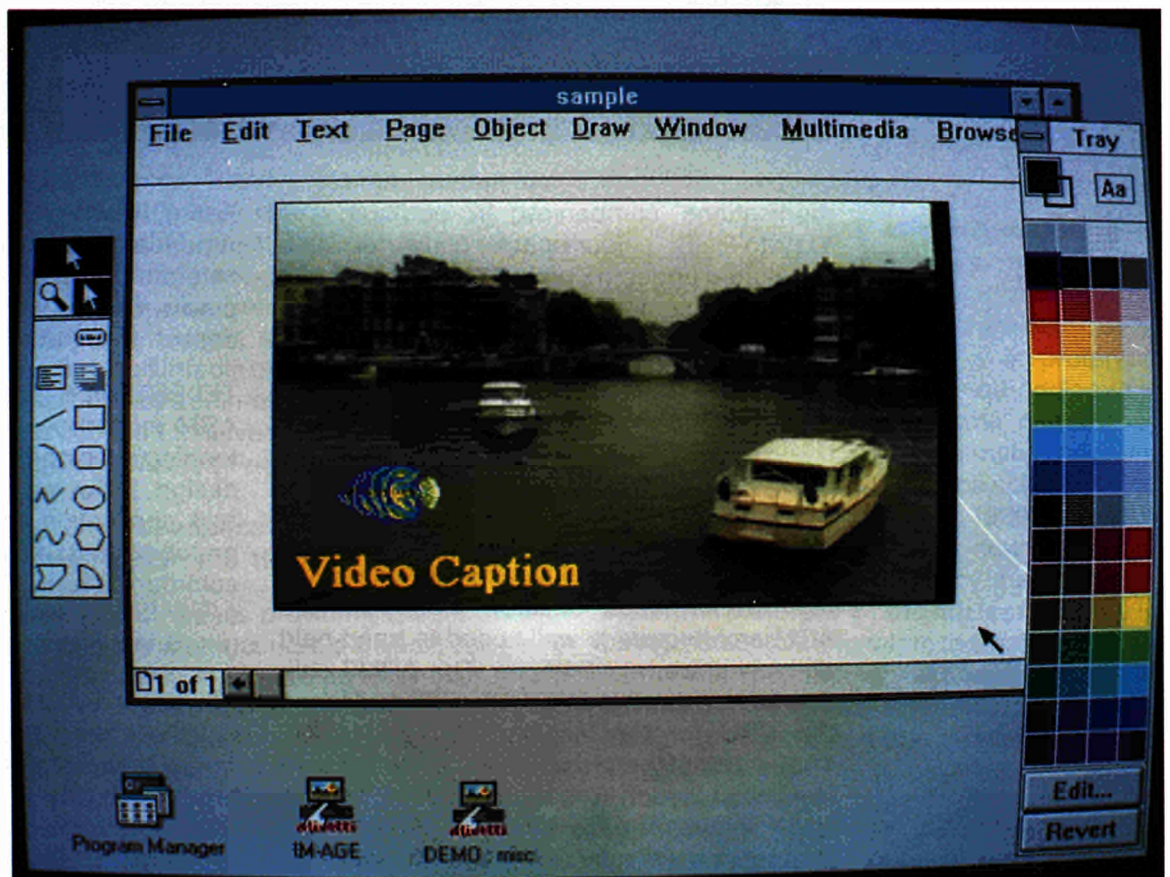
Workstations are the end-user's key to open systems and the principal interface for advanced applications, including multimedia and support for cooperative working. The market for workstations has been steadily rising, and is expected to reach ECU 9 billion in 1994 in Europe alone. To date it has been dominated by American products, but the research done in ESPRIT is now putting European industry in a strong competitive position. Significant results have been achieved across a range of workstation types, notably multimedia workstations for the general office (MULTIWORKS, project 2105), scientific workstations (EWS, project 2569) and very high performance technical workstations (SPIRIT, project 2484).

MULTIWORKS provides high bandwidth at all levels so that the workstations can handle

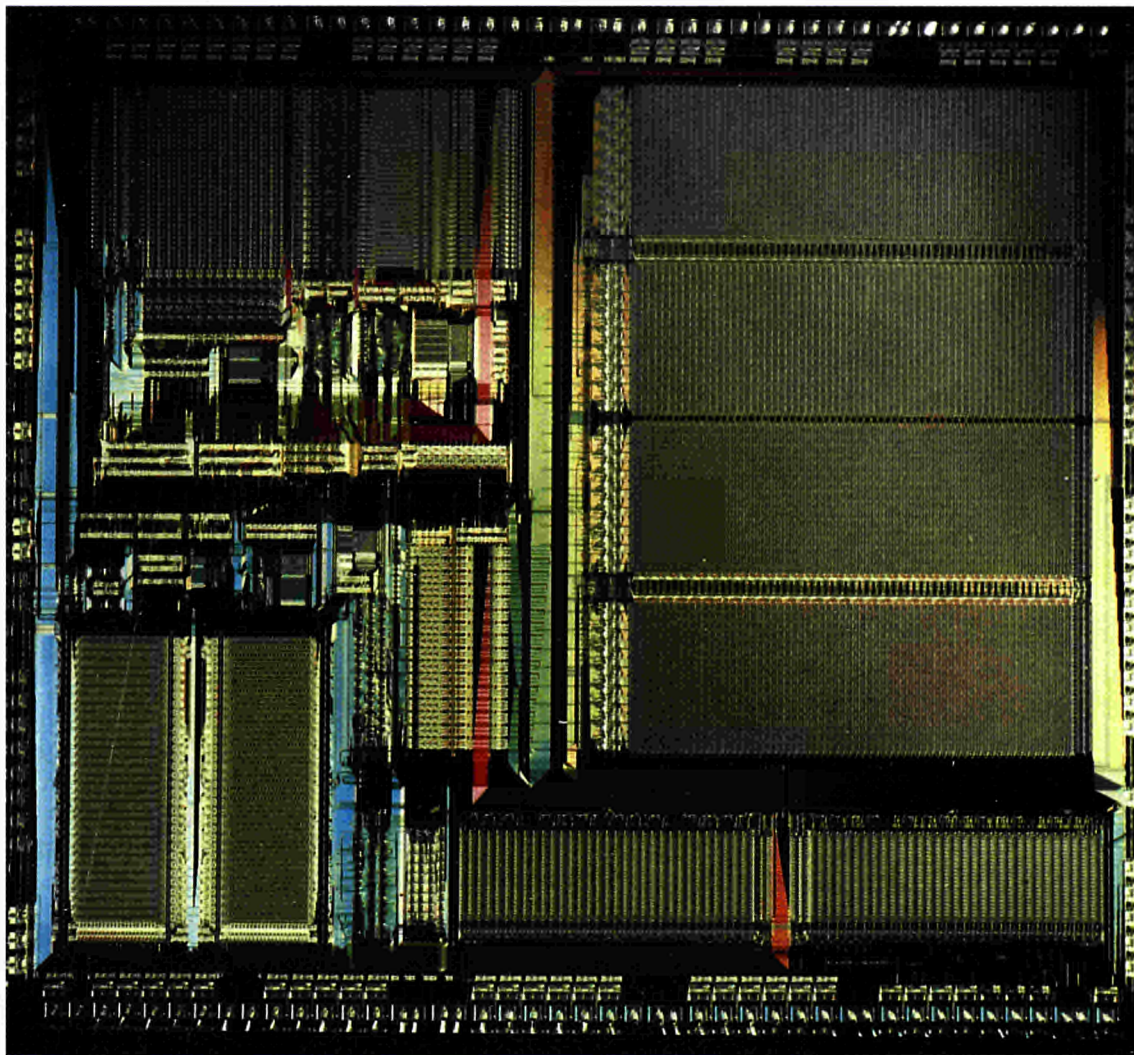
video, voice and sound as easily as today's systems handle text and graphics. Users are able to interact with the system using traditional methods such as keyboard and mouse, and newer methods including handwriting and speech. The project is producing two types of workstation: one intended for applications development, and another for the end-user. Prototypes of these were shown at the 1990 ESPRIT Conference exhibition.

Some products have already benefited from the work, with major product developments scheduled for 1992 and beyond. The Acorn R260 workstation uses technologies developed under the project, including the MEMC2 memory controller which significantly improves memory handling. A high-end knowledge engineering development system has been completed and is being commercialized through an agreement to market it with Lispworks. An enhanced multimedia editor based on the earlier Raphael and Balzac developments has been completed. An ISDN bit-rate adapter component developed under the project is now offered as a standard component by SGS-Thomson, and interest in it has been expressed by telecom-

Multimedia production: a screen from Olivetti's IM-AGE upgrade kit for Olivetti PCs, stemming from work in the MULTOS and MULTIWORKS projects. Full-motion video, photographs, animations, and stereo sound can be combined to produce, for example, business presentations, interactive training packages, and point-of-sale displays. Features include the control of multimedia peripherals such as video disc players and cassette recorders, the capture and editing of still images from video sources, and editing streams of video images.



High processing power: the latest version of Acorn's RISC microprocessor, the ARM3, pictured here, has high (15 Mips) processing power and low (0.4 watt) power requirements, making it an ideal choice for mobile equipment. This microprocessor was developed in MULTIWORKS (project 2105) and forms the CPU for Acorn's R260 machine. TELESTATION (project 5233) is using a version of the ARM3 in its work on portable workstations.



munications companies. In addition, the YUV-to-RGB colour-space converter chip developed under the project is now offered as a standard component by Philips.

The project has also contributed to the establishment of a new company, Advanced RISC Machines Ltd, a joint commercial venture involving several IT companies (including Acorn and Apple) in exploiting key results from MULTIWORKS, including the ARM RISC processor. In addition to supporting extremely high performance desktop machines, the ARM architecture is well-suited to hand-held and low-power applications. The ARM3 chip was funded through MULTIWORKS and forms the CPU for the Acorn R260 and A540. Thousands of these machines have been sold since their launch in 1990, complementing the large installed base of over 130 000 Archimedes computers already in use. An upgrade card containing the ARM3 for R140 owners has also proved popular, and besides

Acorn, the chip has been used by Radius, an American company, for their graphics accelerator card, which plugs into Apple computers. Overall, more than 150 000 ARM processor units have been sold to date.

TELESTATION (project 5233), which uses the ARM microprocessor, is integrating and extending developments in portable workstation design, including multimedia user-interfaces and application architectures, to provide a prototype portable workstation with integrated communications. Results are expected to be used in commercial products announced before the end of 1991.

While general office workstations are of increasing importance in business, scientific workstations play a major role in enhancing the productivity of engineers and scientists. Results achieved under EWS (project 2569) are helping European companies to offer a range of competitive products. The first workstation product shipments based on EWS

are expected in early 1992. The project has already formed the basis for both hardware and software products including an object-oriented database running under the distributed operating system CHORUS, an innovative geometric modelling system, and a multiprocessor system for use in electronic simulation accelerators.

Very high performance technical workstations are needed for use in technical and engineering offices and other environments where performance is of paramount importance. SPIRIT (project 2484) has been working on producing a platform for a European technical workstation based on a tightly-coupled shared-memory multiprocessor system with Futurebus⁺ as the central standard. Some versions of the hardware and software components have been implemented on the industry standard VME bus and are now marketed by the industry partners.

Further exploitation of the results of both EWS and SPIRIT is planned by a consortium of companies formed from the projects. The initial products will be derivatives of the basic workstation (BWS) developed by GIPSI under the EWS project. The companies currently involved include GIPSI (F), Grupo APD (E) and Kontron (D).

In order that users may find the European 'family' of workstations attractive to work with, special emphasis has been put on advanced user interfaces. These exploit the human factors results of several ESPRIT projects, particularly HUFIT (project 385). HUFIT's results are also being used directly in various commercial developments: for example, the Dialogue Manager, a development tool for building multimedia user-interfaces, has been developed by a spin-off company, ICIA GmbH, and licensed to several major IT companies, including Hewlett-Packard.

Meeting the application needs of enterprises in the 1990s

Work in ABHS-P is providing European application solutions across a diverse range of domains and in so doing has generated generic models and prototype solutions that can form the basis for applications in many market sectors.

Managing paper-flow. The results achieved by ASTRA (project 831) and PROMINAND (project 878) on managing the flow of paper through organizations have led to commercial

product developments which have now begun to appear on the market. The Olivetti IBIS family has made significant use of the research results. User organizations will also benefit from a manual of IT uptake guidelines. In addition, the work has laid the ground for further developments within PANDA (project 5432). Developments similarly linked to case handling made in IWS (project 82) are being exploited by Bull (F) in their IMAGE WORK system.

Improving access to information. There is a pressing need for systems that can reduce information overload by guiding users to the items most relevant to them. Three projects have produced particularly notable results during the past 18 months. Nokia Telecommunications is using results from SIMPR (project 2083) to enhance the efficiency of access to technical information about their digital telephone exchanges. KIM (project 5638) has been applying knowledge-based systems technology to enable users to retrieve information from different systems without having to learn different query languages. Results are being exploited in ESA (European Space Agency), and other agreements with industrial organizations in Europe have been completed. MULTOS (project 28) has developed an automatic classification system for retrieving multimedia documents according to their semantic content. Results from this project are being used in a range of Olivetti's products.

Managing responses to emergencies. It is essential that emergencies are managed as effectively as possible with the resources and management techniques available. ISEM (project 2322) is developing a prototype toolbox as part of an overall methodology for developing distributed systems capable of handling international emergencies such as nuclear emergencies, major oil spillages and natural disasters, and during 1990 produced two prototype components, now being integrated into a full emergency management system. A prototype for the nuclear industry is being installed at Tecnatom in Spain, and one for the chemical industry at Kommunekemi in Denmark. The results of ISEM work are also being commercialized in a product marketed in the USA.

Overcoming language barriers. Both in business and in public administration, language barriers are obstacles hindering effective cooperation among organizations in

the different Member States. One aspect of the problem concerns the sharing of technical information. Here TWB (project 2315) has developed a leading-edge translator's workbench, designed to meet the needs of professional translators.

TWB has been effective in stimulating several important commercial developments. Triumph-Adler is releasing a PC-based translation support system running under MS Windows. This product is expected to be launched in 1992. Siemens-Nixdorf is commercializing a workstation version of TWB that integrates several tools using the Frame-Maker environment running on Unix, and several organizations have expressed an active interest in the commercial possibilities of the MATE system, which consists of an integrated set of tools for helping develop and use the large term-banks needed in specialized fields. Several other commercially exploitable stand-alone systems have

emerged from the project, including spelling-verification products and a document converter handling MS Word, WordPerfect and the METAL automatic translation system.

Vehicle scheduling applications. Efficiency in scheduling vehicles is important in containing costs while still delivering a high quality of service. PONTIFEX (project 2111) has developed a prototype scheduling system to help airlines deal with this problem. Systems previously available have dealt with only one or a few aspects of the total problem in an unintegrated way. PONTIFEX is the first system to solve all aspects within a single integrated system using a novel combination of operations research and artificial intelligence techniques. Versions of the prototype are being evaluated by Alitalia and Iberia for airline scheduling. The benefits of the PONTIFEX research extend beyond aircraft scheduling to many other transport applications (such as road freight and mass transit), where systems can be built by customizing the generic system.

Very high-fidelity colour image processing. Image processing systems used for general office applications, even those used in current desktop publishing systems, are not adequate for applications where very precise colour calibration and high-quality reproduction are required. VASARI (project 2649) fills this gap and provides the European IT industry with a means of achieving a dominant market position in the field. The VASARI system shows promise in a wide range of applications where high-resolution image capture and the faithful reproduction of colours is of critical importance, such as in the paint and textile industries and in the field of medicine.

The VASARI system includes innovative image-processing software and a leading-edge digital acquisition system based on a high-resolution camera mounted on a precision-engineered three-dimensional positioning system. A prototype of the system has been installed in the National Gallery in London to help establish a high-fidelity archive of paintings that can then be used to keep track of subtle changes in the collection over time. The archive will also provide a set of digital master images from which copies can be made for educational and home entertainment use. As a demonstration of the latter, a prototype CD-ROM has been produced for use in computer-aided learning.

Handling emergencies: the system developed in the ISEM project can handle the automatic call-out of fire, police and ambulance services, while a structured dialogue takes the user through the decisions that must be handled by a responsible human agent.



Patient care. Health care throughout the European Community would benefit from a European information and communication network based on a comprehensive set of accepted standards and agreed rules for data protection. This is the focus for RICHE (project 2221). The purpose of the project is to integrate the results derived from ESPRIT, AIM and other Community programmes into a system characterized by an emphasis on basing medical care and nursing on the patient's record. The work is expected to pave the way for setting up a new company at the end of the project for the commercial development, marketing, installation and maintenance throughout Europe of a hospital information

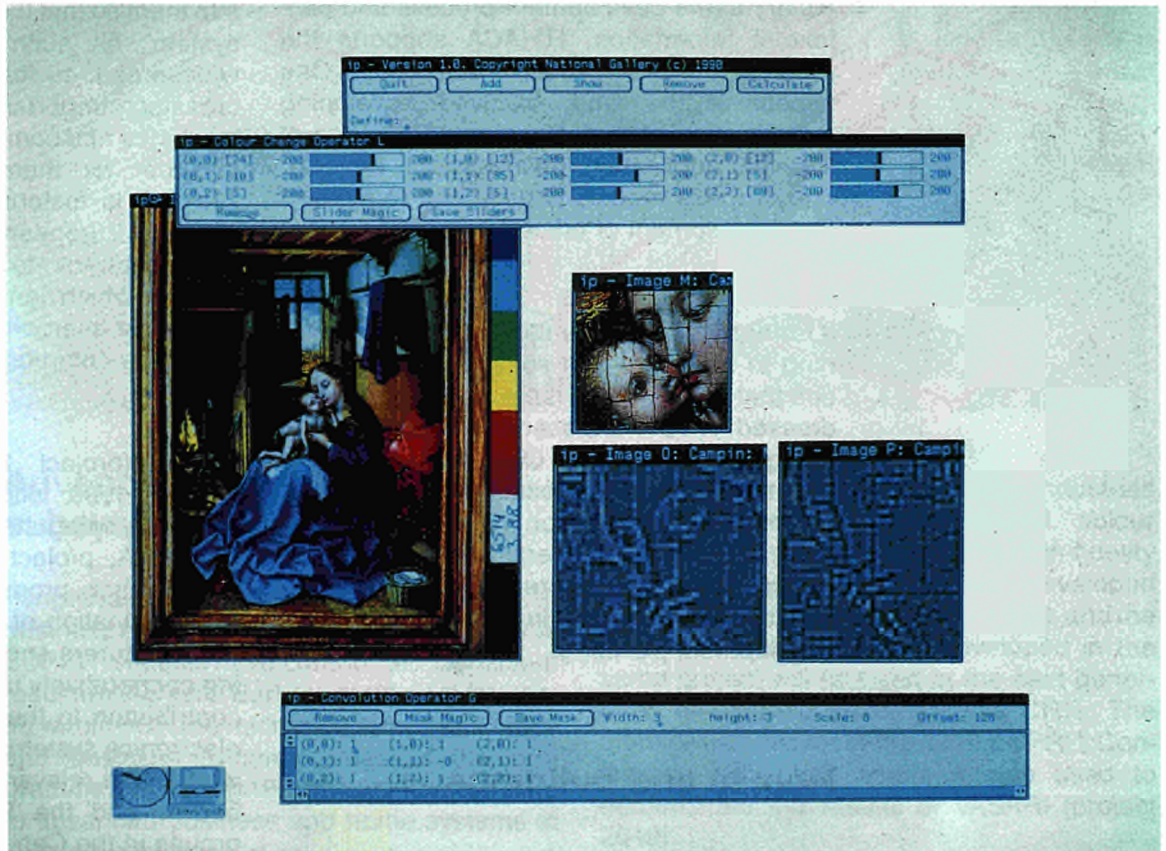
The uptake challenge

A recurring problem in the development of IT has been the relative lack of communication between suppliers and users. The work in ABHS-P has contributed to changing this situation by demonstrating the benefits of greater user involvement in IT projects. In many of the projects mentioned above a strong user orientation is apparent. For example, in TWB, Daimler-Benz is a user organization with a major technical translation requirement. In PONTIFEX, Alitalia is a partner and

strategy for exploiting IT. A prototype embodying a large proportion of the high-level knowledge-base was demonstrated at the 1990 ESPRIT Conference exhibition.

Definition of an overall IT strategy leads on to the process of system development. Here HECTOR (project 2082), building on several earlier projects, aims to develop concepts and tools for building organizational information systems. OISEAU, a prototype HECTOR system linking a system developer to a database of methods and tools, was

Great paintings live on screen: the VASARI system can capture images of delicate paintings (still in their frames) using a robotic scanner, and then analyse the craquelure, the network of fine cracks caused by the deterioration of pigment or varnish. The VASARI system is being used to monitor changes in works of art as they age or are subject to the rigours of exhibitions, and to apply computer-aided learning techniques to the field of art history, which requires the accurate reproduction of paintings on-screen. Applications foreseen in industry include paint manufacturing and food processing, where accurate colour-matching is important.



Iberia an associate. In RICHE, representatives from government and hospitals from all the Member States belong to a special interest group. And in VASARI, the National Gallery in London is a partner and the Direction des Musées de France an associate. In this way the Community's ESPRIT programme is fostering closer liaisons between IT providers and user organizations.

Beyond user involvement in R&D, attention to organizational factors can be an important element in the practical success of IT in an organization. Building on earlier work and integrating results from other fields, IT-USE (project 2144) is developing an IT awareness aid for high-level decision-makers, helping them to develop an appropriate organizational

demonstrated at the 1990 ESPRIT Conference exhibition. One partner is now developing this further for commercial exploitation, and another is developing a training tool based on the HECTOR reference framework.

An important part of the process of system definition and development is the analysis of the information flows that need to be supported and the system resources these require. A number of leading companies are now using OrgSolution, a commercial product developed from work in OSSAD (project 285).

Building the software required for an application is a complex and potentially costly activity. The process can be made more efficient if ap-

appropriate tools and generic models are available, with support for reusing concepts and software used in other application developments. A prototype software environment for building applications has been developed by ITHACA (projects 2121 and 2705), using an object-oriented approach, and is available on licence for evaluation purposes. Previous object-oriented approaches have supported the reusability of code, but ITHACA goes further: by providing easy access to objects together with information about the relationships among them, plus the history of the development process and contextual information, ITHACA supports the reusability of expertise as well as of code. One aspect of the work involved developing generic models that can support a range of specific application development projects; one of these models is designed to support the development of office applications.

It is important at all levels from strategic planning to hardware and software implementation that quality-of-life issues are properly addressed. A software scenario support tool is being developed within QLIS (project 5374) to help the IT industry forecast the likely impact of new IT applications on the quality of life at work and at home. Several large commercial organizations have already expressed interest in using this tool in their future product development planning.

Homes and buildings

IT will extend beyond the boundaries of businesses and public administrations into homes and intelligent buildings. The market in Europe and world-wide is enormous, taking account of both new homes and buildings and the retrofitting of those already built. Developments in Japan and the USA bear testimony to the interest which Europe's competitors have in taking a major share of this market. If European companies are to be able to compete effectively, they need to be taking action now to develop an agreed framework of standards within which competitive product developments can take place. The important advances made in ABHS-P have meant that European industry has moved in the past few years from lagging behind developments in Japan and the USA to its current leading posi-

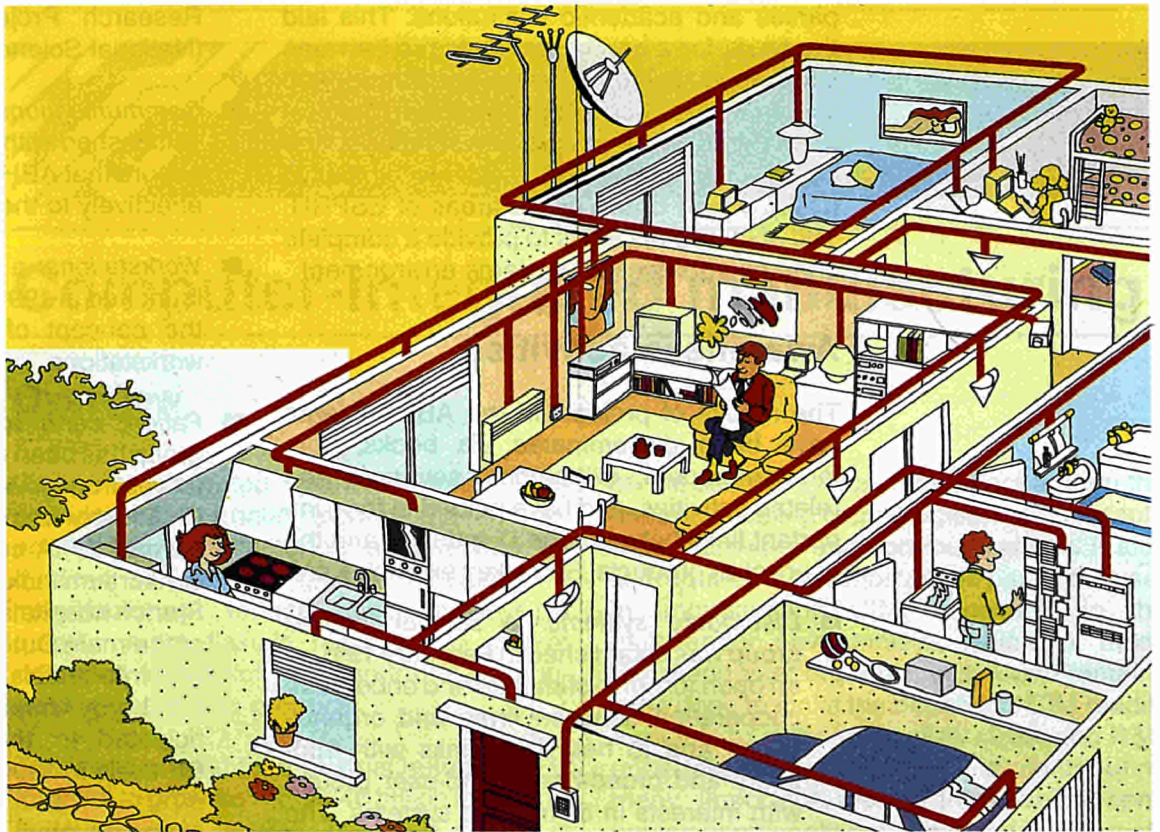
tion. The European approach is compatible with the Japanese D2B standard but is more complete and 'future-proof', providing a comprehensive standard for home systems now and in the future.

The European approach to home systems envisages a system in which intelligence is distributed throughout the home in areas of most concern to users, such as safety, comfort and entertainment. In such a system, many common household appliances and consumer products will have IT components built into them so that they can be connected to the system. As such systems become more widespread, so manufacturers will find it increasingly important to build the necessary intelligence and connectivity into their products in order for them to remain competitive. ABHS-P is fostering collaborative research amongst European companies that will allow manufacturers to develop products and systems which can be sold separately and yet can all be interconnected and work together through a common home system.

HOME (project 2431) was launched in January 1989, following earlier work on the EUREKA Integrated home systems project (EUREKA, project 84). The home systems specification, produced in HOME, represents the culmination of work involving 11 leading manufacturers and service companies working cooperatively under ESPRIT. It is a major contribution to the definition of world home electronics systems standards, including the work of the relevant ISO/IEC standardization bodies and the European standardization groups in the Cenelec organization.

Two complementary projects have been launched to carry the work further. These are Integrated interactive home (IIH, project 5448) and Home interactive environment (HIVE, project 5140). IIH consolidates the results of HOME and develops a media-independent architecture for the home network which takes into account the need to interwork with other systems. The project also addresses the conformance-testing and standards-validation aspects. HIVE provides the enabling technologies required to integrate products from different companies into a common system with an appropriate human interface. Other projects are researching related topics, such as electronic shopping (EUROSHOP, project 5346).

The integrated home: the home systems specification developed by HOME (project 2431) will enable many common household appliances and consumer products to be connected to a common communications system, as visualized here. Members of the HOME consortium have recently founded the European Home Systems Association (EHSA) to promote the harmonization and use of standards for homes and other buildings throughout the world.



Advanced peripheral subsystems

Peripherals are essential subsystems in business and home systems, and a number of ESPRIT projects have contributed significant results in this field. Early projects were launched within both the microelectronics and office and business systems areas of the programme, but during 1990 the work was moved to advanced business and home systems to improve coordination.

A topic of particular strategic importance for European R&D has been flat-panel displays. The projects FELICITA (2360) and MATRIX-LCD (2283) are currently working on this topic, whose significance arises from developments in HDTV and the growing market for low-cost, lightweight screens for aerospace and automotive applications. The first year's work in MATRIX-LCD has already led to a product announcement from Thomson LCD of full-colour liquid crystal displays for avionics. An interesting spin-off from FELICITA has been equipment for use in manufacturing layers of thin-film transistors in silicon.

Completed ESPRIT projects continue to influence the development of innovative Euro-

pean peripherals products. Barco Industries recently launched an advanced colour monitor, Calibrator, that uses the high-fidelity colour correction techniques developed within MODEL-DISPLAY (project 612), and the very high speed amplifier developed in the same project will be used in the next generation of high-resolution graphic CRTs. The monitor was shown at the 1990 ESPRIT Conference exhibition, where it was used to demonstrate the results of VASARI (project 2649).

Building strength in open microprocessor systems

Microprocessors form an essential and integral part of IT applications in areas ranging from cars to office workstations. As both the range and complexity of such applications increase, the need is growing for greater interoperability among the processors concerned and easier migration paths from one processor to another.

In recognition of this, a workshop on the theme of developing a competitive microprocessor systems environment for computers and embedded control was held in 1989, attended by representatives from more than 70 com-

panies and academic institutions. This laid the basis for a continuing dialogue between suppliers and potential users, and during 1990 a series of workshops defined the requirements for a major new initiative, the Open microprocessor systems initiative (OMI), which draws on all areas of ESPRIT. The objective of OMI is to provide a complete open microprocessor systems environment.

Awareness activities

The results of projects in the ABHS-P area have been disseminated via books, conference papers, exhibitions, seminars and related activities, and have helped to form important links between the IT industry and the users of its products. Some key examples are:

- *Distributed systems:* a special interest group was established in February 1991 as an open forum to stimulate and encourage cooperation between firms and organizations and to help form links with end-users and broad-based end-user groups with interests in distributed systems. The group operates on a programme which includes plenary meetings two or three times a year and meetings of topic-oriented workgroups.

As part of this initiative, and in response to interest from both European and US organizations, workshops were held in Brussels and Washington DC to discuss the technical achievements and industrial implications of the work on distributed systems, especially the achievements of ISA (project 2267) and COMANDOS (projects 834 and 2071). The workshops helped to identify areas in which collaboration between European and US organizations could be mutually beneficial, and established a basis for more detailed discussions with particular organizations, including DARPA (Defense Advanced

Research Projects Agency) and NSF (National Science Foundation).

- *Communications:* links have been established with the RACE programme to ensure that ABHS-P's work can contribute effectively to the goals of RACE.
- *Workstations:* a series of workshops was launched in 1991 to discuss and elaborate the concept of a 'family' of European workstations.
- *Patient care:* a RICHE special interest group has been established with representatives from government, hospitals and the IT industry from each Member State and several EFTA countries. Members of the consortium include STAF (representing 75 French hospitals), BAZIS (representing 35 of the main Dutch hospitals) and Lombardia Informatica (representing the main Lombardy hospitals). Over 80 people participated in the last meeting held in Brussels in 1990.
- *Home systems:* work done in ESPRIT has been a major stimulus to the formation of the new European Home Systems Association (EHSA) which aims to promote cooperation, standardization and harmonization and to ensure that standards are properly applied. The results of HOME (project 2431) were presented to the industry at a special conference in Amsterdam held in January 1991. A model home system covering 100 square metres (including four rooms) was demonstrated, and the full specification for a system complying with the home systems standard made available. Over 600 copies of this specification have been distributed to interested parties around Europe, and in the light of the interest expressed, it is now available as a book (published by Springer-Verlag).



Computer-integrated manufacturing

Overview

Computer-integrated manufacturing (CIM) provides the information technology (IT) needed by the manufacturing and service industries to achieve greater efficiency in manufacturing, reduce costs, achieve a quicker, more flexible response to market demands and exploit new opportunities for incorporating IT into products.

The world market for industrial automation is forecast to grow from ECU 46 billion in 1989 to ECU 79 billion in 1995. The R&D in CIM is helping European industry to achieve a significant share of that market, including the developing markets for products incorporating IT components and for the CIM hardware and software technologies themselves.

The manufacturing sector, supported by engineering industry, is the second-largest sector in the Community economy after the service sector, to which manufacturing operations make a substantial contribution. The cycle time from design to product, especially in the electronics sector, has become a key factor in the battle for markets. Together with the need for greater efficiency and a more flexible response to market requirements, demand has induced a steep rise in the IT-related portion of the unit cost of most products and capital goods. R&D carried out in CIM is helping European companies to compete effectively with American manufacturers, with their economies of scale, and with the Japanese and the newly industrialized countries of the Asian rim, whose capacity for innovation in the techniques and organization of manufacturing has put them in a strong position.

Computer-integrated manufacturing is typical of many engineering applications. It provides a stringent test-bed for the real-time control of physical processes. It places heavy demands

on the skills of system integrators and on the generic enabling technologies, including software, hardware and communications. It also still requires much effort on the part of the user in implementing CIM, especially in the multivendor environments typical of many European user organizations. Much remains to be done to make the benefits of CIM readily available to companies of all sizes, and R&D undertaken within ESPRIT is contributing many important results from which companies can benefit both now and in the years to come.

Opening up the manufacturing environment

In Western Europe and the USA, manufacturing companies spend considerable time and effort on integrating components from different suppliers. In recent years there has been a proliferation of computer-based design and manufacturing subsystems, but progress towards linking these subsystems to provide a cost-effective integrated solution to users' needs has been limited by incompatibilities of languages, data formats, protocols and communication methods between the products of different vendors. This area of integration is being approached through a number of major projects involving major Community equipment vendors and users. These projects exert a strong influence on international standardization, and lead to the provision of economical, customized multivendor systems that can be progressively implemented by enterprises of all sizes.

Improving competitiveness and productivity

Work in this area covers the design and validation of complete manufacturing systems in the

discrete parts, batch and process industries. The factors regarded as crucial to success differ from one industrial sector to another. In some cases it is the product innovation rate, while in others it may be plant productivity, total quality, process flexibility, or efficiency of supply or distribution channels which is considered the most important.

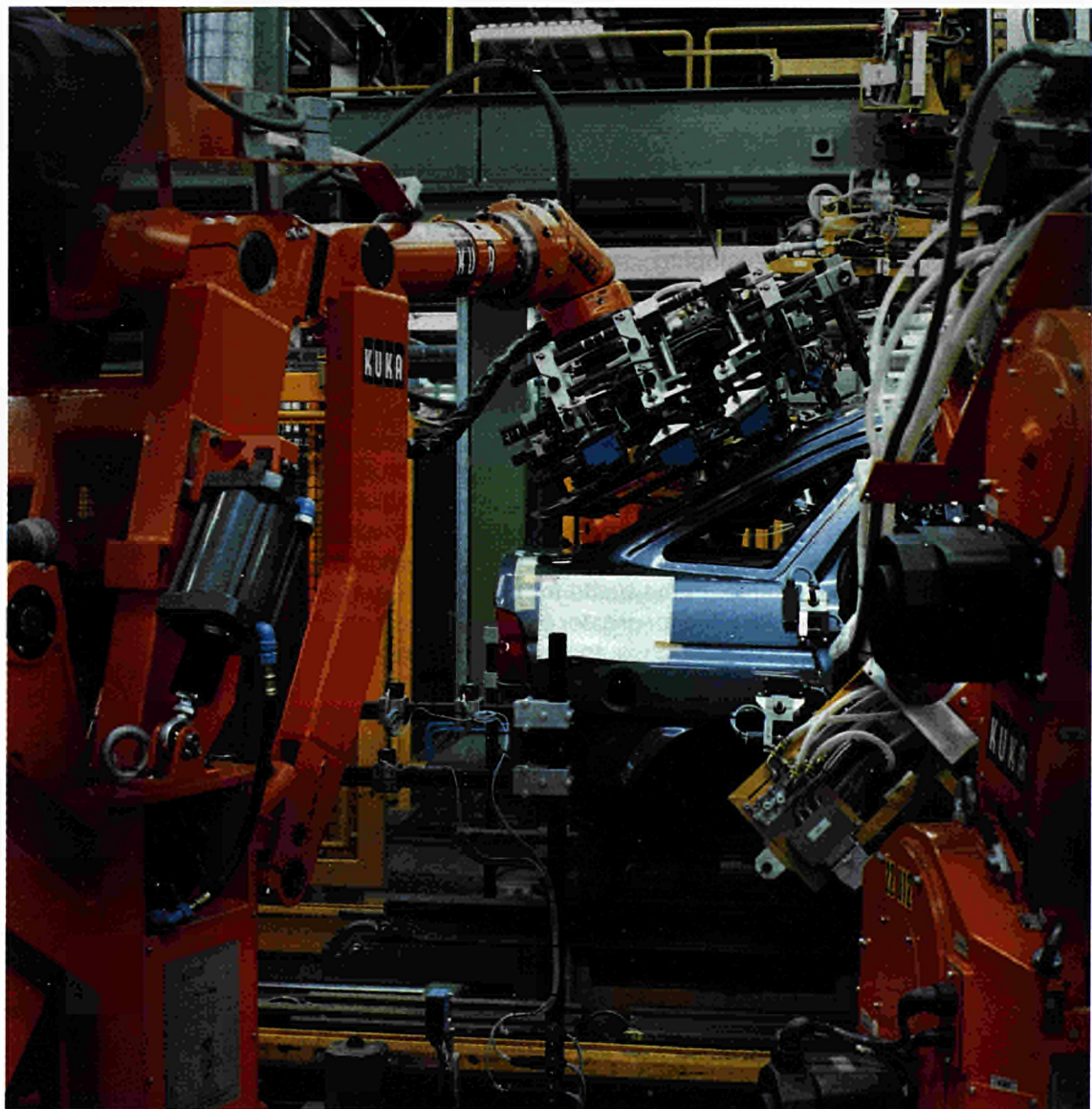
The objectives are to shorten the time needed to bring products to market, to improve quality, and to reduce costs. The IT components developed must be of an easily manageable size so that they can be assimilated into the integration strategy of a company and so that smaller companies are able to invest in the available technology in a step-by-step fashion. They must also conform to widely accepted architectural constraints as well as existing and emerging standards so that system

integrators can use them to assemble customized solutions meeting the requirements of particular users. As many of these technological developments have significant effects on the way people work and the skills they require, projects in this area give high priority to human and organizational factors.

Improving the end product

The engineering design process can be regarded as comprising requirements capture, design specification, analysis, evaluation and synthesis. The process needs to take account of external constraints such as those from production and marketing. It is iterative, draws on engineering judgement and experience, and is validated by testing. Infor-

Accurate calibration: shown here is a car moving along a factory assembly line, while a robot fits its rear window into place. Requiring the ability to position components precisely and reliably within tight space constraints, this kind of task requires robots to be recalibrated throughout their working life after any repairs or modification of the work-space. CAR (project 5220) and CIM SEARCH (project 5272) are developing the calibration tools and methods required.



mation technology today is applied most widely in the design specification activity, i.e. computer-aided design (CAD).

The other elements of the design process do not yet take full advantage of emerging IT. General modelling tools are required to integrate the information flow between the various levels of an engineering system. Apart from CAD applied to product design, this includes computer-aided engineering (CAE) for product analysis and evaluation, and process description techniques required for computer-aided manufacturing (CAM). There is also the need for subsets of information to be transferred from one activity to another. For example, the final results of a finite element analysis (an aspect of CAE) often need to be transferred to the user of a CAD system. The resultant design changes then often need to be transferred back to CAE for an iterative re-analysis. This can happen, for example, in car manufacturing, where a finite element analysis may show unacceptable stresses or strains on parts of the body, requiring that the design be modified. It is essential that this information transfer takes place rapidly if effective benefits are to be derived from the integration process. Modelling tools are required to enable information in the form of data, knowledge and procedures to be readily transferred between various distributed databases in the CIM system. This in turn requires attention to all aspects of standardization related to data transfer and communication.

Effective control of resources

To meet the changes in market demands and customer requirements, a manufacturing enterprise, be it large or small, must be able to respond and adapt quickly. Production planning, control and scheduling systems under development within ESPRIT, including quality control tools and systems for collecting and analysing process control statistics, allow the necessary flexibility by predicting manufacturing system throughput and highlighting potential problems. Effective use of such systems can reduce production lead-times, thus improving the economies of manufacture by reducing the amount of capital bound up in stocks and work in progress and allowing the accurate prediction of delivery dates.

Many manufacturing plants are already using early project results and show the power of advances in this area, such as developments in

just-in-time (JIT) manufacture and optimized production technology (OPT) techniques. Improved control structures enable increased flexibility, allowing, for example, a production line to be quickly and smoothly diverted to the production of a small batch of units with a particular variation (a higher-performance component, for example) and just as quickly and smoothly switched back to producing the standard product. IT systems can also help in tracking the life-history of product components, identifying where and when they were built, serviced, modified or repaired, so providing the information required for a high-quality after-sales service to customers during the lifetime of the product. R&D in CIM is also moving towards IT components which can help manufacturers achieve tighter coordination of multi-site, multi-supplier operations.

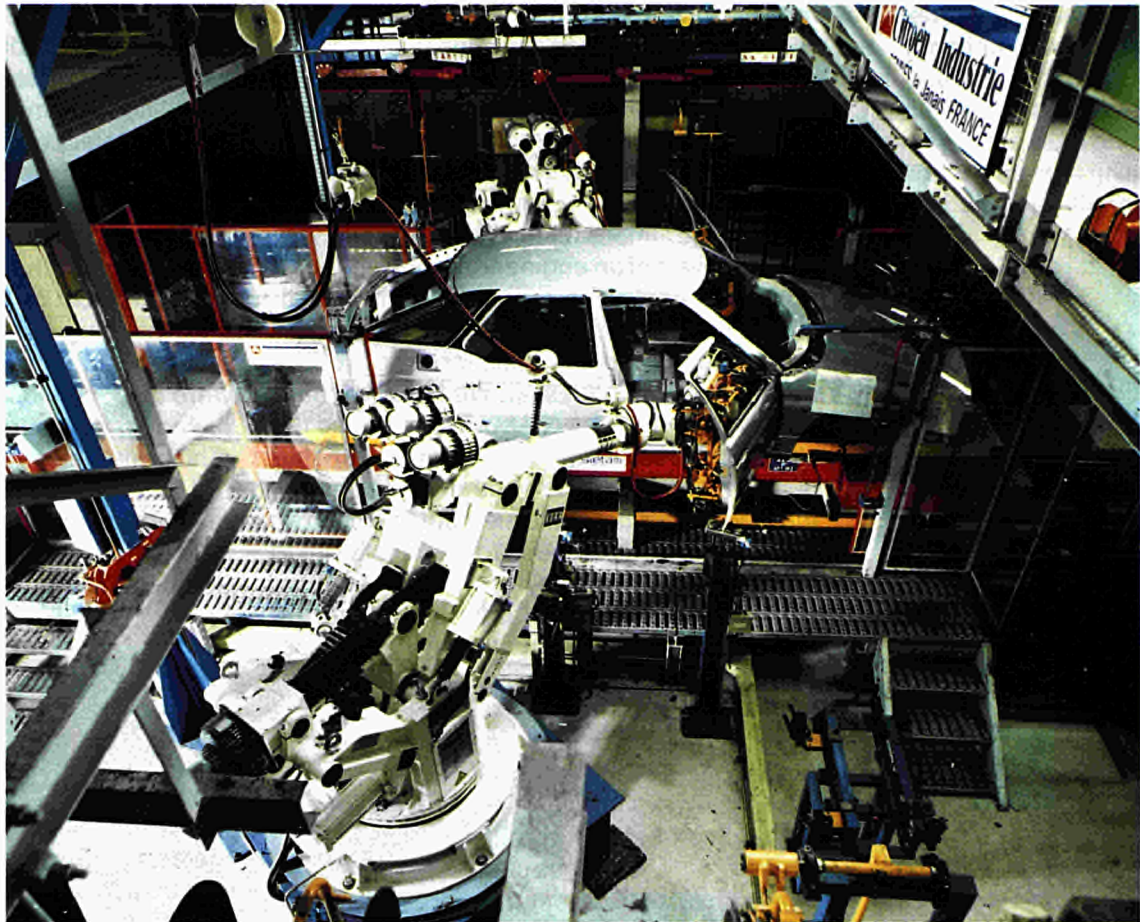
Making the product

Every manufacturing enterprise depends for its productivity not only on the skills of its workforce, but also on the supply of efficient equipment such as machine tools, robots, materials handling equipment, and sensors and actuators for process control. A common thread linking projects in this field is the multidisciplinary development approach, combining elements of control theory, mechanical engineering, the development of fast digital processors and the associated embedded software, and 'intelligent' sensors and actuators. This work has led to advances in machine and robot control, including fault diagnosis, and has improved the efficiency of robots on the factory floor for such applications as assembly, welding, paint-spraying and materials handling. It has also extended the use of robots into new application areas. For example, the ability to cope with unstructured and hazardous environments has led to projects which open the way to automating the transport of materials on building sites and in forestry and agricultural locations, open quarries, docks and warehouses. These areas need new intelligent machinery, such as harvesters, rock-drilling machines, construction equipment and large-area cleaning machines.

Architectures and communications

A prerequisite to enable full integration in a manufacturing environment is the ready

Advanced manipulation: the new generation of robots, off-line programming tools and a sensor-based robot controller developed in ARMS (project 2637) enables European industry to tackle the most sophisticated assembly operations, such as attaching the interior panel of a car door, shown here. The ARMS project has targeted several applications in the automotive and domestic appliance industries, including subcomponent assembly (doors, dashboards, front-ends), assembly of these components into vehicles, and the assembly of washing-machines, refrigerators and cookers.



availability of open systems with a functionality that gives maximum flexibility to users. In order to achieve this a number of projects have been supported that have contributed to both standardization and product development.

CIM architecture: European pre-standard established

In the consortium for AMICE (project 5288), 20 European organizations, research institutes, systems suppliers and system users are cooperating to define a CIM open systems architecture, CIM-OSA, building on earlier work in projects 688 and 2422. CIM-OSA aims to provide the infrastructure that will facilitate the increased use of IT industry-wide, and consists of a modelling framework for describing an enterprise's functionality, behaviour, information resources and organization in a consistent way. Emphasis is placed on providing the means for expressing the contents of a particular enterprise model in a user-oriented language. A key part of the implementation model is the Integrating infrastructure, dealing with the definition of the integrating services, such as communications, information,

machine and human front-ends, and the business process. In 1990/91 the validation of the basic concept was performed through case studies in the aerospace, automotive and electronics industries, a limited prototype demonstrating the use of the basic CIM-OSA construct has been developed, and a European pre-standard 'Enterprise modelling framework' (ENV 40 003) has been established and accepted as the current basis for standardization work by ISO TC 184.

Business communication for manufacturing chains

Where AMICE concentrates on modelling the inner workings of an industrial enterprise, CMSO (project 2277) focuses on inter-enterprise operations with the aim of developing methods, tools, interfaces and architectures that facilitate the exchange of technical and commercial data between independent organizations working together in a manufacturing or distribution environment. Particular emphasis is placed on solving the logistics problems that occur in the automotive industry. The project has developed an integrated EDI architecture and the CMSO-

BOX, which allows intelligent servers to be configured to handle the communication needs occurring in a logistics chain.

No manufacturing integration would be possible without a robust and reliable communications system based on standardized communications protocols. Following on from pilot installations at British Aerospace, BMW and Aeritalia, CNMA (project 2617), the flagship project in the field of factory communications, has successfully commissioned and demonstrated the use of CNMA communication in an automated manufacturing demonstration site at Universität Stuttgart. This links CAD, CAM and computer-aided planning (CAP) systems and equipment on the shop floor, and demonstrates network management and directory services. In parallel with the AMB machine-tool trade fair (Internationale Ausstellung für Metallbearbeitung), a conference was held in Stuttgart in September 1990 on communications in manufacturing, incorporating tutorials on Manufacturing message specification (MMS) and Network management and covering wider technical and business issues. A large number of visitors to the AMB fair took advantage of the opportunity to visit the CNMA demonstrator.

CNMA commissioned two further industrial pilots during 1990. The Aerospiale pilot is a prototype defence manufacturing facility, and the one at Renault a test laboratory and demonstrator for network management which is being used to develop and refine techniques for the use of artificial intelligence in Network management technology (NMT). Two conferences were held at the Renault pilot site in January 1991. Many presentations were given on CNMA Open systems interconnection (OSI) and Renault's Open systems approach. A conference was held in April 1991 by Magneti Marelli in Italy at which CNMA and Open systems were presented to an influential audience from the automobile industry. A further pilot at Magneti Marelli's alternator manufacturing facility in San Salvo is being commissioned. 1990 also saw the issue of a new implementation guide for CNMA (IG 4.1) replacing the previous IG 4.0 issued in 1989.

The market penetration of products based on CNMA will be largely dependent on the extent to which they conform to the emerging standards. The major activity of TT-CNMA (project 2292) in 1990 was the provision of test services at Universität Stuttgart to the partners of

the CNMA project. This activity provided a proving ground for exercising and evaluating the test technologies being developed by the TT-CNMA project partners. The justification for investing in test technology is to enable the efficient building of application systems components from different vendors which adhere to agreed open standards. The availability of test systems is a prerequisite for the establishment of an open systems world where both developers produce and users buy open systems products because they are both economically and technically superior to alternatives. The prototype test systems used at the university were interoperability test systems for Manufacturing message specification (MMS) and Network management (NM), and conformance test systems for MMS application interface (MMSI), MS, NM, and directory services.

As open systems technology develops, two further requirements are emerging: the need for computer assistance in producing test systems from protocol and profile specifications, and the need to make the test tools easy to use. The project has addressed both these needs, and TNC and Fraunhofer-IITB, the developers of lower and upper layer test tools respectively, have worked with Swedish Telecom to demonstrate that the process of producing and executing test suites for a particular protocol can be automated to a large degree. TNC, Fraunhofer and SPAG have begun specifying and implementing an improved human-interface to the test tools to make operation and assessment of test results easier.

As a response to the requirement for products with response times appropriate to the factory environment, ACERLI and Alcatel-TITN have initiated work on performance measurement. This is being followed up in the successor project to TT-CNMA, TT-CNMA II (project 5392).

Recognizing the wider use of a number of communications technologies, including token ring, Ethernet, X.25 and token bus, TNC have developed Router and MAC Bridge test systems to support the testing of interconnections among different kinds of network.

The activities associated with the pilot site at Universität Stuttgart have been followed by further enhancements. Where possible, the test suites have been enlarged and aligned with developing international standards. Experience and understanding of the testing of systems working together has been further

enlarged by the development of a second interoperability test system.

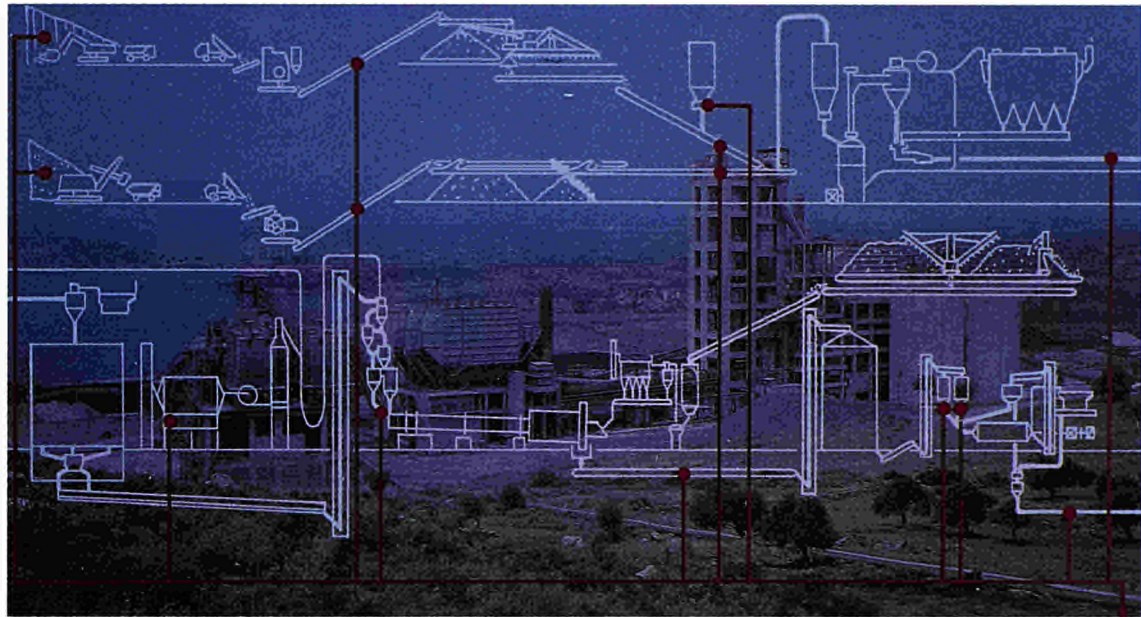
Mobile communications for manufacturing

The goal of FCPN (project 2198) is to specify, develop and test a prototype multi-service communication system based on mobile infra-red-linked terminals for indoor industrial applications. The system will particularly address the need for mobility and for reliable communications in all kinds of factories and for a wide variety of tasks. Specifications have led to an architecture description on which further developments will be based. As infra-red radiation and the appropriate link protocols have not yet been standardized, effort will be put into proposals for a universal infra-red

going on in other application areas, such as the process industries.

Many large and complex plants such as those dealing with cement, food-processing, car manufacturing, steelworks and tyre manufacturing, are controlled by distributed networks of programmable logic controllers. In such plants the operators exert control via interactive schematic diagrams. The design of the control system is a very labour-intensive engineering process and at present there is little scope for the reuse of standardized sub-systems. In addition, the designers are frequently forced to switch from one target controller to another in order to comply with the purchasing policy of their clients. DSCDIC (project 2588) is overcoming these difficulties by providing design engineers with a com-

Plant control: monitoring and controlling the Heracles Milaky cement plant in Greece is done via a schematic (the overlay) built up from the plant-wide signals of programmable logic controllers (PLCs). The PLCs sense material flows, temperature, pressure, etc., and can actuate processes and operations. Designing such distributed control systems needs general-purpose design tools, such as those developed in DSDIC (project 2588).



interface compatible with existing communication protocols.

Design and implementation of manufacturing systems

Traditionally, work on the application of IT in manufacturing has focused primarily on applications in factories producing discrete parts, and the effort has been driven by the needs of the people who design the end product and those who design and manage the manufacturing plant, including the supply of raw materials, subcomponents and other items. A considerable amount of work is now

mon platform for developing distributed programmable logic control (PLC) systems for different target machines. In close collaboration with FL Smidth (DK), one of the world's largest manufacturers of cement plants, AEG (D) and GEC (UK), together with Procos (DK) have agreed on the specification of a new development system to support work both in the design office and when commissioning on site. The user interface is complete, and a communication link to one of the target controllers (GEM 80) has been implemented under X11/UNIX. The other components of the design system are in progress and some of them are building on the reuse concepts and design reuse support facilities developed under the earlier ASPIS project (401).

Improved process control

Throughout the process industries there are increasingly heavy demands on the control systems employed. These must not only guarantee a high level of plant availability and profitability but also minimize environmental damage through controlling effluents and conserving energy. A major contribution to this effort is being made by DIAS (project 2172), which is developing new intelligent sensors and actuators, integrating them with a fast communications network and providing advanced tools for plant control, management and maintenance. A pre-industrial series of intelligent sensors is being manufactured for use in the project. Software for the specific applications and the field bus has been developed by Hartmann & Braun (D) and Bailey Esacontrol (I). The work is being validated at selected sections of three different plants. The engineering and installation at the nuclear power plant auxiliary steam generator at Electricité de France (EDF) at Le Havre is complete, and commissioning is in progress. Installation has begun at the ENEL fossil-fuel power plant, where the system is concerned with a high-pressure part of a regenerative cycle, and has also begun at three industrial polymerization reactors at the Montefibre chemical plant. The systems being installed have resulted from close collaboration between the users (EDF, EDP, and

Montefibre), instrumentation vendors (Hartmann & Braun, Bailey Esacontrol) and software companies (SEMA, MENTEC) involved.

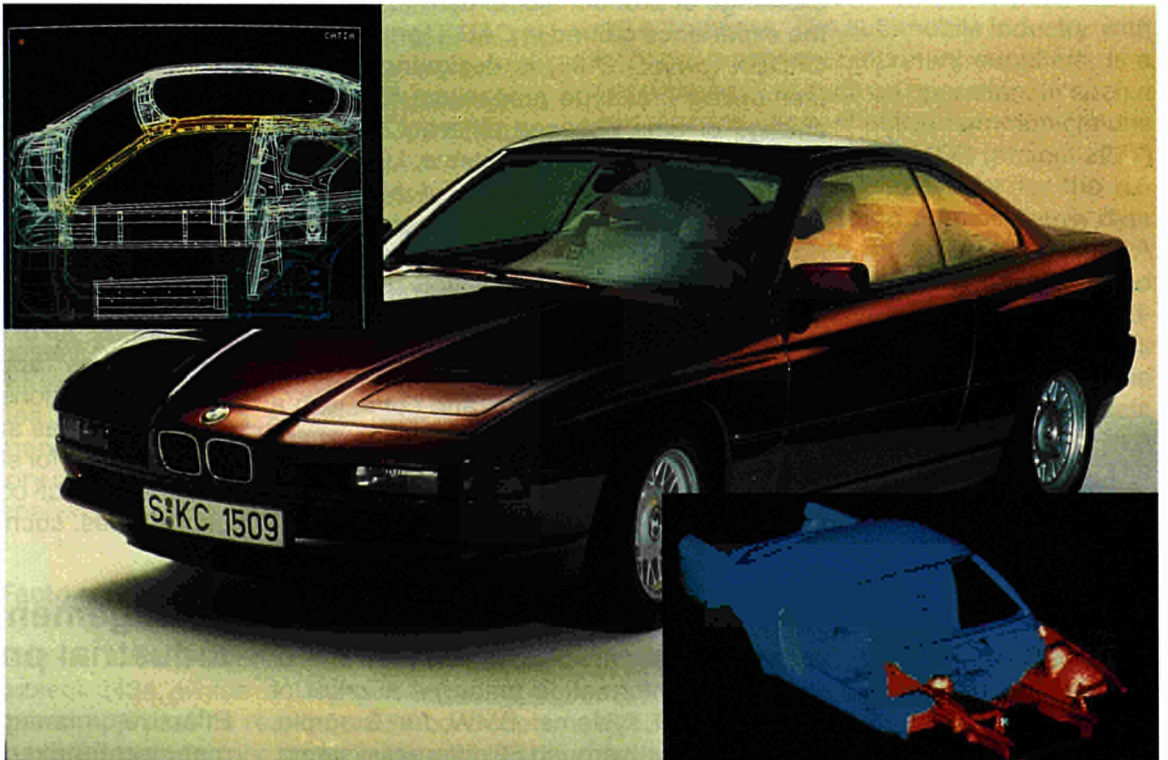
New applications

The building industry, in spite of its present complexity, fragmentation and sensitivity to economic conditions, is a prime target for applying IT as the best possible means of improving quality/cost ratios in the fields of building design and construction, maintenance and change of use. This can be achieved by using IT as the enabling technology which integrates the activities of those involved in building projects, including the client, the design and engineering unit, the supplier network and the construction site management. CIB, an exploratory action on computer-integrated building (action 5604), consisting of a coordinated set of 11 teams, has been established to examine requirements in this field. A working report has been produced which discusses the potential benefits of IT-based integration and defines possible lines of future action.

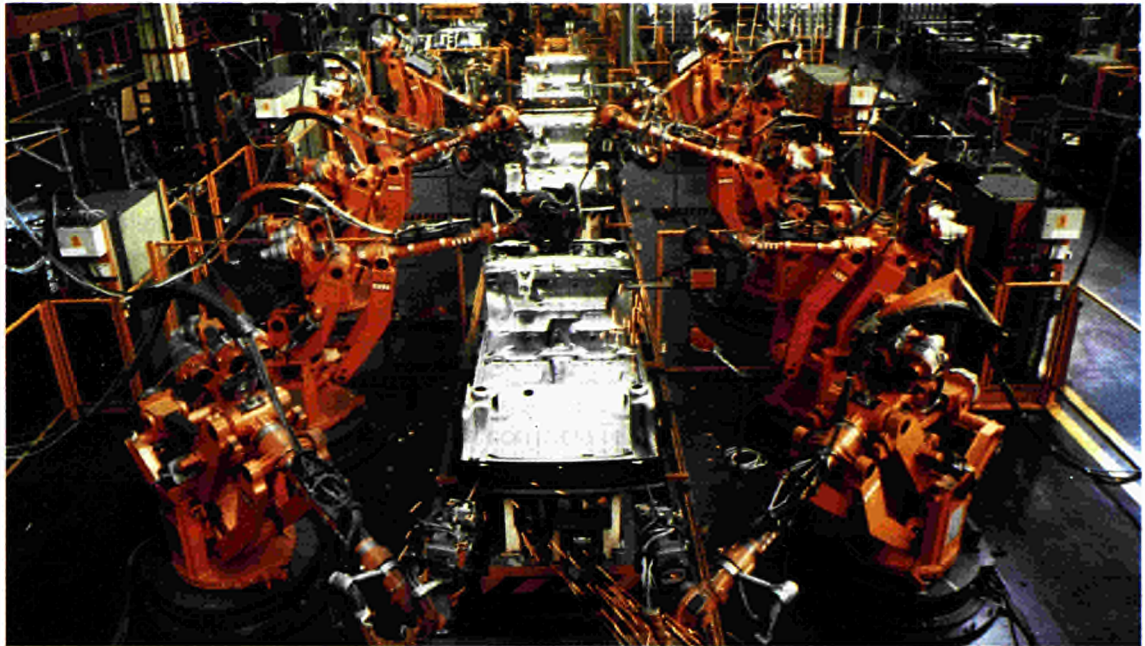
Engineering design

IT-based tools used by engineers for the design of products and manufacturing pro-

Design tasks: *the car's wire-frame representation (top left of picture) is used for stress analysis; the solid model (bottom right) for analysing interior spaces. CADEX (project 2195) has developed standards and protocols to enable the exchange of data between different representations of products and different modelling systems — for example, the data from the solid model describing the space available for headlights can be sent directly to the headlight supplier's own CAD system.*



Cooperating robots: shown are robots carrying out welding tasks in a car factory. Simulating the layout and job sequence for such robotized car-assembly lines allows a check to be made on whether a particular robot can carry out its programmed task. The main objective of CIM-PLATO (project 2202) is to develop the tools and components for planning the manufacturing process.



cesses are subject to two strong pressures. First, there is an ever-increasing demand to exchange electronically designed specifications and the data required for performing analysis and simulation. Second, there is a demand for more sophisticated tools which incorporate in their internal models a wide range of information on manufacturing, material properties and other aspects of the design context, far beyond that contained in simple CAD systems.

Based on the emerging ISO standard for the exchange of product model data (STEP) and the experience gained in CAD*I (project 322), CADEX (project 2195) is designing and implementing prototype processors for the exchange of data between different CAD and finite element modelling systems. Using well-defined STEP subsets, CADEX has developed application protocols for the exchange of the boundary representation and sculptured surface model descriptions widely used in the automotive and aerospace industries.

All CADEX processors are based on the same intermediate data structure, and come with a software toolbox that allows users to share independently developed software. The first STEP-based processor has been scheduled for launch on the European market before the end of 1991, and the CADEX project has already demonstrated prototypes at BMW and Fiat, where they are being used to help these consortium partners deal with the problems of exchanging information among a number of different CAD systems. BMW, for example, need to deal with around 60 different systems,

including those used by their approximately 350 suppliers. This type of problem is very common in the CAD world, and represents a major market opportunity. The world market for CAD/CAM software is forecast to grow from ECU 2 550 million in 1989 to ECU 5 160 million in 1993.

Within IMPACT (project 2165), integration is based on a new approach using 'features' at all stages of the manufacturing process. This allows semantic integration at the level of application software. This approach required the development of a global reference model, which is now under consideration for adoption by other ESPRIT projects. A further requirement was the development of a data manager system and a data manager interface, both of which have achieved international recognition. Improved functionality has been provided through two new combined solid and surface modellers, and also a new process planning system based on knowledge-based techniques. All of these have been based on the 'features' approach, and a number of small applications are now coming on the market, such as automatic numerical control programming for sheet-metal parts and for the manufacture of components with very complex shapes, such as a ship's propeller.

Management and control of industrial processes

Effective management and control of manufacturing resources can range from the

real-time monitoring of the behaviour of a single piece of machinery through to the scheduling of operations and logistics of a multi-site multi-supplier network of inter-connected manufacturers.

Integrated sensors

Integration of intelligent sensors and advanced control techniques is the objective of KB-MUSICA (project 2671). In addition to the development of new sensors, work on signal processing enables the extraction of more information about the process and the performance of the sensor itself. The technical and economic merits of using digital communication through a field bus are being evaluated, and knowledge-based systems for the process industry are being developed which reduce the down-time resulting from process defects and perform online fault detection, thus reducing costs resulting from damage to the plant as well as reducing the risks of accidents which might affect human life and the environment.

Different aspects of the project are being demonstrated at four sites: an ICI chemical plant, a Krupp plastic mould injection machine, an ENASA robot deburring system, and a Stephens glass-manufacturing furnace.

Special-purpose sensors have been developed for the Krupp demonstrator which measure the wall-thickness of plastic bottles and the temperature profile in the mould. The ICI demonstrator is using new sensors to detect atmospheric pollution. Mathematical models relying on multi-variable control have been developed for all demonstrators, and for the glass manufacturing application a prototype of a new furnace temperature controller has been designed and installed. Knowledge-based systems of varying degrees of complexity are now in use, including one which suggests process modifications based on measurement of the quality of the plastic bottles produced, and another which recommends to the plant operator in the glass factory optimal operating set points based on an analysis of online data from the factory floor.

Factory management

Control, but of a different nature, is the topic of project 2434, which is taking a knowledge-based approach to real-time CIM controllers for distributed factory supervision and is ad-

ressing manufacturing in small, medium and large batch sizes. The work has been validated by factory implementations in plants manufacturing products as diverse as car tyres and car radios. The large consortium, led by Philips Research Laboratory in Hamburg, has successfully completed a programme of work which is now resulting in products such as workcell and shop-floor controllers for dynamic scheduling, maintenance planning, quality management, a portable knowledge-acquisition module for factory use and a relative expert system shell specially designed for CIM applications. This latter development is being commercialized by ARS under the product name RES-D2, and a knowledge-based quality assurance package (Total quality assurance — TQA) together with the knowledge acquisition tool required for its maintenance (Knowledge acquisition quality — KAQ) are being commercialized by Pirelli Informatica.

Reducing production costs

The main objective of much of the effort in CIM is to provide IT-based components that can be used to reduce production costs by lowering stock levels, predicting and shortening lead times, and increasing the level of service. In several fields of manufacturing the end-product appears at the end of a complex supply chain that can also be regarded as a logistics network of independent but closely interworking enterprises. The automobile industry, with its huge range of component suppliers, is a good example of such an operation. In such a complex structure, effective communications are crucial for success. CMSO (project 2277) is providing the building blocks for the exchange of technical and administrative data throughout multi-site, multi-supplier chains. A logistics chain simulator has been completed and an implementation guide for the standardized tools and interfaces is available. Work is continuing on improved functionality of the management system for the exchange of data such as that required for quality control in a heterogeneous product development. The prototype installed at automobile component manufacturers Karmann and Lucas, partners in the consortium, is based on a generalized Electronic data interchange (EDI) communication system. The work is in line with the development of standards such as ODETTE and EDIFACT for administrative data and IGES and STEP for technical and product description data.

Robotics and shop-floor systems

The use of robotics in manufacturing has been steadily rising during the last decade. Work in CIM is helping European companies to develop a competitive edge in robotics in several key areas.

Calibration

Quality control in robot production, application of off-line programming techniques and demands for high accuracy of robots need robot calibration procedures (model-based parameter-identification methods using advanced measuring procedures). Using these procedures, internal parameters of the robot can be determined which cannot be measured directly. For example, where a robot is used for welding, the exact position of the tip of the tool used for welding (and therefore the spot that will actually be welded) has to be calculated from data concerning such matters as the angle and length of the robot's arm, the angle of rotation of the robot, and so on. Theoretically, the welding spot is exactly determined by such data. In practice, slight variations during the manufacture of each robot, combined with changes over time as the arm bends slightly or gears become worn, mean that the robot has to be calibrated. This calibration needs to be repeated from time-to-time if inferences are to remain accurate.

CAR (project 5220) is aimed at developing a prototype of an automatic system for robot calibration with the ability to identify the values of all the parameters that make a significant contribution to a robot's stationary accuracy, such as geometric-kinematic parameters, joint elasticity, backlash and eccentricity, and beam elasticity. The aim is to provide sufficient flexibility to allow calibration of various types of robots, and permit recalibration after robot repair and installation using a low-cost measuring system.

An industrial experimental set-up for calibration has already been assembled at KUKA and first trials performed. This is the first industrial installation of its kind in the world that gives a complete and accurate identification of both geometrical and mechanical features of a robot. The Leica company is preparing to market the calibration system. It has been presented to major companies in the German automotive industry, where it has generated great interest.

Interoperability in robotics

Closely linked to the project on data exchange between CAD systems, NIRO (projects 2614 and 5109) is developing a set of processors and software tools which will enable the configuration of multi-vendor robotic systems. Work done in the project will lead to improved and extended standards for kinematics, inclusion of robot-specific technological information, a robot-programming language and intermediate code for robot control units. The project has already contributed directly to the developing international standard STEP in the field of robot kinematics and has provided the draft proposal ISO DP 10303 Part 105.

Robot finishing: a niche market

While competition for more efficient and cheaper robots increases, new robot applications emerge and create niche markets. Robot finishing is considered to be a very attractive field because of the tremendous industrial needs and the numerous technological questions demanding urgent solutions. ICI (project 2640) was initiated by Zenon, a Greek engineering company specializing in industrial robot applications. The main objective of the project is to develop a robot cell capable of providing perfect finishing for castings and efficient visual inspection of their surfaces.

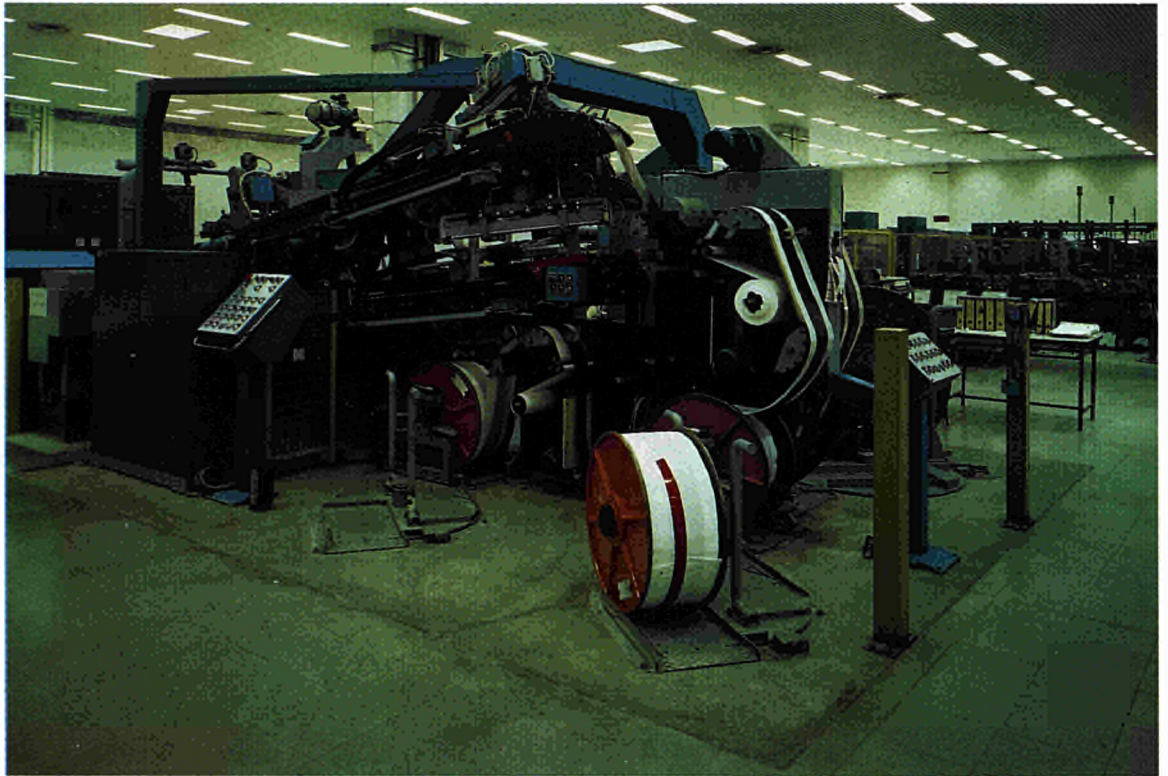
The project is addressing the two major problems encountered in the manufacture of casting-based products: the grinding process, which is extremely demanding in terms of dexterity and power, and the need for the inspection for post-polishing defects to be 100% reliable.

The replacement of manual work by robots has already been attempted by other machine tool manufacturers, and some robot-based systems are starting to appear on the market. However, the solutions are only partially satisfactory because of the limited range of shapes that can be handled and associated programming and operational difficulties. Inspection constitutes a serious production bottleneck for several manufacturers, and has not been dealt with satisfactorily until now.

The ICI project has undertaken a very thorough approach to finishing, polishing and inspection. The mathematical modelling of the grinding process led to strict definitions of the requirements for the tools. Combined with sophisticated parts surface analysis and off-

Factory supervision:

Pirelli's Bollate car-tyre factory requires a reliable quality assurance and inspection system to monitor the performance of equipment such as the tyre cord machine pictured here, and to automatically supply, 'just-in-time,' the components and raw materials needed throughout the factory. Project 2434 (on knowledge-based techniques for factory supervision) has enabled development of an expert system that could easily be tailored to this application.



line programming techniques, this permitted the design of a prototype (for Metalworks of At-tika SA) for polishing and finishing bathroom taps and sanitary fittings that is scheduled to be operational by September 1991.

Coupling robot grinding with automated visual inspection is an innovative step which, after two years of intensive research, has led to successful results. Advanced image-processing filters implemented on powerful specially designed parallel computing hardware today offer the possibility of visually inspecting a complete surface of a tap in less than a minute and of detecting defects as small as 0.1 mm. Project 2640 has made an important step towards opening up the difficult robot application area of finishing.

Autonomous robots

Situations often arise where it is necessary to carry out work in hazardous environments. Forestry, quarrying and mining provide examples. Such situations can also arise as a result of natural disasters (such as when transporting medical supplies or equipment to rescue teams after an earthquake). In these kinds of circumstances it would often be useful to be able to send in an unmanned vehicle that could find its own way across the terrain to where it was needed, avoiding obstacles and hazards on the way, and perform

the necessary work when it arrived without risk to human life. Such autonomous machines would allow work to be done faster and with less human risk.

PANORAMA (project 2483) has made a significant contribution to this area by producing a prototype autonomous vehicle fully equipped with actuators, perception and navigation sensors and computing hardware and software. This vehicle is now used as a project test-bed for tasks that need to be carried out in unstructured or hazardous environments. To date, the first versions of the following functions have been successfully tested: visual beacons detection, attention focusing, environment modelling, local path planning, localization, and piloting. The vehicle's features include the controlled actuation of steering, throttle and brakes, and it is also able to navigate autonomously outdoors on an industrial site while 'blind'.

The first integration of the on-board part of the PANORAMA system in the test-bed vehicle is planned for the end of 1991, and it is foreseen that the vehicle will perform autonomously in a complex environment by the beginning of 1992. This work lays the necessary basis for tackling more complicated scenarios, leading up to forest and open-mine environments by the end of 1993.

Another issue in the project is the computing hardware architecture which combines ad-

vantages of the well-known VME-based systems (for interfaces with sensors and actuators) and the high computing power potentialities of transputer-based architectures (parallelization of high-level processing for modelling, planning and decision-making processes), enabling the easy upgrading of system performance and a high degree of flexibility in development. This task involves particularly close collaboration among project partners.

Shop-floor vision systems

Sophisticated vision systems are not only required for guiding autonomous vehicles and robot grippers, but are also needed in other shop-floor operations. They form the link between CAD/CAM and automated inspection and assembly systems. This is well demonstrated in two projects. In the field of printed-circuit board manufacturing, TRIOS (project 2017), led by Siemens, uses advanced laser technology to solve the problem of achieving fast, 3D high-resolution high-speed data acquisition that is independent of the surface condition of the work-piece. One of the first and outstanding results of the project was a ranking filter for real-time 3D data processing on a single chip. Its use has been

validated in test-beds for the inspection of patterns on high-density printed-circuit boards and for the assembly of populated boards. In the field of complex mechanical parts, VIMP (project 2091) compares images from an online vision system with those derived from a CAD system to provide a much more reliable and faster assessment of quality than can be achieved with conventional methods using mechanical measurements.

Materials tracking

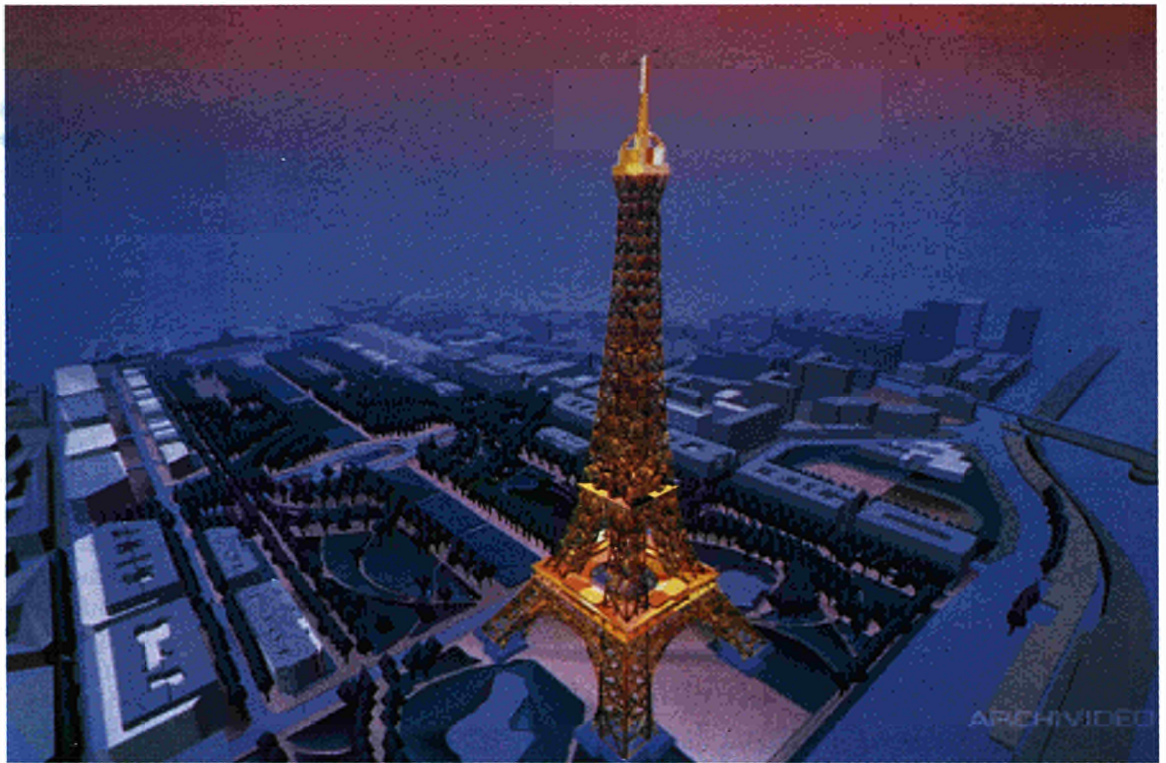
The tracking of goods and materials in an industrial environment is the aim of HIDCIM (project 2127). The system is based on computer-generated holographic tags which can store up to 1 kbit of information on a 3 x 3 mm tag that is easily attached to equipment or work-pieces. Compared with available techniques this represents a very high density of information.

The tags, which are small pieces of the 'digital paper' developed by the chemical company ICI (UK), are coated to protect them from dirt and scratches. The optical read/write process makes them immune to electrical interference. They can be attached to the components of a product (for example, the parts of

Autonomous robots: this unmanned car is a test-bed for the integrated sensors and scene-recognition systems developed in PANORAMA (project 2483). Navigational decisions are made by the knowledge-based processing of various sensorial inputs and by using a satellite-based global positioning system. The results of the project are expected to be incorporated into vehicles capable of carrying out a range of hazardous mining, quarrying, forestry, agricultural and inspection tasks in an autonomous fashion.



Transputer power: *the transputer-based system employed by Capton, a partner in VIMP (project 2091), can generate sophisticated simulations such as the one shown here. The VIMP approach to inspecting manufactured parts involves comparing an online image of the workpiece with an image generated from data stored in the manufacturer's CAD system. The 3-D data stored is transformed into a 2-D projection corresponding to the angle of view of the image sensor.*



a car, refrigerator or television set) or to a machine tool in order to provide a history of its manufacture and servicing. The tags can only be written to once, but as they are very inexpensive, it is entirely feasible to update a tag by simply replacing it with an updated version.

The 'digital paper' medium consists of an optically active dye polymer which is coated onto a metallized polyester base. The data points are recorded by a focused infra-red laser beam without any chemical post-processing. Information retrieval is done by illuminating the 'holotag' with a laser diode and reconstructing the 2D bit-pattern with a Fourier transform lens.

The reading station is very simple, based on a standard charge-coupled device camera connected to a computer. The camera can read a tag from up to 50 cm away, and the reading process is tolerant of mechanical vibration and largely unaffected by dust and scratches, due to the coating on the tag and the redundancy of the holographic storage technique.

At present, tags are written to under laboratory conditions, and work is in progress on developing a writing station that can be used in normal factory or other environments. A prototype demonstration has been set up at the machine tool manufacturer, Mandelli, where alpha-numeric information used to tag tool carriers is supplied by a CIM network. The

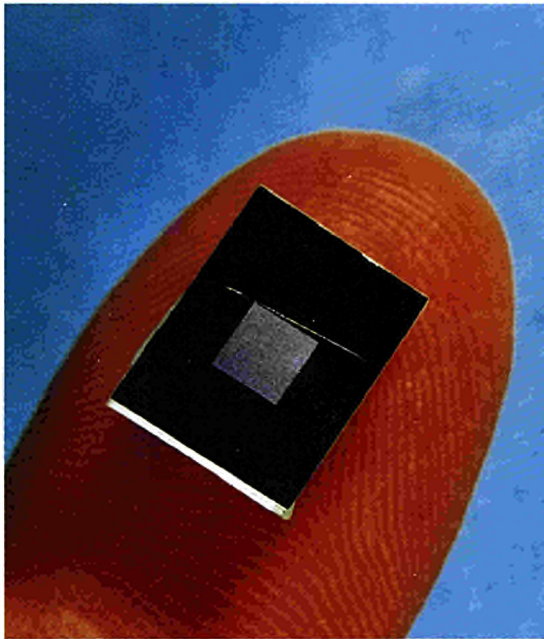
tags ensure that the correct tools are used for the applications concerned.

Application awareness and technology transfer

Under the banner of CIM-Europe, a wide range of activities are carried out each year in order to familiarize workers in the area of CIM with developments outside their own projects, and to disseminate to a wider audience information on results which have been achieved, particularly potential end-users of the new technologies. The largest of these events is the annual CIM Conference, the sixth of which was held in May 1990 in Lisbon and the seventh, in May 1991, in Turin. Changing the venue stimulates the active participation of local industry, and the site visits to manufacturing plants have become a popular and enlightening feature of the conference programme.

In addition, there are regular meetings of special interest groups on topics such as human factors, field bus, and model-based predictive control. Workshops are also held which focus either on the main topic of interest of a project, such as the IMPACT (project 2165) workshop on 'Product modelling', or concentrate on a subject, such as 'CIM in Pro-

Digital paper: a holographic image is stored on this cheap, disposable 'digital paper' tag, 3 mm square, developed in HIDCIM (project 2127) for tracking equipment and workpieces. The information on a tag is read by a special camera connected to a decoding computer, and is unaffected by factory dirt or electrical interference.



cess industries' or 'Mechatronics and robotics', which serves as a link between several projects. The conference and workshop proceedings are published in order to disseminate information on the progress reported to as wide an audience as possible.

A more basic form of technology transfer is under way in MICIM (project 2706). The MICIM team are applying a number of ESPRIT CIM results in real factory environments ranging from the manufacture of electronic components (Philips PCB manufacturing plant) to electromechanical components (Carlo Gavazzi). The experience gained is being packaged as a training methodology for provision to other teams finding themselves in similar situations. Along with a number of other issues, they are addressing the application of the CIM-OSA methodology and implementation of data-exchange mechanisms between previously incompatible CAD systems.



Basic research

Overview

Continual technological innovation is essential to maintain and strengthen the global competitiveness of Europe's IT industry, and the ESPRIT Basic research actions have been instrumental in providing the underlying knowledge and expertise needed to create future breakthroughs. A Europe-wide community of advanced research in IT has been established, and closer collaboration fostered between the academic community and advanced industrial research centres.

Actions in Basic research aim to promote collaborative research in areas with the potential to produce future advances and breakthroughs relevant to the long-term goals of the European IT industry and its users. The areas selected are upstream of industrial R&D and clearly capable of benefiting from collaborative fundamental research on a European scale. These selection criteria are particularly applicable to large-scale research efforts, often interdisciplinary, that would be too ambitious for individual teams to undertake.

As a result of the original call for proposals in 1989, 61 actions and 13 working groups were selected that focus on a range of key areas including superconductivity, optical computing, design methodology for integrated circuits, logic programming, concurrency, databases, knowledge representation, computer vision, neural networks and robotics. About 75% of participants in Basic research actions are newcomers to the ESPRIT programme and represent a net gain in the contribution made by the fundamental research community to the European IT industry's overall R&D effort. The transfer and uptake of results is being ensured by links to industry sector activities (through open workshops and the involvement of industrial participants in reviewing Basic research actions) and by direct involvement (over a quarter of the actions have industrial participants, and the proportion is

rising as the work undertaken matures). In addition, 'Networks of excellence' have been conceived and set up to reinforce and further develop the strong patterns of cooperation that have been emerging between teams of researchers.

Networks of excellence foster collaborative research

A Network of excellence is a grouping of research teams sharing common long-term technological goals and closely coordinating their research and training activities. In principle, a Network of excellence is open to all organizations working towards the same goals, wherever in Europe they may be, though the research teams constituting the 'nodes' of a network (based in a research centre, academic department or industrial laboratory) must collectively possess a critical mass of top-level experts, skills in all the disciplines required to attain the objectives set, and state-of-the-art facilities.

Three Networks of excellence were launched early in 1991 in exploratory one-year phases. These three pilot networks have clear technological goals in the areas of Language and speech (Network 3701), Distributed computer systems architectures (Network 3702) and Computational logic (Network 3703). They are expanding rapidly from a limited base of founder-members — the Computational logic network alone now has over 50 participants. It is expected that valuable insights will be gained during this exploratory period into the best way of operating future networks.

Typically, the participating institutions define a strategy for the achievement of their common technological goals and devise a framework within which projects undertaken by different

members can fit. In addition, Networks of excellence take measures such as promoting the mobility of researchers, designing curricula and interdisciplinary course material, acting as clearing houses for research results, and promoting exchanges of staff with industry so as to foster training and technology transfer. All these contribute to their goals.

The close links between the nodes of a Network of excellence mean that access to any one node gives access to the resources of the entire network — interdisciplinary know-how, special skills, or material resources. Such accessibility has favourable implications for human resource development, the cohesion of Europe, and, in particular, for technology transfer and industrial innovation: instead of having to develop a working relationship with several research centres, a firm need only contact one node of the network to gain access to the expertise of them all.

The distributed nature of Networks of excellence also helps ensure that 'excellence' is not drained away from regions with less well-established technological traditions. In such regions viable nodes of European networks can be found, even if establishing self-sustained 'centres of excellence' would be unrealistic. Local industry can easily obtain the most advanced research results, and the local research community gains access to wider industrial markets.

The collective strength of a Network of excellence is expected to attract doctoral and post-doctoral students to spend part of their research time in different nodes. This will help provide the interdisciplinary skills that Europe needs. The majority of researchers trained in this way are expected to find a future in industry as sorely needed systems engineers — people with a complete view of a technology's development from conception through to implementation.

Another Basic research initiative, the VLSI design action, has made excellent progress in remedying a particular skills shortage: the ability to design VLSI circuits.

VLSI design action exceeds training targets

During 1990, EUROCHIP, the service organization for the ESPRIT VLSI design action (3700), entered its first full year of oper-

ation. The launch of the action was prompted by an acute shortage of VLSI designers within the Community, a shortage that has limited the use of advanced microelectronic technologies in a number of industrial sectors and particularly their take-up by SMEs (small and medium-sized enterprises). On current estimates at least an additional 3 000 students a year, besides the present 1 500, need to be trained in the necessary skills. The main obstacle to training which the action addresses is access to silicon and the resources and facilities required to make good use of this (such as workstations, computer-aided design (CAD) software, testers and trainers). 200 academic institutions are now involved: 60 receive support for their own design training facilities (including lecturer posts, CAD software and access to industrial fabrication facilities); a further 60 have been provided with free access to fabrication facilities, and, attracted by the advantages of the service, an additional 80 institutions are taking part at their own expense.

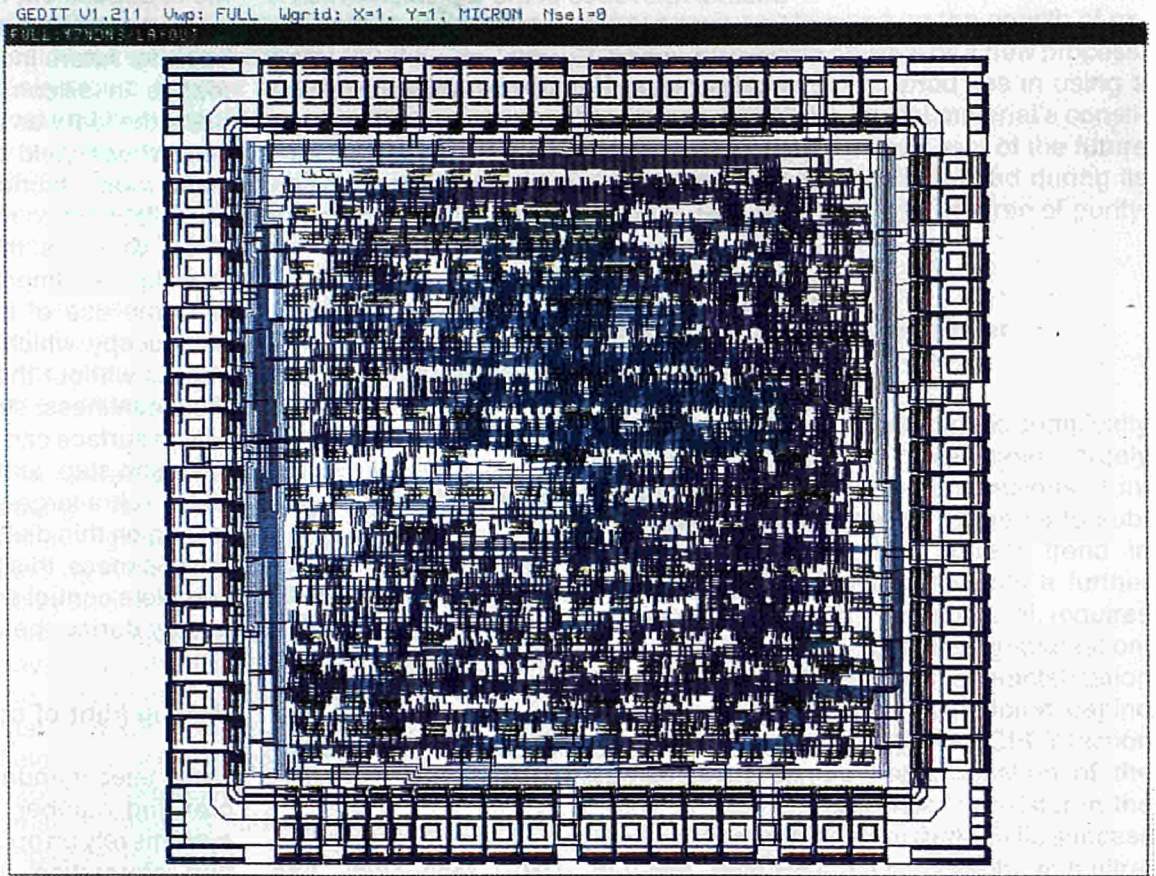
These participating institutions are supported by the central service organization, EUROCHIP, composed of five eminent research institutes from different Member States, that handles negotiations on their behalf with the suppliers of hardware, software and fabrication facilities. Strategic guidance is provided by a steering board drawn from industry and academia.

To date, 900 CAD software packages have been installed under the EUROCHIP agreement, and training in the use of CAD software has been completed for around 320 academic instructors. Some 80 workstations and IC (integrated circuit) testers have been provided to selected participating institutions, and a further 300 workstations have been bought by institutions at their own expense.

Fabrication contracts with five European foundries are now in place, and several fabrication routes (particular set-ups of manufacturing procedures) are in regular service. These include digital and analogue CMOS, advanced CMOS for complex digital designs, GaAs for monolithic microwave integrated circuits, and BiCMOS technologies on chips, wafers and ICs.

The VLSI design action has already enabled approximately 300 courses to be held, providing a total of around 700 000 student course-hours and resulting in the design of more than 350 VLSI chips, of which 200 have

VLSI design training: a graphical representation of the design layout for a microelectronic circuit, as seen by the designer on a workstation. The design shown contains the control and processing units, the interface control and the memory manager for an asynchronous digital neural network. Created by a student of the Universidad Autonoma de Barcelona participating in the VLSI design training action (3700), the chip was manufactured by ES2 as part of the second EUROCHIP fabrication run.



been fabricated and 120 tested. More than 5 000 students have been trained in the first full year of operation, a total which actually exceeds the action's original objective of tripling the number of trainees from 1 500 to 4 500 per year.

Research actions contribute to industrial innovation

All research actions have now completed their first 18 months of activity, and there is already evidence of their impact on the European IT research scene:

- ESPRIT Basic research has quickly gained momentum and generated considerable enthusiasm in the IT research community. One indication of this is the increasing number of researchers applying to join or become associated with existing actions, often without requesting additional funding.
- In addition to a large number of joint publications by researchers, it is becoming increasingly evident that strong cooperation mechanisms (in addition to the Net-

works of excellence described above) have been put in place throughout Europe to tackle difficult problems, integrate related approaches and bring together the different disciplines required.

- Evaluations by independent reviewers have identified a number of developments and results with clear industrial significance. Indeed, several industrial projects have already incorporated ideas and approaches consolidated during the first year of the ESPRIT Basic research activity.
- A survey of the current state of research actions shows the effect on training. An estimated 30% of Basic research funds (excluding the VLSI design training action described earlier) go to support doctoral and post-doctoral researchers, while at the same time putting their training to immediately useful ends. Moreover, it is estimated that about 1 000 doctoral theses are currently being prepared that are directly related to Basic research actions.
- The enthusiasm generated by ESPRIT Basic research, as well as the perceived in-

dustrial relevance of the topics on which it focuses, has stimulated very active interest outside Europe as well. A good number of researchers who were pursuing careers in the USA, Japan and other parts of the world have been recruited by participants in Basic research actions, reversing part of the 'brain-drain' from Europe of researchers in IT R&D.

Several significant results have already been produced by Basic research actions, and highlights from the main areas of activity are described below.

Novel techniques improve device performance

The research carried out in advanced materials processing and basic device characteristics is aimed at the realization of novel materials with electronic and optical characteristics that increase the yield and enhance the performance of integrated circuits and other components.

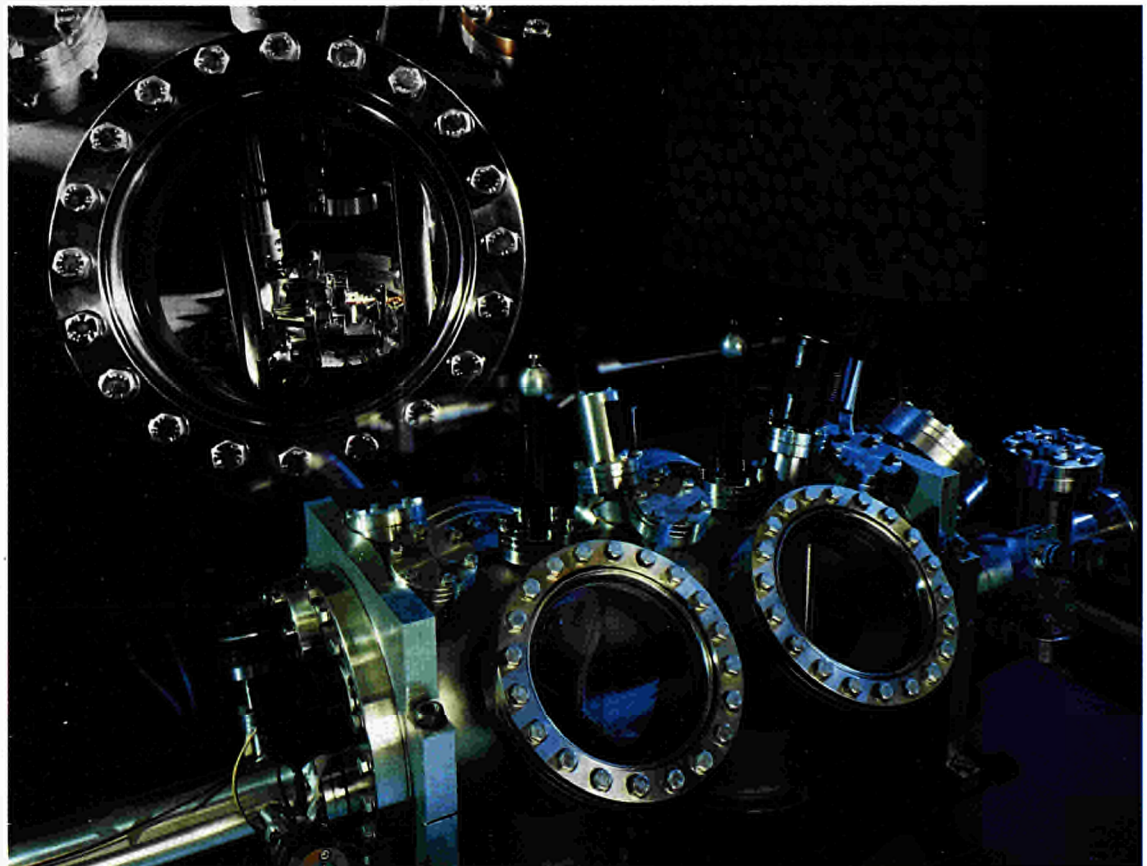
A research-scale linear cluster tool based on ultra-high vacuum (UHV) technology has been built by the members of PROMPT (Action 3109). This contains a station for UHV

metal deposition, ultra-dry oxidation and ion-beam sputtering, and promises to provide a basis for future increases in yield and performance in silicon fabrication. During initial trials, the tool was used to fabricate MOS test-sets whose yield equals that of established clean-room fabrication methods (conventional fabrication techniques are optimized at 90%, which is the starting point for UHV techniques). Improved quality has resulted from the use of *in situ* scanning tunnelling microscopy, which permits a range of quality checks without the vacuum being broken — the cleanliness, structure and flatness of the silicon surface can now be verified, prior to the oxidation step, at the atomic level. For future ULSI (ultra-large-scale integrated) devices relying on thin dielectric layers of less than 10 nm thickness, this kind of processing will give complete control and hence a higher assured quality during the crucial oxidation process.

Making light of communications

Many telecommunication systems and an increasing number of information processing systems rely on optical processes for transmitting information. To date, no optoelectronic components have been devised that can be manufactured using silicon technology. New

MOS structures: a research-scale linear cluster tool for ultra-high vacuum (UHV) semiconductor processing has been built by PROMPT (action 3109). The ion beam scattering, residual gas analysis and scanning tunnelling microscopy (STM) facilities fitted allow all stages of the oxidation step to be controlled. Shown is part of the apparatus, the integrated STM, and a clean silicon surface prepared for UHV processing.



materials with optical characteristics that allow the direct coupling of silicon chips to optical fibres would enable the production of optoelectronic devices of better quality, lower cost and higher performance, and enormously simplify the wider use of optical devices. HESSILSIL (action 3026) has developed a new material in thin-film form (FeSi_2 in its semiconducting phase) with the necessary characteristics plus the ability to produce luminescence of the wavelength required. A collaboration with Philips Research Laboratories was arranged to transfer the research results to an industrial environment.

The overall goal of research in optical computing is to develop concepts and technologies for improving information processing in areas, such as electromagnetically noisy environments, which pose difficulties for electronic systems. With the specific aim of developing the field of optical logic processing, new parallel non-linear optical processing methods for coding information into laser fields are being researched in TOPP (action 3260). A prototype system for recognizing small numbers of patterns has recently been implemented in collaboration with Alina/Alitalia (I). Research has also focused on the reduction of quantum noise in light beams. NOROS (action 3186) aims to use optoelectronic and non-linear optical devices to reduce the noise caused by the corpuscular nature of light. Before the action started, the best results achieved — noise reduction factors of up to 60% — were not good enough for practical applications. NOROS has achieved a world-record 90% noise reduction, making possible applications in the area of secure optical communications, as recently demonstrated by the Defence Research Agency (UK), a partner in the consortium.

Superconductivity

The discovery of high-temperature superconductivity in oxide compounds has led to the formulation of a large number of theories to explain the mechanism involved, though none of the models that have so far emerged has become a commonly accepted basis for explaining the phenomenon. The problem largely stems from a lack of experimental data (inelastic neutron scattering data in particular), and here research into materials preparation and characterization is a key issue. Good progress in this area has been

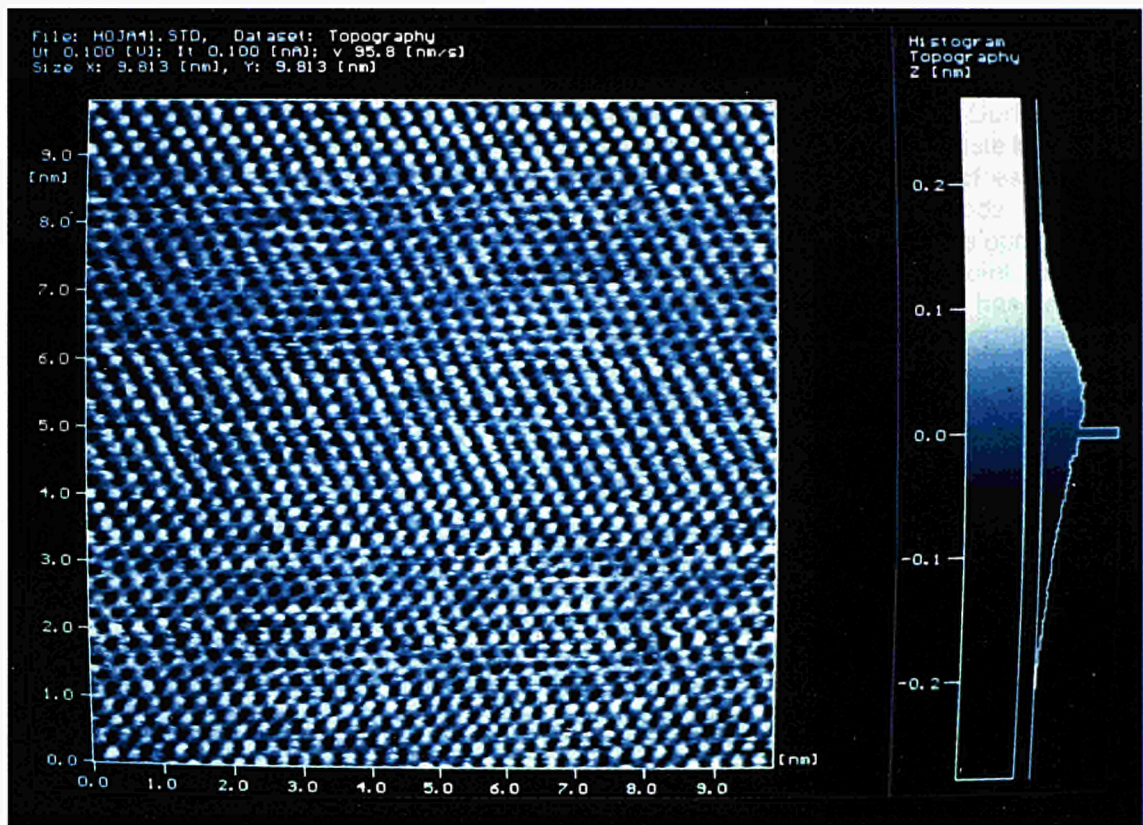
achieved in SUPRADYNAMICS (action 3327), where work has focused on the growth of extremely pure single crystals by a new process. The originality of the method lies in using a container to melt the crystal material's constituents that is itself a component of the future crystal and is therefore consumed during its growth. This ensures a high degree of purity.

Nanotechnology and molecular electronics

Increased levels of integration and complexity in integrated circuits have been largely achieved by shrinking the dimensions of individual semiconductor components to sub-micron dimensions. The current trend in microelectronics, pointing towards a further scaling-down to the nanometre level, requires new advances in growth, implantation, lithography, etching and characterization techniques, and is the driving-force behind the new 'nanotechnology'. NANOFET (action 3042) has achieved the fabrication of the smallest working field-effect transistor in the world (25 nm gate-length) through its success in using electron-beam lithography with ultra-submicron precision. By applying the same technique, the fastest pseudomorphic transistors ever made in Europe have been manufactured on pseudomorphic delta-doped AlGaAs/InGaAs epitaxial layers with current gain cut-off frequencies exceeding 170 GHz at room temperature.

The molecular electronics approach to fabricating ultra-small electronic components is to synthesize molecules that can be reliably switched between different states and then be assembled into structures that can store data and process it in predictable ways. A variety of such molecules have been designed and synthesized in the past 18 months by MOLSWITCH (action 3314) and OLDS (action 3200). Outstanding work has also been carried out on the modelling, synthesis and physical characteristics of conducting molecular crystals by MOLCOM (action 3121). In addition, a new technique, scanning near-field optical microscopy, has been developed in the OLDS action to enable the characterization of the thin-film molecular assemblies designed and prepared by this consortium. The technology is being commercially developed by a consortium partner, Helmut Hund GmbH (D).

Molecular electronics: OLDS (action 3200) has developed scanning near-field optical microscopy and scanning tunnelling microscopy (STM) as new tools for storing and retrieving information at the nanometre scale. Shown is the atomically resolved structure of a Langmuir-Blodgett film and, on the right of the screen, an analysis of its topography. OLDS is studying two kinds of organic molecules: conjugated (i.e. those with electron transport properties) to be used for molecular 'wiring', and lipid molecules (i.e. those with defined dipole moments) for representing information.



The reliability of circuits fabricated with sub-micron devices is an important problem-area for designers of advanced microelectronics components. The limitations in the performance of submicron devices caused by noise are under investigation by NOISE (action 3017). It had been assumed that the performance of circuits could be improved by cooling them to very low temperatures. However, an important result from NOISE is the discovery that the ageing of transistors is accelerated at such temperatures: designers will now be able to trade-off performance enhancement against degradation time.

Towards convivial software: more readily designed, easier to use

Moving away from components and hardware, a number of fundamental problems in computer science are being addressed by several Basic research actions. These cover both software design and evaluation methods, and aim both to reduce programming effort through improving design methods and to facilitate the development of more flexible, user-friendly systems. A further goal is to foster the development of programming languages that are far more expressive than any now in common industrial use, and to pro-

vide them with environments supporting high-level concepts.

Basic research actions have progressed towards these goals by addressing a range of key issues such as program semantics and parallel computing, logic and meta-logic reasoning, new models for programming, and complete systems based on graph grammars.

The latest results of COMPULOG (action 3012) were the focus of a symposium on computational logic held in conjunction with the ESPRIT Conference in November 1990. One of the results of this action has been the development of a new declarative logic programming language, GÖDEL, which has strong typing, modules and facilities for use in meta-programming. Besides making software engineering easier, the declarative nature of GÖDEL opens up possibilities for exploiting the parallelism of future systems with substantial gains in efficiency over other less declarative logic programming languages. Also developed within COMPULOG have been novel techniques, notably in the area of program transformation, that will reinforce the efficiency gains.

Flexible systems often encounter performance problems. These can be addressed through systems that enhance the performance of compilers and by employing better

algorithms. The latter approach is exemplified by the work of ALCOM (action 3075), which has succeeded in designing over 60 algorithms that are very much more efficient than those previously in use. These include routing techniques for networks of processors, recently adopted by industry in the development of the Inmos C104 routing chip, which is being used in conjunction with the new Inmos T9000 transputer. A library of tested algorithms has been made accessible to the computer science community.

New computing paradigms are expected to provide the environments necessary for resolving many long-standing problems in software development. One new paradigm is exemplified by the research on 'graphs' in COMPUGRAPH (working group 3299). Graphs are mathematical structures used in computer science to represent concepts ranging from the abstract syntax of a program to schemas of object databases, and specialized techniques for manipulating graphs more efficiently are needed. COMPUGRAPH's research has focused on the practical and theoretical aspects of hyper-edge replacement, which is one approach to graph transformation, and has led to a new generation of highly efficient rule-based inference mechanisms.

Paradigms are adopted by computer scientists to define both languages and software development environments. Central to the success of these environments is the assistance they provide the development team in 'proving' the correctness of a system under development without the need for testing — which in practice can rarely, if ever, be exhaustive. PROCOS (action 3104) has produced a method for capturing requirements for real-time, embedded, safety-critical systems. This is now being tested in collaboration with Danish National Railways.

The integration of paradigms to combine their various advantages is the focal point of several actions. One example is INTEGRATION (action 3020) which is integrating object-oriented, functional and logic programming and has already developed a new parallel object-oriented language whose functional characteristics address fundamental problems identified in earlier ESPRIT projects.

In the complementary field of operating systems, CONCUR (action 3006) has developed a concurrency workbench (CWB) for the analysis of practical distributed and

concurrent systems. The adoption of a performance verification algorithm within CONCUR allows the properties of systems modelled using the CWB to be checked more rapidly than hitherto, a feature which is already being applied in practice.

An important research theme in the information and database systems areas is the integration of a full set of technologies — from object stores to user interfaces — to allow a total application to be built within an integrated environment. For instance, FIDE (action 3070) has succeeded in defining integration rules and tests: these were demonstrated by having the Galileo database programming language running with data provided independently by the Napier 88 persistent store.

Measuring software reliability

Despite advances in the manufacture of hardware, the reliability of computer software is especially difficult to measure. Techniques for building reliable software and techniques for evaluating what has been built have proved far more elusive than their hardware counterparts, though knowing how much one can depend on a piece of software is crucially important. Partly as a result of work carried out in PDCS (action 3092), methods have been defined for obtaining accurate reliability estimates and predictions for certain classes of programs. This has far-reaching implications. In particular, it now makes it possible for software vendors to use the reliability of their products, backed up by a scientific evaluation, as a marketing feature. Furthermore, the achievements of PDCS form the basis for planned pre-standardization efforts undertaken by the IFIP Working Group on the dependability of concepts and definitions.

From sensation to perception

Several Basic research actions have adopted a strongly multidisciplinary approach to the investigation of human cognition. INSIGHT (action 3001), for example, has brought together neuroscientists, cognitive psychologists and computer vision experts to pioneer new ideas on the functioning of vision systems operating in a three-dimensional dynamic environment. INSIGHT's research has demonstrated that when someone looks at a moving image, the neuronal response in the higher-level visual cortex is sensitive to information about the moving scene as a whole. Moreover, if part of

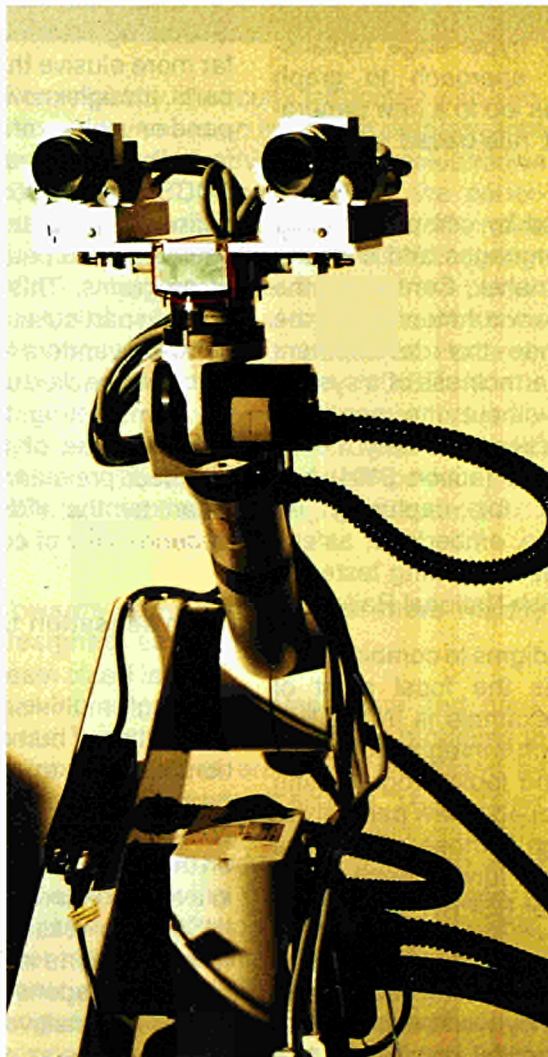
the image is momentarily occluded, the neuronal response at the higher cortical level fills in the missing information. This complementing of sensory information with implicit knowledge had been postulated and partially achieved in artificial vision systems, but has never been directly demonstrated before. INSIGHT's achievement represents an important step forward in the understanding of natural vision, and is expected to pave the way for the development of artificial vision systems able to operate in a changing three-dimensional world.

Vision as process (VAP) (action 3038) is developing techniques for the control of perception in a continuously operating artificial vision system. The VAP system integrates real-time processes for binocular camera control, image description, 3D scene modelling and symbolic scene interpretation. The consortium is developing control mechanisms which exploit observed temporal context and goal-oriented user instructions to

direct vision processing for the continuous operation of the integrated system. Early results have confirmed that a number of vision problems are substantially simplified by the use of an active controllable sensor and continuous processing. The consortium has constructed three prototype binocular camera heads as well as a set of computer boards for real-time multi-resolution image description and tracking. Arrangements have recently been concluded for the image description boards to be commercialized by ITMI, a leading French supplier of machine vision systems.

In conventional robotics, 'motion' generally takes place once a sequence of investigative interactions has established the parameters for movement. In contrast, SUBSYM (action 3234) is experimenting with direct vision-to-motion planning systems that eliminate the need for this stage. By storing a visual representation in an analogue buffer also containing predictive information on the scene in question, sensorimotor actions (such as hand-eye coordination between a video camera and a robot arm) can be planned and monitored. In the course of the action a powerful technique that can be used for robot navigation has been developed. Its ability to adapt in real time to topological changes, and to simultaneously compute the paths of multiple robots, is unmatched by any other method.

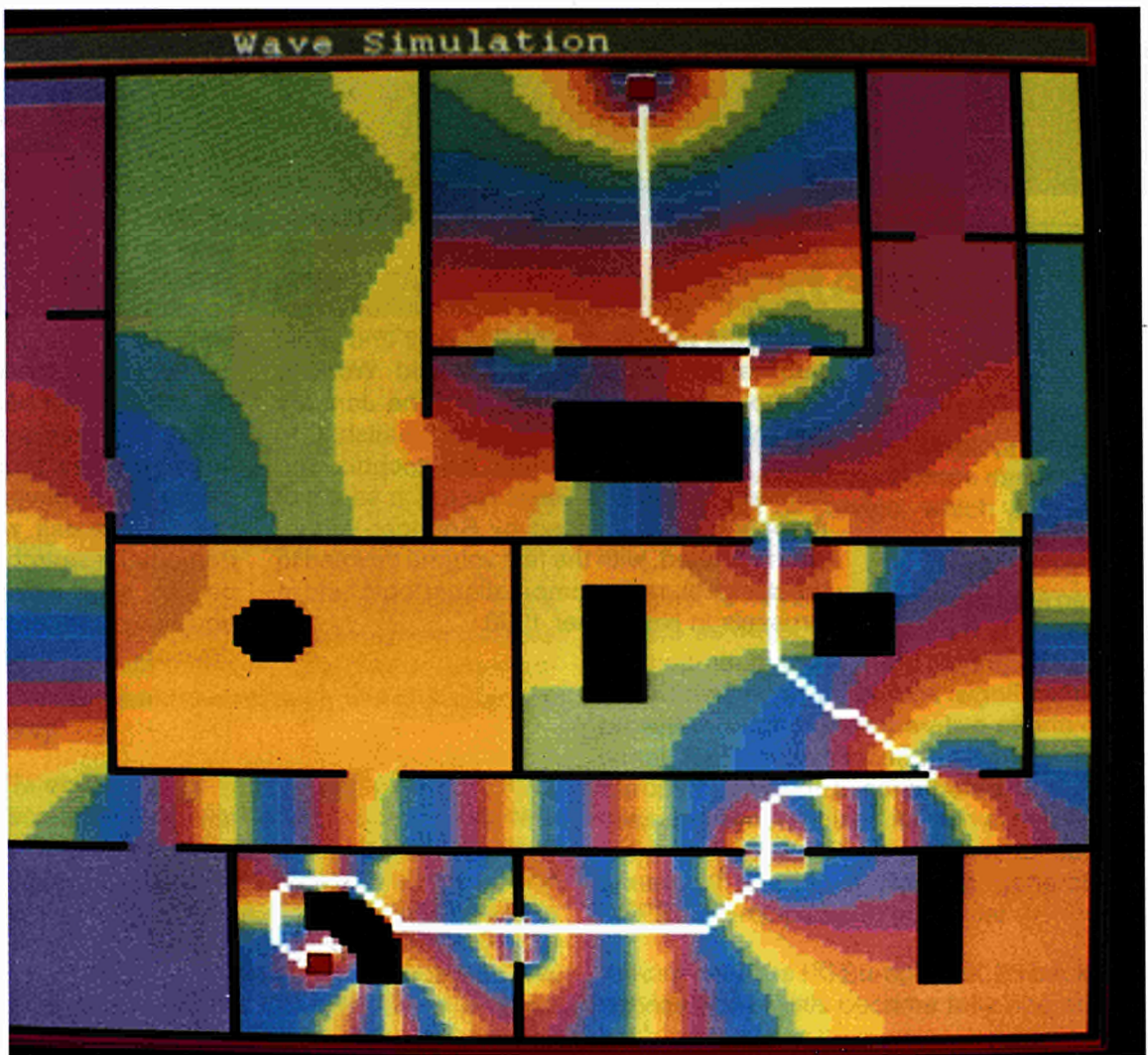
In vision: VAP (action 3038) has developed this prototype of a vision robot which is able to keep its focus of attention on moving scenes. It can recognize dynamic patterns, and can continuously coordinate the aiming and focusing of its eyes with its movements, employing advanced real-time computing and sensing to do so. The dedicated hardware boards developed in the course of the work are being commercialized by ITMI of Grenoble, France.



Speech recognition

Communication through sound and speech is less well understood than communication through vision. Fundamental research is essential if the long-term goal of direct speech communication with information processing systems is to be achieved. ACCOR (action 3279) studies human speech production in several languages with two main objectives: to recognize the invariants among these different languages, and to minimize the number of parameters necessary when modelling speech production. The research is vital for improving the efficiency of speech recognizers by simplifying their acoustic preprocessors. In the course of its work, the ACCOR consortium has developed a unique multisensor speech-data acquisition system which is already attracting interest from speech therapists, phoneticians, and scientists investigating the human speech production process. The system will be commercially

Finding the way: a computational metaphor for path generation gleaned from fluid dynamics has been developed in SUBSYM (action 3234). This powerful technique finds the optimal path for a robot to navigate through any maze, no matter how complex. Its abilities to adapt in real time to topological changes in the maze and to compute, simultaneously, the paths for additional robots are unmatched. The picture represents the interior of a building with walls, doors and desks. The white line is the path found from the red square (in the room at the top) to the destination behind the desk at bottom left. The colours represent intermediate stages in the generation of the path.



released in August 1991 by Phonologia, a company set up by the consortium.

At the other end of the speech processing and recognition continuum, ACTS (action 3207) has modelled auditory processing with such high resolution that the 'formants' of speech (the frequency bands that give a sound its particular quality, timbre or tone colour) can be resolved. The model provides a better representation of our auditory sensations than the activity observed in the auditory nerve, and has already allowed artificial speech recognizers to work more efficiently than with traditional sonograph front-end processors, especially in noisy conditions.

In Europe, with nine major languages in the countries of the Community alone, there is a strong motivation to develop multilingual human-computer interfaces, which can be considered as intermediate steps towards the

goal of fully automated translation systems. DYANA (action 3175) is carrying out research that will help in the development of a computational and cognitively motivated model of how spoken language is understood, and is addressing fundamental issues in computational linguistics, speech understanding, syntax, semantic representation and reasoning, and the interfaces between all these areas. One important focus of work during the second year of the action was that of bridging the gap between computational linguistics and speech technology. A system was demonstrated which automatically labels intonation contours, and foundations for a theory of computational phonology were developed. Substantial progress was also made on the development of a comprehensive unification formalism for linguistic description. Both strands of work are moving the consortium — and the Community — towards the forefront of this highly competitive and rapidly evolving field.

Awareness activities

During 1990/91 the Basic research actions published a large number of papers in leading scientific journals. Many presentations were made in international conferences, and over 100 workshops were organized involving participants from both industry and academia. Two editions of synopses — succinct descriptions of the aims, approach and methods, progress and results, potential impact and latest publications of each Action and Working Group — were published, and the January 1991 version sent, in a targeted mailshot, to every European university, polytechnic and research institute. A Basic research series of monographs, published by Springer-Verlag, was launched, with the first volume devoted to the symposium on computational logic held in Brussels in November 1990.

Outlook

The activities comprising Basic research have begun to provide the necessary foundation for a broad range of new industries, with the results of any one action expected to feed into several other ESPRIT projects and areas of industrial R&D. Results, such as the demonstration of the way the brain handles certain cognitive processes, have long-term implications for fields of research as diverse as medicine and robotics, and the discovery of the unexpected behaviour of microcircuits at low temperatures will have an immediate influence on new product development. Just as important, however, is the demonstration that there are areas where the route from fundamental research to applied technology can be very short indeed, especially when small and lively companies take up the challenge of developing and exploiting new ideas.



Information exchange system

Overview

The international cooperation that characterizes ESPRIT requires that project participants communicate with each other not only by the traditional methods of conferences, seminars, workshops and special interest groups, but also via communications services that enable them to make immediate contact with their partners in other organizations or countries in an easy and cost-effective way.

To encourage the cross-fertilization of ideas, scientists and engineers should also be able to readily identify and contact participants in ESPRIT projects other than their own, and to access the Commission's scientific databases (hosted on the DG XIII sponsored 'ECHO' host computer in Luxembourg). It is also desirable that participants in other Community programmes, and indeed European scientists generally, should have high-quality, cost-effective communications tools and network facilities. To this end, three lines of activities are pursued within the Information exchange system (IES):

- The provision of communication services to ESPRIT participants.
- Projects aiming to accelerate the availability of OSI-conformant computer communications software.
- Harmonization of the implementation of inter-computer communication protocols, to be achieved by providing strong encouragement for the adoption of the ISO-OSI model. Particular support is given to Europe-wide networking activities such as the EUREKA COSINE project in order to enable interworking between researchers and their computers located in all participating countries.

These three types of activity are closely related: the communications services im-

prove as new technical developments take place, and users across Europe demand even higher levels of service, which accelerates harmonization activities.

The past 18 months have ushered in a new era for IES as major, long-planned changes and developments took place. During this period R&D networking in Europe significantly improved through the cooperative efforts of national R&D networks and initiatives at the European level. IES contributed to this process and synchronized its own activities with major international developments for the benefit of European R&D in general and ESPRIT participants in particular.

In April 1990 the IXI European X.25 backbone service at 64 kbit/s became fully operational.

The progression of the EUREKA COSINE activity reached important milestones with the award of contracts for several COSINE sub-projects.

Usage of the EuroKom system continued to increase, paving the way for its launch as a service independent of Community funding.

Activities supported

The most important activities supported by ESPRIT IES are:

EuroKom

Throughout 1990, EuroKom continued to make good progress in increasing its number of customers, with some 2 200 registered users reading an average of over 200 000 messages per month. As a direct result of the sustained improvements in the use of EuroKom, 1991 marked an important turning point for the service when it became fully self-supporting at the beginning of the year.

EuroKom will continue to provide services to the IT R&D community as its primary market. These services, especially its conferencing facility, are expected to remain an important and attractive complement to the other OSI-based services now emerging.

IXI

IXI, the international X.25 infrastructure backbone service for R&D, connects 20 public and private X.25 networks in 17 European countries. It also provides direct connections for several specific users (such as the JRC, CERN, EuroKom and the CEC). The major portion of funding provided by ESPRIT enabled the IXI pilot service to be launched in 1989 with the aim of constructing a high capacity, reliable network service providing links between national research networks at higher speeds (64 kbit/s), greater reliability and lower cost than those available from public services.

The service commenced regular operation in April 1990. Since then traffic volume has steadily increased, reaching about 16 Gbit/month in the spring of 1991. IXI will also provide the interconnections for the Y-NET service (see below).

Plans for upgrading to a 2 Mbit/s European backbone service were developed. In October 1990 the Y-NET project was launched. By the end of 1991, the pilot IXI service will have been replaced by a full-scale service.

Y-NET

Y-NET, a new ESPRIT pilot OSI action, was launched at the 1990 ESPRIT conference and exhibition by Teleo SpA, who have been contracted to implement the project via the Y-NET Management Unit (located in Brussels) in conjunction with a group of European manufacturers, who are also donating equipment for the project. The operational and management costs will be met by the IES.

Y-NET aims to provide communication services to all researchers participating in ESPRIT and other Community-supported R&D programmes using OSI-conformant systems. Particular emphasis is being placed on the needs of SMEs, who have hitherto experienced difficulties in accessing pan-European research networks.

The OSI-based network services to be provided during the 48-month project initially comprise X.400 mail services and FTAM (file transfer access and management), with X.500 directory services and ODA (office document architecture) available in a later phase. These facilities are intended to complement and facilitate access to services which have been launched or are currently in the process of being established under COSINE.

COSINE

The EUREKA COSINE project is dedicated to furthering the use of OSI-based communications by the European research community. The approach is to federate national OSI networking in the R&D domain through a set of specific activities (COSINE sub-projects) at the European level. Support for this project is provided by the Commission, including the provision of the project officer and secretariat functions.

COSINE has now launched several sub-projects, amongst them two aiming to improve specific aspects of European OSI interworking:

- (i) a message-handling project (MHS) to coordinate X.400 traffic at European level originating from national MHS projects;
- (ii) a gateway service for message-handling and file transfer to connect European R&D networks with those in the USA.

Other COSINE activities, such as a pilot international directory service and pilot support and information services, are coming on stream, with initial availability to users planned for the second half of 1991.

Subsequent COSINE activities have recently embarked on their implementation plans: pilots for FTAM interworking testing, virtual terminal and connectionless network services, and the support of international user-groups.

RARE

The work of the RARE (Réseaux associés pour la recherche européenne) association, through which national and international R&D networks cooperate in order to harmonize their different technical approaches, has continued to receive support from ESPRIT. This involved support both to specific RARE work-

ing groups and to the RARE X.400 MHS (message-handling system) pilot project which aims to encourage researchers to migrate to OSI-based electronic mail services.

Cooperation with R&D networks in the USA

The first steps have been taken to improve data communications between researchers in ESPRIT and those in programmes and projects funded under the National Science Foundation (NSF) and DARPA. Two working group meetings on R&D networking (in Brussels and Washington) were held as part of a major workshop involving ESPRIT and NSF/DARPA devoted to R&D collaboration in a number of specific areas. The proceedings of this workshop have been published.

Information dissemination

A major source of information dissemination has been the *IES Newsletter*, published every two months since it was launched in autumn 1985. During 1990 six editions of the News-

letter were published, containing information of specific interest to specialists in research networking as well as special sections provided by CEN-Cenelec and other IT standards bodies. A COSINE section was introduced in August 1987. In the first quarter of 1991 the Newsletter, after 31 issues, was merged with the *News Review Supplement* of the new *XIII Magazine*, published by DG XIII. Former readers of the *IES Newsletter* can continue to follow the activities of IES in the 'Programmes in action' section under the heading 'ESPRIT News'.

Outlook

The provision of standards-based communication services to European research remains the goal of IES. This is not only a technical issue, but is also closely connected to the introduction of suitable organizational concepts for R&D networking at the European level. Preliminary discussions with major European participants in R&D networking are under way, and include talks with the US authorities on transatlantic cooperation.



Awareness activities

Encouraging participation

DG XIII plays a very active role in alerting European academia and industry to forthcoming calls for proposals and in assisting potential participants to prepare proposals that stand the best chance of success. During 1990/91:

- The 1991 **work programme** and complementary background material were prepared after consultations involving the convening of industrial working groups and experts' workshops and on the basis of guidance and advice from the ESPRIT Advisory Board and Management Committee. An **information package** was prepared containing an overview of the programme, specifications of the form proposals should take, the evaluation and selection criteria employed, detailed notes on contract conditions, and descriptions of consortia-forming mechanisms. In mid-1991 over 25 000 copies were mailed or otherwise distributed, together with the work programme and background material.
- Fifteen **national information days**, with around 2 500 attendees in total, were held during 1991 in Community and EFTA Member States to help make potential participants aware of the rationale and content of the work programme and the call for proposals. Four **international information days** were organized in Brussels, where over 1 500 participants were given detailed information on each work area and provided with every opportunity to identify potential partners via posters, noticeboards, the use of the Eurocontact 'matchmaker' database, and the provision of venues for formal and informal meetings. A particular aim of these events was to ensure that information about ESPRIT was efficiently transmitted to the more outlying regions of

the Community in order to give them an equal opportunity of participating in the programme.

- As in previous years, DG XIII was greatly assisted in disseminating information about ESPRIT by the **National contact points** (NCPs) established in every Community and EFTA Member State to provide a permanent and visible local presence for ESPRIT. NCPs maintain stocks of ESPRIT publications, provide early notice of calls for proposals, assist potential and actual participants, participate in information days, and administer local versions of the Eurocontact database. The Euroguichets, established to promote access, especially for smaller companies, to Community programmes in general, are another important source of ESPRIT information. **ESPRIT Clubs** were set up in Belgium, France, Spain, Greece, Italy, Denmark, Germany, Portugal and the United Kingdom, under the auspices of local trade, professional or governmental bodies, to further disseminate information about the programme.
- Potential programme participants were also reached by numerous **articles** and **information notes** written for a wide range of specialist journals, and the launching, in April 1991, of the Commission's quarterly *XIII Magazine* and *XIII News Review*.

Promoting contacts and disseminating results

DG XIII also takes an active part in promoting contact between ESPRIT participants. Now that such communications have been established for several years, a European IT community has become firmly established.

One outcome of this effort is that a great deal of communication now takes place within this community without the Commission's explicit involvement, as shown by the increasing number of European conferences and interest groups set up in the last few years.

The transfer of R&D results into actual use is of prime importance to ESPRIT participants and the European IT industry, and the Commission has made a special effort in the past 18 months to provide a supportive framework for technology transfer. The basis for both fostering contacts between participants and publicizing results was provided by the events and services described below.

The annual conference and exhibition, the major public event of the ESPRIT programme, was held in Brussels from 12 to 15 November 1990 and attracted more than 3 000 participants.

The ESPRIT Conference provides many opportunities, both formal and informal, for people representing political, industrial and scientific interests within the European IT community to meet and discuss results, achievements and issues of common concern.



As in former years, the conference addressed both policy and technical issues. Policy was covered in the day-long **IT Forum**. In the morning session, chaired by Mr F. M. Pandolfi, the Commission Vice-President responsible for information technology and telecommunications, leading politicians and industrialists joined Mr Pandolfi and Mr J.-M. Cadiou, direc-

tor of ESPRIT, in discussing a range of broad strategic issues of importance to the future of IT in Europe. Prof. A. Ruberti, Italian research and higher education minister then chairing the Research Council, and Mr T. von der Vring, chairman of the European Parliament's Committee on Budgets, took part, as well as Prof. P. Aigrain, scientific advisor to the chairman of the Thomson Group, Mr F. D. Maier, AEG board-member, Prof. H. G. Danielmeyer, Siemens board-member, and Mr P. Hughes, director and former chairman of Logica.

The afternoon session, chaired by Mr Carpentier, Director-General of DG XIII, tackled the theme of 'The impact of information technology on society', with speakers addressing the topics of health, privacy, education, the workplace and the natural environment.

**1990 IT Forum
(morning session)**

Professor A. RUBERTI, chairman of the Research Council, opened the proceedings by providing an overview of the commercial environment in which European companies were now operating. With the advent of the single market, he said, there would be explosive growth in the demand for and development of services. In order that these opportunities could be exploited to their best possible advantage by European companies, it was essential that there be a cooperative approach by organizations, and in many cases vertical integration might be desirable or even necessary. Cooperation was vital at all stages in the development of new products and services, and the success of the ESPRIT programme in encouraging primary research had shown what could be achieved.

Mr T. VON DER VRING, chairman of the European Parliament's Committee on Budgets, painted a bleak picture of the state of the European IT industry, which, he said, had lost its sense of direction and was suffering as a result of squabbling between vested interest groups and Member States. The recent takeover of ICL by Fujitsu was a vivid manifestation of these problems, he felt, and represented a low point for the European IT industry; a revision of Community IT strategy was desperately needed. There was no doubt that political

and economic support was necessary for industry to compete on equal terms with the Japanese. The problem, however, was in defining priorities. The questions which needed to be asked were as follows:

- Was a Community strategy needed?
- Which sectors should benefit from the available resources?
- Was the funding approach correct?
- To what extent should there be a social dimension to research?

To date, Mr von der Vring said, the Community had taken the view that cooperation in precompetitive research would solve all the IT industry's problems. It had been naïve in making this assumption. What was required was a redefinition of what was understood by competition and a better understanding of how it shaped the IT industry. At present the problems presented by competition were solved by takeovers. Not only was a European policy on mergers needed, but also a facility for providing a European solution for companies in difficulties. In addition, more thought should be given to strategic support for European industry, involving the three interrelated areas of research, social and regional policy.

Mr P. AIGRAIN, Thomson Electronics, considered that the situation in Europe was not as bleak as other speakers had suggested. The top five companies in Europe in both the computer and software industries were all gaining a market share in Europe. Europe was still strong in electronics, which boded well for the future; for example, in 10 years' time, 25% of a car's value would be its electronics — more than that constituted by the sheet steel industry. Where difficulties did exist, Mr Aigrain concluded, this was despite the ESPRIT programme, not because of it.

Mr F. D. MAIER, AEG, regretted the fact that the availability of money for R&D in Europe was limited. This was a disaster when it was considered that present high growth-rates were accompanied by a lowering of barriers to Eastern Europe, combined with economic stagnation in North America. The shortage of funding would almost certainly leave the IT sector in the same position as the Swiss watch industry, which had bought components from foreign suppliers

only to see them start making their own products, putting the Swiss manufacturers out of business. The answer was to follow the Japanese example, where companies were well resourced as part of large integrated groups. In a European context this might be achieved in the form of close cooperation between organizations in the form of 'vertical integration alliances' between users and producers, with particular emphasis on the needs of SMEs. Mr H. G. DANIELMEYER, Siemens, expressed similar views.

Mr P. HUGHES, Logica, drew attention to the growing importance of the software services market in Europe, and appealed for a more appropriate level of attention to this sector from both the media and national administration. With software and services rapidly becoming the dominant component of the IT industry, ESPRIT and national administrations should in future:

- strive for a better understanding of the admittedly very disaggregated software industry;
- ensure much greater involvement by users at the earliest stages of research;
- place more emphasis on advanced software engineering.

Mr J-M. CADIOU, Director of ESPRIT, addressed the question of the competitiveness of the European IT industry. He pointed out that over the 1984-89 period more than 13 000 companies in this sector had increased their share of the European market by 8 percentage points (from 47 to 55%) and more than doubled their total R&D investment, despite falling profit margins and rising costs.

Mr Cadiou did not minimize the severity of the slow-down in demand for information technology nor the structural difficulties affecting the sector, and also drew attention to the much higher long-term R&D capital costs suffered by European IT companies compared to their Japanese equivalents. However, the catalytic effect of the ESPRIT programme had had a significant influence on the industry, bringing together organizations from all over Europe and resulting in more than 300 major technology results so far. He cited three examples of important technology developments: in lithography (wafer-stepper oper-

ating in the deep ultraviolet frequency range to produce 0.25 micron chip circuit geometries); parallel computer systems (T800 Transputer); and systems integration. Looking into the future, Mr Cadiou said that the necessity of ever-higher investment in R&D, together with the lowering of profit-margins, pointed to an increasing need for cooperation on the basis pioneered by ESPRIT. The proposed next phase of the programme would be characterized by an increased level of user involvement; a new initiative in technology transfer and acquisition, especially in the software area, to improve the take-up of the latest technologies; an emphasis on critical microelectronics components; and a doubling of the Basic research part of the programme.

Mr F. M. PANDOLFI, Commission Vice-President responsible for information technology and related industries, said that a Commission policy document would be available in the near future. Its main points would be as follows:

- concentration on a smaller number of strategic issues,
- on the supply side, an emphasis on new types of integrated projects,
- on the demand side, encouragement for public sector services in Member States to link up databases.

The specific areas to be addressed would include:

- Extension of the European nervous system (ENS) programme, which had already been formally incorporated into the third framework programme.
- 'Le Grand Réseau' — building up the necessary infrastructure to enable all the new services to be available across the Community.
- Improving the mobility of young researchers through the Human capital and mobility programme.

The first three days of the conference were devoted to technical sessions, with 130 presentations including descriptions of important results, panels discussing topics of general interest, and workshops on specific issues. A special session took place on information technology and the environment. A

major part of the conference was the **exhibition** of ESPRIT results, which featured 100 projects involving more than 300 companies. The demonstrations ranged from intermediate findings through to industrial prototypes and included impressive results from all areas of the programme. Following on from an initial seminar held in the 1989 conference week on the **technology transfer** of results, where several case-studies of successful technology transfer out of ESPRIT projects were presented, a seminar took place during the 1990 conference on **technology acquisition**: several conclusions were reached, including the importance of nominating a 'project champion', responsible for technology transfer, from the outset of a project.

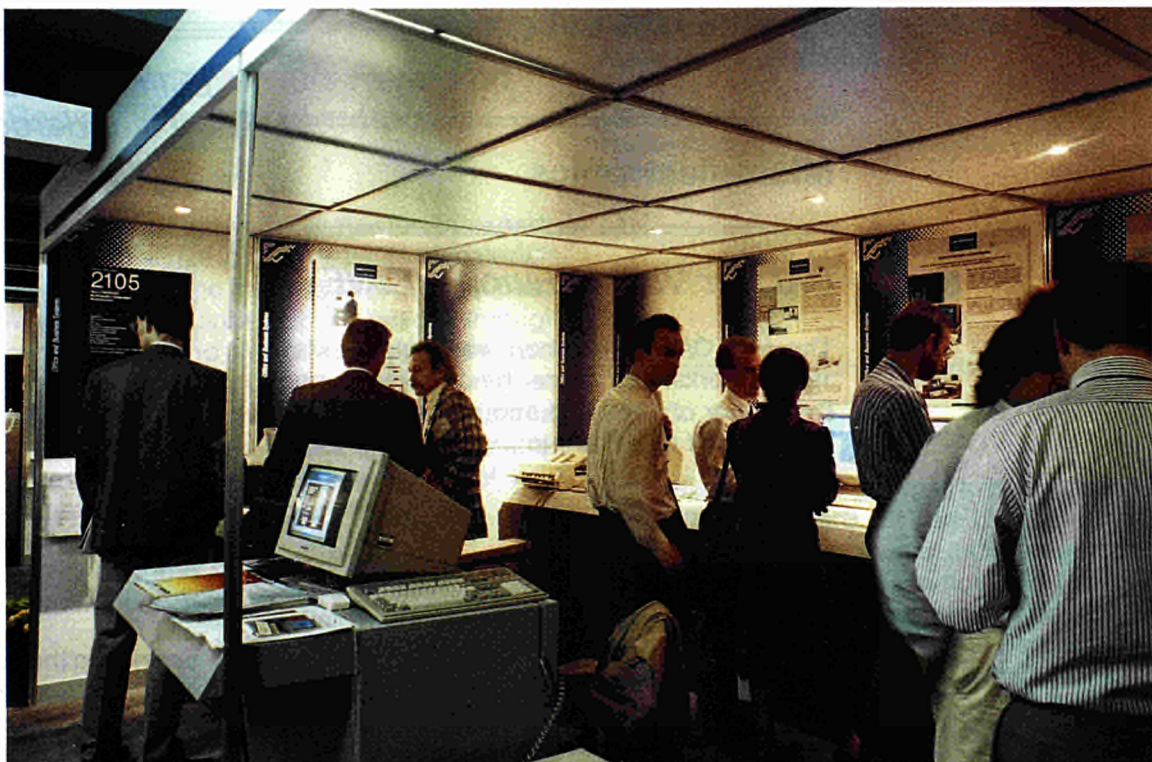
In addition, the ESPRIT programme was presented at numerous **conferences, workshops** and **seminars** throughout the Community and abroad. With the programme's high profile in the IT community, presentations on ESPRIT are invited for most of the relevant conferences world-wide, and it is common for contributions from ESPRIT project participants to dominate European events. The Commission has exhibited ESPRIT at numerous technology conferences in the past 18 months, held in most of the Community Member States and also in several EFTA countries. The Commission has also encouraged and sponsored presentations at technical conferences by project representatives. In addition, a seminar for ESPRIT contractors on **project management** was held in June 1991, where participants had the opportunity to identify, and suggest solutions for, the typical management problems that arise in the course of an ESPRIT project.

Special interest groups (SIGs) continue to provide an important communications medium between projects with common interests and between projects and industry. The current groups are briefly described, together with their contact points, at the end of this chapter.

ESPRIT information

The most general and widely used description of ESPRIT projects and their results is contained in the **project synopses**. The eight-volume set contains summary descriptions covering, in each case, a project's objectives, progress, results, and commercial prospects, and giving details of participating organiza-

The 1990 Conference exhibition featured 100 projects involving more than 300 companies.



tions, contact points, start date and duration. A master index and list of participants is included. The synopses were completely revised for the September 1990 edition to include the 107 new projects and 43 exploratory actions selected for funding that year. Over 100 000 volumes were distributed at various events, by direct mailshot and in response to enquiries. An interim update was issued in June 1991, and the next full edition will be available in autumn 1991. The synopses are also available as an electronic database via the EuroKom service. **Technical factsheets** were prepared for over 100 projects for distribution at exhibitions and other events.

Major reports of the final results of ESPRIT projects are increasingly disseminated in the form of **monographs**, and in the past 18 months a dozen have been published by Springer-Verlag (see bibliography). The proceedings of the 1990 ESPRIT Conference were published by Kluwer. In addition, a series of **occasional papers** was started in 1991, under the aegis of the Commission, to improve the interim reports emanating from projects. Information is also provided via *XIII News Review*, the supplement to the recently launched *XIII Magazine*, which covers the activities and programmes supported by DG

XIII. This ESPRIT **Progress and results report** itself makes available an overview of the programme's status to the interested layperson as well as acting as a reference document.

The **ESPRIT Information Desk** provides institutions, participants (potential and actual), the media and interested individuals from both within and outside the Community with information about the ESPRIT programme. The type of information requested ranges from the very general (on Community R&D policy) to the very specific (concerning particular projects and participants). As well as dealing with requests for information, the information desk supports ESPRIT at exhibitions, conferences and other public events. In a typical month several hundred requests for documents are received and several thousand documents sent out.

Press-releases and **information sheets** are regularly mailed out or distributed at press briefings and conferences to several hundred periodicals, journalists, companies and institutions. They cover calls for proposals, selection of projects to be funded, announcements of conferences and other notable events or news items.

Special interest groups

Microelectronics

CAD for VLSI in Europe (CAVE)

The first CAVE workshop was held in May 1983. Workshops were held in May and December of 1990 and another in May 1991. The aims of CAVE are to:

- disseminate the results of ESPRIT CAD projects
- ensure the rapid and consistent exploitation of new research ideas by means of selected tutorials
- maintain the strong sense of identity of the existing community of CAD researchers in Europe
- encourage strategic thinking and debate on critical issues and draw up recommendations for future action in this field.

Contact: Mike Newman — CEC, DG XIII-A3
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Lithography

This group has the following objectives:

- exchanging views in the field of optical, E-beam and X-ray lithography
- promoting the standardization of metrology procedures.

The group meets once or twice a year. The core participants are partners in ESPRIT and EUREKA projects, but others may participate in certain events. A workshop was held in Brussels in November 1990 during the annual ESPRIT Conference.

Contact: Leo Karapiperis — CEC, DG XIII-A3
 ☎ +32/2-236-8034 Fax: +32/2-236-8389

VLSI manufacturing automation and standards

This group has the following objectives:

- exchanging views and experience about the implementation of standards and recommending changes and additions to them
- promoting future industrial cooperative actions for tackling VLSI automation-related problems
- collating semiconductor manufacturing requirements for automation and reliability in order to provide informal recommendations to manufacturers and users
- promoting the use of and disseminating information about a uniform set of standards.

The group meets at least twice a year. The core participants are partners in ESPRIT and EUREKA projects; others may participate by invitation. Two workshops were held in Brussels in 1990.

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Integrated circuit (IC) reliability

The main objectives of the group are to:

- establish a framework for coordinating current and new activities within ESPRIT in this area
- provide a forum for the dissemination of results and for stimulating their take-up and use in other projects
- prepare surveys on the state of the art of major reliability issues.

The first workshop was held in April 1990, when relevant results from all ESPRIT projects covering the topic of IC reliability were presented and discussed.

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 IMEC vzw
 Kapeldreef 75
 B-3030 Leuven
 ☎ +32/16-281-211 Fax: +32/16-22-9400

Electronic Materials Research Society/Electronic materials network

More than 10 networks of European experts have been active in various fields of materials science under the framework of the European Materials Research Society which, through conferences and symposia, maintains contacts with over 2 000 researchers. These ESPRIT-funded networks offer both industrial and university researchers open forums for assessing the potential of a variety of new materials.

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Analogue circuit design

The broad aims of this new group are to create a network of analogue researchers; provide a forum for the exchange of ideas; debate and establish research activity priorities; enable the rapid dissemination of relevant ESPRIT project results; obtain and provide updates on new trends in the analogue domain; and to enable the formation of new international working relationships in the area of analogue circuit design.

The first workshop took place in Milan in September 1991; two a year are planned, together with a bi-annual newsletter for members.

Contact: Dave Broster — CEC, DG XIII-A3
 ☎ +32/2-236-8021 Fax: +32/2-236-8389

Information processing systems

Graphics and interaction

The objective is to encourage information exchange in the computer graphics field. A workshop on user interface management and design was held in Lisbon in June 1990. Its proceedings (edited by J. Lee *et al.*) have been

published by Springer-Verlag in the Eurographic Seminars series.

Contact: D. A. Duce
 Rutherford Appleton Laboratory
 Chilcot, Didcot
 OX11 0QX
 United Kingdom
 ☎ +44/235-445-511 Fax: +44/235-445-831

LISP

The objective of this group is to prepare an international standard for the LISP programming language. It is open to all European parties interested in the definition and use of a standardized LISP. Four meetings have been held up to the middle of 1991 to prepare 'The EULISP definition'.

Contact: Jérôme Chailloux / Greg Nuyens
 ILOG
 2, avenue Galiéni
 F-94253 Gentilly
 ☎ +33/1-466-366-315-66
 Fax: +33/1-466-315-82

VDM-Europe/Formal methods Europe

VDM-Europe was formed in 1985 with the aim of increasing the awareness, use, development and standardization of the Vienna development method (VDM). A major change is taking place in 1991: VDM-Europe is becoming Formal methods Europe, a forum for any formal method user. Industrial use will be a major focus of attention.

Contact: Alejandro Moya — CEC, DG XIII-A4
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Software maintenance

This SIG acts as a communication forum for its members, who are drawn from industry and research institutes across Europe. The main aim is to establish and publish information on the practice of software maintenance. This brings benefits to the practitioners them-

selves, who can compare their operations with those of others, and to researchers, who can learn of the problems that truly concern people, and so guide their research accordingly.

Contact: Mrs Hilary Calow
FI Group plc
Sapphire West, Streetsbrook Road
Solihull B91 1QY
United Kingdom
☎ +44/21-711-4242 Fax: +44/21-711-4200

European Languages Standards Group for MIMD computers

This working group concentrates on standardizing parallel constructs in Fortran 90 and C. Regular meetings are held to write the draft standards. Collaboration is being sought with similar groups in the USA to ensure there is no duplication. Final drafts will be distributed for public comment.

Contact: Rolf Hempel
GMD Institut F1/T
Schloß Birlinghoven
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☎+49/2241-142-575 Fax:+49/2241-142-889

Metrics

The objective of this group is the promotion of software metrics and certification. Coordinated by PYRAMID (project 5425), it organizes various events throughout the Community, some of which are devoted to specific metrics application areas such as banking, telecommunications, the health sector, etc.

Contact: Frédéric Copigneaux
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Aeropole Bat. A
F-31700 Blagnac
☎ +33/61-719161 Fax: +33/61-718867

Advanced business and home systems — Peripherals

Open microprocessor systems initiative (OMI)

OMI aims to provide a complete competitive microprocessor capability for both computer systems and embedded control, ranging from very high performance (over 1 000 Mips) to very low power (down to 0.01 watt). The initiative will build on European strengths in advanced RISC microprocessors, and will be both technically and institutionally 'Open'. The new family of OMI microprocessors will be provided as macrocells in a standard design library of microelectronic components. Users will be involved at all stages of the initiative. Universities will obtain early access to developments under a technology transfer scheme so that the next generation of young hardware, software and applications engineers is trained in using the OMI technology.

Contact: Rosalie Zobel — CEC, DG XIII-A5
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RICHE (Réseau d'information et de communication hospitalier européen)

The RICHE (project 2221) special interest group aims to inform hospital managers, decision-makers in health-care ministries, representatives of health organizations, etc., about the RICHE project in order to raise awareness and stimulate comment and discussion.

Contact: Prof. Van der Werff
SIG Services Ltd
Maliebaan 50
Postbus 14066
3508 SC Utrecht
The Netherlands
☎ +31/30-345-611 Fax: +31/30-313-149

Distributed systems (SIGDIS)

Established in February 1991, this SIG aims to stimulate and encourage cooperation between firms and organizations and to help form links with end-users and broad-based end-user groups with interests in distributed systems. The group operates on a six-month rolling programme which includes plenary meetings two or three times a year and meetings of topic-oriented workgroups. Workshops have been held in Brussels and Washington DC to discuss the technical achievements and industrial implications of the work on distributed systems, especially the achievements of ISA (project 2267) and COMANDOS (projects 834 and 2071). The workshops helped to identify areas in which collaboration between European and US organizations could be mutually beneficial, and established a basis for more detailed discussions with particular US organizations, including DARPA and NSF.

Contact: Mr M. Eyre
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 Poseidon House
 Castle Park
 Cambridge CB3 02D
 United Kingdom
 ☎ +44/223-323-010 Fax: +44/223-359-779

European Home Systems Association (EHSA)

The European Home Systems Association (EHSA) has been founded by members of the HOME (project 2431) consortium. Membership or associate membership of the Association is open to organizations, companies or individuals, both in Europe and beyond, who support the following aim: to enable the introduction of integrated applications in homes and buildings by supporting and promoting activities that lead to the harmonization and use of standards for homes and buildings throughout the world.

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 5600 MD Eindhoven
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 ☎ +31/ 40-734311 Fax: +31/ 40-732037

Peripherals

The objectives of this SIG are to:

- form a group of experts in the field of peripherals with a common interest in establishing a strong European R&D base
- propose actions to fill gaps in the overall European peripherals activity
- ensure that studies include an analysis of the evolution of the technology with respect to market opportunities
- redefine the notion of 'peripherals' with respect to newly emerging functionalities, manufacturing techniques and market approaches.

The group will meet at least three times a year. It is open to participants in Europe working in the field of peripherals technologies and sub-systems.

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Computer-integrated manufacturing

CIM-Europe

CIM-Europe, now in its seventh year, continued to expand its role in disseminating information about the progress, achievements and results of the Computer-integrated manufacturing (CIM) part of the ESPRIT programme both to the CIM R&D community and to manufacturing industry. 1990/91 was characterized by a continued emphasis on public events (the annual conferences and many workshops), and by an internal assessment of CIM-Europe's structure and operations, which resulted in the formulation of an action plan for the development of CIM-Europe's interest groups.

Two types of interest group are now distinguished: the first aims to bring related CIM project teams together, while the second type is centred around particular topics, and includes members of the wider CIM community as participants. Interest groups cover topics

Quality control: *The inspection of complex surfaces, such as the fan-blades pictured here, requires the intelligent processing of information derived from sensors and its comparison with CAD data about the product. CIM-Europe helps bring together members of the ESPRIT CIM and wider CIM community interested in this and many other topics.*



such as model-based predictive control, human and organizational factors in CIM, advanced robotics and intelligent sensors, and CIM architecture and communications. Over 20 technical and discussion meetings were organized in 1990/91. Special topic workshops were held on robotics (in Genoa), open systems architecture (Brussels), project 477 (Dublin, Turin and Eindhoven), project 623 (Berlin), model-based predictive control (Paris), project 809 (Twente), communications for manufacturing (a congress in Stuttgart), 'Implementing CIM' (Saarbrücken), and on project 2165, IMPACT (Berlin). In addition, sessions on ESPRIT CIM were held at the EuroPIA (Liège) and Robotics (Copenhagen) conferences.

The highlight of 1990 was the sixth annual conference, hosted by the Portuguese Ministry of Industry and Energy in Lisbon from 15 to 17 May. Over 300 delegates attended over 40 presentations. The seventh conference, with around 350 delegates, was held in Turin from 28 to 31 May 1991 and was co-hosted by Fiat.

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Basic research

High-temperature superconductivity (HTSC)

A high-level advisory panel composed of 12 European scientists and industry experts and chaired by Nobel Prize-winner K. A. Müller is advising the Commission on matters related to HTSC activities. In 1990 the panel met twice. In its first session a workplan for low-current applications was discussed and endorsed. The second session, which took place on 26 and 27 November in Strasbourg, was organized in tandem with a workshop where Community-funded HTSC projects presented their research work and results. The panel also advised the Commission on the preparation of a brochure on superconductivity.

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 ☎ +32/2-236-8078 Fax: +32/2-236-8390



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Commission of the European Communities
BA29 1/28
200 rue de la Loi
B-1049 Brussels*

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 Postfach 10-52-80
 Tiergartenstr. 17
 D-6900 Heidelberg

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 PO Box 211
 1000 AE Amsterdam
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 Roetersstraat 13
 1018 WB Amsterdam
 The Netherlands

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 D-5205 Sankt Augustin 1

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CIM-Europe SIG on advanced information processing (eds)
Advanced information processing in CIM
 CIM-Europe workshop proceedings, Bremen, 20 to 22 September 1989

CIM-Europe SIG on human factors in CIM (eds)
Human-centred CIM
 CIM-Europe workshop proceedings, Bremen, 20 to 22 September 1989

Richalet, J., Tzafestas, S. (eds)
Computer-integrated design of controlled industrial systems
 CIM-Europe workshop proceedings, Paris, 26 to 27 April 1990

Scheer, A-W. (ed)
Implementing CIM
 CIM-Europe workshop proceedings, Saarbrücken, 3 to 4 December 1990

CIM in the process industry
 CIM-Europe workshop proceedings, Athens, 20 to 21 June 1991

CNMA implementation guide, Rev. 4.1
 July 1990 (project 2617, CNMA)

Computer-integrated manufacturing open systems architecture
 CIM-Europe workshop proceedings, Brussels, 7 to 8 March 1990

Open systems architectures and communications: preparing the enterprise for CIM
 CIM-Europe workshop proceedings, Aachen, 13 and 14 June 1991

The above are available from:
 CIM-Europe Secretariat
 CEC - DG XIII/A6
 BA31 1/82
 200 rue de la Loi
 B-1049 Brussels



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Microelectronics

- 10**
High-level CAD for interactive layout and design
Bull, Daimler Benz, GEC, Plessey Company
- 14**
Advanced interconnect for VLSI
GEC, Plessey Company, Telefunken Electronic, Thomson-CSF
- 97** **CATHEDRAL**
Advanced algorithms, architecture and layout techniques for VLSI dedicated digital signal processing chips
Bell Telephone, IMEC, Philips, Ruhr-Universität Bochum, Siemens
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Compound semiconductor materials and integrated circuits - I
Philips, Plessey Company, Siemens, Thomson-CSF
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Submicron bipolar technology - I
Cemota, Plessey Company, Technische Universität Berlin, Telefunken Electronic, Thomson-CSF
- 244** **HYETI**
High-yield, high-reliability ULSI system
British Telecommunications, Bull, CEA, Cirrus Computer, IMAG-LGI, INPG, SGS-Thomson Microelectronics, Technische Hochschule Darmstadt, University of Brunel
- 245**
Silicon-on-insulator (SOI) materials and processing: towards 3-D integration
CEA, CNET, GEC, National Microelectronics Research Centre, SGS-Thomson Microelectronics, University of Cambridge
- 255**
CAD methods for analogue and GaAs monolithic ICs
CISE, Politecnico di Torino, Siemens, Telettra
- 263**
Integrated optoelectronics on InP
Alcatel, Alstom Recherche, CNET, CSELT, GEC Research, Marconi Research, Heinrich-Hertz, Standard Elektrik Lorenz, STC-ICL, Thomson-CSF
- 271** **ADVICE**
Automatic design validation of integrated circuits using E-beam
British Telecommunications, CNET, CSELT, IMAG-LGI, Trinity College Dublin
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Submicron bipolar technology - II
RTC, Siemens
- 305**
Assessment of silicon MBE layers
Daimler Benz, GEC, ISA Ribier
- 334**
Plasma deposition technology for magnetic recording thin-film media
BASF, Leybold Heraeus, SAGEM
- 369**
Physical-chemical characterization of silicon oxynitrides in relation to their electronic properties
IMEC, Matra-MHS, Philips, UKAEA, Universiteit van Utrecht
- 370**
Silicon-on-insulator systems combined with low-temperature silicon epitaxy
GEC, IMEC, Mietec
- 380**
Optical interconnect for VLSI and high bit-rate ICs
GEC Research, Marconi Research, Telettra, University of Southampton
- 412** **BiCMOS**
A high-performance CMOS bipolar process for VLSI circuits
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Molecular engineering for optoelectronics
CNET, ICI, Imagedata, Thomson-CSF, université Notre-Dame de la Paix
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Improvement of yield and performance of ICs by design centring
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Materials and technologies for high mobility TFTs for LC display-bus drivers
AEG, CNET, CSEE, Thomson-CSF
- 509**
Substrates for CMOS VLSI technology
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GEC, Thomson-CSF

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Daimler Benz, GEC, IMEC

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Compound semiconductor materials and integrated circuits - II
Bell Telephone, CNET, Farran Technology, GEC, STC-ICL, Telefunken Electronic

544

Investigation of all aspects of interconnection of high pincount ICs
BPA-Technology and Management, British Aerospace, Lucas, National Microelectronics Research Centre

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SPECTRE

Submicron CMOS technology
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High-resolution plasma etching in semiconductor technology: fundamentals, processing and equipment
Fraunhofer IM, Johnson Matthey Chemical, Leybold Heraeus, Mono Light Instruments, UKAEA

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CAD for VLSI systems
Alcatel, British Telecommunications, CNET, CSELT, Daimler-Benz Elektronik Centralen, GMD, Italtel Telematica, Matra-MHS, SGS-Thomson Microelectronics

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British Telecommunications, CEA, INPG, National Microelectronics Research Centre, SGS-Thomson Microelectronics, Technische Hochschule Darmstadt

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Packages for high-speed digital GaAs integrated circuits
Mo Valve Company, Thomson-CSF

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Large-area complex LCDs addressed by thin-film silicon transistors
AEG, Aristoteles University of Thessaloniki, CNET, GEC, Modulex, Thomson-CSF, Università di Bologna

843

Compound semiconductor ICs
Farran Technology, GEC, Philips, Plessey Company, Siemens, STC-ICL, Thomson-CSF

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ECIP

European CAD integration project
Alcatel, Bull, Philips, SGS-Thomson Microelectronics, Siemens, STC-ICL

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AIDA

Advanced IC design aids
SGS-Thomson Microelectronics, Siemens, STC-ICL

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Basic technologies for GaInAs MISFETs
Aixtron, Philips, RWTH Aachen, Wacker-Chemie

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High-density mass storage memories for knowledge and information storage
Bull, BASF, CEA/LETI, Thomson-CSF, Simulog, Glaverbel, Bogen Electronic

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High-performance VLSI packaging for complex electronic systems
British Telecommunications, Bull, GEC Research, Marconi Research

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Three-dimensional algorithms for robust and efficient semiconductor simulator
Analog Devices, GEC, IMEC, National Microelectronics Research Centre, Philips, Rutherford Appleton Laboratory, SGS-Thomson Microelectronics, STC-ICL, Trinity College Dublin, Università di Bologna, University College Swansea

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Technology of GaAs-GaAlAs bipolar integrated circuits
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Optical interconnect for VLSI and high bit-rate ICs
GEC Research, Marconi Research, Telettra, University of Southampton

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Multiview VLSI-design system ICD
British Telecommunications, ICS, INESC, PCS Computersysteme, Technische Universiteit Delft, Technische Universiteit Eindhoven, University of Essex

1007

0.5 micron X-ray lithography: sources, masks, resist and transferred image
CNR-IESS, CNRS, King's College London, SGS-Thomson Microelectronics, Thomson-CSF

1043

Advanced mask and reticle technology for VLSI submicron microelectronics devices
BMP Plasmatechnologie, British Telecommunications, Ferranti, IMEC, Siemens, Valvo Unternehmensbereich

1056

Ultrasensitive impurity analysis for semiconductor structures and materials
Cameca, IMEC, Philips Research Laboratories UK, Siemens

1058

Knowledge-based design assistant for modular VLSI design
IMEC, INESC, Philips

1128

Large diameter semi-insulating GaAs substrates suitable for LSI circuits
Philips, université catholique de Louvain, Wacker-Chemie

1270

Advanced processing technology for GaAs modulation doped transistors and lasers
CNET, Eltec, Forth Research Centre, Plessey, University of Wales

1551

AMS

Advanced manufacturing system
Marconi, SGS-Thomson Microelectronics

1563

ACAFS

Automatic control of an ASIC fabrication sequence as demonstrated in the plasma etch area
Bertin & Cie, European Silicon Structures, Leybold Heraeus, Mietec, Plasma Technology

2016

BASE

Bipolar advanced silicon for Europe

IMEC, Philips Gloeilampenfabrieken, Plessey, Ruhr-Universität Bochum, SGS-Thomson Microelectronics, Siemens Semiconductors, Technische Hochschule Darmstadt, Technische Universität Berlin, Telefunken Electronic, Trinity College Dublin, Università di Catania, Swindon Silicon Systems, DRA, National Technical University of Athens

2035

Advanced GaInAs-based transistors for high-speed integrated circuits

Farran Technology, Forth Research Centre, Philips, Picogiga, Plessey, STC-ICL, Thomson-CSF, Universidad Politécnica de Madrid, université de Lille

2039

APBB

Advanced PROM building blocks

Deister Electronic, Eurosil Electronic, Gemplus Card International, IMEC, INESC, INPG, Plessey, SGS-Thomson Microelectronics, Università di Bologna, University College Cork

2048

Deep UV lithography

ASM-Lithography, CEA/LETI, Carl Zeiss, Fraunhofer-IPA, Hoechst, Nederlandse Philips Bedrijven, Siemens, Siemens Semiconductors, University of Edinburgh

2072

ECIP

European CAD integration project

Bull, INESC, INPG, Institut méditerranéen de technologie, Nederlandse Philips Bedrijven, SGS-Thomson Microelectronics, Siemens, Siemens-Nixdorf, ICL, Universität Paderborn, Thomson-CSF, Thomson-CSF/SINTRA-ASM, UCI microélectronique, Rutherford Appleton Laboratories, University of Manchester, GMD

2075

APACHIP

Advanced packaging for high performance

Bull, GEC Research, Hoechst Ceramtec, MCTS, National Microelectronics Research Centre, Siemens-Nixdorf, Souriau & Cie, Technische Universität Berlin

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ADCIS

Analogue/digital CMOS ICs

Anacad-Computer Systems, CNM, CNET, Instituto Superior Técnico, Matra-MHS, Mietec, National Microelectronics Research Centre, Universidad de Sevilla

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STORM

Process modelling and device optimization for submicron technologies

CNET, CNR-Istituto Lamel, Fraunhofer IM, IMEC, National Microelectronics Research Centre, Plessey, SGS-Thomson Microelectronics, Università di Bologna

2260

SPRITE

Interactive silicon compilation for high-performance integrated systems

CGED, IMEC, INESC, Philips, Racal Research, DRA, Siemens

2265

DRYDEL

Dry develop optical lithography for ULSI

CEA, Farran Technology, IMEC, Philips, Plessey, Siemens, UCB Electronics

2268

CANDI

Combined analogue/digital integration

AEG, Alcatel, Standard Electrica, Dosis, Fraunhofer-IMSS, Plessey, SGS-Thomson Microelectronics, Telefunken Electronic, Thomson-CSF, Universität Dortmund, université Pierre et Marie Curie

2270

IDPS

Integrated design and production system

Bell Telephone, CNET, INMOS, Plessey, SGS-Thomson Microelectronics, Siemens, Siemens-Nixdorf, STC-ICL, Thomson-CSF

2272

SMILE

Technological feasibility of high-voltage smart-power ICs for lighting applications

Alcatel Standard Electrica, CNM, Elektronik Centralen, National Microelectronics Research Centre, Philips, SGS-Thomson Microelectronics, Università di Genova, Università di Pisa

2281

UNITED

High-T_c superconducting thin films and tunnel junction devices

CNRS, Philips, Thomson-CSF, université de Paris-VII, Universiteit Van Twente, University of Cambridge

2284

Optoelectronics with active organic molecules

CEA, CNET, ICI Imagedata, Thomson-CSF, université Notre-Dame de la Paix

2289

OLIVES

Optical interconnections for VLSI and electronic systems

AKZO International Research, CNM, Forth Research Centre, IMEC, Plessey, Siemens, STC-ICL, Swiss Federal Institute of Technology, Thomson-CSF, University College London

2318

EVEREST

European vanguard efforts on research and engineering of systems for testing

Bennetts Associates, Bull, Elektronik Centralen, Herie, IMEC, INESC, Philips, Scantest System, Siemens, Technische Universiteit Eindhoven, Telefónica, Universidad de Cantabria, Universidad Politécnica de Cataluña, Universidad Politécnica de Madrid, Universität Duisburg, Universität Gesamthochschule Siegen, université de Montpellier, University College Dublin, University Brunel, RE Technology

2319

ASIC multichamber rapid thermal processing with microwave enhancement

CEA, CNRS-LAAS, SGS-Thomson Microelectronics, Siteda, Addax, STC-ICL, University of Edinburgh

2394

ASAC

Application-specific architecture compilation

Bull, Hitec, INESC, Ing. C. Olivetti, SGS-Thomson Microelectronics, Siemens, STC-ICL, UMIST

2403

MCBRIDE

Development of a multichamber batch reactor for the production of multilayer interpoly dielectrics

AMTC, CEA/LETI, SGS-Thomson Microelectronics

2426

IDPS

Very fast implementation of complex systems on silicon

Bull Italia, Bull, ES2, IMEC, Marconi, Philips, Robert Bosch Silicon & Software Systems, University of Strathclyde

2430

BICMOS

A high-performance CMOS/bipolar process for VLSI circuits

Entwicklungszentrum für Mikroelektronik, INESC, Nederlandse Philips Bedrijven, Phoenix, VLSI Consultants, Siemens Semiconductors, Trinity College Dublin, Universität Stuttgart

2437

ICARE

Industrial characterization of an advanced resonant etcher

Alcatel, CEA-LETI, CNM, CNET, Nederlandse Philips Bedrijven, STC-ICL, Trinity College Dublin

2478

Research into boundary scan test implementation

Elektronik Centralen, INESC, Matra, Philips, SGS-Thomson Microelectronics, Siemens, Silicon & Software Systems, Thomson-CSF

2518
Wafer and epilayer improvement correlated with device performances for InP-based optoelectronics
 Aixtron, ICI Wafer Technology, Philips-LEP, RWTH Aachen

5002
New generation DUV-stepper optics
 ASM-Lithography, Carl Zeiss, Heraeus Quarzschmelze

5003 **PLANET**
Multiwafer planet MOVPE reactor
 Nederlandse Philips Bedrijven, Aixtron, Polyflow, Telefónica

5004 **SEDESES**
Selective deposition of silicides and epitaxial silicon
 Advanced Semiconductor Materials International, Alcatel, CNET, IMEC, National Microelectronics Research Centre, Siemens

5005 **ESD**
Protection for submicron technologies
 IMEC, Philips, Siemens, Technische Universität München

5014
Mask and reticle technology for advanced high-density and ASIC devices
 Balzers, BMP, Plasmatechnologie, Compugraphics International, IMEC, Polymer Laboratories, Semisystems, Siemens, Valvo Unternehmensbereich, Wild Leitz Instruments

5018 **COSMIC**
GaAs monolithic analogue circuits for microwave communication systems up to 23 GHz
 Argumens, CNET, Forth Research Centre, Fraunhofer-IIS, Ingenieurbüro für IMHT, Philips, Picogiga, Plessey, DRA, Siemens, Telefónica, Telettra, Università di Roma-La Sapienza

5020 **PATRICIA**
Proving and testability for reliability improvement of complex integrated architectures
 Abstract Hardware, GEC, Italtel Telematica, Politecnico di Milano, University of Bristol

5026 **METRICS**
High precision automated CD metrology station
 Nederlandse Philips Bedrijven, IMEC, Integrated Circuit Testing, Rutherford Appleton Laboratory, SGS-Thomson Microelectronics, Siemens, University of Edinburgh

5029 **SUBSOITEC**
High-performance submicron SOI/CMOS technologies
 CEA, CNRS-LPCS, Fraunhofer, Marconi, National Microelectronics Research Centre, Sextant Avionique, SGS-Thomson Microelectronics, Telefunken Systemtechnik, Thomson-CSF, University of Sheffield

5030 **FREE**
Fast reticle equipment for Europe
 ELISA, Cambridge Instruments, SGS-Thomson Microelectronics, Valvo Unternehmensbereich, University of Cambridge, Technische Universiteit Delft, National Research Centre 'Demokritos'

5031 **MOSDT**
Metal-organic research for semiconductor epitaxy
 Forth Research Centre, ISA Riber, DRA, RWTH Aachen, Thomson-CSF, CNET, Universität Stuttgart, CNR, Metaleurop Preussag Pure Metals, SMI Organometallic Division

5032 **AIMS**
Advanced integrated millimetre-wave subassemblies
 Alcatel, Daimler-Benz, Elektronik Centralen, Telefunken Electronic, Telefunken Systemtechnik, Thomson-CSF, université de Lille

5033 **PLASIC**
Performance and reliability of plastic encapsulated CMOS ASICs
 Elektronik Centralen, Mietec, National Microelectronics Research Centre, SGS-Thomson Microelectronics, Standard Elektrik Lorenz

5041 **PROMIMPS**
Process module integration for a multichamber production system
 Alcatel, AST Elektronik, Balzers, CEA, CSIC, Fraunhofer-IFT, Philips, Plasmos, SGS-Thomson Microelectronics, Siemens

5047 **QUICKCHIPS**
A very quick turnaround system for ASIC design and manufacturing supporting multiple design tools and implementation technologies
 INESC, CPRM, Milano Research Centre

5048 **ACCES**
ASIC 0.5 micron CMOS
 British Telecommunications, CNET, European Silicon Structures, IMEC, Matra-MHS, Mietec, Plessey, Standard Elektrik Lorenz, STC-ICL, Telefónica, Telefunken Electronic

5051 **MORECO**
Integrated circuits for mobile reader and communicator for ISO-standard smart-cards
 Telefónica Sistemas, Bull, Philips Composants, Telesincro, Sinory, ELGEIEC

5052 **MONOFAST**
Monolithic integration beyond 26.5 GHz
 Alcatel, Farran Technology, GAAS Code, National Microelectronics Research Centre, University of Cambridge, University of Glasgow

5056 **AD 2000**
Advanced CMOS analogue/digital and digital/analogue converters
 Instituto Superior Técnico, Italtel SIT, Universidad de Sevilla (AICIA), Università di Pavia, Fujitsu Spain

5075 **IDPS**
Integrated design and production system
 Philips International, Robert Bosch, ES2, SGS-Thomson Microelectronics, Siemens, Plessey, STC-ICL, Bull

5080 **JPL**
Joint logic project
 Philips International, ES2, Plessey, Siemens-Nixdorf, Telefunken Electronic, SGS-Thomson Microelectronic, Mietec, Matra-MHS

5081
Manufacturing science and technology
 Siemens-Nixdorf, ES2, Mietec, Plessey, SGS-Thomson Microelectronics, Telefunken Electronic, STC, Philips International, Matra-MHS

5082
JESSI CAD-frame
 Siemens-Nixdorf, Technische Universiteit Delft, ICL, Swedish Telecom, Siemens, SGS-Thomson Microelectronics, Nederlandse Philips Bedrijven, Bell Telephone, University of Manchester, Universität Paderborn, Fernuniversität Gesamthochschule Hagen, Swedish Institute of Microelectronics, Plessey, Forschungszentrum Informatik an der Universität Karlsruhe, IMEC, GMD, CNET, Robert Bosch

5083 **GAME**
Special action in microelectronics for Spain
 By mid-1991 over 30 projects had been proposed to the GAME committee for support under this action

5084 **CTA-SME**
Concerted technology access for small and medium-sized enterprises

5691 **AICI**
Special action in microelectronics for Portugal
 INESC, Animee, Tecmic, Challenge

5692 **VLSI-DPE**
Special action in microelectronics for Greece: Hellenic VLSI design and prototyping environment
 Intracom, Ergon, Zenon, University of Patras, National Technical University of Athinai, Computer Technology Institute, Forth Research Centre, University of Thrace Demokritos, NCSR Demokritos, L-Cube

Information processing systems

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Advanced algorithms and architectures for speech and image processing
 AEG, CSELT, GEC, Thomson-CSF, universit  Louis Pasteur de Strasbourg

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A basis for a portable common tool environment
 Bull, GEC Research, Marconi Research, Ing. C. Olivetti, Siemens-Nixdorf, STC-ICL

96 **ESB**
Expert system builder
 CIMSA, CSELT, Plessey, Søren T. Lyngsø, Tecsiel

107 **LOKI**
A logic-oriented approach to knowledge and databases supporting natural user interaction
 BIM, Cretan Computer Institute, Fraunhofer-IAO, Scicon, SCS Informationstechnik

112
Knowledge integration and management systems
 Alcatel, Alsthom Recherche, Bull, Siemens

125 **GRASPIN**
Personal workstation for incremental graphical specification and formal implementation of non-sequential systems
 ALGMD, Ing. C. Olivetti, Siemens, Tecsiel

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Time dependency and system modelling in KBS design for industrial process applications
 CISE, Framentec

266 **PEACOCK**
Software development using concurrently executable modules
 Eurosoft Systems, Hatfield Polytechnic, Roke Manor Research, Universit t Dortmund, Universit t Karlsruhe

267 **ASSET**
Automated support for software engineering technology
 GPP, Plessey

280 **EUROHELP**
Intelligent help for information systems users
 Courseware Europe, CRI, DDC/CRI, STC-ICL, University of Leeds

282 **SPMMS**
Software production and maintenance management support
 Data Management, GSI Tesci Software, Sema Metra Group, Siemens, Alcatel, Sofemasa, STC-ICL

283 **FOR-ME-TOO**
Formalisms, methods and tools
 Bull, CSELT, Siemens, Syseca

300 **REQUEST**
Reliability and quality of European software
 AEG, CISI, Elektronik Centralen, Esacontrol, GRS, BNR-Europe, Thomson-CSF, UKAEA

302
Investigation of performance achievable with highly concurrent interpretations of functional programs
 CAP, Sogeti Innovation, INRIA, STC-ICL, University of Stirling

304
Design of techniques and tools to aid in the analysis and design of knowledge-based systems
 Scicon, SCS Informationstechnik, South Bank Polytechnic, STC-ICL, Universiteit van Amsterdam

311 **ADKMS**
Advanced data and knowledge management systems
 Bull, Ing. C. Olivetti, Siemens-Nixdorf, Technische Universit t Berlin

315 **RAISE**
Rigorous approach to industrial software engineering
 Brown Boveri & Cie, CRI, STC-ICL

316 **ESTEAM**
An architecture for interactive problem solving by cooperating data and knowledge bases
 CAP Sogeti Innovation, CSELT, ONERA-Centre, Philips, Politecnico di Milano

348 **GIPE**
Generation of interactive programming environments
 BSO, CWI, INRIA, Sema Metra Group

387 **KRITIC**
Knowledge representation and inference techniques in industrial control
 British Telecommunications, Framentec, Krupp, Queen Mary College

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Program development by specification and transformation
 Alcatel Standard El ctrica, CRI, Syseca, System, Universit t Bremen, Universit t des Saarlandes, Universit t Dortmund, Universit t Passau, University of Strathclyde

393 **ACORD**
Construction and interrogation of knowledge bases using natural language text and graphics
 Alcatel, Alsthom Recherche, Bull, Triumph Adler

401 **ASPIS**
Application software prototype implementation system
 CAP, Sogeti Innovation, GEC Research, Marconi Research, Ing. C. Olivetti, Tecsiel, universit  Joseph Fourier (Grenoble)

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Software environment for the design of open distributed systems
 Agence de l'informatique, Bull, CNRS-LAAS, Politecnico di Milano, STC-ICL

415 **PALAVDA**
Parallel architectures and languages for AIP: a VLSI-directed approach
 CSELT, Daimler-Benz, GEC, Philips, Siemens-Nixdorf, Bull

419 **IMU**
Image and movement understanding
 Captec, Katholieke Universiteit Nijmegen, Trinity College Dublin, Università di Genova, Video Display Systems

432 **METEOR**
An integrated formal approach to industrial software development
 Alcatel, Alsthom Recherche, ATT Telecommunication, COPS, CWI, Philips, TXT, Universität Passau, université de Paris-Sud

440 **MADS**
Message-passing architectures and description systems
 Alcatel, Alsthom Recherche, Bell Telephone, Delphi, Vrije Universiteit Brussel

510 **TOOL-USE**
An advanced support environment for method-driven development and evolution of packaged software
 CISI, Generics Software, GMD, Onera-CERT, université catholique de Louvain

527 **CFID**
Communication failure in dialogue: techniques for detection and repair
 Alcatel-ESC, Linguistics Institute of Ireland, Memory Computer, St Patrick's College, Università di Pisa, University of Leeds

530 **EPSILON**
Advanced knowledge-based management system
 CRISS, Bense, INSA, Systems & Management, Università di Pisa, Universität Dortmund

532 **GENEDIS**
Real-time generation and display of 25-D sketches for moving scenes
 Barr & Stroud, University of Strathclyde, Zeltron

599 **EMG**
Knowledge-based assistant for electromyography
 CRI, Judex Datasystemer, Logica, NUC, University of London

814 **PIMS**
Project integrated management system
 BSO, CAP Gemini Sogeti, PA Consulting Group, Turing Institute

818 **DELTA-4**
Definition and design of an open dependable distributed computer system architecture
 Bull, CNR-IEI, CNRS-LAAS, Ferranti Computer Systems, Fraunhofer Institut für Information, IMAG-IGI, INESC, J-S Telecom, Mari Group, Telettra, Università di Bologna

820 **QUIC**
Design and experimentation of a KBS development tool-kit for real-time process control applications
 Aérospatiale, Ansaldo Impianti, CAP Gemini Sogeti, CISE, Framentec, FL Smidth, University of Heriot-Watt

835 **PROSPECTRA-D**
Demonstration of PROSPECTRA methodology and system
 Alcatel Standard Eléctrica, Syseca

857 **GRADIENT**
Graphics and knowledge-based dialogue for dynamic systems
 ABB Asea Brown Boveri, CRI, Katholieke Universiteit Leuven, Universität Kassel, University of Strathclyde

865 **MUMP**
Non-monotonic reasoning techniques for industrial planning applications
 Aeritalia, Battelle Institut, ELSAG

866 **COUSTO**
Integrated optical technologies for real-time wideband optical signal processing
 GEC Research, Marconi Research, Selenia, University College London

867 **ARTS-IP**
Adaptive real-time strategies for image processing: a case for satellite data
 Dornier System, ESIEE, GEC Research, Marconi Research, Hunting Technical Services, Politecnico di Milano, Polytechnic of Central London, Selenia, Thomson-CSF

874 **CONCORDIA**
Integrated environment for reliable systems
 J-S Telecommunications, Mari Group, Telettra, Università di Bologna

881 **FORFUN**
Formal description of arbitrary systems by means of functional languages
 Bell Telephone, Katholieke Universiteit Nijmegen, Sagantec, Technische Universiteit Delft

891
Development of an efficient functional programming system for the support of prototyping
 Non-standard Logics, STC-ICL, Universiteit van Twente, University of St Andrews

892 **DAIDA**
Advanced interactive development of data-intensive applications
 Forth Research Centre, BIM, GFI, SCS Informationstechnik, Universität Frankfurt, Universität Passau

898 **PHOX**
External interface for processing of 3-D holographic and X-ray images for analysis and control
 BIAS, GEC, IRAM, Scanray, Universität Dortmund

928 **RUBRIC**
A rule-based approach to information systems development
 BIM, James Martin Associates, Micro Focus, UMIST

937 **DESCARTES**
Debugging and specification of Ada real-time embedded systems
 Électronique Serge Dassault, Dassault-Breguet-Aviation, Foxboro Nederland, GSI, System, Technische Universiteit Eindhoven, University of Stirling

938 **IMPW**
Integrated management process workbench
 CETE Méditerranée, NIHE, STC-ICL, Imperial College of Science, Technology & Medicine, Verilog

940 **DMA**
Depth and motion analysis
 ELSAG, GEC, INRIA, ITMI, Matra, Noesis, Università di Genova, University of Cambridge

951 **PACT**
PCTE-added common tools
 Bull, Eurosoft Systems, GEC Software, Ing. C. Olivetti, Siemens, STC-ICL, Syseca, Systems and Management

967	PADMAVATI	1106	Prolog III
<i>Parallel associative development machine as a vehicle for artificial intelligence</i>		<i>Further development of Prolog and its validation by KBS in technical areas</i>	
CSELT, GEC, Thomson-CSF, First International		Daimler-Benz, GIT, Prologia, Robert Bosch, universit� d'Aix-Marseille	
973	ALPES	1117	KIWI
<i>Advanced logical programming environments support</i>		<i>Knowledge-based user-friendly system for the utilization of information bases</i>	
Bull, CRIL, Enidata, Technische Universit�t M�nchen, Universidade Nova de Lisboa, universit� de Paris-Sud		CRAI, DDC/CRI, Enidata, INRIA, Philips, Universit� di Roma-La Sapienza, Universitaire Instelling Antwerpen	
974	KNOSOS	1133	.ISIDE
<i>A knowledge-based environment for software system configuration reusing components</i>		<i>Advanced model for integration of DB and KB management systems</i>	
Alcatel, CNET, Dornier System, ESI, Matra, Yard Software Systems		Agusta, ARS, CRIL, INRIA, SAGEM, Simulog	
1005	MUST	1158	ATES
<i>Next-generation database management system</i>		<i>Advanced techniques integration into efficient scientific application software</i>	
ABSY, Syseca, Universit�t Kaiserslautern		CISI, Philips	
1015	PALABRE	1252	AMADEUS
<i>Integration of artificial intelligence, vocal input/output and natural language dialogue: application to directory services</i>		<i>A multi-method approach for developing universal specifications</i>	
British Telecommunications, CNET, CNRS, Sarin, Telematica, SESA		BIM, HITEC, Interprogram, Telef�nica CTNE, UMIST	
1033	FORMAST	1256	CHAMELEON
<i>Formal methods for asynchronous system technology</i>		<i>Dynamic software migration between cooperating environments</i>	
Advanced System Architectures, ERNO Raumfahrttechnik, Loughborough University of Technology, Imperial College of Science, Technology & Medicine, Universit�t Kaiserslautern		Delphi, Harlequin, Non-standard Logics	
1035	COOP	1257	MUSE
<i>2-D coherent optical dynamic processor</i>		<i>Software quality and reliability metrics for selected domains: safety management and clerical systems</i>	
GEC, Thomson-CSF, universit� libre de Bruxelles		Brameur, CRIL, EBO, TUV	
1041	GENESIS	1258	TRUST
<i>A general environment for formal systems development</i>		<i>Testing and consequent reliability estimation for real-time embedded software</i>	
Imperial Software Technology, Philips, Imperial College of Science, Technology & Medicine		Centre for Software Reliability, John Bell Technical Systems, LDRA, SES Software Engineering Services, University of Liverpool	
1063	INSTIL	1261	HTDS
<i>Integration of symbolic and numeric learning techniques</i>		<i>Host-target development system</i>	
Cognitech, GEC Research, Marconi Research, universit� de Paris-Sud		Logica, Marconi, SFGL, Softlab	
1072	DIAMOND	1262	SFINX
<i>Development and integration of accurate operations in numerical data processing</i>		<i>Software factory integration and experimentation</i>	
CWI, Numerical Algorithms Group, Siemens, Universit�t Karlsruhe		CRI, ERIA, Sema Group, SFGL, Tecnopolis Csata Novus Ortus	
1074		1265	SEDOS-D
<i>Shipboard installation of knowledge-based systems: conceptual design</i>		<i>SEDOS Estelle demonstrator</i>	
Danish Maritime Institute, Krupp, Lloyd's Register of Shipping, Soft International, Soren T. Lyngso, The East Asiatic Company, University of Athina		E2S, Marben, Verilog	
1085	SUPERNODE	1271	SED
<i>Development and application of a low-cost, high-performance multiprocessor machine</i>		<i>SETL experimentation and demonstrator</i>	
APSI, IMAG, INMOS, DRA, Thorn EMI, University of Southampton		CNAM, Enidata, Thomson-CSF, Universit�t Hildesheim, University of Patras	
1094	PRACTITIONER	1277	SAPPHIRE
<i>Support system for pragmatic reuse of software concepts</i>		<i>PCTE portability</i>	
Asea Brown Boveri, CRI, PCS Computersysteme, University of Brunel		GIE-�meraude, Sema Group UK, Software Sciences	
1098	KADS	1282	PAVE
<i>A methodology for the development of knowledge-based systems</i>		<i>PCTE and VMS environment</i>	
CAP Gemini Innovation, Scicon, SCS Informationstechnik, South Bank Polytechnic, STC-ICL, Universiteit van Amsterdam		GEC Software, Syseca	
		1283	VIP
		<i>VDM interfaces for PCTE</i>	
		Praxis Systems, CWI, OCE-Nederland	

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| <p>1520 ALF
 <i>Advanced software engineering environment logistics framework/Accueil de logiciel futur</i>
 Cerilor, Computer Technologies, CRIN/ADILOR, GIE-Émeraude, Grupo de Mecánica del Vuelo, STC-ICL, Universität Dortmund, université catholique de Louvain</p> | <p>1613 ITS
 <i>Evaluation of an intelligent tutoring system for industrial and office training</i>
 Shell, Datamat Ingegneria dei Sistemi, Education Technology Institute</p> |
| <p>1527 SPEM
 <i>Software productivity evaluation model</i>
 CERCI, Fuigi Italiana, O Dati Española, Sofemasa, UKAEA</p> | <p>2025 EDS
 <i>European declarative system</i>
 Bull, CCIP, Chorus Systèmes, Computer Technology Institute, European Computer Industry Research Centre, INESC, Infosys, INRIA, Siemens-Nixdorf, STC-ICL, Swedish Institute of Computer Science, Systems & Management, Telefónica, Imperial College of Science, Technology & Medicine, Universidad Politécnica de Cataluña, University of Athinai, University of Bristol, University of East Anglia, University of Heriot-Watt, University of Manchester</p> |
| <p>1532
 <i>A preliminary study of a vector processing-oriented parallel architecture</i>
 Bull, Siemens</p> | <p>2046 MERMAID
 <i>Metrication and resource modelling aid</i>
 Data Management, NCC, City University London, University College Cork, Volmac Software Groep</p> |
| <p>1535 APHRODITE
 <i>A PCTE host-target distributed testing environment</i>
 Bull, Chorus Systèmes, Delphi, Ferranti Computer Systems, Philips, université de Liège</p> | <p>2059 PYGMALION
 <i>Neurocomputing</i>
 Alcatel, Alsthom recherche, CEA-LETI, Computer Technology Institute, CSELT, École normale supérieure, INESC, INRIA, IRIAC, Philips, Politecnico di Torino, SGS-Thomson Microelectronics, Standard Elektrik Lorenz, Thomson-CSF, Universidad Politécnica de Madrid, université Joseph Fourier de Grenoble-I, University College London</p> |
| <p>1542 INDOC
 <i>Intelligent documents production demonstrator</i>
 ARG, Epsilon Software, INESC</p> | <p>2080 REX
 <i>Reconfigurable and extensible parallel and distributed systems</i>
 2I Industrial Informatics, GMD, GSI, Intracom, Siemens-Nixdorf, Stollmann, Technische Universität Berlin, Imperial College of Science, Technology & Medicine, Universität Karlsruhe, University of Oxford</p> |
| <p>1550 DRAGON
 <i>Distribution and reusability of Ada real-time applications through graceful and online operations</i>
 Dornier System, GSI, University College Wales Aberystwyth, University of Lancaster</p> | <p>2092 ANNIE
 <i>Application of neural networks for industry in Europe</i>
 Alpha SAI, Artificial Intelligence, British Aerospace, CETIM, IBP Pietzsch, Peat Marwick Consultants, Siemens, Technische Hochschule Darmstadt, UKAEA, University of Athinai</p> |
| <p>1558 EQUUS
 <i>Efficient qualitative and quantitative use of knowledge-based systems in financial management</i>
 Citymax, Riada & Co, University College London</p> | <p>2094 SUNSTAR
 <i>Integration and design of speech understanding interfaces</i>
 AEG Olympia, Alcatel Face Standard, Daimler-Benz, Fraunhofer-IPA, INESC, Jydsk Telefon, Telefónica, Universität Stuttgart</p> |
| <p>1560 SKIDS
 <i>Signal and knowledge integration with decisional control for multi-sensory systems</i>
 British Aerospace, CNRS-LAAS, Krupp, Maps Informática Industrial, Matra Rovsing, Universidad Politécnica de Cataluña, University of Oxford</p> | <p>2101 ARS
 <i>Adverse environment recognition of speech</i>
 CSELT, Logica, Matra, Page Iberica, Politecnico di Torino, Telecom Paris, Universidad Politécnica de Madrid, University of Cambridge, University of Keele</p> |
| <p>1570 ESCA
 <i>Application of expert systems to industrial chemical analysis</i>
 Katholieke Universiteit Nijmegen, Organon International, Philips Scientific, Vrije Universiteit Brussel</p> | <p>2104 POLYGLOT
 <i>Multi-language speech-to-text and text-to-speech system</i>
 Bull, CNRS-LIMSI, Katholieke Universiteit Nijmegen, Philips, Ruhr-Universität Bochum, Syntax Software Sistemi, Triumph Adler, Universidad Nacional de Educación, Universidad Politécnica de Madrid, University of Edinburgh, University of Patras, CRAI</p> |
| <p>1588 SPAN
 <i>Parallel computer systems for integrated numeric and symbolic processing</i>
 Computer Technology Institute, INESC, PCS Computersysteme, Thomson-CSF, Thorn EMI, University College London</p> | <p>2133 IMSE
 <i>An integrated modelling support environment</i>
 Fraunhofer, INRIA, Simulog, SINTEF Group, BNR Europe, Thomson-CSF (LCR), Thomson-CSF (CIM), Università degli Studi di Milano, Università degli Studi di Pavia, Università di Torino, Universität Dortmund, University of Edinburgh</p> |
| <p>1592 TAO
 <i>Therapy adviser for oncology</i>
 CITSA, Medimatica, University of Leeds</p> | <p>2148 VALID
 <i>Validation methods and tools for knowledge-based systems</i>
 Centre d'Estudis Avançades de Blanes, Cognitech, CRI, Universidad Politécnica de Madrid</p> |
| <p>1598 REPLAY
 <i>Replay and evaluation of software development plans using higher-order meta-systems</i>
 Alpha SAI, CISI, CRI, E2S, Onera-CERT</p> | <p>2151 SCOPE
 <i>Software certification on program in Europe</i>
 Cabinet Benoussan, CEA, City University London, Elektronik Centralen, ERIA, Enoteam, Glasgow College, GMD, GRS, NIHE, Technical Research Centre of Finland, TÜV Bayern, UKAEA, University of Strathclyde, Veridatas, Verilog</p> |
| <p>1609 SMART
 <i>System measurement and architectures techniques</i>
 CCS, CEA, CRI, Matra, Paisley College of Technology</p> | |

2152 VIEWS
Visual inspection and evaluation of wide-area scenes
 Framentec, Fraunhofer Institut für Information, GEC Research, Marconi Research, Krupp Atlas Elektronik, Thomson-CSF, Queen Mary & Westfield College, University of Reading

2154 MLT
Machine learning toolbox
 Alcatel, Alsthom Recherche, British Aerospace, Forth Research Centre, GMD, INRIA, I-Soft, Siemens-Nixdorf, Turing Institute, Universidade de Coimbra, université de Paris-Sud, University of Aberdeen

2163 KBS-SHIP
Shipboard installation of knowledge-based systems: design and installation
 Cambridge Consultants, Danish Maritime Institute, Danmarks Tekniske Højskole, Instituto Superior Técnico, Krupp, Lloyd's Register of Shipping, Soft International, Søren T. Lyngsø, The East Asiatic Company, University of Athinai

2167 AITRAS
An intelligent real-time coupled system for signal understanding
 Artificial Intelligence Systems, Cognitech, CRIN, Laborelec, Tecnatom

2177 GIPE II
Generation of interactive programming environments II
 ADVORGA FA Meyer, Bull, CWI, GIPSI, INRIA, Planet, PTT Research, Neher Laboratories, Sema Metra Group, Technische Universität Darmstadt, Universiteit van Amsterdam

2218 SUNDIAL
Speech understanding and dialogue
 CAP Gemini Innovation, CNET, CSELT, Daimler-Benz, IRISA, Logica, Politecnico di Torino, Saritel-Sarin, Telematica, Siemens-Nixdorf, Universität Erlangen-Nürnberg, University of Surrey

2252 DELTA-4
Definition and design of an open dependable distributed system architecture
 Bull, CNR-IEI, CNRS-LAAS, Ferranti Computer Systems, Fraunhofer Institut für Information, INESC, Mari Group, Renault Automation, Sema Metra Group, UKAEA, Unibanque, université Joseph Fourier de Grenoble-I, University of Newcastle

2255 TOPMUSS
Tools for processing multi-sensorial signals for plant monitoring and control
 Alcatel, Audi, Cegelec Projects, Danmarks Tekniske Højskole (IAL), DIESEL, Bailey Esacontrol, Fraunhofer IITB, Krupp Atlas Elektronik, Stewart Hughes, Universität Hannover (IFW), University of Brunel, Ruston Gas Turbines Engineering Research Centre

2256 ARCHON
Architecture for cooperative heterogenous online systems
 Amber, CEC-JRC Ispra Establishment, CERN, Electricity Association Services, Framentec, Iberduero, Krupp Atlas Elektronik, LABEIN, Queen Mary & Westfield College, Universidade do Porto, université libre de Bruxelles, Universiteit van Amsterdam, University of Athinai, Volmac Nederland

2288 NAOPIA
New architectures for optical processing in industrial applications
 Krupp, Risø National Laboratory, Thomson-CSF, Universität Erlangen-Nürnberg

2301 ORDIT
Development of a methodology for specifying non-functional requirements
 Algotech, Husat Research Centre, Mari Group, University of Newcastle, Work Research Centre

2304 LOTOSPHERE
Lotosphere
 Alcatel, Standard Electrica, Ascom Holding, British Telecommunications, CNR-IEI, CNRS-LAAS, CPR, GMD, INRIA, OCE-Nederland, PTT Research, Neher Laboratories, Syseca, Technische Universität Berlin, Tecciel, Universidad Politécnica de Madrid, Universiteit van Twente, University of Stirling

2316 MUSIP
Multisensor image processor
 GEC Research, Marconi Research, Hunting Technical Services, Marconi, MBB, Thomson-CSF, Università di Genova, University of Reading

2354 DARTS
Demonstration of advanced reliability techniques
 CEGB, Ceselsa, DSMC, EDF, GRS, UKAEA

2384 METKIT
Metrics education tool kit
 Brameur, British Telecommunications, CAP, DIDA*EL, GMD, SES, South Bank Polytechnic, Verilog

2397 PROMISE
Process operator's multimedia intelligent support environment
 Algotech, Dow Benelux, IDS, Katholieke Universiteit Leuven, Realice Scottish Power, Tecciel, University College Dublin, University of Strathclyde, Work Research Centre

2409 EQUATOR
Environment for qualitative temporal reasoning
 CENA, CISE, École polytechnique fédérale de Lausanne, Eria, ETRA, Ferranti Computer Systems, PTT Switzerland, Laben, Politecnico di Milano, SWIFT, Syseca, Imperial College of Science, Technology & Medicine, University College London

2424 KIWIS
Advanced knowledge-based environments for large database systems
 Alcatel, Bell Telephone, Craienidata, Origin/International Business Consultants, Philips, Swedish Institute of Computer Science, Università dell'Aquila, Università della Calabria, Universitaire Instelling Antwerpen, University of Kreta

2427 TROPICS
Transparent object-oriented parallel information computing system
 CAP Sogeti Innovation, CWI, Delphi, Infosys, Ing. C. Olivetti, Katholieke Universiteit Nijmegen, Philips, Siemens-Nixdorf, Stollmann, Thomson-CSF, Universiteit van Twente

2443 STRETCH
Extensible KBMS for large knowledge-based application
 Agusta, Alcatel Alsthom Recherche, Infosys, INRIA, MBP Software & Systems, Politecnico di Milano, STZ, TXT, Fernuniversität Gesamthochschule Hagen

2447 GENESIS
A European, distributed memory, parallel supercomputer for numerical applications
 Bull, Chorus Systèmes, GMD, DRA, Siemens, Syseca, University of Liverpool, University of Southampton

2469 TEMPORA
Integrating database technology, rule-based systems and temporal reasoning for effective software
 BIM, Hitec, Logic Programming Associates, Sintef, Swedish Institute of Computer Science, Sybase, Imperial College of Science, Technology & Medicine, université de Liège, University of Manchester

2471 PEPMA
Parallel execution of Prolog on multiprocessor architectures
 BIM, Katholieke Universiteit Leuven, Meiko, Swedish Institute of Computer Science, Universidad Politécnica de Madrid, University of Bristol

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| <p>2474 MMI2
 <i>A multi-modal interface for man-machine interaction with knowledge-based systems</i>
 ADR-CRISS, BIM, École des mines de Saint-Étienne, INRIA, INSOS, Rutherford Appleton Laboratory, University of Leeds</p> | <p>2686 COSMOS
 <i>Cost management with metrics of specification</i>
 Alcatel Austria — Elin, British Telecommunications, Nijenrode Universiteit voor Bedrijfskund, Techforce, Telefónica, University of London Goldsmith's College</p> |
| <p>2487 REDO
 <i>Maintenance, validation and documentation of software systems</i>
 Centrisa, Computer Technologies, Delft Hydraulics, Dr Jens Grumann Daten-Kommunikation, EDF, ITS, Lloyd's Register of Shipping, Marconi, NIHE, University of Oxford</p> | <p>2701 PUMA
 <i>Universal message-passing architectures</i>
 Bull, Chorus Systèmes, École normale supérieure, GMD, Inmos, DRA, Siemens, Syseca, University of Liverpool, University of Southampton</p> |
| <p>2502 VOILA
 <i>Variable object identification, location and acquisition</i>
 ELSAG, GEC, INRIA, Matra, Roke Manor Research, Università di Genova (DIST), Università di Genova (FISICA), University of Oxford, University of Sheffield</p> | <p>2702 GENESIS II
 <i>Development of a distributed memory MIMD system for very high performance numerical computing</i>
 Pallas, GMD, Krupp Atlas Elektronik, Stollmann, University of Southampton, University of Liverpool, Meiko Scientific, CHAM, TNO, Universität Wien, Universidad Politécnica de Cataluña, University of Jyväskylä, Tritech, Simulog, NA Software, European Centre for Medium-Range Weather Forecasts, INRIA, First International, Dornier Luftfahrt</p> |
| <p>2528 SUPERNODE II
 <i>Operating systems and programming environments for parallel computers</i>
 Aptor, Danish Parsim Consortium, Grupo APD, INPG, IPSYS Software, Numerical Algorithms Group, Ove Arup & Partners, DRA, Syseca, Telmat Informatique, Thorn EMI, Universidad Politécnica de Cataluña, University of Liverpool</p> | <p>2703 HSSC
 <i>High-speed scientific computer</i>
 ACRI</p> |
| <p>2537 ICARUS
 <i>Incremental construction and reuse of requirements specifications</i>
 Alcatel, Alstom Recherche, Alcatel Standard Eléctrica, INRIA, Sema Metra Group, Teice Control, université Notre-Dame de la Paix, Universidad Politécnica de Cataluña</p> | <p>2716 AMUS
 <i>A multiscalar supercomputer</i>
 ACRI, Forth Research Centre, EUCAD, SEKAS, Siemens Semiconductors, University of Manchester</p> |
| <p>2565 ATMOSPHERE
 <i>Advanced techniques and models of system production in a heterogeneous, extensible and rigorous environment</i>
 CAP Gemini Innovation, Bull, Siemens-Nixdorf, Nederlandse Philips Bedrijven, Siemens, GMD, 2I Industrial Informatics, Bull Italia, SERC, University of Strathclyde, Universität Dortmund, Universität Paderborn, Telesoft, SFGL, Sema Group, Nokia, Intecs Sistemi, GIE-Émeraude, Generics Software, GEI, Computer Technologies</p> | <p>5111 DOCKET
 <i>Document and code knowledge elicitation toolset</i>
 Computer Logic R&D, CRIAI, Software Engineering Service, SOGEI, UMIST, Universidade Portucalense</p> |
| <p>2570 MACS
 <i>Maintenance capability for software</i>
 Centro de Cálculo de Sabadell, CISI, SESA, Tecnopolis Csata Novus Ortus, Universität Bremen, Universiteit van Limburg</p> | <p>5143 ARTIST
 <i>Advanced reasoning tool for model-based diagnosis of industrial systems</i>
 CEPESA, CISE, Delphi, Heriot-Watt University, LABEIN, Siemens</p> |
| <p>2576 ACKNOWLEDGE
 <i>Acquisition of knowledge</i>
 CAP Gemini Innovation, Computas Expert Systems, GEC Research Marconi, Sintef, Group Telefónica, Universidad Politécnica de Madrid, Universiteit van Amsterdam, University of Nottingham</p> | <p>5146 REAKT
 <i>Environment and methodology for real-time knowledge-based systems</i>
 Comptas Expert Systems, CRIN, Etnoteam, Grupo de Mecánica del Vuelo, Marconi, Syseca, Thomson-CSF, Universidad Politécnica de Valencia</p> |
| <p>2589 SAM
 <i>Multi-lingual speech input/output: assessment, methodology and standardization</i>
 CNR, CRIN/Adilor, CSELT, Daimler-Benz, ELAB, Jydsk Telefon, Logica, National Physical Laboratory, PTT Research, Neher Laboratories, DRA, Ruhr-Universität Bochum, Smiths Industries Aerospace & Defence Systems, Televerket, The Royal Institute of Technology, TNO, Universität Bielefeld, University College London</p> | <p>5170 STATLOG
 <i>Comparative testing and evaluation of statistical and logical learning algorithms on large-scale applications for classification, prediction and control</i>
 Brainware, Daimler-Benz, Isoft, MBB, Turing Institute, Universidad de Granada, Universidade do Porto, Universität Lübeck, University of Strathclyde</p> |
| <p>2592 VIDIMUS
 <i>A generic vision system for industrial applications</i>
 British Aerospace, CEA-LETI, Daimler-Benz, Deutsche System-Technik, Ibermatica, Philips, Thomson-CSF, University of Strathclyde, Valvo Unternehmensbereich</p> | <p>5184 LOCOMOTI
 <i>Low-cost moving symbols recognition through intelligent vision engineering</i>
 Elliop, Katholieke Universiteit Leuven, Robert Bosch, Universidad Politécnica de Madrid</p> |
| <p>2615 ITSIE
 <i>Intelligent training systems in industrial environments</i>
 Alcatel, Alstom Recherche, CRI, CISE, Iberduero, LABEIN, Marconi, Universidad del País Vasco, University of Heriot-Watt</p> | <p>5192 SPELL
 <i>Interactive system for spoken European language training</i>
 Alcatel Face Standard, Oros, Tecnopolis Csata Novus Ortus, Università di Roma-La Sapienza, University of Edinburgh</p> |
| <p>2620 FOCUS
 <i>Front-ends for open and closed user systems</i>
 Indecon, Loughborough University of Technology, Metek, Numerical Algorithms Group, Philips, Solvay, Imperial College of Science, Technology & Medicine, Universidad Politécnica de Cataluña, Universität Münster</p> | <p>5204 PAPYRUS
 <i>Pen and paper input recognition using script</i>
 Active Book Company, CAPTEC, Katholieke Universiteit Nijmegen, Nottingham Polytechnic, Olivetti Systems & Networks, Pacer Systems, Università di Genova</p> |

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- 5210** **AIMS**
Advanced information management system
 Datamont Feruzzi Group, Deutsches Herzzentrum Berlin, ERIA, Non-standard Logics, ONERA-CERT, Quinary, Technische Universität Berlin, Universidad del País Vasco
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- 5212** **FASST**
Fault-tolerant architecture with stable storage technology
 August Systems, Bull, ETRA Electronic Traffic, INRIA, Stollmann, Toisys, Trinity College Dublin, Universidad Politécnica de Madrid, Universidad Politécnica de Valencia, University of Newcastle
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- 5225** **ARVISA**
Advanced real-time vision system and architecture
 Carl Zeiss, CEA, ELSAG, FIM-FGAN, Fraunhofer-ISI, INPG, Kontron Elektronik, Krupp Atlas Elektronik, Matra, Philips, Signum Computer, Thomson-CSF, Universidad Politécnica de Cataluña, VTE
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- 5246** **PRINCE**
Prolog integrated with constraints and environment for industrial and financial applications
 Banque La Henin, BIM, Daimler-Benz, FAW, Katholieke Universiteit Leuven, Prologia, Robert Bosch, Universidad Politécnica de Madrid, université d'Aix-Marseille, University of Bristol
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- 5248** **KADS-II**
An advanced and comprehensive methodology for integrated KBS development
 CAP Gemini Logic, CAP Sogeti Innovation, ECN, Entel, IBM France, Lloyd's Register of Shipping, Siemens, Swedish Institute of Computer Science, Touche Ross Management Consultants, Universiteit van Amsterdam, Vrije Universiteit Brussel
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- 5254** **PLUS**
A pragmatic-based language understanding system
 CAP Gemini Innovation, CNRS-LIMSI, ITK, Omega Generation, CAP Gemini SCS Becom, UMIST, Università di Pisa, University of Bristol, University of Göteborg, Katholieke Universiteit Brabant (ITK)
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- 5291** **CHIC**
Constraint handling in industry and commerce
 AIS, Avions Marcel Dassault, Braghenti, Bull, CMSU, ECRC, ETRA, Iberia Líneas Aéreas de España, Onera-Cert, Renault RNUR, Siemens, STC-ICL, Imperial College of Science, Technology & Medicine
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- 5293** **GALATEA**
Neurocomputing
 Computer Technology Institute, CRAM, INESC Informatica Sistemi, INPG, Philips, SGS-Thomson Microelectronics, Siemens, Thomson-CSF, University College London
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- 5304** **MULTILEX**
A multi-functional standardized lexicon
 CAP Gemini Innovation, Fraunhofer-IAO, GETA, L-Cube Information Systems, Lexicon, Philips, Ruhr-Universität Bochum, Siemens-Nixdorf Informationssystem, Siemens-Nixdorf Sistemas de Información, Triumph Adler, Università di Pisa, université de Paris-VII, Vrije Universiteit Amsterdam, University of Manchester, University of Surrey
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- 5311** **BUSINESS**
Business class
 Applied Logic Research, Datamont, Feruzzi Group, ERIA, Etnoteam, Société des outils du logiciel, TAO, Télé systèmes, université de Nice
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- 5312** **EMIR**
European multilingual information retrieval
 CEA, Systex, Transmodul, université de Liège
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- 5327** **REBOOT**
Reuse bases on object-oriented techniques
 Bull, CAP Sogeti Innovation, INPG, Sema Group, Siemens, Sintef, Televerket, TXT
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- 5330** **NOMOS**
Knowledge acquisition for normative reasoning systems
 Axon, CNR-IDG, Hellaslex, INESC, IRETIJ, SOGEI, STEP-Informatique, Tecsiel
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- 5342** **PROOFS**
Promotion of formal methods in the European software industry
 Entel, France câbles et radio, Prisma Informatica, Sligos, Technische Universiteit Eindhoven, TNO
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- 5345** **DIMUS**
Data integration in multisensor systems
 Ansaldo, ELSAG, Istituto Trentino di Cultura, Signum Computer, Technische Universität München, Thomson-CSF, Università di Genova
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- 5362** **IMAGINE**
Integrated multi-agent interactive environment
 Intrasoft, Rijksuniversiteit Leiden, Roke Manor Research, Siemens, Steria, Imperial College of Science, Technology & Medicine, University of Keele
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- 5363** **GLAD-IN-ART**
Glove-like advanced interface for the control of manipulative and exploratory procedures in artificial realities
 AITEK, Eeidetics, Scuola Superiore, Technology Applications Group, Trinity College Dublin, Video Display Systems
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- 5365** **VITAL**
A methodology-based workbench for KBS life-cycle support
 Andersen Consulting, Bull, Koninklijke PTT Nederland, Nokia Research Centre, Onera-Cert, Open University, Syseca, University of Nottingham
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- 5375** **ISSS**
Intelligent signals, sensors and surveillance
 Academisch Ziekenhuis Rotterdam, Aristoteles University of Thessaloniki, Daltek, IBC-DANICA, Philips, Scaitech
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- 5383** **LACOS**
Large-scale correct systems using formal methods
 Bull, CRI, INISEL, Lloyd's Register of Shipping, Matra, Space Software Italia, STC-ICL, Sypro København, Technisystems
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- 5390** **RTGC**
Real-time gaze control
 GEC, INRIA, SAGEM, University of Oxford
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- 5398** **SHAPE**
Second-generation hypermedia application project environment
 Alcatel, Bureau Marcel van Dijk, Datamont Feruzzi Group, Transtools, University of Glasgow
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- 5399** **COMPARE**
Compiler generation for parallel machines
 ACE, CWI, GMD, Harlequin, INRIA, Steria, Universität des Saarlandes
-
- 5404** **GP MIMD**
General-purpose MIMD machines
 CERN, Grupo Apd, INESC, Inmos, IRISA, Meiko Scientific, Parsys, Parsytec, Siemens, Swedish Institute of Computer Science, University of Southampton
-
- 5409** **COMPLEMENT**
Comprehensive large-scale engineering methodologies and training
 British Aerospace, CEGELEC, GEI, HCS Industrial Automation, Intrasoft, Ipsys Software, IRT, Matra, RWTH Aachen, SAS, Software Ireland, Syseca, Systems Designers Europe, Universidad de Murcia, University of Southampton, University of Ulster, Veridatas
-
- 5425** **PYRAMID**
Promotion of metrics
 Brameur, Desisco, Euroexpert & Partners, Siemens, Veridatas

5429 **MUSIC**

Metrics for usability standards in computing
 Veriditas-Brameur, Data Management, Ergonomic Institut, Husat Research Centre, National Physical Laboratory, SEMA Group, Technische Universiteit Delft, Universitat Múnster, University College Cork

5433 **NEUFODI**

Neural networks for forecasting and diagnosis applications
 Austrian Research Institute of Artificial Intelligence, BIKIT, EYS, KTAS, LABEIN, Société lyonnaise des eaux

5441 **BOOTSTRAP**

Bootstrap
 2I Industrial Informatics, E2S, Etnoteam, Robert Bosch, Technische Universität Graz

5473 **PAYDIRT**

Processing architecture yielding deductions in real time
 Krupp, Atlas Elektronik Bremen, Lloyd's Register of Shipping, SINAPSE, Société lyonnaise des eaux

5477 **CONSTRUCT**

Computer-aided knowledge engineering for construction tasks
 Renault automation, Siscog, Vrije Universiteit Brussel

5494 **AMI**

Applications of metrics in industry
 Advanced Software Technology, Alcatel Austria — ELIN, Bull, Corelis Technologie, GEC Alsthom, GEC Marconi, ITS, RWTÜV, South Bank Polytechnic

5516 **ROARS**

Robust analytical speech recognition system
 CRIN, ENA Telecomunicaciones, Thomson-CSF, Universidad Politécnica de Valencia

5570 **IPTES**

Incremental prototyping technology for embedded real-time systems
 CEA, ENEA, IFAD, Mari Group, Politecnico di Milano, Technical Research Centre of Finland, Telefónica, Universidad Politécnica de Madrid

5661 **STANDARDIZATION**

Standardization for object-oriented systems
 D-Tech, INTECS International, Teclab

5662 **SOFTWARE TOOLS**

Software tools: intercommunications
 Dr Jens Grumann, Daten-Kommunikation, Software España, Systems & Management, Téchforce

5663 **REAL-TIME**

Real-time systems
 Autograph International, CSC, Diseño y Metodología, Intron, Katholieke Universiteit Leuven, System

5664

Multimedia systems and human-computer interface
 Envirotech International, Epsilon Software, Selisa, Silvertch

5665

Trends in operating systems for parallel computing
 GPR, Standard International Consulting

5666

Massively parallel platform
 Active Memory Technology, Dancomp (Decanter, Richter & Rosenstand), PCS Computersysteme, Pliroforiki, TECMIC

5667

Parallelizing tools
 AIIIT, Elabodater, Parseq, TNO, Tritech

5668

Neural computing
 ARITEX, DIDA*EL, IBP Pietzsch, Jenni-International User Group, Software de Base

5669

Measurement of advanced architecture
 Algotech, First International, Mental Images, Simulog

5670

Fault-tolerant systems
 SEPA, Software Científico y Técnico, Verilog

5671

Improvement of complex systems using KB techniques
 Corelis Technologie, Ingegneria Informatica, Knossos Technologies, Søren T. Lyngsø, Vision Computing

5672

Vision systems
 Athinai Technology Centre, INTECS International, Maptel

5673

Multisensor systems
 AIIIT, And Software, Universidade de Coimbra, Zenon

5674

Quality assessment in KBS
 AITEC, Cetena, IGC, LDRA

5675 **AMKBS**

Applications of multi-agent KBS
 Artificial Intelligence Systems, Elabodater, Indecon, Advanced Technology, Instituto Superior Técnico, PROSS

5676 **PCTE**

PCTE policy options
 Elios informatique, Generics Software, GMD, OVUM

5677 **ROBUST**

Robust speech understanding
 ENA Telecomunicaciones, Knowledge, Lernout & Hauspie Speech Products

PARALLEL COMPUTING ACTION **PCA**

LRI Lab. de Recherche Vidal-Naquet en Informatique, Universidad Politécnica de Madrid, Technische Universität Berlin, University of Thessaloniki, Technische Hochschule Darmstadt, University of Athinai, Universität Erlangen-Nürnberg, Johann Wolfgang von Goethe Universität Frankfurt, Odense Universitet, Università di Bologna, université de L'État à Mons, Polytechnic of Central London, Politecnico di Milano, Universität Karlsruhe, Universität Köln, National Technical University of Athinai, Technische Universiteit Eindhoven, Università di Bari, Katholieke Universiteit Leuven, Universität Paderborn, Rijksuniversiteit Gent, TNO, Onera-CERT, Vrije Universiteit Brussel, University of Sheffield, CNR, University College London, Trinity College Dublin, Università di Genova, University of London (Birkbeck College), University College of North Wales, IFISIC-Rennes, University of Bristol, Katholieke Universiteit Nijmegen, University of Reading, Universität Bremen, INESC, Universiteit Twente, Universiteit Kaiserslautern, Universidade do Porto, Universidade Nova de Lisboa, université Louis Pasteur (Strasbourg), Universidad Politécnica de Cataluña, University of Ulster, Università di Torino, CSIC, INT, université de Bourgogne, Alborg Universitet, Università di Roma II, université de Franche-Comté, université Pierre et Marie Curie

Advanced business and home systems — Peripherals

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 <i>A multimedia filing system</i>
 Battelle Institut, CNR-IEI, Cretan Computer Institute, Epsilon Software, ERIA, Ing. C. Olivetti, Philips, Triumph Adler</p> | <p>285 OSSAD
 <i>Office support systems analysis and design</i>
 Centre d'études du management, IOT, CRI, Università degli Studi di Milano</p> |
| <p>43 E-INTERFACE
 <i>Standardization of integrated LAN services and service access protocols</i>
 Alcatel, British Telecommunications, Bull, CAP Gemini, Sogeti, CSELT, GEC Research, Marconi Research, OCE-Nederland, Philips International, Plessey, RCE, Roke Manor Research, Siemens-Nixdorf, Universiteit van Twente</p> | <p>291 LING-ANALYSIS
 <i>Linguistic analysis of the European languages</i>
 Acorn Computers, CNRS-LIMSI, Ing. C. Olivetti, Katholieke Universiteit Nijmegen, Ruhr-Universität Bochum, Tecnopolis Csata Novus Ortus, Universidad Nacional de Educacione, University of Patras</p> |
| <p>56 FAOR
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 GMD, STC-ICL, The East Asiatic Company, Universität Köln-BIFOA</p> | <p>295 PAPER
 <i>The paper interface</i>
 AEG Electrocom, Ing. C. Olivetti, Philips, Plessey</p> |
| <p>59 MINSTREL
 <i>New information models for office filing and retrieval</i>
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 <i>Secure, open, multimedia integrated workstation</i>
 AEG Electrocom, Bull, CSELT, INESC, INRIA, Italtel Telematica, RITEL, SCK-CEN, Sema Group Belgium</p> |
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 <i>Human factors laboratories in information technologies</i>
 Bull, Fraunhofer-IAO, Husat Research Centre, Ing. C. Olivetti, Philips, Piraeus Graduate School, Siemens, STC-ICL, Universidade do Minho, Universität Münster, University College Cork</p> |
| <p>73 BWN
 <i>Broad-site local wideband communication system</i>
 CEC, Bell Telephone, CISI, CMSU, France câbles et radio, SG2, Informatique Stollmann, université de Liège</p> | <p>395 INCA
 <i>An integrated network architecture for office communications</i>
 GEC, Ing. C. Olivetti, Modcomp, Siemens-Nixdorf, Systems Wizards, University College London</p> |
| <p>82 IWS
 <i>Intelligent workstation</i>
 Bull, Forth Research Centre, INRIA, Katholieke Universiteit Nijmegen, OCE-Nederland, Vrije Universiteit Brussel</p> | <p>449 SPEECH
 <i>Investigation into the effective use of speech at the human-machine interface</i>
 British Maritime Technology, Cortec, Fincantieri, STC-ICL, Voice Input</p> |
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 Alcatel, CRIN, Siemens</p> | <p>563 PICA
 <i>A high compression picture-coding algorithm for videotex</i>
 British Telecommunications, CCETT, CSELT, IBA, KTAS, PTT Research, Siemens-Nixdorf</p> |
| <p>169 LION
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 Alcatel, British Telecommunications, CSELT, Politecnico di Milano, université de Paris, université Paul Batier de Toulouse, University of Patras</p> | <p>612 MODEL-DISPLAY
 <i>Modelling and simulation of the visual characteristics of modern display technologies under office work conditions</i>
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| <p>231 DOEOIS
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 Bull, STC-ICL, Trinity College Dublin, Universität Stuttgart</p> | <p>813 TODOS
 <i>Tools for designing office systems</i>
 CNR-IEI, Dornier System, Italtel Telematica, OCE, Politecnico di Milano, Sema Metra Group, Systems & Management, Thomson-CSF, Universität Köln-BIFOA, université de Paris-I</p> |
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 <i>Cognitive simulator for user interface design</i>
 Alcatel-ESC, GEC, Logos Progetti, Medical Research Council</p> | <p>831 ASTRA
 <i>Advanced and integrated office systems prototypes for European public administrations</i>
 Bull, Cesia, CRIAI Datacentral, Datenzentrale Schleswig-Holstein, GSI, Ing. C. Olivetti, MC2, Silogia, Sogei</p> |
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 <i>Communications systems architecture</i>
 ITK, Mari Group, Philips, Roke Manor Research, SYD</p> | <p>834 COMANDOS
 <i>Construction and management of distributed office systems</i>
 ARG, Bull, CNR-IEI, Fraunhofer IM, IMAG, INESC, Ing. C. Olivetti, Siemens-Nixdorf, STC-ICL, Trinity College Dublin, Universität Stuttgart</p> |
| <p>249 UCOL-1
 <i>Ultra-wideband optical coherent LAN</i>
 Alcatel, Face Standard, GEC Research, Marconi Research, Politecnico di Milano</p> | <p>853 TRUE-COLOUR
 <i>Acquisition, compression and reproduction of true-colour image documents</i>
 Ing. C. Olivetti, Intersys Graphic, Katholieke Universiteit Leuven</p> |

855 **TYPEWRITERS**

European typewriters and other workstations integration
AEG Olympia, Ing. C. Olivetti, Politecnico di Torino, Triumph Adler

870 **TALON**

Testing and analysis of local area optical networks
Cossor Electronics, NKT Elektronik

878 **PROMINAND**

Extended office process migration with interactive panel displays
IAB, Modulex, Risø National Laboratory, Scaitech, Technische Universität München

890 **PANGLOSS**

Parallel architecture for networking gateways linking OSI systems
7-Technologies, CAP, PCS Computersysteme, université de Liège, Universiteit van Twente, University of Reading

901 **DOMESDAY**

An intelligent general public data, voice and picture storage retrieval system
BBC, Bureau van Dijk, CRIN, Logica, Philips Gloelampenfabrieken

925 **CODING-256**

Coding for moving pictures and still pictures at 256 Kbit/s and 64 Kbit/s
Alcatel, GEC, Philips, Société anonyme de télécommunication, Sepa, Telefónica

954 **IKAROS**

Intelligence and knowledge-aided recognition of speech
Alcatel, Alsthom Recherche, Fraunhofer-IAO, GEC, Universität Stuttgart

956 **COCOS**

Components for future computing systems
Bull, Ing. C. Olivetti, INRIA, SGS-Thomson Microelectronics, Siemens-Nixdorf, STC-ICL

998 **MARS**

Highly secure office information systems
Bertin & Cie, COPS, Protexarms Rovsing, Universität Köln-BIFOA, University of East Anglia

1024 **PODA**

Piloting the office document architecture
Alcatel, Bull, Ing. C. Olivetti, OCE-Nederland, Siemens, Siemens-Nixdorf, STC-ICL, Syntax Software Sistemi, Queen Mary & Westfield College, University College London

1030 **IT-UPTAKE**

Human and economic factors in IT uptake processes
Empirica, Irish Medical Systems, STC-ICL, Work Research Centre

1051 **A-Si IMAGER**

Amorphous silicon contact imager for office and graphic applications
Agfa Gevaert, CNRS-Lepsi, IMEC, MBB

1057 **MIAC**

Multipoint interactive audiovisual communication
Alcatel, Face Standard, British Telecommunications, CNET, CSELT, PTT Research, Neher Laboratories, STC-ICL, Telefónica, Thomson-CSF

1059 **DAMS-1**

Dynamically adaptable multi-service switch
J-S Telecom, Roke Manor Research, TN Telenorma

1533 **MIS**

Multilingual information system
Bull, Ing. C. Olivetti, Siemens-Nixdorf, STC-ICL

1541 **MULTILINGUA**

Multilingual speech input-output assessment, methodology and standardization
CNET, CSELT, Jydsk Telefon, Universiteit van Amsterdam, University College London

1573 **IBASS**

Intelligent business application support system
Bull, Datamont, Feruzzi Group, Langton, Siemens-Nixdorf, South Bank Polytechnic

2001 **SPRITE**

Storage, processing and retrieval of information in a technical environment
ADV/ORGA FA Meyer, AEG Electrocom, Alcatel, Armines, Katholieke Universiteit Brabant, OCE-Nederland, Trinity College Dublin, Universität Hamburg, Daimler-Benz, Akademie der Wissenschaft

2013 **MAGNOPTIC**

Development of European magneto-optical drives
CEA, Coventry Polytechnic, NIHE, GEM, Olivetti Systems & Networks, Philips Nederland, Philips Dupont Optical

2054 **UCOL-2**

Ultra-wideband coherent optical LAN
Alcatel, Alsthom Recherche, Face Standard, COSI, Daimler-Benz, IDATE-Yves Gassot, INESC, PTT Research, Neher Laboratories, Standard Elektrik Lorenz, STC-ICL, Telettra España, University of Southampton

2058 **ICI**

Intelligent communication interface
British Telecommunications, SAIT Electronics, Universidad Politécnica de Cataluña, Universidad Politécnica de Madrid

2071 **COMANDOS-2**

Construction and management of distributed open systems
Bull, Chorus Systèmes, Fraunhofer-ITW, IMAG-LGI, INESC, Siemens-Nixdorf, Trinity College Dublin, Universidad Politécnica de Cataluña, Universität Stuttgart, University of Glasgow

2082 **HECTOR**

Harmonized European concepts and tools for organizational information systems
CAP Sogeti Innovation, CRAI, Delga International, Dornier Systems, Fraunhofer-IPA, IOT, KPMG-Peat Marwick McLintock, PA Consulting Group, Universität Köln-BIFOA

2083 **SIMPR**

Structured information management: processing and retrieval
CAP Gemini Europe, CRI, Dublin City University, Nokia, Research Unit for Computational Linguistics, Universidade Católica Portuguesa, Universiteit van Amsterdam, University College Dublin, University of Strathclyde

2100 **MAX**

Metropolitan area communication system
3IT, Alcatel, CSELT, Hewlett-Packard, KTAS, L-Cube Information Systems, NKT, Sirti, université de Paris-VI, University of Patras

2102 **COMIS**

Standard for coding moving images on digital storage media
British Telecommunications, CNET, CSELT, Deutsche Thomson-Brandt, Eikon, Inmos, Halbleiterwerk der Deutsche, Philips Research Laboratories UK, PTT Research, Neher Laboratories, Sidac, Thomson-CSF, TN Telenorma, Universität Hannover

2103 **MASCOT**

Multi-environment advanced system for colour treatment
Computer Logic R&D, Hitec, ICI, Ing. C. Olivetti, Katholieke Universiteit Leuven, Kern & Co, OIS, Syntax Software Sistemi, Thomson-CSF

- 2105** **MULTIWORKS**
Multimedia integrated workstations
 Acorn Computers, AEG Olympia, Bull, Chorus Systèmes, Daimler-Benz, GMD, Harlequin, Ing. C. Olivetti, INPG, INRIA, Philips, Polytechnic of Kreta, SGS-Thomson Microelectronics, Triumph-Adler, Tecnopolis Csata Novus Ortus, Télésystèmes
- 2109** **TOOTSI**
Telematic object-oriented tools for services interfaces
 Algotech, ARG, Centro di Cultura Scientifica — A. Volta, Desarrollo de Software, Infotap, Politecnico di Milano, Saritel, Sophiatec, Télésystèmes, université de Nice-Lisan, System & Management
- 2111** **PONTIFEX**
Planning of non-specific transportation by an intelligent fleet expert
 Aeritalia, CAP Gemini Europe, CNR-IASI, Iberia Lineas Aéreas de España, Siemens-Nixdorf, O Dati Española SL, Sipe Optimization, TAP Air Portugal, Trademco Trut — Kykloforiaki
- 2114** **LSVI**
Large-size visual interface design for multimedia workstation terminals
 Pilkington, Standard Elektrik Lorenz, Thomson-CSF
- 2121** **ITHACA 1**
Integrated toolkit for highly advanced computer applications
 Bull, CAP Sogeti Innovation, CNRS-LADL, Communication and Management System Unit, D-TECH, Datamont Feruzzi Group, Delphi, E2S, Forth Research Centre, INRIA, Politecnico di Milano, Siemens-Nixdorf, TAO, Trinity College Dublin, Università degli Studi di Milano, Universität Karlsruhe, université de Genève
- 2125** **ETR**
Electrothermal ribbon
 AEG Olympia, Baltea, Ing. C. Olivetti, Manchester Polytechnic
- 2144** **IT-USE**
Information technology uptake support environment
 Datacentralen, Futurmedia, Groningen University, Handelshøjskolen i København, Irish Medical Systems, Memory Computer, Work Research Centre
- 2146** **DAMS-2**
Dynamically adaptable multiservice system
 INESC, J-S Telecom, RWTH Aachen, STC-ICL, TN Telenorma, Universidad Politécnica de Madrid, Universität Kaiserslautern, Universität Stuttgart, University of Patras
- 2170** **SUPERDOC**
A set of software tools for a document workstation
 Addax, Bull Italia, Epsilon Software, INESC, Lombardia Informatica, Politecnico di Milano, Selisa, Sistemas Multiposto e Distribuidos, Strategic International, Teseo
- 2221** **RICHE**
Health services information and communication network for Europe
 Actir-Sante, Bazisleid, Bull, GESI, IRIAM Irish Medical Systems, Lombardia Informatica, SIG Services, STAF-Conseil de Filière, Università Cattolica del Sacro Cuore, NHS Management Information Centre
- 2239** **SESEFA**
Self-service facilities architecture
 ERIA, IKOSS-Software Service, Prisma Informatica, Silogia, Università di Firenze, ERITEL
- 2267** **ISA**
Integrated systems architecture for ODP
 British Telecommunications, CASEG, Chorus Systèmes, CNET, Computer Technology Institute, Deutsche Thomson-Brandt, Daimler-Benz, Digital Equipment, GEC Marconi, GEC Plessey Telecommunications, GESI, Hewlett-Packard, Modcomp, Philips International, Siemens, STC-ICL, Syseca, Televerket
- 2283** **MATRIX-LCD**
Active matrix LCD for TV and office systems
 AEG, Aristoteles University of Thessaloniki, GEC, IMEC, Rytrak Seleco, Thomson-CSF, Thomson-LCD
- 2294** **TOBIAS**
Tools for object-based integrated administration systems
 GIE-Émeraude, Intecs International, Intrasoft Planet, University of Newcastle
- 2315** **TWB**
Translator's workbench
 Mercedes Benz, Fraunhofer-IPA, L-Cube Information Systems, Siemens-Nixdorf, SPAI, Triumph Adler, Universidad Politécnica de Cataluña, SNI CDS
- 2322** **ISEM**
IT support for emergency management
 ADVORGA FA Meyer, ENEA, GRS, IGC, Jydske Telefon, Risø National Laboratory, SCK-CEN, Studsvik Nuclear Technical Research Centre Finland, Tecnatom, Técnicas Reunidas, Uitesa
- 2360** **FELICITA**
Development of ferroelectric liquid crystal devices for information technology applications
 BDH, GEC, Lagerwall RL, Merck, OCE-Nederland, Robert Bosch, DRA, Seleco, Thomson-CSF, Thorn EMI, Universidad Politécnica de Madrid, Università di Bari, University of Hull
- 2374** **PODA-2**
Piloting of the office document architecture
 ICL, British Telecommunications, Siemens-Nixdorf, Olivetti Information Services, Alcatel TITN, OCE-Nederland, IBM Deutschland, Bull, University College London, SSI
- 2382** **ELO**
Elusive office
 Bonnscrip, CLS Computer Lernsysteme, Empirica, Fraunhofer-ISI, Heptacon Neptune Freight, OEVA-Versicherungen, Otter Online, Rutherford Appleton Laboratory, Standard Elektrik Lorenz
- 2404** **PROOF**
Primary rate ISDN OSI office facilities
 3 Net, Systems Wizards, University College London
- 2431** **HOME**
Home systems
 AEG, Alcatel Standard Eléctrica, Asea Brown Boveri, Bang & Olufsen, Bassani Ticino, British Telecommunications, Busch-Jäger-Elektro Centre, GEC, Honeywell Europe, Ikerlan
- 2455** **LTI**
Large-image terminals
 Nokia Grätz, Standard Elektrik Lorenz, Thorn EMI, University of Heriot-Watt
- 2463** **ARGOSI**
Applications-related graphics and OSI standards integration
 COSI, Fraunhofer Graphische Datenverarbeitung, GESI, GMD, INRIA, Laser-Scan Laboratories, Rutherford Appleton Laboratory, Tecciel, Thomson-CSF, University of East Anglia
- 2466** **KWICK**
Knowledge workers intelligently collecting, coordinating and consulting knowledge
 ADVORGA FA Meyer, Artificial Intelligence Systems, Bull, CEC, ISPRa Establishment, CMSU, CNRS, Elsa Software, Elsevier Science Publishers, Espasa-Calpe, IRIAM, Maatschappij Voor Informatica Diensten, Office Workstations, Tecograf Software, Università degli Studi di Milano, University of Glasgow

2476 <i>Bank '92</i> Banco de Sabadell, Banco Herrero, Bull España, Caja de Ahorros del Mediterráneo, Caja Insular de Ahorros de Canarias, CAP Gemini Sogeti, Computer Logic R&D, Credito Italiano, Entel, Ikoss, INESC, CRI, Prisma Informatica, Silogia, STC-ICL, Thomson-CSF, Unibanque	BANK '92	5011 <i>Bootstrap project for joint European printer server</i> Bull, OCE-Nederland, Siemens-Nixdorf	JEPS
2484 <i>High-performance technical workstation</i> ACE, British Aerospace, Caption, GIPSI, Kontron Elektronik, Telmat informatique, Queen Mary & Westfield College, Universität Tübingen, University of Sussex, École polytechnique fédérale de Lausanne	SPIRIT	5012 <i>Bootstrap project for a multiple device file server</i> Bull, Philips, Rodime	PREJEEMI
2499 <i>CD-ROM workbench</i> ACT, Clarinet Systems, Elektrotron, Katholieke Universiteit Nijmegen, Textware	CDR	5140 <i>Home interactive environment</i> Bang & Olufsen, Centra Burkle, Honeywell Europe, Jydsk Telefon, University of Bristol	HIVE
2512 <i>Intelligent area communication and information system</i> Administração do Porto de Lisboa, Port Autónom de Barcelona, Bull Italia, CSELT, Entel, INESC, Ositel, Prisma Informatica, SECURE, SEGET, SIRTI, SISMET, Porto di Genova, Stollmann, SYD, Synergia, Tecno T&G, Telefónica, Televas, Universidad Politécnica de Madrid, Universität Stuttgart	IACIS	5165 <i>Distributed open management architecture in networked systems</i> Harwell Laboratory, ITK, Mari Group, Philips, Roke Manor Research Limited, Siemens, université Pierre et Marie Curie, University of Athinaí, Architecture Projects Management	DOMAINS
2563 <i>General distributed architecture for unified communication in heterogeneous OSI-environments</i> ADVORGA FA Meyer, Dannet, Fischer & Lorenz, Project Management Consultants, RC-Computer Telefónica, Universidad Politécnica de Madrid	GAUCHO	5167 <i>European raster image processor for common fonts and page description languages</i> Autograph International, Fraunhofer Graphische Datenverarbeitung, URW	EURORIP
2569 <i>European workstation</i> Bull, Chorus Systèmes, Fraunhofer Graphische Datenverarbeitung, GIPSI, Grupo Apd, INESC, INRIA, Rutherford Appleton Laboratory, Siemens-Nixdorf, University of Brunel	EWS	5193 <i>Metropolitan area communication system</i> Alcatel, British Telecommunications, CSELT, Hewlett-Packard, IRIT, KTAS, L-Cube Information Systems, NKT, SIRTI, Telettra, université Pierre et Marie Curie, University of Athinaí	MAXI
2633 <i>Magnetic media for future ultra-high-density information storage</i> Agfa Gevaert, Aristoteles University Thessaloniki, BASF, CNRS-Mulhouse, Du Pont de Nemours de Luxembourg, Institut national polytechnique de Lorra, université de Bordeaux	MAG-UHD	5199 <i>A distributed environment monitor for the ISA architecture</i> Architecture Projects Management, Mari Group, Universidade de Aveiro	ISA-DEMON
2638 <i>Advanced display optimization tools</i> British Aerospace, City University (London), OCE-Nederland, Sogitec, TNO	ADOT	5203 <i>Innovative techniques for recognition and processing of documents</i> AEG Electrocom, CTA, EWH Koblenz, Nottingham Polytechnic, Olivetti Systems & Networks, Pacer Systems, Università di Napoli	INTREPID
2649 <i>Visual arts system for archiving and retrieval of images</i> Brameur, Direction des musées de France, Dörner Institut, Eikon, National Gallery, Syseca, Telecom Paris, Thomson-CSF, TÜV, University of London (Birkbeck College)	VASARI	5233 <i>Telestation</i> Active Book Company, Alcatel, ARG, Daimler-Benz, Hewlett-Packard, Olivetti Systems & Networks, Perihelion Software	TELESTATION
2684 <i>Multipoint interactive audiovisual system</i> Alcatel, Amper, British Telecommunications, CNET, CSELT, PTT Research, Neher Laboratories, Telefónica	MIAS	5252 <i>Hypertext authoring</i> CEC-JRC Ispra Establishment, Epsilon Software, GMD, Ing. C. Olivetti, Politecnico di Milano, Siemens, Systems & Management	HYTEA
2704 <i>Development of a dedicated microprocessor with a universal crypto processor and its integration into high-security IC-cards</i> Bull, Siemens	CRYPTO-CARD	5279 <i>European distributed system integration project</i> British Telecommunications, Bull, CAP Sogeti Innovation, CNRG, Datamont Feruzzi Group, Ensta-Liès Grupo, INESC, INRIA, Kapsch, Siemens, STC Technology, Trinity College Dublin, Universitaire Instelling Antwerpen, Volmac Nederland, Architecture Projects Management	HARNESS
2705 <i>Integrated toolkit for highly advanced computer applications</i> Bull, CNRS-LADL, CMSU, D-TECH, Datamont Feruzzi Group, Delphi, Forth Research Centre, PTT Research and Development, Gip Altair, IFATEC, INRIA, Politecnico di Milano, Siemens-Nixdorf, SQL Databanksysteme, TAO, Technische Universität Dresden, Trinity College Dublin, Università degli Studi di Milano, Universität Zürich-IRCHEL, université de Genève	ITHACA	5303 <i>IT support for distributed cooperative work</i> Århus Universitet, Empirica, GMD, Jydsk Telefon, STC-ICL, Storebæltsforbindelsen-Great Belt, Triumph Adler, X-TEL Services	EUROCOOP
		5320 <i>Piloting ODA extensions and their applications in systems</i> Bull, IBM Deutschland, Olivetti Information Services, Siemens-Nixdorf, STC-ICL, Syntax Software Sistemi, University College London	PODA-SAX

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- 5322** **CHALLENGE**
Standardized EDI platform for applications using OSI
Bull HN Information Systems, EPEC, Epsilon Software, Ibermatica, Informabel, Irish Medical Systems, Siemens-Nixdorf, Pross
-
- 5341** **OSI 95**
High-performance OSI protocols with multimedia support on HSLANs and B-ISDN
Alcatel Austria — Elin, Bell Telephone, Bull, INRIA, Institut national des télécommunications, Intracom
-
- 5346** **EUROSHOP**
Distributed electronic shopping and integrated retail logistics for Europe
Corte Inglés, GIE-Recherche Haussmann, Littlewoods Organization, Siemens-Nixdorf, Sligos
-
- 5371** **PEMMON**
Performance management and monitoring of open networks in heterogeneous contexts
CSEE, Selenia, université Pierre et Marie Curie, University College Dublin
-
- 5374** **QLIS**
Software scenario models for quality of life in information society
Bang & Olufsen, BBC Productions, Open University, CAP Sogeti Innovation, Copenhagen Business School, Datamont Feruzzi Group, Fiat, Siemens-Nixdorf, Universität Marburg
-
- 5376** **ROCKI**
Raster to object conversion aided by knowledge-based image processing
Algotech, CNR, Fraunhofer-IPA, OCE-Nederland, TNO
-
- 5386** **OMIMAP**
Open microsystems initiative: microprocessor architecture project
Acorn Computers, Active Book Company, Bull, European Educational Software, IMEC, Inmos, Olivetti Systems & Networks, DRA, Siemens, Thomson-CSF, University of Manchester
-
- 5402** **FODATEC**
Feasibility demonstration of ODA for technical documents
Bureau van Dijk, Caption Kapsch, Universidad Politécnica de Cataluña, Universität Karlsruhe
-
- 5405** **HERMES**
Highly interactive environment resource management extendible system
Algotech Sistemi, Ayuntamiento de Sevilla, Azienda Servizi Municipali Comune di Brescia, CRI, Kommunedata, Novosoft, Paisley College Technology
-
- 5432** **PANDA**
Public administration demonstrator
Bull, Datacentralen, Grupo APD, IABG, SOGEI, Telefónica
-
- 5444** **ACIBS**
Architecture for computer-integrated business systems
CMSU, Norcontel (Ireland), Philips, Trinity College Dublin
-
- 5448** **IIH**
Integrated interactive home
British Telecommunications, Daimler-Benz, GEC Marconi, Legrand, Philips International, Siemens, Thomson-CSF, Thorn EMI, Zeltron
-
- 5469** **CITED**
Copyright in transmitted electronic documents
British Library, Bull, Bureau van Dijk, Charles Clark, Computer Industry Research Unit, Elsevier Science Publishers, Jaime Brull, NTE, Oxford University Press, Telematic Services, Télésystèmes
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- 5470** **MORESYS**
Accreditation and access control for smart-card mobile reader and communications system
Bull, Elgelec, SINORG, Telefónica, Telesincro
-
- 5492** **PROVIDE**
Digital distribution of video
Desisco, Iselqui
-
- 5631** **WINS**
Wireless in-house network studies
Alcatel Portugal, Ergon, Maintenance & Automation, Ste Seferiades & Associates, Universidade de Aveiro, Universidad Politécnica de Madrid, NTUA Propagation Group, NTUA Microwave & Optics Group, Universidad de Las Palmas de Gran Canaria, University of Limerick, LEREA SNC
-
- 5633** **HYTECH**
Hypertextual and hypermedia documentation
Datamont, Ifatec, INESC, Magneti Marelli, Universität Münster, Etnoteam
-
- 5634** **AURA**
Adaptable user interfaces for reusable applications
Fraunhofer, ISA, Mari Group, Thomson-CSF, University of Leeds
-
- 5636** **ALDUS**
Artificial legal draftsman for use in sales
Machine Intelligence, BIKIT, Hellenic Information Systems, Universiteit van Amsterdam, Wolters Kluwer, Imperial College of Science, Technology & Medicine, DIDA*EL, CNR-IDG
-
- 5638** **KIM**
Knowledge-based information management
Consorzio Roma Ricerche, Futurmedia, GESI, Irish Medical Systems, Software Italia, Trinity College Dublin, Università di Roma-La Sapienza
-
- 5639** **SMESPRIT**
An SME expert support system for planning and reporting about information technology
Addax, Algosystems, Delphi, Experteam, Hellenic Management Association, LSE
-
- 5640** **PIA**
Public information access
Sistemas Modulares, Association Acropol, System & Management, INESC
-
- 5641** **INCH**
Intelligent charts
Bull, CMSU, Datenzentrale Schleswig-Holstein, IGN-France international, INESC, ISSI, Kommunedata, Magistratsdirektion Wien, Télésystèmes
-
- 5644** **EXPORT**
Extended X-protocol for office-related technology
CNRG, Framentec, Meterquest
-
- 5650** **ERWIN**
European railways wireless in-house network
Autophon, CER, Plessey, Dialog Informatique
-
- 5652** **HYPERDOCSY**
Automatic production of technical documentation
Alcatel, Alsthom Recherche, Avions Marcel Dassault-Breguet Aviation, OC Consulting Engineers & Planners, Siemens SI
-
- 5653** **FOES**
Front-office environment study
Banque nationale de Paris, Bull, Concept Logiciels Expert, Pliroforiki, SELISA, Thorn EMI, Time Sharing, University College London
-

5656 **OSMOSE**
Open standard for multimedia optical storage environments
 Espasa-Calpe, Ing. C. Olivetti, Pergamon Compact Solution, Philips TDS

5660 **PECOS**
Perspectives on cooperative systems
 AIS, BIKIT, EMMEPI, Industrias de Telecomunicazione Lombardia, Mari Group, Universidad Politécnica de Madrid

Computer-integrated manufacturing

9
Exploitation of real-time imaging for arc welding
 Babcock Energy, Messer Griesheim, RWTH Aachen, Welding Institute of Cambridge

34
Design rules for computer-integrated manufacturing systems
 ISTEEL

75
Design rules for the integration of industrial robots into CIM systems
 Fraunhofer IPK, University College Galway, Renault Automation, RPK der Universität Karlsruhe

92 **CIPI**
A computer-integrated production insula: design rules and standards
 Logica

118
General-purpose sensory-controlled systems for parts production
 Comau, IPA-Fraunhofer Gesellschaft, OCN-PPL, Siemens-Nixdorf, SINCON

179
Integrated electronic subsystems for plant automation
 AEG, GEC Marconi Research

197
Computer-aided thermal image technique for real-time inspection of composite material
 Barr & Stroud, CNR, University of Strathclyde

278
Integrated sensor-based robot system
 IPA-Fraunhofer Gesellschaft, Joyce-Loebl, Mari Group, Robert Bosch, Universidade Nova de Lisboa, National Technical University of Athinai, University of Newcastle

293
Knowledge and decision support for material-handling systems
 Alcatel, Alsthom Recherche, CGP, Fraunhofer-IPK, IBM Deutschland, Instituto Superior Técnico

319
Data transfer between CIM systems and management information systems
 Computer Systems Development, Mentec International, Trinity College Dublin

322 **CAD-I**
CAD interfaces
 BMW, Cisigraph, Cranfield Institute of Technology, Danmarks Tekniske Højskole, GFS, Katholieke Universiteit Leuven, Kernforschungszentrum Karlsruhe, Leuven Measurement & Systems, NEH Technology, Rutherford Appleton Laboratory, Universität Karlsruhe

338
Product design for automated manufacture and assembly
 CIMAF, COMAU, Cranfield Institute of Technology, Renault automation

384
Integrated information processing for design planning and control of assembly
 AEG, Fraunhofer-IPK, GEC Research, Marconi Research, Induyco/Investronica, Télémécanique

409
Development of an integrated process and operations planning system with the use of interactive 3-D modelling techniques
 EXAPTSystems Technology, Matra Datavision, Volkswagen

418
Open CAM system allowing modular integration into factory management of a workshop structured in functional cells with various levels of automation
 CIG, Ing. C. Olivetti, Logica, Matra, Procos, RTM, RWTH Aachen, université de Bordeaux

477 **COSIMA**
Control systems for integrated manufacturing
 COMAU, Digital Equipment, Renault automation

496 **PAPILLON**
Design and specification of configurable graphics subsystems for CIM
 Generics Software, GTS, Trinity College Dublin

504 **PAQO**
Plant availability and quality optimization
 ADERSA, AMTRI, Battelle Institut, Danobat Coop, GRS, Ikerlan, Stewart Hughes, Technische Hochschule Darmstadt

534
Development of a flexible automated assembly cell and associated human factors study
 Dantec Elektronik, Medical Research Council, Risø National Laboratory, Vrije Universiteit Brussel, Westland

595
The application of CIM to welded fabrication
 Ålborg Shipyard, Danish Welding Institute, Italsiel, Odense Steel Shipyard, Università di Genova, Welding Institute of Cambridge

623
Operational control for robot system integration into CIM
 CNR-LADSEB, FIAR, Fraunhofer-IPK, Kuka Schweißanlagen & Roboter, Politecnico di Milano, PSI, Renault automation, Seram, Universidad Politécnica de Madrid, Universidade Nova de Lisboa, Universität Karlsruhe, université de Valenciennes, Universiteit van Amsterdam, University College Galway

688 **AMICE**
A European computer-integrated manufacturing architecture
 AEG, Aérospatiale, Alcatel, AT&T Nederland, British Aerospace, Bull, CAP Gemini Innovation, Cegelec Projects, Digital Equipment, Dornier System, Fiat Aviazione, Hewlett-Packard France, IBM Deutschland, Italsiel, Philips, Procos, RWTH Aachen, SEIAF, Siemens, STC-ICL, Volkswagen

809

Advanced control real-time CIM systems and concepts for flexible automation

Krupp, STC-ICL, TDS Dextralog, Technische Universiteit Delft, Universiteit van Twente

812

Experimental centre for system integration in CIM

Aeritalia, ELSAG, Philips, Politecnico di Milano, RWTH Aachen, SESA

850

Predesign of FMS for small-batch production of electronic cards

CSEA, ERIA, Eurosoft Systems

909

Development of tools for economic evaluation of CIM in smaller manufacturing companies

AMTRI, BIBA-Bremen, Institute for Industrial Technologies, CIMAF, Danmarks Tekniske Højskole, Mentec International, WTCM/CRIF

932

Knowledge-based real-time supervision in CIM

AEG, ARS, BICC Technologies, CEA, Fiar, Fraunhofer IPA, Philips, Pirelli, Politecnico di Milano, SGN Graphael, SIS AV, Universität Karlsruhe, université de Savoie

955

CNMA

Communication network for manufacturing applications

Aeritalia, BMW, British Aerospace, Bull, CGE, Elf Aquitaine, Fraunhofer Institut, GEC, Olivetti IS, Ricerca SCPA, PSA, Siemens-Nixdorf, STC-ICL

975

TRACIT

Transponders for real-time activity control of manufacturing links to CIM information technology systems

Polydata, Redar NAH-Ortungstechnik, TMTED

1062

ACCORD

Computer-aided engineering software for advanced workstations in the CIM environment

Athinai School of Economics, Bertin & Cie, GEC Research, Marconi Research, Philips, Société générale de techniques et d'études, Trinity College Dublin, Università di Genova, Vector Fields

1136

DASIQ

Distributed automated system for inspection and quality control

CEA-LETI, Microtecnica, SAGEM, Universität Hannover, Visitec

1199

Human-centred CIM system

BICC Technologies, Danmarks Tekniske Højskole, Dansk Teknologisk Institut, Greater London Enterprise, Krupp, NEH Technology, Rolls Royce, Universität Bremen, University of Liverpool, University of Manchester

1556

VITAMIN

Visualization standard tools in manufacturing industry

Fraunhofer Institut für Industrieinformation, Politecnico di Milano, Syseca, Team, université de Valenciennes

1561

SACODY

A high-performance flexible manufacturing system robot with dynamic compensation

AEG, Bertin & Cie, Katholieke Universiteit Leuven, Kuka Schweißanlagen & Roboter, Leuven Measurement & Systems, University College Dublin

1572

Basic technologies for high-performance solid-state image sensors

Thomson-CSF, Valvo Unternehmensbereich

1653

Intelligent process control by means of expert systems

Centre d'Estudis Avançades de Blanes, CNRS-LAAS, Dornier System, Eltec Elektronik, Miniwatt, Philips Composants, Universidad Politècnica de Catalunya

2010

NEUTRABAS

Neutral product definition database for large multifunctional systems

BIBA, Bremer Vulkan, Chantiers de l'Atlantique, GEC Alsthom, Construnaves, Cotec Computing Services, Decision International, Gesellschaft zur Entwicklung von DV-Methoden, Howaldtswerke — Deutsche Werft, Institut de recherche de construction navale, ITS, Schiffko, Sener-Sistemas Marinos, Technische Universität Berlin, Universidad Politècnica de Madrid, université Paul Sabatier de Toulouse, University of Strathclyde

2017

Automated process and assembly inspection by 3-D vision

INISEL, Philips Robotiker, Siemens, Silicon & Software Systems, Universität Erlangen-Nürnberg, Zenon

2032

CIM ALIVE

Implementation addressing levels of integration in various environments

AEG, Carlo Gavazzi Impanti, CEC Electrical Projects, Philips, SNIA BPD — Fiat Group

2043

MARIE

Mobile autonomous robot in an industrial environment

Framatome Group, Framentec, Hitec, IAI, Metek, Robert Bosch, Universiteit van Amsterdam, University of Strathclyde, Volmac Nederland

2090

EPIC

Early process design integrated with controls

Info Systems, City University (London), Intrasoft, Metek Motor Oil, Planet, Special Analysis & Simulation Technology, TNO

2091

VIMP

Vision-based online inspection of manufactured parts

Caption, CCD and CAD Image Comparison, Fraunhofer Institut für Information, Sponeri, Universität Karlsruhe, université Louis Pasteur de Strasbourg

2127

HIDCIM

Holographic labelling techniques for automatic identification in CIM environments

ICI Imagedata, King's College London, Krupp, Mandelli, Standard Elektrik Lorenz, Universidade do Porto

2165

IMPACT

Integrated modelling of products and processes using advanced computer technologies

Games Ingenieri France, Hellenic Aerospace Industry, Krupp, Lips, Unibed, Norsk Data, PAFEC, RWTH Aachen, Centre for Industriforskning, Sintef Group, Technische Universität Berlin, TNO, Universität Karlsruhe

2172

DIAS

Distributed intelligent actuator and sensors

EDF, Electricidade de Portugal, Empresa Fabril de Máquinas Eléctricas, ENEL, Esacontrol, Hartmann & Braun / Schoppe & Fäser, Instituto Superior Técnico, Mentec International, Montefibre, Sema Group Belgium

2178

RA-IQSE

Revision advisor — an integrated quality support environment

Asociación de La Industria Navarra, Computer Technologies, CRI, HCS Industrial Automation, Paisley College of Technology

2189

BIPMS

Building industry project management system

Baan Info Systems, Centre scientifique et technique de la construction, UTI Services

2192 **AIMBURN**
Advanced intelligent multisensor system for control of boilers and furnaces
 Electricidade de Portugal, Fábrica de Vidros Barbosa & Almeida, IDS, IGC, Instituto Superior Técnico, Mague, Servotrol, Imperial College of Science, Technology & Medicine, Trion Präzisionselektronik & Co, Unisoft

2195 **CADEX**
CAD geometry data exchange
 BMW, Det Norske Veritas, Disel, FECS, Fiat Aviazione, GFS, Hewlett-Packard, Isykon Software, Italcad Tecnologie e Sistemi, Norsk Data, Procad, Senter for Industriforskning, Siemens-Nixdorf, University of Leeds

2198 **FCPN**
Factory customer premises network
 Compañía Sevillana de Electricidad, EDF, INPT/ENSEEIH, National Research Centre, Polydata, Pross, Robert Bosch, Thomson-CSF, Universidad Politécnica de Madrid, University of Patras, University of Thrace 'Demokritos'

2202 **CIM-PLATO**
CIM system planning toolbox
 Bull, CNR-LADSEB, Fiar, Fraunhofer-IPK, Induyco/Investronica, Kuka Schweißanlagen & Roboter, Politecnico di Milano, Psi, Renault Automation, Universidad Politécnica de Madrid, Universidade Nova de Lisboa, Universität Karlsruhe, Universiteit van Amsterdam, University College Galway

2277 **CMSO**
CIM for multi-supplier operations
 Actis Zentrale Verwaltung, Afia, Alcatel, BIBA, Institute for Industrial Technologies, Catia Software Service, CMSU, DAF, Helsinki University of Technology, Instituto Superior Técnico, Lucas Automotive, OY Saab-Valmet, Technische Universiteit Delft, University of Warwick, Vegla Vereinigte Glaswerke, Wilhelm Karmann

2280 **LAMA**
Large manipulators for CIM
 AEG, Bertin & Cie, CASA, Dansk Teknologisk Institut, Fraunhofer-IPA, Fraunhofer-IPK, HF Jensen, Moog Controls, Putzmeister-Werke

2292 **TT-CNMA**
Testing technology for communications networks for manufacturing applications
 Acerli, Alcatel, BMW, Fraunhofer Institut für Informationstechnik, Siemens, SPAG-CCT, Swedish Telecom, TNC

2312 **CIRCE**
Application and enhancement of an experimental development centre
 Aeritalia, Alcatel, Elsag, Philips, RWTH Aachen

2331 **ADEPT**
Advanced distributed environment for production technology
 CMSU, Sema Group UK, Syntax Factory Automation, Teknecomp

2338 **IMPACS**
Integrated manufacturing planning and control system
 Alcatel, Alsthom Recherche, Comau, Digital Equipment, PA Consulting Group, université de Bordeaux, University College Galway, CENTUNION

2349
Fault tolerance in the control and management of production systems
 Adersa, AMTRI, Ikerlan, Mandelli, Pegaso/Enasa, PSA, Seram, Stewart Hughes

2415
Distributed manufacturing planning and control
 Harmonic Drive Antriebstechnik, Krupp, RDP Technology, Technische Universiteit Delft, Imperial College of Science, Technology & Medicine

2422 **AMICE II**
Amice II/P — CIM-OSA releases
 AEG Aerospaiale, British Aerospace, Alcatel, ATT Nederland, Bull, CAP Gemini, Sogeti, Cegelec Projects Digital Equipment, Dornier System, Fiat Aviazione, Hewlett-Packard France, IBM Deutschland, Italsiel, Philips, Procos, RWTH Aachen, SEIAF, Siemens-Nixdorf, STC-ICL, Volkswagen

2428 **IPCES**
Intelligent process control by means of expert systems
 Centre d'Estudis Avançades de Blanes, CNRS-LAAS, Dornier System, Eltec Elektronik, Philips Composants, Miniwatt, Solam-CAM, Universidad Politécnica de Cataluña

2434
Knowledge-based real-time controllers for distributed factory supervision
 Alcatel Austria — Elin, ARS, BICC Technologies, CEA, CGE, Fiar, Fraunhofer-IPA, Games Ingenieri, Noratom, Philips, Pirelli, Politecnico di Milano, RWTH Aachen, SIS AV, Steria, Tecnicas Reunidas, Universität Hannover, Universität Karlsruhe, université de Savoie

2439 **ROCOCO**
Real-time monitoring and control of construction site manufacturing
 Biba, Bremer Vulkan, British Maritime Technology, Cortec, CAP Gemini Europe, Chantiers de l'Atlantique, GEC Alsthom, Eleusis Shipyards, Fincantieri Helsinki, University of Technology, Magnemag, Masa-Yards, Microlog Team, Universiteit van Amsterdam

2457 **FLEXPLAN**
Knowledge-based planning and control in manufacturing environments
 ADVORGA FA Meyer, Artificial Intelligence Systems, CIM-Fabrik Hannover, IDS, Katholieke Universiteit Leuven, LVD Company, Metek, NTE, Universität Hannover

2483 **PANORAMA**
Advanced perception and navigation system for autonomous mobile applications
 British Aerospace, Mobile Robots, CEA, CRIF/WTCM, Easams, EID, Helsinki University of Technology, LNETI, Rauma-Repola, Sagem, Sepa, Tampelle Technical Research Centre of Finland, Universidad Politécnica de Madrid, University of Southampton

2486 **DYNAMO**
Integrated CAE techniques for dynamic analysis of structures
 Fiat Aviazione, Katholieke Universiteit Leuven, Leuven Measurement & Systems International, NCODE International, Politecnico di Torino, Porsche, Straco, Tritech, Universität Karlsruhe, université de technologie de Compiègne

2527 **CIDAM**
System with distributed database and configurable modules
 Digital Kienzle, Fiat Aviazione, Fichtel & Sachs, Mannesmann Hartmann & Braun, Sesam, Syseca, Trinity College Dublin, Universität des Saarlandes

2588 **DSDIC**
Design support for distributed industrial control
 AEG, GEC Electrical Projects, F. L. Smidth & Co., GEC Research, Marconi Research, Procos

2590 **IPDES**
Integrated product design system
 CETIM-Établissement de Senlis, Charmilles technologies, Coretech International, Deltacam Systems, École centrale de Lyon, Exapt-Systems, Gildemeister Automation, IDS, Kade-Tech, Matra, Mecánica de La Pena, Technische Hochschule Darmstadt

2614 **NIRO**
Neutral interfaces for robotics
 Byg Systems, CASA, Danmarks Tekniske Højskole, Dansk Ingeniør System, Disel, Kernforschungszentrum Karlsruhe, PSI, Reis & Co Maschinenfabrik, Seeber

2617 **CNMA**
Communications network for manufacturing applications
 Aeritalia, Aérospatiale, Alcatel, British Aerospace, Bull, CEGELEC Projects, Comconsult Communication Technologies, École polytechnique fédérale de Lausanne, Fraunhofer Institut für Information, Magneti Marelli, Olivetti IS, Ricerca SCPA, Renault, DiO Robotiker, Siemens-Nixdorf, Universidade do Porto, Universität Stuttgart

2623 **MAGIC**
Methods for advanced group technology integrated with CAD/CAM
 CAP Gemini, Sogeti, CETIM-Établissement de Senlis, LVD Company, Michel van de Wiele, WTCM/CRIF

2626 **AUTOCODE**
Intelligent system for automatic processing of design codes of practice
 Analyse de systèmes et informatique, Babcock & Wilcox Española, Ingeciber, CAE ISQ, Unisys España, Universidad Politécnica de Madrid

2637 **ARMS**
Advanced robotics manipulation system
 CEA, Citroën-PSA, CRIF/WTCM Industrial Automation, Industrie Zanussi, INRIA, Kuka Schweißanlagen & Roboter, Sipa, Tecnomatix Europe, Télémécanique, UKAEA, Zeltron

2640 **ICI**
Integration of intelligent process control and inspection in robot finishing
 Andenosa-Empresa Nacional de Óptica, Fraunhofer-IPK, Joyce-Loebl, Metalworks of Attika, University of Newcastle, Zenona

2656 **IDRIS**
Intelligent drive for shop-floor systems
 Mari Group, Nada Consulting Group, Robert Bosch, University of Newcastle

2658 **ARTIFACTS**
Advanced robotics in flexible automation: components, tools and strategies
 Fraunhofer-IPA, Intracom, Joyce-Loebl, Loughborough University of Components, Technology Mari Group, Robert Bosch, Siemens, Sincon, Universidade Nova de Lisboa, Universität Erlangen-Nürnberg, Universität Stuttgart, Zenon

2671 **KB-MUSICA**
Knowledge-based multi-sensors systems in CIM applications
 ARS, British Maritime Technology, Cortec, Cambridge Control, CGE Drägerwerk, Fabrica Escola Irmaos, Stephens EP, Fraunhofer-IPK, ICI, Krupp, Pegaso/Enasa, Senter for Industriforskning, Tecnopolis, CSATA Novus Ortus, Turing Institute, université de Savoie

2706 **MICIM**
Methodology for the introduction of CIM
 Carlo Gavazzi Systems, GEC Marconi, Philips International, TNO

2711 **MULTICON**
Multi-level shop-floor control
 AEG, AEG Ibérica de Electricidad, Biba, Carlo Gavazzi Impianti, Compagnia Generale Contatori, Officine Galileo di Sicilia, Technische Universität Braunschweig, Tecnopolis Csata Novus Ortus

5104 **CNMA**
Communications network for manufacturing applications
 Alcatel, British Aerospace, Bull, École polytechnique fédérale de Lausanne, Efavec, Fraunhofer-IITB, Magneti Marelli, Siemens-Nixdorf, Olivetti Information Services, Renault, Robotiker, Siemens, Syntax Software Sistemi, Télémécanique, Universidade do Porto, Universität Stuttgart

5109 **NIRO**
Neutral interfaces for robotics
 Byg Systems, Construcciones Aeronauticas, Danmarks Tekniske Højskole, Dansk IngeniørSystem, Disel Fiat, Kernforschungszentrum Karlsruhe, Odense Steel Shipyard, PSI, Reis & Co Maschinenfabrik, SEEBER

5114 **DIREK**
Knowledge-based real-time diagnosis and repair for a complete robotized handling and storage system
 BMT Fluid Mechanics, Pirelli, Siemens, SNIA BPD — Fiat Group

5136 **LITE**
Links and interfaces for tool data exchange
 Adeg, CIM-Centre NW F Technologie Transfer, Ikerlan, Kendu S Coop, RWTH Aachen, TOOL, Universität Karlsruhe

5161 **KBL**
Design, development and implementation of a knowledge-based leitstand
 AHP Havermann und Partner, AIC Management, IDS, Institute of Product Development

5168 **CACID**
Computer-aided concurrent integral design
 Albert Nestler Electronics, Association française de normalisation, BER Dessindus, Danobat Coop, Falko Standard EDV Software, Tecnation per l'Innovazione Tecnologica, Universität Karlsruhe

5172 **IDAM**
An integrated design and analysis environment for advanced magnetic devices
 Ansaldo, Bertin & Cie, Electrotecnica Artech, Labein, Polymotor, Rutherford Appleton Laboratory, Università di Genova, Vector Fields

5178 **DISCO**
Distributed management and coordination of scheduling system in a multisite production environment
 AEG, Bull, Fraunhofer-IAO, ISA, Magneti Marelli, PROMIP

5194 **CIVIS**
CIM vision system
 Adec Robot, Fraunhofer-IPA, I2S, IMEC, Kronimus, Optec, PSI Co Laboratories RCA

5206 **FICIM**
Fieldbus integration into CIM
 AEG Automatisierungstechnik, Alcatel, Bull, École polytechnique fédérale de Lausanne, EDF, Endress & Hauser, Esacontrol, Fraunhofer-IITB, Gespac, Hartmann & Braun / Schoppe & Fäser, Namur, Nuovo Pignone, Philips Robotiker, Senter for Industriforskning, Siemens, Softing, Universidade do Porto, Universität Karlsruhe, Universität Stuttgart

5220 **CAR**
Calibration applied to quality control and maintenance in robot production
 Fraunhofer-IPK, Kuka Schweißanlagen & Roboter, Leica, Taighdeclar Genesis Teoranta, Universiteit van Amsterdam

5272 **CIM-SEARCH**
Open sensor integrated architecture for managing manufacturing uncertainty
 Prozeßsteuerung und Schweißtechnik, Renault automation, University of Surrey

5288 **AMICE**
Amice II/M — CIM-OSA releases
 Aérospatiale, Alcatel, ATT Nederland, British Aerospace, Bull, CAP Gemini Europe, Daimler, Digital Equipment International, Ensidesa, Fiat Gepro, Hewlett-Packard France, IBM Deutschland, Italsiel, Philips, Procos, RWTH Aachen, Siemens, STC-ICL, Universidad de Valladolid

-
- 5292** **MOSAIC**
Modular open system architecture for industrial motion control
 BMW, CEA, Fagor, Fraunhofer-IPA, Marben, Mari Group, Mikron, Odense Steel Shipyard, Philips, ROL, Tecniro, Universität Stuttgart-IFF
-
- 5338** **CIMPLIFY**
Computer-integrated manufacturing of PCBs by laser-induced photolithography
 Electrónica Básica, ENS-DE chimie de Mulhouse, Philips, Rijksuniversiteit Gent, UCB Electronics, Universidad del País Vasco
-
- 5352** **PROFIT**
Process plant reliable operations facilitated and enhanced by information technology
 City University, DSM Research, Intrasoft, Modcomp, Sast, Sintef Group, Statoil, TNO
-
- 5369** **HEPHAESTOS**
Intelligent robotic welding systems for unique fabrications
 Algosystems, Centre de robotique intégrée, I & T Kalogeridis, IAI, Technische Universiteit Eindhoven, Torre, University of Goteborg, University of Lund, Welding Institute of Cambridge
-
- 5379** **FRUIT**
Fresh fruit tracking system
 Bristol Polytechnic, Fomesa, Robotec, Syntax Factory Automation, Trademco
-
- 5391** **HYPERFACE**
A hypermedial user interface management system for industrial applications
 CESI, CNR-IMU, Ensidesa, ERIA, Enoteam, INESC, Non-standard Logics, Università degli Studi di Milano
-
- 5392** **TT-CNMA II**
Testing technology for CNMA — Phase II
 Acerli, Alcatel, BMW, Bull, Fraunhofer-IITB, SPAG
-
- 5416** **CIMDATA**
A database for selection of CIM tools
 Cambashi, Fordesi, Fraunhofer-IPK, GEPRO, Longman Cartermill, Teknologisk Institut, TNO, WTCM/CRIF
-
- 5417** **BECAUSE**
Benchmark of concurrent architectures for use in scientific engineering
 Bertin & Cie, INRIA, Parsys, Rutherford Appleton Laboratory, University of Athinaí, Vector Fields
-
- 5424** **CIMPLE**
User-driven and configurable tool set for CIM implementation in SMEs
 Asociación de Investigación, Tekniker, BIBA-Bremen, Institute for Industrial Technologies, Blobis, Fordesi, IBK System- und Softwarehaus, Isardata, Kewill Systems, Nokia Research Centre
-
- 5467** **CIMSIM**
Integrated simulation for economic and technical evaluation of CIM implementation and management for SMEs
 ABC Systems & Software, AMTRI, BIBA, Institut for Industrial Technologies, CAP Gemini Europe, CERN, Fordesi, Isomag, Teknologisk Institut, WTCM/CRIF
-
- 5471** **FAME**
Five-axis manufacturing
 Fidia, Spalips Unibed, NEH Technology, Norsk Data, Norsk Jetmotor, Sintef Group, Technische Universität Berlin, Universität Stuttgart, Waldrich Siegen
-
- 5474** **COALA**
Computer-aided manufacturing layout design
 CAP Gemini Europe, Ilog, INRIA, Orbis, Serete Productique, université libre de Bruxelles
-
- 5478** **SUB-CONTROL**
Modular framework for evolutionary implementation of shop-floor control
 Asociación de la Industria Navarra, Fraunhofer-IPA, Hyperion Energy System, INESC, Picotron
-
- 5497** **PROCIC**
Process computer for computationally intensive control
 Delta T, Instituto Superior Técnico, Microprocessor Engineering, THOT Informatique
-
- 5499** **CODE**
Computer-supported enterprise-wide data-engineering
 Extech, Manager Software Products, Pilkington, RWE-DEA für Mineralöl und Chemie, Universität des Saarlandes
-
- 5510** **VOICE**
Validating OSA in industrial CIM environments
 Fraunhofer-IPK, ISMCM, Kernforschungszentrum Karlsruhe, Prism Computer & Communication Systems, Renault automation, TNO, Traub, Zenon
-
- 5524** **MDS**
High-performance computing for multidisciplinary dynamic simulation of mechanism
 ABB Robotics, Dansk Teknologisk Institut, Det Norske Veritas, Dornier System, FEMVIEW, Kernforschungszentrum Karlsruhe, Norsk Forsvarsteknologi, Sintef Group, Syntax Factory Automation
-
- 5532** **CIMPRES**
CIM model and implementation concept in precision and special tooling industry
 CIM-Fabrik Hannover, EICAS Automazione, IBM Deutschland, OSI, RWT, Wilhelm Fette
-
- 5564** **IDEAL-CIM**
Integrated design and evaluation of assembly lines within CIM
 AEG, Delta Industrie Informatik, Fraunhofer-IAO, Intracom Intrasoft, Sema Metra Group
-
- 5601**
Design and implementation of CNMA-based networks for CIM applications in SMEs
 Intracom, Fraunhofer-IPK
-
- 5602** **KNOBA**
Knowledge-based real-time systems for fault diagnosis of flexible manufacturing systems
 Asociación de Investigación, Teknikerdoimak, Fatronik System, GEPRO, LABLEIN, Technische Universiteit Delft
-
- 5603** **CIM-SME**
Joint technical and organizational design of CIM systems for SMEs
 BIBA, Cheshire Henbury Research & Consultancy, Danmarks Tekniske Højskole, EXTECH, GEPRO, Intervisie Strategie & Organisatie Advies
-
- 5604** **CIB**
Computer-integrated building
 CSTB, D'Appolonia, Dialogic, Euroexpert & Partners, PCK & Associates, Scott Wilson Kirkpatrick & Partners, SOGEA, Taywood Engineering, Technische Universiteit Delft, université de Liège, Volmac Nederland
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- 5605** **CIA**
Application of concepts, architectures and technology to computer-integrated agriculture
 Big Dutchman, Danish Meat Research Institute, Fraunhofer-IAO, Hotrasoft, I & ME Gesellschaft für Informatik & Mikroelektronik, Land-Data

5606 PRO-DATIS

Analysis of car crash behaviour through simulation
Cranfield Institute of Technology, ESI-Engineering Systems, FECS, Systex

5607 FLEXICOM

Multimedia communication system for the SME manufacturing environment
BICC Technologies, Globalsis Engenharia Sistemas, Greater London Enterprise, Solari Udine, TSI, University College Galway, University of Strathclyde

5608 TRAMON

Material flow transportation monitoring system
CLB Electronics, ORE, Polydata, Redar Nah-Ortungstechnik

5609 SMART

Yield improvement in SMD assembly
Fine Pitch, CSEA, University College Cork, Valtronic France, Weld-Equip

5610 ASSAN

Advanced sensor systems for autonomous navigation
Calabrese Engineering, CRIF/WTCM, Isra Systemtechnik, Robosoft, Sincon, Technische Hochschule Darmstadt, Tecnopolis Csata Novus Ortus, Università di Genova, Zenon

5611 OFSES

Fibre-optic sensor systems
Catsaros Automation, Leas Industrie, National Research Centre 'Demokritos', Imperial College of Science, Technology & Medicine

5620 ADONIS

Adaption of numerical hydrodynamic tools for integration into ship design systems
Astilleros Españoles, Cetena, Concentration Heat & Momentum, Danish Maritime Institute, DMT-Marinteknik, EMIT

5630

AI for fashion design and manufacturing
ABC Tecniche Avanzate di Gestione, ECC Couture, Face, Investil, Pili Carrera, Universidad de Málaga, Zenon

Basic research

3001 INSIGHT

Vision systems for a natural human environment
Centre de mathématiques de l'École polytechnique, INRIA, Katholieke Universiteit Leuven, Royal Institute of Technology, Ruhr-Universität Bochum, Università di Genova, Universität Karlsruhe, Universiteit van Utrecht, University College London, University of Keele, University of Oxford, University of Sheffield, University of Stirling

3003 CLICS

Categorical logic in computer science
Århus Universitet, CNRS-ENS, GMD, INRIA, Imperial College of Science, Technology & Medicine, Università di Parma, University of Cambridge

3006 CONCUR

Theories of concurrency: unification and extension
CWI, INRIA, Swedish Institute of Computer Science, Universiteit van Amsterdam, University of Edinburgh, University of Oxford, University of Sussex

3011 CEDISYS

Models, languages and logics for concurrent distributed systems
Århus Universitet, INRIA, Università di Pisa, University of Sussex

3012 COMPULOG

Computational logic
ADER, European Computer Industry Research Centre, Katholieke Universiteit Leuven, RWTH Aachen, Imperial College of Science, Technology & Medicine, Uninova, Università di Pisa, Università di Roma, Universität Kaiserslautern, Universität Passau, Universität Tübingen, université d'Aix-Marseille, University of Bristol, University of Edinburgh, University of Uppsala

3014

High-temperature superconductivity: concepts, models and methods
ISI, Max-Planck-Gesellschaft für Festkörperforschung, Rutherford Appleton Laboratory

3017 NOISE

Electrical fluctuations and noise in advanced microelectronics: submicron, 2-D gas and low-temperature devices
CNET, IMEC, Plessey, Research Caswell, Technische Universiteit Eindhoven, Università di Modena, université de Lille, université de Montpellier, Universiteit van Utrecht

3020 INTEGRATE

Integrating the foundations of functional, logic and object-oriented programming
CNRS, CWI, Philips Research Laboratories, Imperial College of Science, Technology & Medicine, Universidade Nova de Lisboa, Università di Pisa

3023 IS-CORE

Information systems: correctness and reusability
INESC, Katholieke Universiteit Brabant, Technische Universität Braunschweig, Imperial College of Science, Technology & Medicine, Universität Dortmund

3026 HESSILSIL

Heterostructures of semiconducting silicides on silicon: applications to Si-compatible optoelectronic devices
CRMC2-CNRS, Universidad Autónoma de Madrid, Università di Roma II, universités de Paris-VI et de Paris-VII, IESS-CNR

3030 ACQUILEX

Acquisition of lexical knowledge for natural language processing systems
CNR, Universidad Politécnica de Cataluña, Università di Pisa, Universiteit van Amsterdam, University College Dublin, University of Cambridge

3038 VAP

Vision as process
Ålborg Universitet, INPG, Linköping University, Royal Institute of Technology, University of Surrey, LIFIA, LTRF

3041 MESH

Possible mechanisms for high-T_c superconductivity and phenomenological approaches
CNRS-PMTM, Forth Research Centre, Universität Dortmund, Universität Karlsruhe, université de Paris-Sud, University of Oxford

3042 NANOFET

Performances and physical limits of heterostructure field-effect (HFET) transistors
ARMINES, CNRS, IMEC, University of Cambridge

3043 LATMIC

Lateral microstructures: fabrication, low dimensionality effects and applications to III-V devices
CNET, CNRS, National Microelectronics Research Centre, DRA, Universität Stuttgart, University of Cambridge, University of Exeter

3049 **NERVES**
Innovative architectures for neurocomputing machines and VLSI neural networks
 CSEM, École polytechnique fédérale de Lausanne, INPG, Politecnico di Torino, St Patrick's College, Universität Dortmund, Universität Stuttgart, université catholique de Louvain, université Joseph Fourier de Grenoble-I, University of Edinburgh, University of Oxford

3059 **ECOLES**
Development of representation in machine learning
 Turing Institute, Universidade do Porto, université de Paris-Sud, University of Bradford

3066 **AMODEUS**
Assimilating models of designers, users and systems
 Københavns Universitet, Logica Cambridge Ltd, Medical Research Council, Rank Xerox, Standard Elektrik Lorenz, université Joseph Fourier de Grenoble-I, University of York

3070 **FIDE**
Formally integrated data environment
 IEI-CNR, Gip Altair, Università di Pisa, Universität Hamburg, université de Paris-Sud, University of Glasgow, University of St Andrews

3074 **SEMAGRAPH**
The semantics and pragmatics of generalized graph rewriting
 CNRS, CWI, Katholieke Universiteit Nijmegen, STC-ICL, Imperial College of Science, Technology & Medicine, University of East Anglia

3075 **ALCOM**
Algorithms and complexity
 Århus Universitet, Computer Technology Institute, École des hautes études et sciences sociales, Freie Universität Berlin, INRIA, Trinity College Dublin, Universidad Politécnica de Cataluña, Università di Roma-La Sapienza, Universität des Saarlandes, Universiteit van Utrecht, University of Warwick, Rijksuniversiteit Utrecht

3085 **DRUMS**
Defeasible reasoning and uncertainty management systems
 Centre d'Estudis Avançats de Blanes, CNRS-LRI, Imperial Cancer Research Fund, IRISA, Queen Mary College, Universidad de Granada, université d'Aix-Marseille, université libre de Bruxelles, université Paul Sabatier de Toulouse

3086 **LDS**
Low dimensionality structures for future quantum semiconductor devices
 CNRS, École centrale de Lyon, LEAME/ISEN Lille, Forth Research Centre, INSA Lyon, Universidad de Barcelona, Universidad Politécnica de Madrid, université Blaise Pascal de Clermont-II, University College Cardiff

3092 **PDCS**
Predictably dependable computing systems
 Centre for Software Reliability, CNR-LEI, CNRS, Technische Universität Wien, Universität Karlsruhe, University of Newcastle, University of York

3096 **SPEC**
Formal methods and tools for the development of distributed and real-time systems
 Forth Research Centre, Katholieke Universiteit Nijmegen, Swedish Institute of Computer Science, Technische Universiteit Eindhoven, Imperial College of Science, Technology & Medicine, université de Grenoble, université de Liège, University of Manchester, University of Oxford

3104 **PROCOS**
Provably correct systems
 Århus Universitet, Danmarks Tekniske Højskole, Royal Holloway & Bedford New College, Universität Kiel, University of Manchester, University of Oxford

3105 **MOHAWC**
Models of human-actions in work context
 ISPRA, Risø National Laboratory, Roskilde Universitetscenter, Universität Bamberg Psychologie II, université de Liège, université de Paris-Nord, University of Manchester, University of Uppsala

3109 **PROMPT**
Programme for MOS processing technology
 Harwell Laboratory, IMEC, University of Cambridge

3121 **MOLCOM**
Conducting organic materials as molecular components for microelectronics
 CNRS, H. C. Ørsted Institute, ADIST-Instituto Superior Técnico, LNETI

3124 **SEMANTIQUE**
Semantics-based program manipulation techniques
 École Polytechnique, Københavns Universitet, Imperial College of Science, Technology & Medicine, University of Glasgow

3125 **MEDLAR**
Mechanizing deduction in the logics of practical reasoning
 INPG, ONERA-CERT, Research Institute for Symbolic Computation, Imperial College of Science, Technology & Medicine, Universität Kaiserslautern, université Paul Sabatier de Toulouse, Universität München, University of Oslo

3133 **NANSDEV**
Nanostructures for semiconductor devices
 CNM, IMEC, Ludwig Maximilian Universität, Philips Research Laboratories, Technische Universiteit Delft, Thomson-CSF, University of Glasgow

3143 **FOF**
Factory of the future production theory
 Bremen Institute for Industrial Technologies, Danmarks Tekniske Højskole, Helsinki University of Technology, SINTEF Group, Technische Universiteit Eindhoven, université de Bordeaux, University College Galway

3146 **DIRTYSUPRA**
Study of the influence of impurities on the properties of high T_c superconductors
 Max-Planck-Institut für Festkörperforschung, université de Paris-Sud, université libre de Bruxelles

3147 **PHOENIX**
Hierarchical integration of logic and functional paradigms: specifications, refinement and implementation
 GMD, Katholieke Universiteit Nijmegen, Imperial College of Science, Technology & Medicine

3148 **DEMON**
Design methods based on nets
 GMD, Rijksuniversiteit Leiden, Technische Universität München, Universidad de Zaragoza, Università degli Studi di Milano, Universität Passau, université de Paris-Sud, université libre de Bruxelles, University of Newcastle

3149 **MUCOM**
Multisensory control of movement
 CNR, CNRS, Katholieke Universiteit Nijmegen, Ruhr-Universität Bochum, université catholique de Louvain, université de Genève, University of Zürich

3152
Foundations of legal reasoning
 Imperial College of Science, Technology & Medicine, università di Pisa, Universität Kiel, Universität Tübingen, université d'Aix-Marseille, University College Cork, University of Edinburgh, University of London, University of Oxford, Bristol Polytechnic, Machine Intelligence Ltd

3160 **DIALOGUE**
Models for explanation and learning
 City University, CNR — Istituto di Linguistica Computazionale, Queen Mary College, Università di Pisa, University of the Aegean

3166 **ASMICS**
Algebraic and syntactic methods in computer science
 École normale supérieure de Lyon, INIC, LITP, Politecnico di Milano, Rijksuniversiteit Leiden, RWTH Aachen, Technische Universität Berlin, Technische Universität München, université de l'État à Mons, université de Lille, Università degli Studi di Milano, Università di Napoli, Università di Palermo, Universität des Saarlandes, université de Bordeaux, University College Dublin

3168 **DX CENTRES**
Limiting factors in III-V semiconductor devices due to donor-related deep states
 CNRS, Universidad Politécnica de Madrid, Università di Pisa, Universität Paderborn, université de Paris-VII, University of Lund, University of Sheffield

3174 **Si/Ge SLS**
Ultrathin silicon/germanium superlattices
 AEG, University of Lund, Universität München, University of Newcastle

3175 **DYANA**
Dynamic interpretation of natural language
 Technische Universität München, Universität Stuttgart, Universität Tübingen, Universiteit van Amsterdam

3177 **EPIOPTICS**
European project: investigation of optical probe techniques for interface characterization
 DRA, Technische Universität Berlin, Trinity College Dublin, Università di Messina, Università di Roma II, University College Cardiff, University of Liverpool

3178 **REFLECT**
Reflective expertise in knowledge-based systems
 BSR Consulting, ECN-NETH Energy Research Foundation, GMD, Interface Concilium, Universiteit van Amsterdam

3180 **FOCUS**
Foundations of optoelectronic computers
 IMEC, LEP Philips, Roke Manor Research, Trinity College Dublin, Universidad de Madrid — ETSI, Universidad Politécnica de Madrid, université de Paris-VII, University College London, University of Sheffield

3186 **NOROS**
Quantum noise reduction schemes in optical systems
 CNRS, CNET, INFM, Universität Konstanz, Max-Planck-Institut für Quantenoptik, DRA

3191 **BASIC GOODS**
Basic research actions for a geographic object-oriented database system
 Algotech, CNR-ISRDS, CNR-IASI, Fernuniversität Hagen, Universität Freiburg, INRIA, Università di Roma-La Sapienza

3199 **EOC**
ESPRIT optical computing
 CERT, CNET-CNRS, CNRS-LAAS, Heriot-Watt University, IMEC, IOTA, Istituto Nazionale di Ottica, Johann Wolfgang von Goethe-Universität, King's College London, Odense Universitet, Politecnico di Milano, Technische Universität Braunschweig, université Louis Pasteur, université de Toulon, Universidad de Madrid, Universität Erlangen-Nürnberg, Universität Kaiserslautern, Universität Münster, Vrije Universiteit Brussel

3200 **OLDS**
Structure and transport properties of organic low-dimensional systems for application to information technology
 Helmut Hund, Max-Planck-Institut für Festkörperforschung, Trinity College Dublin, Università di Genova, Universität Tübingen, University of Edinburgh, University of London (Queen Mary College)

3207 **ACTS**
High-resolution speech recognition: auditory connectionist technologies for speech
 INESC, INPG, Medical Research Council, Università di Milano, University of Cambridge, University of Edinburgh

3215 **CHEOPS**
Higher order logic-supported design for complex data-processing systems
 IMEC, Philips Research Laboratories, University of Cambridge

3216 **CHARME**
Correct hardware design methodology: towards formal design and verification for provably correct VLSI hardware
 Politecnico di Torino, Technische Hochschule Darmstadt, IMEC, université de Provence, University of Strathclyde

3219 **KAUDYTE**
Knowledge acquisition and use in dynamic task environments
 Institut für Informatik der Universität Bonn, Universität Bayreuth, Universität der Bundeswehr, université libre de Bruxelles, University of Oxford

3228 **SPRINT**
Speech processing and recognition using integrated neuro-computing techniques
 CAP Gemini Innovation, École nationale supérieure des télécommunications, IRIAC, DRA, Standard Elektrik Lorenz, Universidad Politécnica de Madrid

3230
Common foundations of functional and logic programming
 CNRS, Eidgenössische Technische Hochschule, Swedish Institute of Computer Science, Università di Roma, Universität Kaiserslautern, University College Swansea, University of Athinaí

3234 **SELF**
Organization and analogical modelling using subsymbolic computing
 CEAB-Blanes, Rolf Nevanlinna Institute, Universität Hamburg, université de Genève, université libre de Bruxelles, University of Lappeenranta, Vrije Universiteit Brussel

3237 **PATMOS**
Power and timing modelling, optimization and specification
 Telecom Paris, Universidad Politécnica de Canarias, Universität Kaiserslautern

3245 **LF**
Logical frameworks: design, implementation and experiment
 Chalmers University of Technology, INRIA, Università di Torino, université de Paris-VII, University of Cambridge, University of Edinburgh, University of Manchester, University of Oxford

3247 **DESON**
Disorder and electrical properties in silicon oxynitrides
 CNRS-LEPES, IMEC, Universidad Autónoma de Madrid, université de Montpellier, Universiteit van Utrecht

3249 **WGQR**
European working group on qualitative reasoning
 École polytechnique fédérale de Lausanne, Fraunhofer IITB, Heriot-Watt University, Siemens, Università degli Studi di Milano, University College London

3260 **TOPP**
Transverse optical patterns
 INFM, Physikalisch-technische Bundesanstalt

3264 **COMPASS**
A comprehensive algebraic approach to system specification and development
 Katholieke Universiteit Nijmegen, Technische Universität Berlin, CRI, Technische Universität Braunschweig, Universidad Politécnica de Cataluña, Università di Genova, Universität Bremen, Universität Dortmund, Universität Passau, université de Paris-Sud, University of Edinburgh

3267
Use of children's and teachers' explanations in the specification of systems of explanation for intelligent learning environments
 Kingston Polytechnic, London Institute of Education, London Mental Models Group (King's College), Royal Danish School of Educational Studies, université de Paris-Sud

3274 **FIRST**
Fundamentals of intelligent reliable robot systems
 INPG, Katholieke Universiteit Leuven, Università di Genova, Universität Karlsruhe, University of Oxford

3279 **ACCOR**
Articulatory-acoustic correlations in coarticulatory processes: a cross-language investigation
 CNR-Consiglio Nazionale delle Ricerche, CNRS, Ludwig-Maximilians-Universität, Siemens, Trinity College Dublin, Universidad de Barcelona, Universidad Politécnica de Valencia, University of Reading, University of Stockholm

3280 **NANA**
Novel algorithms for new real-time VLSI architectures
 IMEC, INPG, INRIA, Katholieke Universiteit Leuven, Technische Universiteit Delft

3281 **ASCIS**
Behavioural synthesis, partitioning and architectural optimization for complex systems on silicon
 IMEC, INPG, Danmarks Tekniske Højskole, Technische Hochschule Darmstadt, Technische Universiteit Eindhoven, University of Patras

3299 **COMPUGRAPH**
Computing by graph transformations
 Freie Universität Berlin, Rijksuniversiteit Leiden, Technische Universität Berlin, Università di Pisa, Universität Bremen, université de Bordeaux

3314 **MOLSWITCH**
Evaluation of molecular switch type devices: theory and experiment
 Københavns Universitet, Max-Planck-Institut für Festkörperforschung, université de Strasbourg, University of Uppsala

3327 **SUPRADYNAMICS**
Lattice dynamics of high T_c single crystal superconductors
 CNRS-CRPHT, Kernforschungszentrum Karlsruhe

3350 **COSTY**
Computers and optics study group
 CNET, IMEC, Philips-LEP, Roke Manor Research, Trinity College Dublin, Universidad de Madrid — ETSI, Universidad Politécnica de Madrid, université de Besançon, université de Paris-VII, université libre de Bruxelles, University College London, University of Athinaï, University of Sheffield

3351 **DANDI**
Dialogue and discourse
 BIM, Copenhagen School of Economics & Business, École Polytechnique, IDSIA-Fondazione dalle Molle, Institiuid Teangeolaiochta Eireann, Institut für Deutsche Sprache, Katholieke Universiteit Brabant, Katholieke Universiteit Nijmegen, Max-Planck-Institut für Psycholinguistik, UMIST, Università di Milano, Università di Udine, Universität des Saarlandes, Universität Stuttgart, Universität Tübingen, Universitaire Instelling Antwerpen, université de Liège, Universiteit van Amsterdam, University of Cambridge, University of Essex, University of Oslo

3352
Working group on vision
 Ålborg Universitet, City University London, CNRS-LAAS, Fraunhofer-IITB, INPG, Linköping University, Morpho-Systèmes, NIHE, Norwegian Institute of Technology, Philips, Royal Institute of Technology, Tampere University of Technology, Technische Universität Hamburg, Technische Universität München, Trinity College Dublin, Universidad Politécnica de Cataluña, Universidade de Aveiro, Universidade de Coimbra, Universidade do Minho, Universidade Nova de Lisboa, Università di Genova, Università di Torino, Università di Trento, Università di Udine, Universität Karlsruhe, université de Paris-VI, University College of North Wales (Bangor), University of Brunel, University of Kent, University of Surrey, University of Sussex

3700 **VLSI DESIGN**
VLSI design training action

Ålborg Universitet, Centre commun de micro-électronique, City University London, CMSU, CNRS, Danmarks Tekniske Højskole, Dorset Institute, École polytechnique fédérale de Lausanne, ENSEA, Fachhochschule Augsburg, Fachhochschule Ulm, Georg-Simon-Ohm Fachhochschule, GMD, Helsinki University of Technology, Heriot-Watt University, IMEC, INPG, INSA, Institute of Higher Professional Education, Instituto Superior Técnico, Johann Wolfgang von Goethe-Universität, Katholieke Industriële Hogeschool West-Vlaanderen, King's College London, LABEIN, Lancashire Polytechnic, Middlesex Polytechnic, Napier Polytechnic of Edinburgh, National Microelectronics Research Centre, Newcastle upon Tyne Polytechnic, NIHE, Plymouth Polytechnic, Pôle de formation en micro-électronique, Politecnico di Milano, Politecnico di Torino, Polytechnic of Central London, Portsmouth Polytechnic, Rijksuniversiteit Gent, Rutherford Appleton Laboratory, RWTH Aachen, Sheffield City Polytechnic, Staffordshire Polytechnic, Tampere University of Technology, Techdarm Technische Hochschule Darmstadt, Technische Universität Braunschweig, Technische Universität Graz, Technische Universität Hamburg, Technische Universität Wien, Technische Universiteit Delft, Teesside Polytechnic, Thames Polytechnic, Trent Polytechnic, Trinity College Dublin, université de Lille, Universidad de Barcelona, Universidad de Cantabria, Universidad de Las Islas Baleares, Universidad de Las Palmas, Universidad de Sevilla, Universidad Politécnica de Cataluña, Universidad Politécnica de Madrid, Universidad Politécnica de Valencia, Universidade de Aveiro, Universidade de Coimbra, Universidade do Porto, Università di Bologna, Università di Genova, Università di Parma, Università di Pisa, Università di Roma, Universität Bremen, Universität des Saarlandes, Universität Duisburg, Universität Hagen, Universität Hamburg, Universität Kaiserslautern, Universität Karlsruhe, Universität Oldenburg, Universität Passau, Universität Tübingen, université catholique de Louvain, université de Montpellier, université de Paris-VII, université Pierre et Marie Curie, Universiteit van Amsterdam, Universiteit van Twente, University College of North Wales, University of Aberdeen, University of Bath, University of Bradford, University of Bristol, University of Brunel, University of Cambridge, University of Kreta, University of Essex, University of Exeter, University of Hull, University of Kent, University of Liverpool, University of Manchester, University of Newcastle, University of Nottingham, University of Oulu, University of Patras, University of Reading, University of Sheffield, University of Strathclyde, University of Sussex, University of Thracè 'Demokritus', University of Ulster

3701
Network of excellence in speech and natural language
 Roskilde Universitet, LIMSI/CNRS, Universität Stuttgart, University College Dublin, Instituto di Linguistica Computazionale/CNR, Universiteit Amsterdam, INESC, Ålborg Universitet, CNRS (Aix-en-Provence), National Technical University of Athinaï, University of Cambridge, Københavns Universitet, Universität Hamburg, UMIST, Università di Pisa, Rijksuniversiteit Utrecht, Universiteit van Tilburg, Universität des Saarlandes

3702
Network of excellence in distributed computing systems architecture
 Università di Bologna, Università di Pisa, University of Cambridge, INESC, INRIA/IRISA, Universität Kaiserslautern, LAAS/CNRS, Universiteit van Twente, Technische Universität Wien, Architecture Project Management, Bull-IMAG, Chorus Systèmes, Computer Technology Institute, ETSIT, IEI del CNR, Itatel, GMD-Fokus, université de Liège, Trinity College Dublin, Rijksuniversiteit Utrecht, Vrije Universiteit Amsterdam

3703
Network of excellence in computational logic
 Université d'Aix-Marseille-II, CWI, University of Bristol, University of Edinburgh, SLS CAP Gemini, Universität Kaiserslautern, Katholieke Universiteit Leuven, Universidade Nova de Lisboa, Universidad Politécnica de Madrid, ECRC, Universität Passau, Università di Pisa, Università di Roma I, Università di Roma II, IRST, University of Uppsala

Information exchange system

33 **ROSE**

Research open systems for Europe
Bull, GEC, Ing. C. Olivetti, Siemens, STC-ICL

130 **ELAN**

The Unix-united aspects of the IES
Mari Group, SG2

700 **ELAN**

ESPRIT/European local area network
Bull, ICL Belgium, Olivetti, Siemens Data

706 **EUROKOM**

Computer conferencing and electronic mail
University College Dublin

710

Information exchange system (IES) support services
IEGI, Expertel, Noveau Medias, GRS, Longman-Cartermill, IOS

717 **HERMES**

Message-handling survey and trends for the IES user community
Fischer Madsen & Lorenz Petersen

718 **CARLOS**

Communications architecture for layered open systems
Fischer Madsen & Lorenz Petersen, RC International, Universidad Politécnica de Madrid, CASE Communications, INESC, PMC, Universidad Politécnica de Cataluña

719 **THORN**

The obviously required name-server
Bull, CERN, DFN, GEC, Ing. C. Olivetti, INRIA, Siemens, STC-ICL, Systems Wizards, University College London

5700 **Y-NET**

Y-Net
Teleo, Bull, Olivetti Systems and Networks, Siemens-Nixdorf Informationssysteme



Industry participants and sites

2I Industrial Informatics Freiburg	Adepa Montrouge	AIC Management Torino
3-Net Basingstoke	Aderfrance Marseille	AIIT Gerrards Cross
7-Teknologi København	Administração do Porto de Lisboa Lisboa	AIS Milano
A. T. Kearney London	ADR-CRISS Grenoble	AITEC Milano
ABB Robotics Vasteras	ADVORGA A. Meyer Wilhelmshaven	Aixtron Aachen
ABC Milano	Advanced Mechanics & Engineering Guildford	Albert Nestler Electronics Lahr
ABC Systems & Software Athinaí	Advanced Semiconductor Materials International Bilthoven	Ålborg Shipyard Ålborg
Abstract Hardware Uxbridge	Advanced Software Technology Milano	Alcatel Amsterdam; Chilly-Mazarin; Colombes; Évry; Harlow; La- Ville-du-Bois; Lannion; Les Ulis; Malakoff; Massy; Morangis; Paris; Puteaux; Toulouse
ABSY Bruxelles	Advanced System Architectures Camberley	Alcatel Alsthom Recherche Marcoussis
ACE Amsterdam	AEG Berlin; Frankfurt; Ulm; Böfingen	Alcatel Austria — Elin Wien
ACEC Charleroi	AEG Automatisierungstechnik Selinenstadt	Alcatel Bell Telephone Antwerpen
Acerli Fontenay-aux-Roses	AEG Electrocom Konstanz	Alcatel Face Standard Milano; Pomezia
Acorn Computers Cambridge	AEG Iberica de Electricidade Rubi	Alcatel Portugal Cascais
Acropol Association Nancy	AEG Olympia Konstanz; Wilhelmshaven	Alcatel Standard Eléctrica Madrid
ACT Paris	Aeritalia Napoli; Roma; Torino	Algosystems Athinaí
Actir-Santé Louveciennes	Aérospatiale Châtillon; Les Mureaux; Paris	Algotech Roma
Actis Zentrale Verwaltung Stuttgart	Afia Porto	Algotech Sistemi Frosinone
Active Book Company Cambridge	Agence de l'informatique Paris-la Défense	Alpha Athinaí
Active Memory Technology Reading	Agfa Gevaert Edegem; München	Alsys Henley-on-Thames
Addax Athinaí	Agusta Milano	
Adec Robot Schlieren	AHP Havermann und Partner Planegg	

Amber Lykovrisi	ATT Nederland Hilversum	Battelle Institut Frankfurt am Main
Amper Madrid	ATT Télécommunication Bruxelles	BBC London
Anacad Computer Systems Bonn	August Systems Crawley	BDH Poole
Analog Devices Limerick	Autograph International Lyngby	Bell Telephone Antwerpen
Analyse de systèmes et informatique Fontenay-sous-Bois	Port Autònom de Barcelona Barcelona	Bennetts Associates Burr ridge
Andersen Consulting Madrid	Autophon Levallois-Perret	Bense Coesfeld
Ansaldo Impianti Genova	Avions Marcel Dassault-Breguet- Aviation Saint-Cloud; Vaucresson	BER Dessindus Colmar
Applied Logic Research London	Axion Birkerød	Bertin & Cie Les Milles; Plaisir
Applied Magnetics Belgium Turnhout	AXON Porto	Bias Bremen
Apsis Meylan	Ayuntamiento de Sevilla Sevilla	BICC Technologies Hemel Hempstead
Aptor Meylan	Azienda Servizi Municipali Comune di Brescia	Big Dutchman Vechta; BIKIT; Gent
Architecture Projects Management Cambridge	Baan Info Systems Barneveld	BIM Everberg
ARG Vimodrone; Milano	Babcock Glasgow	BLOBIS Almassera
Argumens Duisburg	Babcock & Wilcox Española Bilbao	BMP Plasmatechnologie Garching
Aritex Badalona	Baltea Leini (Torino)	BMW München
ARS Milano	Balzers Balzers	Bogen Electronic Berlin
Artificial Intelligence Watford	Banco de Sabadell Barcelona	Bonnscript Bonn
Artificial Intelligence Systems Bruxelles	Banco Herrero Asturias	BPA-Technology and Management Dorking
Ascom Holding Bern	Bang & Olufsen Struer	Braghenti Malnate
Asea Brown Boveri Heidelberg; Ladenburg	Banque La Henin Paris	Brainware Berlin
ASM-Lithography Veldhoven	Banque nationale de Paris Paris	Brameur Aldershot
Asociación de la Industria Navarra Cordovilla-Pamplona	Barco Industries Kortrijk	Bremer Vulkan Bremen
Association française de normalisation Paris-la Défense	Barr & Stroud Glasgow	British Aerospace Bracknell; Chester; Bristol; London; Preston; Stevenage
AST Elektronik Kirchheim	BASF Ludwigshafen	British Library London
Astilleros Españoles Madrid	Bassani Ticino Varese	British Maritime Technology Cortec Wallsend

British Telecommunications Ipswich; London	Captec — Computer Applied Technics Malahide	Cetena Genova
Brown Boveri & Cie København	Caption Chantepie	CGE Chilly-Mazarin
BSO Utrecht	Carl Zeiss Oberkochen	CGED Bath
BSR Consulting München	Carlo Gavazzi Impianti Milano	CGP Orléans
Bull Angers; Bruxelles; Échirolles; Hemel- Hempstead; Köln; Les-Clayes-sous- Bois; Louveciennes; Massy; Nanterre; Paris; Saint-Martin-d'Hères	CASA — Construcciones Aeronáuticas Madrid	Chantiers de l'Atlantique Gec Alstom Paris
Bull España Madrid	CASEG Watford	Charles Clark London
Bull Italia Milano	Catia Software Service Stuttgart	Charmilles Technologies Meyrin
Bureau Marcel van Dijk Bruxelles	Catsaros Automation Athinaí	Cheshire Henbury Research & Consultancy Macclesfield
Busch-Jäger-Elektro Lüdenscheid	CCIP Noisy-le-Grand	Chorus Systèmes Saint-Quentin-en-Yvelines
BYG Systems Nottingham	CCS Madrid	CIG — Centre d'informatique générale Bruxelles
Cabinet Bensoussan Paris	CEA Grenoble	CIM Aachen; Hannover
Caja de Ahorros del Mediterráneo Alicante	CEGB Leatherhead	CIMAF Porto
Caja Insular de Ahorros de Canarias Las Palmas	Cegelec Levallois-Perret	CIMSA Vélizy-Villacoublay
Calabrese Engineering Modugno	Cegelec Projects Rugby	Cirrus Computer Fareham
Cambashi Cambridge	Centra Burkle Honeywell Europe Schoenaich	CISE Milano
Cambridge Consultants Cambridge	Centrisa Barcelona	CISI Rungis; Toulouse
Cambridge Control Cambridge	Centro de Calculo de Sabadell Barcelona	Cisigraph Vitrolles
Cameca Courbevoie	Centunión Madrid	Citroën Neuilly-sur-Seine
CAP New Malden	Cepsa Madrid	CITSA Santiago
CAP Gemini Europe Bruxelles; Rijswijk	CER Bruxelles	Citymax London
CAP Gemini Innovation Meylan; Paris	Cerci Fontenay-sous-Bois	Clarinet Systems Blackwater
CAP Gemini Logic Stockholm	Cerilor Maxeville	CLB Electronics Amsterdam
CAP Gemini Sogeti Grenoble; Paris; Puteaux	Ceselsa Madrid	CLS Computer Lernsysteme Bonn
CAP Sogeti Innovation Meylan	CESI — Centro Elettrotecnico Sperimentale Milano	COGECO Milano
	Cesia Marseille	Cognitech Paris

COMAU Torino	CRI — Computer Resources International Birkerød; København	Décision International Toulouse
Comconsult Aachen	CRIL Colombes	Deister Electronic Barsinghausen
Compañía Sevillana de Electricidad Sevilla	CSC Amstelveen; Bruxelles	Delga International Madrid
Compugraphics International Glenrothes	CSEA Torino	Delphi Viareggio
Computas Expert Systems Hovik	CSEE Les Ulis; Toulon	Delta Industrie Informatik Waiblingen
Computer Industry Research Unit Norwich	CSELT Torino	Delta T Hamburg
Computer Logic R&D Athinaí	CTA Barcelona	Deltacam Systems Birmingham
Computer Systems Development London	D-Tech Athinaí; Luxembourg	Desarrollo de Software Barcelona
Computer Technologies Co Athinaí	DAF Eindhoven	Desisco Harrow
Concentration Heat and Momentum London	Daimler-Benz Berlin; Frankfurt; Stuttgart; Ulm	Det Norske Veritas Hovik
Concept Logiciels Expert Boulogne	Daltek Borlange	Deutsche Thomson-Brandt Villingen
Construcciones Aeronáuticas Madrid	Dancomp (Decanter, Richter & Rosenstand) København	Dialogic Paris
Construnaves Madrid	Dannet Birkerød	Didatel Milano
COPS Dublin	Danobat Coop Elgoibar	Digital Equipment Galway; München; Kaufbeuren; Bruxelles
Corelis Technologie Boulogne	Dansk Ingeniør System Glostrup	Digital Kienzle Villingen
Coretech International Les Ulis	Dansk Meat Research Institute Danmark	Disc Gent
Correlative Systems International Bruxelles	Dansk Parsim Consortium Charlottenlund	Disel Madrid
Corte Inglés Madrid	Dansk Teknologisk Institut Tåstrup	Diseño y Metodología Madrid
COSI Milano	Dansk Welding Institute Brøndby	DMT Marinetechnik Hamburg
Cossor Electronics Harlow	Dantec Skovlunde	Doimak Elgoibar
Cotec Computing Services Tyne and Wear	Data Management Milano	Domino Milano
Courseware Europe Zaandam	Datacentral Hvidovre; Valby	Dornier System Friedrichshafen
CPRM Lisboa	Datamat Ingegneria dei Sistemi Roma	Dorset Institute Dorset
CRAI Rende	Datamont Ferruzzi Group Milano	Dosiss Dortmund
CRAM Catania	Datenzentrale Schleswig-Holstein Kiel	Dow Benelux Terneuzen
Credito Italiano Milano		

Dr Jens Grumann Daten-Kommunikation Bad Homburg	Electrónica Básica Esparraguera	Envirotech International Athinai
Drägerwerk Lübeck	Electrotécnica Artech Munguía	EPEC Bruxelles
DSM Research Geleen	Elektroson Liempde	Epsilon Software Athinai
DST Bremen	Eleusis Shipyards Elefsina	Ergon Athinai
DT2I Meylan	Elf Aquitaine Saint-Symphorien	Eria Madrid
Dunaiturria y Estanconia Durango	Elgelec Fontenay-les-Briis	Erno Raumfahrttechnik Bremen
Du Pont de Nemours Luxembourg Luxembourg	Elios informatique Lannion	Erovi Barcelona
E2S Gent	ELISA Bures-sur-Yvette	Esacontrol Genova
EASAMS Camberley	Ellemtel Stockholm	ESF Bruxelles
EB Industry and Offshore Oslo	Elliop Madrid	ESI Rungis
EBO Athinai	Elltec Athinai	Espasa-Calpe Madrid
ECAT Luxembourg	Elsag Genova	Etnoteam Milano
ECC Couture Oldenzaal	Elsa Software Meudon-la-Forêt	Etra Electronic Traffic Valencia
EDC Heverlee	Elsevier Science Publishers Amsterdam	Eucad Cheltenham
EDF Chatou	Eltec Elektronik Mainz	Eurodisk Technologies Deeside
Eidetics Blackrock	Emit Bremerhaven	Euroexpert & Partners Aldershot; Paris
EFACEC Porto	Emmepi Milano	Europäisches Computer Industrie Forschungs Center München
Eicas Automazione Torino	Empirica Bonn	European Educational Software Cambridge
EIDE Monte de Caparica	Empresa Fabril de Máquinas Eléctricas Guarderios	European Silicon Structures Rousset
Eigner Karlsruhe	ENA Telecomunicaciones Getafe	Eurosil Electronic Eching
Eikon Roma	Endress & Hauser Maulburg	Eurosoft Systems Suresnes
Elabodater Caserta	Enel Roma	EWB Koblenz Koblenz
Electricidade de Portugal Sacavém	Enidata Bologna; Milano; Roma	Exapt Aachen
Electricity Association Services Chester	ENOSA Madrid	Experteam Slough
Electrolux Mecatronik Malmö	Ensidesa Avilés	Extech Galway
	Entel Madrid	

EYS Bilbao	Framentec Paris	Gildemeister Automation Hannover
F. L. Smidth & Co. Valby	France câbles et radio Paris	Gipsi Saint-Quentin-en-Yvelines
Fábrica de Vidros Barbosa & Almeida Vila Nova de Gaia	Fuigi Italiana Milano	GIT — Gesellschaft für Ingenieurtechniken Essen
Fábrica Escola Irmãos Stephens Marinha Grande	Futurmedia Bognor Regis	Glaverbel Jumet
Face Veldhoven	Gaas Code Cambridge	Globalsis, Engenharia Sistemas Lisboa
Fachhochschule Augsburg Augsburg	Game Ingenieri France Saint-Quentin-en-Yvelines	GN — Great Nordic København
Fachhochschule Ulm Ulm	GEC Chelmsford; Coventry; London; Rochester; Wembley; Whetstone	GPP Oberhaching bei München
Fagor Mondragón	GEC Alstom Saint-Ouen	Greater London Enterprise London
Falko Standard Edv Software Wien	GEC Marconi Borehamwood; London; Stanmore	GRS — Gesellschaft für Reaktorsicherheit Garching
Farran Technology Cork	GEC Software London	Grupo Apd Madrid
Fatronik System Elgoibar Guipúzcoa	GEI Aachen	Grupo de mecánica del vuelo Madrid
FEGS Cambridge	Gemplus Card International Aix-en-Provence	GSI Charenton
Femview Leicester	Generaldirektion PTT Forschung und Entwicklung Bern	GSI Teci Software Paris
Ferranti Chadderton; Cwmbran; Wythenshawe	Generics Software Dublin	GTS Darmstadt
FIAR Milano	Georg-Simon Fachhochschule Nürnberg Nürnberg	Guehring Automation & Co Stetton
Fiat Aviazione Torino	Gepro Aachen	H. F. Jensen København
Fichtel & Sachs Schweinfurt	Gesellschaft zur Entwicklung von DV-Methoden München	Harlequin Barrington; Cambridge
Fidia San Mauro	Gesi Roma	Harmonic Drive Antriebstechnik Limburg
Fincantieri Trieste	Gespac Plan-les-Ouates	Hartmann & Braun Minden
First International Patras	GFI Paris	HCS Industrial Automation Apeldoorn
Fischer & Lorenz Gentofte; Rickmansworth	GfS — Gesellschaft für Strukturanalyse Aachen	Hellaslex Athinaí
Fomesa — Food Machinery Española Valencia	GIE-Émeraude Suresnes	Hellenic Aerospace Industry Schimatari
Fondazione Ugo Bordoni Roma	GIE-Recherche Haussmann Paris	Hellenic Information Systems Athinaí — Marousi
Fordesi Lisboa	Gildemeister Nordrhein-Westfalen	Hellenic Management Association Athinaí
Foxboro Nederland Soest		Helmut Hund Wetzlar

Heptacon London	ICI Imagedata Welwyn Garden City	Ing. C. Olivetti & C. Ivrea; Pisa; Torino
Heraeus Quarzschmelze Hanau	ICI Wafer Technology Milton Keynes	Ingeciber Cae Madrid
Hewlett-Packard Böblingen; Bristol; Wokingham	ICL Belgium Bruxelles	Ingegneria Informatica Padova
Hewlett-Packard France Villefontaine	ICS Enschede	Ingenieurbüro für IMHT Ratingen
Hitec Athinai Kallithea	Idate Montpellier	Inisel Madrid
Hoechst Wiesbaden	IDS Madrid	Inmos Bristol
Hoechst Ceramtec Marktredwitz	IEGI Luxembourg	Insos — Intelligent Software Solutions Barcelona
Honeywell Europe Bruxelles	IFAD Odense	Institute of Higher Professional Education Eindhoven
Hotrasoft Horst	Ifatec Versailles	Institute of Product Development Lyngby
Howaldtswerke — Deutsche Werft Kiel	IGC — Inspección y Garantía de Calidad Madrid	Intecs International Bruxelles
Hunting Technical Services Hemel Hempstead	IGN Paris	Intecs Sistemi Pisa
Hyperion Energy System Cork	Ikoss — Software Service Aachen	Interface Concilium München
I & T Kalogeridis Piraeus	Ilford Knutsford, Cheshire	Intergrated Circuit Testing Heimstetten
I&ME Wolfenbüttel	Ilog Gentilly	Intermetall Freiburg
I2S Bordeaux	Imperial Software Technology Cambridge	Interprogram Diemen
IABG Ottobrunn	Indecon Marousi	Intersys Graphic Bruxelles
IBA Winchester	Indecon Advanced Technology Athinai	Intervisie Strategie & Organisatie Advies Leiden
IBC-Danica Rødovre	Industrias de Telecomunicación Madrid	Intes Stuttgart
Iberduero Bilbao	Industrie Zanussi Pordenone	Intracom Peania
Iberia Líneas Aéreas de España Madrid	Induyco/Investrónica Madrid	Intrasoft Athinai
Ibermática Madrid; San Sebastián	Infoarbed Bertrange	Intron Sittard
IBK System-und Softwarehaus München	Informabel Bruxelles	Investil Vigo
IBM Deutschland Sindelfingen; Stuttgart	Informatica Sistemi (Fiat Group) Milano	IOT München
IBM France Paris	Infosys Puteaux	IPACRI Roma
IBP Pietzsch Ettlingen	Infotap Luxembourg	Ipsys Software Macclesfield
ICI Manchester; Winnington, Northwich	Infratest Industria München	

IRI Roma	Johnson Matthey Chemical Royston	Land-Data Visselhoevede
IRIAM Marseille	Joyce-Loebl Gateshead	Langton London
Iris Paliano	Judex Datasystemer Ålborg	Laser-scan Laboratories Cambridge
Irish Medical Systems Blackrock, Dublin	Jydsk Telefon Århus	LCC Courbevoie
ISA Stuttgart	Kade-Tech Écully	LDRA — Liverpool Data Research Association Liverpool
ISA Riber Rueil-Malmaison	Kapsch Wien	Leas Industrie Saim-Issmier
Isardata Wolfratshausen	Kendu S Coop Segura	Legrand Limoges
Iselqui Ancona	Kern & Co Arrau	Leica Milton Keynes
Isoft Orsay	Kewill Systems Walton-on-Thames	Lerea Illkirch
Isomag München	Knossos Technologies Heraklion	Lernout & Hauspie Speechproducts Ieper
Isomet Laser Systems Cwbran, Gwent	Knowledge Patras	Leuven Measurement & Systems International Herverlee
Isra Systemtechnik Darmstadt	Kommunedata København	Lexikon Ivrea
Issi Paris	Koninklijke Ptt Nederland Groningen	Leybold Heraeus Hanau
Istel Redditch	Kontron Elektronik Eching	LGMI Ivry-sur-Seine
Isykon Software Bochum	KPMG — Peat Marwick Consultants Frankfurt am Main	Lips Unibed Drunen
Italcad Technologie e Sistemi Genova	KPMG — Peat Marwick McLintock London	Littlewoods Organization Liverpool
Italsiel Roma	Kronimus Iffezheim	Lloyd's Register of Shipping Croydon, London
Italtel Telematica Milano; Santa Maria Capua Vetere	Krupp Essen	Logic Programming Associates London
ITMI Meylan	Krupp Atlas Elektronik Bremen	Logica Cambridge; Cobham; London
ITS — Ingeniería y Tecnología de Sistemas Madrid	KTAS — Københavns Telefon Aktieselskab København	Logimatic Ålborg
J-S Telecom Puteaux	Kuka Schweißanlagen & Roboter Augsburg	Logos Progetti Milano
Jaime Brull Madrid	L-Cube Information Systems Athinaí	Lombardia Informatica Milano
James Martin Associates Bruxelles	Laben Vimodrone	Longman Cartermill St Andrews
Jenni — International User Group London	Laborelec Linkebeek	LPS Torino
John Bell Technical Systems Fleet	Lagerwall Bandol	Lucas Birmingham; Belfast

- LVD Company
Wevelgem
- Maatschappij voor Informatica Diensten
Zeist
- Machine Intelligence
Cambridge
- Magistratsdirektion Wien
Wien
- Magnemag
Skovlunde
- Magneti Marelli
Milano
- Mague
Alverca
- Maintenance & Automation
Liège
- Manager Software Products
Pinneberg
- Mandelli
Piacenza
- Mannesmann Hartmann & Braun
Frankfurt
- Mannesmann/Digital
Karlsruhe; Ratingen; Wetter
- Maps Informática Industrial
Barcelona
- Maptel
Madrid
- Marben
Paris
- Marconi
Camberley; Fife; Leicester; Lincoln;
Portsmouth; St Albans
- Mares
Barcelona
- Mari Group
Gateshead
- Masa-Yards
Turku
- Matra
Bois-d'Arcy; Les Ulis; Montrouge;
Saint-Quentin-en-Yvelines; Toulouse;
Val-de-Reuil; Velizy-Villacoublay
- Matra-MHS
Nantes
- MBB — Messerschmitt-Bölkow-Blohm
München; Putzbrunn
- MBP Software & Systems
Dortmund
- MC2
Grenoble
- MCTS — Micro-Connectique
Technologies
Boulogne-Billancourt
- Mecánica de La Pena
Bilbao
- Medimatica
London
- Meiko
Bristol
- Memory Computer
Dublin
- Mental Images
Berlin
- Mentec International
Dublin; Dun Laoghaire
- Merck
Darmstadt
- Messer Griesheim
Frankfurt am Main
- Metalworks of Attika
Athinai
- Metek
Halandri
- Meterquest
London
- Michel van de Wiele
Kortrijk
- Micro
Évry
- Micro Focus
Newbury
- Microin R&D
Montgat
- Microlog
Bargteheide
- Microprocessor Engineering
Southampton
- Microtecnica
Torino
- MID
Nürnberg
- Mietec
Oudenaarde
- Mikron
Eching
- Milano Research Centre
Milano
- Mimetics
Paris
- Ministry of Defence
London
- Miniwatt
Barcelona
- MO Valve Company
London
- Modular Computer
Konstanz
- Modular Computer Services
Wokingham
- Modulex
Billund
- Mono Light Instruments
Weybridge
- Monotype Corporation
Redhill
- Montefibre
Porto Marghera
- Moog Controls
Tewkesbury
- Morpho-Systèmes
Avon
- Motor Oil
Athinai
- Myfra
Montrouge
- NA Software
Liverpool
- Nada Consulting Group
Gateshead
- Namur
Leverkusen
- National Software Centre
Dublin
- NCC — National Computing Centre
Manchester
- Ncode International
Sheffield
- NEA-Lindberg
Ballerup
- NEH Technology
København
- Neptune Freight
Dublin
- NHS
Birmingham
- Nixdorf Computer
Milano
- Nixdorf Computer Software
Dublin
- NKT
Brøndby
- Noesis
Versailles

Nokia Graetz Esslingen	Olivetti Systems and Networks Torino	Perihelion Software Shepton Mallet
Nokia Head Office Helsinki	Omega Generation Bologna	Philips Apeldoorn; Eindhoven; Hilversum; Aachen; Hamburg; Kassel; Nürnberg; Wien; Le Plessis-Robinson; Limeil- Brevannes; Nijmegen
Nokia Research Centre Espoo	Onera-CERT Toulouse	Philips Composants Dreux; Issy-les-Moulineaux; Bruxelles; Louvain-la-Neuve
Non-standard Logics Paris	Optec Rho	Philips International Nijmegen
Norcontel Dublin	Orbis Saarbrücken	Philips Research Laboratories Redhill
Norsk Data Kongsberg; Mühlheim	Organon International Oss	Philips Scientific London
Norsk Forsvarsteknologi Kongsberg	Origin Veldhoven	Phoenix VLSI Consultants Towcester
Norsk Jetmotor Kongsberg	Oros Meylan	Picogiga Les Ulis
Novabase — Sistemas Informação Bases Dados Lisboa	OSI — Officine Stampaggi Industriali Torino	Picotron Aartselaar
Novosoft Madrid	Ositel Meudon-Bellevue	Pili Carrera Porrino
NTE Barcelona; München	Otter Online Mühlheim	Pilkington Lathom; Ormskirk; St Asaph
Numerical Algorithms Group Oxford	Ove Arup & Partners London	Piraeus Graduate School Piraeus
Nuovo Pignone Bari	Ovum London	Pirelli Milano
O Dati Española Barcelona	Oy Saab-Valmet Uusikaupunki	Planet Athinaí
OC Consulting Engineers and Planners Birkørød	PA Consulting Group London	Plasma Technology Bristol
Océ-Nederland Venlo	Pacer Systems Nottingham	Plasmos München
OCN-PPL Torino	Pafec Nottingham	Plessey Beeston; Christchurch; Poole; Swindon; Towcester
Odense Steel Shipyard Odense	Page Ibérica Madrid	Pliroforiki Athinaí
OEVA-Versicherungen Mannheim	Pallas Bonn	Polydata Athinaí
Office Workstations Edinburgh	Parseq Chandlers Ford	Polyflow Louvain-la-Neuve
Officine Galileo di Sicilia Milazzo	Parsys London	Polymer Laboratories Church Stretton
Olivetti Milano	Parsytec Aachen	Polymotor Casella
Olivetti Bruxelles	PCK and Associates Athinaí	Porsche Weissach
Olivetti Information Services Bari	PCS Computersysteme München	Preussag Pure Metals Langelsheim
Olivetti Research Cambridge	Pegaso/Enasa Madrid	
	Pergamon Compact Solution London	

Prism Computer & Communication Systems Athinaï	Robert Bosch Darmstadt; Gerlingen-Schillerhöhe; Erbach; Hildesheim; Reutlingen; Stuttgart	SCAITECH Ballerup; Lyngby
Prisma Informatica Perugia	Robosoft Asnières	Scanray Hvidovre
Procad Karlsruhe	Robotec Bilbourough	Scantest System Værløse
Procos Birkerød	Robotiker Mungia	Schiffko Hamburg
Project Management Consultants Holte	Rodime Europe Glenrothes	Scicon London
Prologia Marseille	Roke Manor Research Romsey	Scott Wilson Kirkpatrick & Partners Basingstoke
Pross Madrid	Rol Orsay	Scottish Power Glasgow
Protexarms Paris	Rolls-Royce Watford	Scs Informationstechnik Hamburg
Prozeßsteuerung und Schweißtechnik Aachen	Rovsing København	Secre Paris
PSA Neuilly-sur-Seine	RSO Milano	Seeber Leifers
PSI Berlin	RTC Paris	SEGET Barcelona
Putzmeister-Werke, Maschinenfabrik Aichtal	RTM Torino	SEIAF Genova
Quinary Milano	Rutherford Appleton Laboratory Didcot	Sekas München
Racal Research Reading	RWE-DEA für Mineralöl und Chemie Hamburg	Seleco Pordenone
Rauma-Repola Tampere	RWT Coventry	Selenia Roma
RC Computer Åbyhøj	RWTUEV Essen	Selisa Chilly-Mazarin; Wissous
RCE — Réseaux communication entreprise Cergy-Pontoise	Rytrak Liverpool	Sema Group Bruxelles; London; Madrid
RDP Technology London	Sagantec Eindhoven	Sema Metra Group Fontenay-sous-Bois; Montrouge; Paris
RE Technology København	Sagem Paris	Semisystems Fruthwilen
Realace Dublin	SAIT Electronics Bruxelles	SENER — Sistemas Marinos Madrid
Redar Nah-Ortungstechnik Darmstadt	Sandretto Industrie Collegno	SEP Puteaux
Reis & Co Maschinenfabrik Obernburg	Saritel-Sarin Telematica Pomezia	Sepa Torino
Renault Rueil-Malmaison	SAS — Space Applications Services Bruxelles	Sept Caen
Renault Automation Boulogne-Billancourt; Le Chesnay	SAST Brentford	Serete Productique Paris
Riada & Co Dublin	SAT Paris	Servotrol Lisboa
		SES Software Engineering Services Neubiberg

SESA Puteaux; Rennes	Sismet Lisboa	Solam-Cam Barcelona
Sesam Torino	Sistemas Multiposto e Distribuidos Lisboa	Solari Udine
Sextant Avionique Vélizy-Villacoublay	Sistemi e Telematica Porto di Genova Genova	Solvay Bruxelles
SFGL Boulogne	Sitisa Addax Montbonnot	Sophiatec Valbonne-Sophia Antipolis
SG2 Génie informatique Paris	Sligos Paris	Souriau Boulogne-Billancourt
SGN Graphael Saint-Quentin-en-Yvelines	SMI Organometallic Division Marseille	Space Software Italia Taranto
SGS-Thomson Microelectronics Gentilly; Grenoble; Milano	Smiths Industries Aerospace & Defence Systems Cheltenham	SPAG Bruxelles
SIDAC Pomezia	SNIA BPD — Fiat Group Milano	Special Analysis and Simulation Technology Brentford
Siemens Berlin; Erlangen; Gräding; Karlsruhe; München; Paderborn; München; Regensburg; Unterschleißheim	Société des outils du logiciel Paris	Speroni Sostegno di Spessa Po — Pavia
Siemens Data Bruxelles Siemens Nixdorf Informa- tion Systems (SNI) Barcelona; München	Société générale de techniques et d'études Puteaux	SQL Databanksysteme Berlin
SIG Services Utrecht	Société lyonnaise des eaux Paris	Staf — Conseil de filière Staf Le Mans
Signum Computer München	Sofemasa Madrid	Standard Elektrik Lorenz Stuttgart
Silicon & Software Systems Dublin	Soft International Den Haag	Standard International Consulting Paris
Silogia Paris	Softing München	Statoil Trondheim
Silvertech Horsham	Softlab München	STC-ICL Bracknell; Harlow; Herts; Kidsgrove; London; Manchester; Newcastle under Lyme; Paignton, Devon; Reading; Sidcup; Stevenage; Sunbury- on-Thames; West Gorton; Wokingham
Simulog Saint-Quentin-en-Yvelines	Software Científico y Técnico Madrid	STE Seferiades & Associates Athinaï
Sinapse Paris	Software de Base Madrid	Step-informatique Paris
Sincon Roma	Software Engineering Service Ottobrunn	Steria Vélizy-Villacoublay
Sinorg Paris	Software España Madrid	Stewart Hughes Southampton
Sipa Vittorio Veneto	Software Ireland Belfast	Stollmann Hamburg
Sipe Optimisation Pratica di Mare	Software Italia Milano	Storebæltsforbindelsen Great Belt København
Sirti Milano	Software Sciences Macclesfield; Cheshire	Straco Compiègne
SIS Milano	SOGEA Rueil Malmaison	Strategic International Athinaï
Siscog Lisboa	SOGEI Roma	
	Sogitec Boulogne-Billancourt	

STZ Gesellschaft Dortmund	Team Ispra; Roma	Télesystèmes Paris
Suprenum Bonn	Techforce Leiden	Telettra Bologna; Cinisello Balsamo; Milano
Swedish Institute of Computer Science Kista	Technisystems Piraeus	Telettra España Madrid
SWIFT La Hulpe	Technology Applications Group Alnwick	Televas Milano
Sybase Bracknell	Teclab Ceparana	Telmat Informatique Sultz
SYD Paris; Puteaux	Tecmic Lisboa	Teseo Milano
Synergia Milano	Tecnation per l'Innovazione Tecnologica Torino	Textware Bagsværd
Syntax Factory Automation Torino	Tecnatom Madrid	The East Asiatic Company København
Syntax Software Sistemi Bari	Técnicas Reunidas Madrid	Thomson — CSF Bagneux; Boulogne-Billancourt; Cagnes-sur-Mer; Cesson-Sévigné; Colombes; Courbevoie; Illkirch- Groffenstaden; Issy-les-Moulineaux; Orsay; Paris; Saint-Égrève; Toulon
Sypro København København	Tecnirob Alfragide	Thomson — LCD Moirans
Syseca Rennes; Saint-Cloud	Tecno T&G Madrid	Thorn EMI Hayes
System Karlsruhe	Tecnomatix Europe Antwerpen	Thot Informatique Angers
System Software Factors Reading	Tecnopolis CSATA Novus Ortus Valenzano	Time-sharing Lisboa
Systems & Management Milano; Torino	Tecograf Software Milano	TMTED Dieren
Systems Designers Europe Camberley	Tecsiel Napoli; Pisa	TN Telenorma Frankfurt am Main
Systems Wizards Torino	Teice Control Madrid	TNC Hemel Hempstead
Systex Gif-sur-Yvette	Teknecomp Cavaglià	TNO Delft
Sysware København	Teldat Madrid	TOC Barcelona
Søren T. Lyngsø Hørsholm	Telefónica Madrid	Tolsys Dublin
TA — Triumph Adler Fürth; Nürnberg	Telefunken Electronic Heilbronn	Tool Annecy-le-Vieux
Taighdeclar Genesis Teoranta An Spideal	Telefunken Systemtechnik Ulm	Torre Navara
Tampelle Tampere	Telelogic Farsta	Touche Ross Management Consultants London
TAO Barcelona	Telematic Services Berlin	Trademco Athinaï
TAP Air Portugal Lisboa	Télémechanique Nanterre; Rueil-Malmaison	Transmodul Saarbrücken
Taywood Engineering Southall	Telesincro Cerdanyola	
TDS Dextralog Blackburn	Telesoft Farsta	

Transtools Madrid	UVA Amsterdam	Waldrich Siegen Siegen
Traub Reichenbach	Valtronic France Gif-sur-Yvette	Weld Helmond
Trialog informatique Paris	Valvo Unternehmensbereich Hamburg	Welding Institute of Cambridge Abington
Trion Präzisionselektronik & Co Berlin	Vdo Luftfahrtgeräte-Werk Frankfurt am Main	Westland Yeovil
Tritech Dublin	Vector Fields Oxford	Whitechapel Computer Works London
Trut — Kykloforiaki Thessaloniki	Vegla Vereinigte Glaswerke Aachen	Wild Leitz Instruments Heidelberg
TSI Roma	Veridatas Paris-la Défense	Wilhelm Karmann Osnabrück
TÜV Essen; München	Verilog Toulouse	Wilhelm Fette Schwarzenbek
TXT Milano	Video Display Systems Firenze	Wolters Kluwer Deventer
UCB Electronics Bruxelles	Vision Computing Dublin	Work Research Centre Dublin
UITESA Madrid	Visitec Seraing	X-Telephone Services Nottingham
Unibanque Paris	Voice Input Cambridge	Yard Software Systems Chippenham
Unisoft Lisboa	Volkswagen Ingolstadt; Wolfsburg	Zeltron Campofornido
Unisys España Madrid	Volmac Nederland Utrecht	Zenon Athina
URW Hamburg	VTE — Videotechnik & Elektronik Braunschweig	
UTI — Services Paris	Wacker-Chemie Burghausen	



University and research institute participants and sites

3IT Toulouse	CEA Fontenay-aux-Roses; Grenoble; Paris	CETIM Senlis
Academisch Ziekenhuis Rotterdam Rotterdam	CEA-LETI Grenoble	Chalmers University of Technology Gøteborg
ACRI Lyon	Cemota Vernaison	City University London
Adersa Verrières-le-Buisson	CENA Orly-Aérogare	CMSU Athinaï
AKZO International Research Arnhem	Centre commun de micro-électronique de l'Ouest Rennes	CNAM Paris
Ålborg Universitet Ålborg	Centre d'Estudis Avançades de Blanes Blanes (Cataluña)	CNET Bagneux; Issy-les-Moulineaux; Lannion; Meylan
AMTRI Macclesfield	Centre d'études du management Puyricard	CNR Padova; Pisa
Århus Universitet Århus	Centre de mathématiques de l'École Polytechnique Palaiseau	CNR-IL Bologna
Aristotle University of Thessaloniki Thessaloniki	Centre de robotique intégrée Paris	CNR-IDG Firenze
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Artificial Intelligence Research Institute Wien	Centre régional de technologie Électrique-Optique Limoges	CNR-IESS Roma
Asociación de Investigación Tekniker Eibar	Centre scientifique et technique de la construction Bruxelles	CNR-IMU Milano
Athinaï School of Economics Athinaï	Centro di Cultura Scientifica Como	CNRG Athinaï
BAZIS Leiden	Centro Nacional de Microelectrónica Madrid	CNRS Aix-en-Provence; Bagneux; Marseille; Orléans; Toulouse; Paris; Grenoble; Strasbourg; Orsay; Valbonne; Sophia Antipolis; Écully; Mulhouse; Villetaneuse
BBC Productions (Open University) Milton Keynes	CERICS Valbonne	Computer Technology Institute Patras
BIBA Bremen	CERN Genève	Consorzio Roma Ricerche Roma
BMT Fluid Mechanics Teddington	CERT Toulouse	Coventry Polytechnic Coventry
Brighton Polytechnic Brighton	CETE Méditerranée Les Milles	CPR Pisa
Bristol Polytechnic Bristol		
CCETT Cesson-Sévigné		

Cranfield Institute of Technology Milton Keynes	École polytechnique fédérale de Lausanne Lausanne	Fraunhofer IFT München
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CRIAI Napoli	Education Technology Institute Milton Keynes	Fraunhofer IITB Karlsruhe
CRIF/WTCM Bruxelles	EHESS-CAMS Paris	Fraunhofer IMS Berlin
CRIN Vandœuvre-lès-Nancy	Eidgenössische Technische Hochschule Zürich	Fraunhofer IMSS Duisburg
CSELT Torino	ELAB Trondheim	Fraunhofer Institut für Information Karlsruhe
CSEM Neuchâtel	Elektronik Centralen Hørsholm	Fraunhofer IPA Stuttgart
CSIC Madrid	ENEA Roma	Fraunhofer IPK Berlin
CSTB Paris	ENS Mulhouse	Fraunhofer ISI Karlsruhe
CWI Amsterdam	ENSEA Cergy	Fraunhofer ITW Dortmund
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Delft Hydraulics Delft	EPFL Lausanne	GETA Grenoble
Deutsches Herzzentrum Berlin Berlin	Ergonomic Institut Berlin	GIP Altair Le Chesnay
Direction des musées de France Paris	ESIEE Noisy-le-Grand	Glasgow College Glasgow
Dörner Institut München	European Centre for Weather Forecasts Reading	GMD Berlin; Darmstadt; Karlsruhe; St. Augustin
Dublin City University Dublin	FAW Ulm	Groningen University Groningen
ECN Petten	Fernuniversität Hagen Hagen	Handelshøjskolen i København Frederiksberg
École centrale de Lyon Écully	FIM-FGAN Ettlingen	Harwell Laboratory Didcot
École des mines de Saint-Étienne Saint-Étienne	Forschungszentrum Linz	Hatfield Polytechnic Hatfield
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École nationale supérieure Fontainebleau	Fraunhofer AIS Erlangen; München	Heinrich Hertz Institut Berlin
École normale supérieure Lyon; Paris	Fraunhofer Graphische Datenverarbeitung Darmstadt	Helsinki University of Technology Espoo
École normale supérieure des télécommunications Paris	Fraunhofer IAO Stuttgart	HERIE Nîmes
École Polytechnique Palaiseau; Paris		Heriot-Watt University Edinburgh

HUSAT Research Centre Loughborough	Institut supérieur d'électronique du Nord Lille	Konstanzun Konstanz
IABG Ottobrunn	Instituto Superior Técnico Lisboa	København Business School København
IASI Arganda del Rey	IPA-Fraunhofer Gesellschaft Stuttgart	Københavns Universitet København
IDSIA Lugano	IRAM Saint-Martin-d'Hères	Labein Bilbao
IKERLAN Mondragón	IRETIJ Montpellier	Lancashire Polytechnic Preston
IMAG Saint-Martin-d'Hères	IRIAC Paris	Linguistics Institute of Ireland Dublin
IMEC Heverlee (Leuven)	IRISA Rennes	Linköping University Linköping
Imperial Cancer Research Fund London	IRIT Toulouse	LITP Paris
INESC Lisboa; Porto	ISI Torino	LNET Lisboa
INFEM Genova	ISMCM Saint-Ouen	LNETH-ICEN Sacavém
Informació Cartogràfica i de Base Barcelona	Istituto Nazionale di Ottica Firenze	London Institute of Education London
INIC Porto	Istituto Trentino di Cultura Trento	London Mental Models Group London
INPG Grenoble	ITK — Informations-Technologie Kiel Kiel	Loughborough University of Technology Loughborough
INPT Toulouse	ITK — Katholieke Universiteit Brabant Tilburg	LSF London
INRIA Le Chesnay; Rennes; Valbonne; Vandœuvre-lès-Nancy	Johann Wolfgang von Goethe-Universität Frankfurt am Main	Ludwig-Maximilians-Universität München
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		National Gallery London

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NIHE Dublin	Ricerca SCPA Bari	Swedish Institute of Microelectronics Stockholm
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Norwegian Institute of Technology Trondheim	Rijksuniversiteit Leiden	Swiss Federal Institute of Technology Zürich
Nottingham Polytechnic Nottingham	Risø National Laboratory Roskilde	Tampere University of Technology Tampere
NUC Ålborg	Rof Nevanlinna Institute Helsinki	Technical Research Centre of Finland Espoo; Oulu
Odense Universitet Odense	Roskilde Universitetscenter Roskilde	Technische Hochschule Darmstadt Darmstadt
Onera — CERT Châtillon; Toulouse	Royal Holloway & Bedford New College Egham	Technische Universität Berlin Berlin
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ORE Utrecht	RSRE Great Malvern	Technische Universität Dresden Dresden
Oxford University Press Oxford	Ruhr-Universität Bochum	Technische Universität Graz Graz
Paisley College of Technology Paisley	Rutherford Appleton Laboratory Didcot	Technische Universität Hamburg Hamburg
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Plymouth Polytechnic Plymouth	SCK-CEN Mol	Technische Universität Wien Wien
Pôle de formation en micro-électronique Toulouse	Scuola Superiore S. Anna Pisa	Technische Universiteit Delft Delft
Politecnico di Milano Milano	Senter for Industriforskning Oslo	Technische Universiteit Eindhoven Eindhoven
Politecnico di Torino Torino	Seram Paris	Tecnopolis Csata Novus Ortus Valenzano (Bari)
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Polytechnic of Crete Chania	Sheffield City Polytechnic Sheffield	Teknologisk Institut Tåstrup
Portsmouth Polytechnic Portsmouth	Sintef Trondheim	Telecom Paris Paris
	SNS Pisa	Televerket Farsta
		Thames Polytechnic London

TNO Apeldoorn; Delft; Den Haag; Eindhoven; Leiden; Utrecht	Universidad Politécnica de Madrid Madrid	Università di Pisa Pisa
Trent Polytechnic Nottingham	Universidad Politécnica de Valencia Valencia	Università di Roma Roma
Trinity College Dublin Dublin	Universidade Católica Portuguesa Lisboa	Università di Roma - La Sapienza Roma
Turing Institute Glasgow	Universidade de Aveiro Aveiro	Università di Torino Torino
UKAEA Didcot; Dorchester; Harwell; London; Warrington	Universidade de Coimbra Coimbra	Università di Trento Trento
UMIST Manchester	Universidade do Porto Porto	Università di Udine Udine
UNINOVA Monte di Caparica	Universidade do Minho Braga	Università di Pavia Pavia
UNIQUEE Belfast	Universidade Nova de Lisboa Monte da Caparica	Universitaire Instelling Antwerpen Wilrijk
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Université de Besançon Besançon	Université Notre-Dame de la Paix Namur	University of Essex Colchester
Université de Bordeaux Talence	Université Paul Sabatier de Toulouse Toulouse	University of Exeter Exeter
Université de Genève Genève	Université Pierre et Marie Curie Paris; Versailles	University of Glasgow Glasgow
Université de Grenoble Grenoble	Université Toulon-Gessy Toulon	University of Göteborg Göteborg
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Université de Lille Lille		University of Jyväskylä Jyväskylä
		University of Keele Keele

University of Kent
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Iraklion

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University of London; Goldsmith's
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University of Lund
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University of Manchester
Manchester

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Garching-München

University of Newcastle
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University of Nottingham
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Oslo

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Oulu

University of Oxford
Oxford

University of Patras
Patras

University of Reading
Reading

University of Sheffield
Sheffield

University of Southampton
Southampton

University of St Andrews
St Andrews

University of Stirling
Stirling

University of Stockholm
Stockholm

University of Strathclyde
Glasgow

University of Surrey
Guildford

University of Sussex
Brighton

University of the Aegean
Athinai

University of Thrace 'Demokritus'
Xanthi

University of Ulster
Coleraine

University of Uppsala
Uppsala

University of Wales
Cardiff

University of Warwick
Coventry

University of York
York

University of Zürich
Zürich

Vrije Universiteit Brussel
Brussel



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